

Programming Manual

saki

[SJ00DCM01-04.1E]

First of all, thank you for purchasing the product of Saki Corporation.

Before using the product, please read this manual carefully together with the supplied manuals to ensure the prolonged life with the proper handling and the operation of this system.

Notations used in this manual

| Notation | Meaning |
|----------------|--|
| DANGER | "DANGER" indicates an imminently hazardous situation which could be threat to life or cause serious injury. |
| WARNING | "WARNING" indicates a potentially hazardous situation which could be threat to life or cause serious injury. |
| CAUTION | "CAUTION" indicates a potentially hazardous situation which could result in injury or equipment (including peripheral) damage. |
| NOTE | "NOTE" indicates an advice on operation. |

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Saki Corporation Programming Manual (Original Instructions)

Basic Operation
Table of Contents

1 Basic Operation of Inspection Software.....I-2

| | |
|---|------|
| 1.1 Basic Operation | I-2 |
| 1.1.1 Window Details | I-2 |
| 1.1.2 Switching Between Enlarged View Screen and Full View Screen | I-3 |
| 1.1.3 Area Moving in the Enlarged View Screen | I-3 |
| 1.1.4 Changing the Magnification | I-4 |
| 1.1.5 Switching Between the Images..... | I-4 |
| 1.1.6 Board Setting | I-5 |
| 1.1.7 Display the Edit Component Data Window | I-7 |
| 1.1.8 Setting the Range | I-10 |
| 1.1.9 Moving Component Data | I-11 |

2 System Setup.....I-12

| | |
|--|------|
| 2.1 System | I-13 |
| 2.1.1 Contents of System..... | I-14 |
| 2.1.2 NG Type..... | I-18 |
| 2.2 Operation Lamp..... | I-19 |
| 2.3 ALC | I-20 |
| 2.4 Motor | I-20 |
| 2.5 Marking..... | I-20 |
| 2.5.1 Collective Setting | I-20 |
| 2.5.2 Setting by Type of Marking | I-21 |
| 2.6 Barcode | I-24 |
| 2.7 Privilege Setting | I-25 |
| 2.7.1 User Accessible Level..... | I-25 |
| 2.7.2 Registration Method of New User..... | I-27 |
| 2.8 Send_DB Setting | I-28 |
| 2.9 Three LED Test..... | I-28 |
| 2.10 Machine Layout | I-28 |
| 2.11 Predefine Setting | I-28 |
| 2.12 Self Diagnosis..... | I-29 |
| 2.13 Machine Origin | I-29 |
| 2.14 DI/O | I-30 |
| 2.15 Focus..... | I-30 |
| 2.16 Show Conveyer | I-30 |
| 2.17 OK/NG Signals | I-31 |
| 2.18 IPM8540Adjust | I-31 |
| 2.19 CPK | I-31 |
| 2.20 Separate Conveyer..... | I-31 |
| 2.21 Output Files | I-31 |
| 2.22 Warning Setting | I-32 |
| 2.23 Repeatability | I-34 |

Inspection Data
Table of Contents

| | |
|--|--------------|
| 1 Make Inspection Data | II-2 |
| 1.1 Make Inspection Data on AOI Machine..... | II-2 |
| 1.2 Make Inspection Data on BF-Editor | II-12 |
| 1.2.1 Transfer Data to BF-Editor..... | II-12 |
| 1.2.2 Make Inspection Data on BF-Editor | II-15 |
| 1.3 Make User Define Format | II-17 |
| 1.4 Auto Deployment of Inspection Data..... | II-25 |
| 1.4.1 Auto Deployment of Chip Component | II-25 |
| 1.4.2 Auto Deployment of IC Component | II-27 |
| 1.5 Search Inspection Data | II-29 |
| 1.6 Inspection Image | II-31 |
| 2 KPK | II-32 |
| 2.1 Inspection Overview | II-32 |
| 2.1.1 OKNGColors Lighting | II-32 |
| 2.1.2 Inspection Method..... | II-32 |
| 2.2 Make KPK Data..... | II-33 |
| 2.2.1 With Bare PCB..... | II-34 |
| 2.2.2 No Bare PCB | II-37 |
| 2.2.3 Auto Deployment of KPK | II-39 |
| 2.3 Adjust KPK Data..... | II-42 |
| 2.3.1 KPK Debug | II-42 |
| 2.3.2 Edit Component Data Window..... | II-44 |
| 2.3.3 Detail Settings of OKNGColors Lighting | II-45 |
| 3 ECD | II-48 |
| 3.1 Inspection Overview | II-48 |
| 3.2 Inspection Procedure | II-48 |
| 3.3 ECD Debug | II-57 |
| 3.4 ECD Mask Function | II-60 |

Inspection Algorithm
Table of Contents

| | |
|--|--------------|
| 1 Inspection Algorithm | III-2 |
| 1.1 New_ASC..... | III-2 |
| 1.1.1 Inspection Overview..... | III-2 |
| 1.1.2 Parameter Setting | III-2 |
| 1.1.3 Setting Procedure | III-3 |
| 1.2 LTracking / WTracking | III-6 |
| 1.2.1 Inspection Overview..... | III-6 |
| 1.2.2 Parameter Setting | III-6 |
| 1.2.3 Setting Procedure | III-7 |
| 1.2.4 The difference between LTracking and WTracking | III-7 |
| 1.2.5 Algorithm V1+V2..... | III-7 |
| 1.3 ColorLTrack / ColorWTrack..... | III-8 |
| 1.3.1 Inspection Overview..... | III-8 |
| 1.3.2 Parameter Setting | III-8 |
| 1.3.3 Setting Procedure | III-9 |

| | |
|--|--------|
| 1.4 ChipMissing3 | III-10 |
| 1.4.1 Inspection Overview..... | III-10 |
| 1.4.2 Parameter Setting | III-10 |
| 1.4.3 Setting Procedure | III-11 |
| 1.4.4 Calculation of Sample Value..... | III-11 |
| 1.5 Length | III-12 |
| 1.5.1 Inspection Overview..... | III-12 |
| 1.5.2 Parameter Setting | III-12 |
| 1.5.3 Setting Procedure | III-13 |
| 1.6 ColorXY | III-14 |
| 1.6.1 Inspection Overview..... | III-14 |
| 1.6.2 Parameter Setting | III-14 |
| 1.6.3 Setting Procedure | III-15 |
| 1.7 AreaColor | III-16 |
| 1.7.1 Inspection Overview..... | III-16 |
| 1.7.2 Parameter Setting | III-16 |
| 1.7.3 Setting Procedure | III-17 |
| 1.8 Average | III-18 |
| 1.8.1 Inspection Overview..... | III-18 |
| 1.8.2 Parameter Setting | III-18 |
| 1.8.3 Setting Procedure | III-19 |
| 1.9 Black/White | III-20 |
| 1.9.1 Inspection Overview..... | III-20 |
| 1.9.2 Parameter Setting | III-20 |
| 1.9.3 Setting Procedure | III-21 |
| 1.9.4 Algorithm BrightLevel..... | III-22 |
| 1.9.5 BrightLevel Setting Procedure | III-23 |
| 1.9.6 Algorithm LandJudgement..... | III-24 |
| 1.9.7 LandJudgement Setting Procedure | III-25 |
| 1.10 Peak | III-26 |
| 1.10.1 Inspection Overview..... | III-26 |
| 1.10.2 Parameter Setting | III-26 |
| 1.10.3 Setting Procedure | III-27 |
| 1.11 Range | III-28 |
| 1.11.1 Inspection Overview..... | III-28 |
| 1.11.2 Parameter Setting | III-28 |
| 1.11.3 Setting Procedure of Shift Inspection..... | III-29 |
| 1.11.4 Setting Procedure of Polarity Inspection..... | III-30 |
| 1.11.5 Use of Average | III-31 |
| 1.11.6 Setting Procedure of Average(SOP)..... | III-32 |
| 1.11.7 Setting Procedure of Average(QFP) | III-33 |
| 1.12 LiftedLead..... | III-34 |
| 1.12.1 Inspection Overview..... | III-34 |
| 1.12.2 Parameter Setting | III-34 |
| 1.12.3 Setting Procedure | III-36 |
| 1.12.4 Liftedlead Setting Window | III-37 |

| | |
|-----------------------------------|--------|
| 1.13 ASLeadLength..... | III-38 |
| 1.13.1 Inspection Overview..... | III-38 |
| 1.13.2 Parameter Setting | III-38 |
| 1.13.3 Setting Procedure | III-39 |
| 1.14 AS_Av_LeadLength..... | III-40 |
| 1.14.1 Inspection Overview..... | III-40 |
| 1.14.2 Parameter Setting | III-40 |
| 1.14.3 Setting Procedure | III-41 |
| 1.15 Distribution..... | III-42 |
| 1.15.1 Inspection Overview..... | III-42 |
| 1.15.2 Parameter Setting | III-42 |
| 1.15.3 Setting Procedure | III-43 |
| 1.16 IC_Solder2..... | III-44 |
| 1.16.1 Inspection Overview..... | III-44 |
| 1.16.2 Parameter Setting | III-44 |
| 1.16.3 Setting Procedure | III-46 |
| 1.17 New_OCR | III-54 |
| 1.17.1 Inspection Overview..... | III-54 |
| 1.17.2 Parameter Setting | III-54 |
| 1.17.3 Setting Procedure | III-55 |
| 1.18 ImageMatchEx..... | III-56 |
| 1.18.1 Inspection Overview..... | III-56 |
| 1.18.2 Parameter Setting | III-56 |
| 1.18.3 Setting Procedure | III-57 |
| 1.19 OCV..... | III-58 |
| 1.19.1 Inspection Overview..... | III-58 |
| 1.19.2 Parameter Setting | III-58 |
| 1.19.3 Setting Procedure | III-60 |
| 1.19.4 Registered Text Edit | III-61 |
| 1.20 Barcode | III-62 |
| 1.20.1 Inspection Overview..... | III-62 |
| 1.20.2 Parameter Setting | III-62 |
| 1.20.3 Setting Procedure | III-63 |

2 Optional Function III-64

| | |
|--------------------------------|--------|
| 2.1 OCR_Pro..... | III-64 |
| 2.1.1 Inspection Overview..... | III-64 |
| 2.1.2 Parameter Setting | III-64 |
| 2.1.3 Setting Procedure | III-65 |
| 2.2 Barcode_Pro | III-72 |
| 2.2.1 Inspection Overview..... | III-72 |
| 2.2.2 Parameter Setting | III-72 |
| 2.2.3 Setting Procedure | III-73 |

Basic Operation

1 Basic Operation of Inspection Software

1.1 Basic Operation

This section describes basic operation of inspection software.

1.1.1 Window Details

The main window consists of the following two frames.

- | | |
|--------------------|--|
| Image Frame | Display scanned image or inspection data. |
| Index Frame | Display operation mode, inspection data name, inspection result, and cursor position coordinate. |

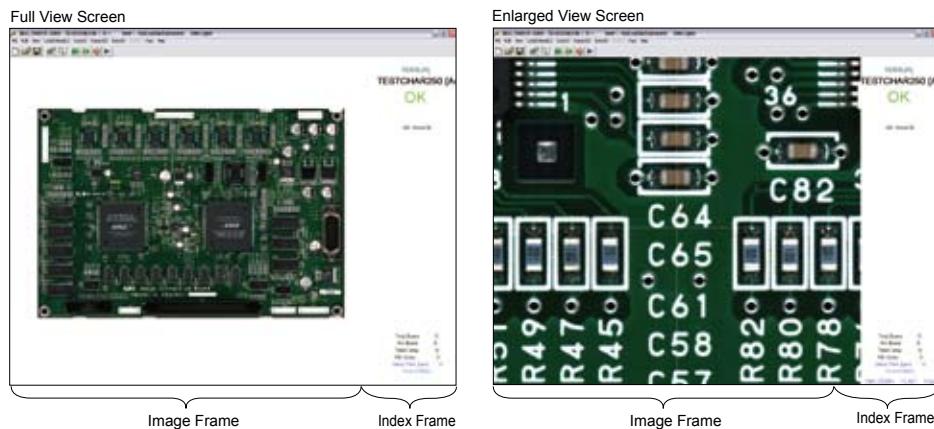


Figure 1-1 Window Names

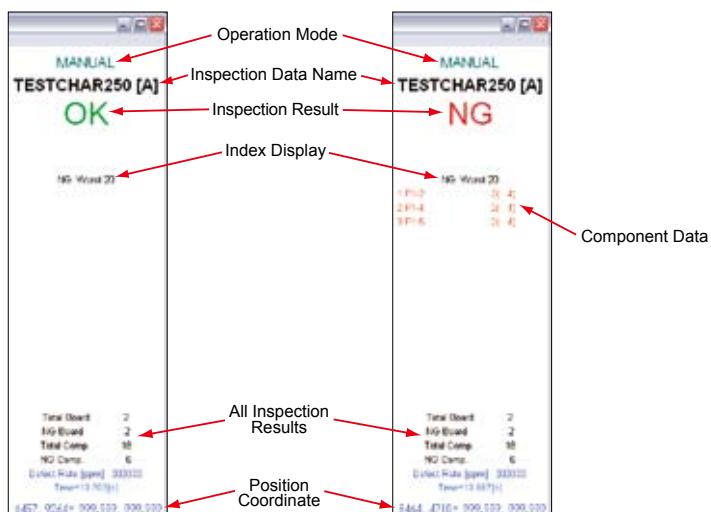


Figure 1-2 Explanation of Index Frame

NOTE **Index Display** can be selected from the following formats. Select **View > Results** from the menu-bar. Display the corresponding components in **Component Data**.

- | | |
|-----------------|---|
| Worst 20 | Rank the components in which defects are found by the number of occurrences, and display the worst 20 components. |
| False 20 | Rank the components in which false defects are found by the number of false defect occurrences, and displays the worst 20 components. |
| NG | Display the components that produced NG inspection results. |
| OK | Display the components that produced OK inspection results. |

1.1.2 Switching Between Enlarged View Screen and Full View Screen

Enlarged View Screen

Left-click on the image in **Full View Screen**. The image is enlarged by centering on the clicked point.

Full View Screen

Left-click the index frame in the **Enlarged View Screen** to go back to **Full View Screen**.

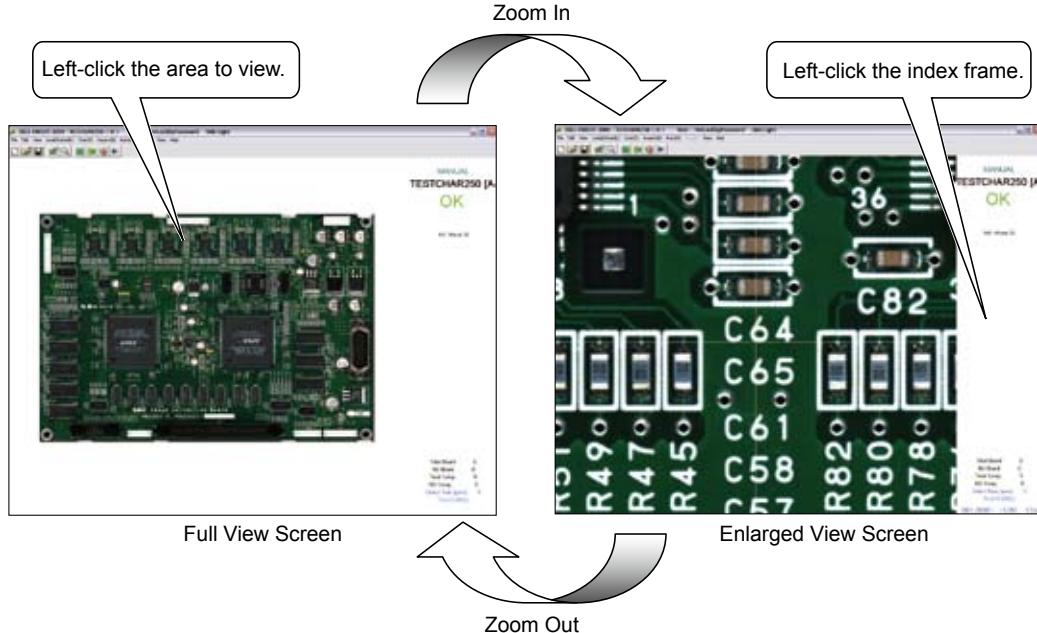


Figure 1-3 Full View Screen and Enlarged View Screen

1.1.3 Area Moving in the Enlarged View Screen

Left-click on the image to move the view area. The area centered on the clicked point is displayed.

Click to edge of the image to return to **Full View Screen**.

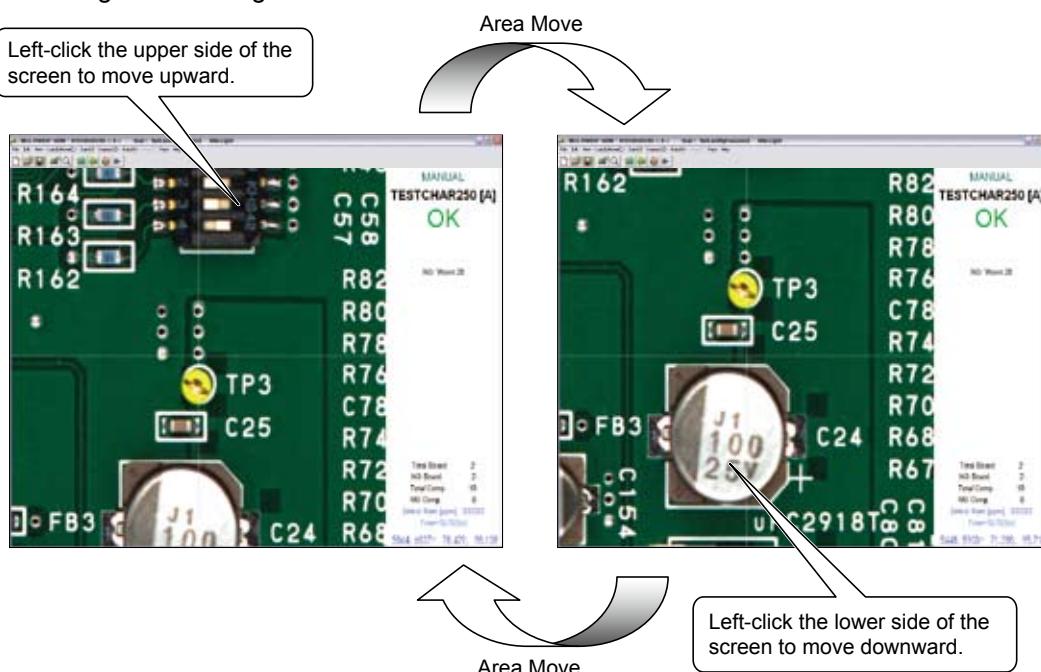


Figure 1-4 Moving in the Enlarged View Screen

1.1.4 Changing the Magnification

The magnification can be changed by pressing **↑** and **↓** in **Enlarged View Screen**. The same operation is available by scrolling wheel of mouse.

Press **↑** or scroll wheel of mouse upward to zoom in the image.

Press **↓** or scroll wheel of mouse downward to zoom out the image.

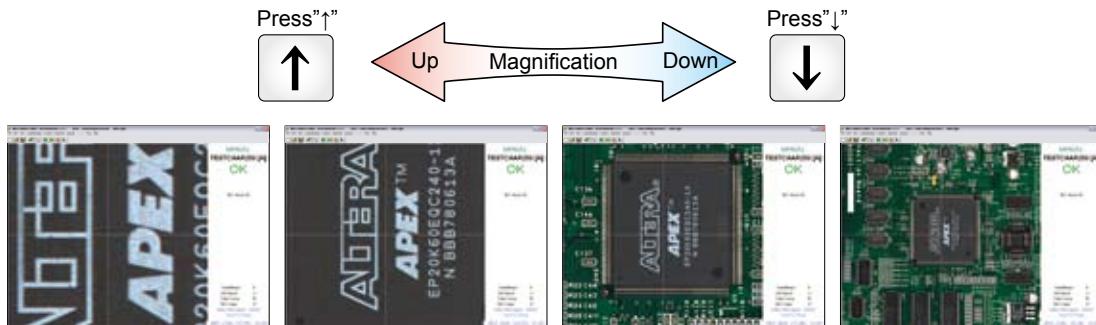


Figure 1-5 Changing the Magnification

1.1.5 Switching Between the Images

Press **D** to switch images among TopLight(Coaxial Overhead Light), SideLight, and LowLight.

<<Full View Screen>>

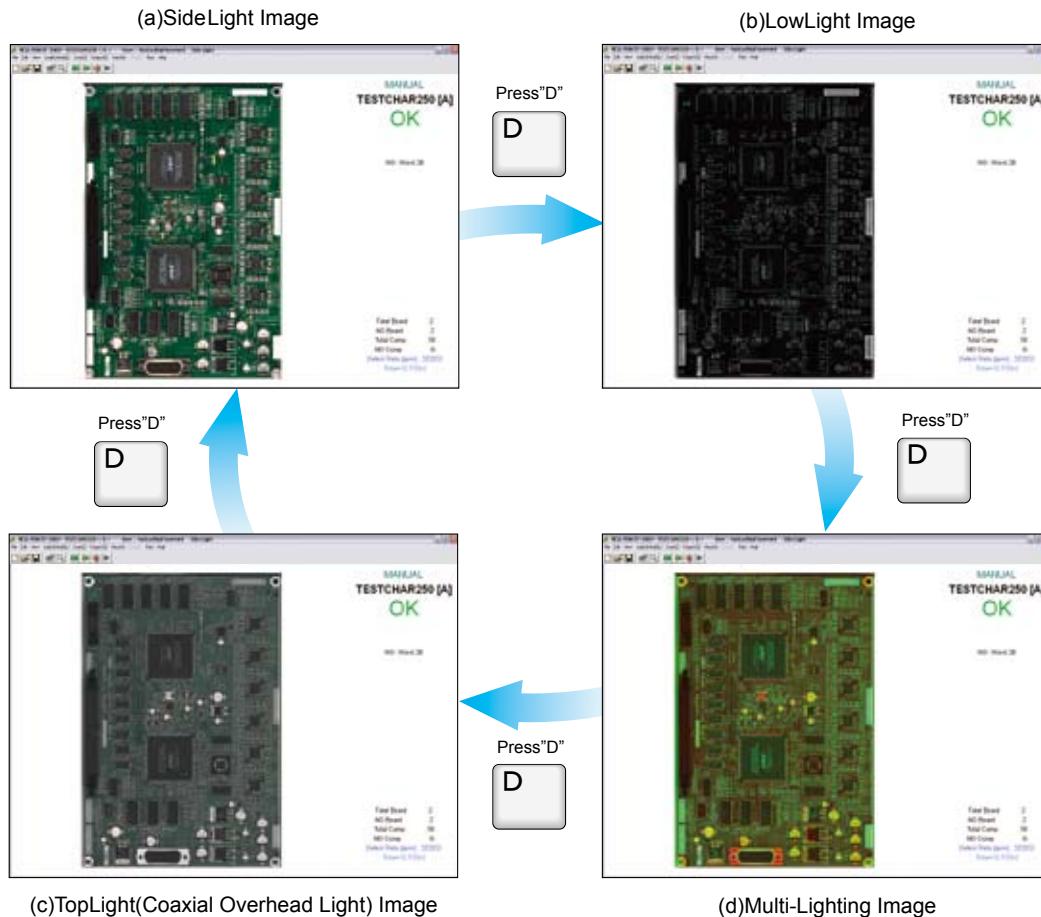


Figure 1-6 Switching Images in the Full View Screen

<<Enlarged View Screen>>

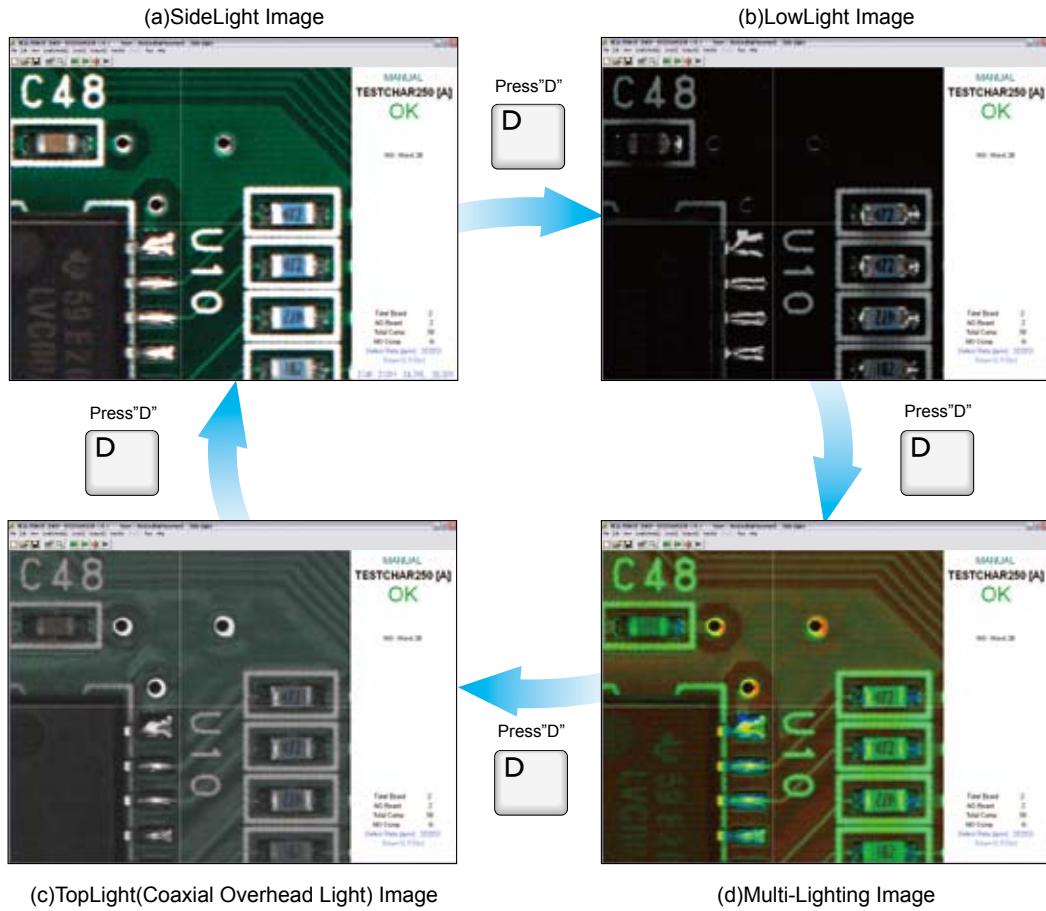


Figure 1-7 Switching Images in the Enlarged View Screen

1.1.6 Board Setting

Open **Board Data** window in Figure 1-8 to check the PCB size, set or edit the PCB data. Press **Board Setting** button on the tool-bar or right-click the index frame to open the window. After all the settings are completed, press **OK**.

NOTE The above operation is available in **Full View** and **Enlarged View Screen**.

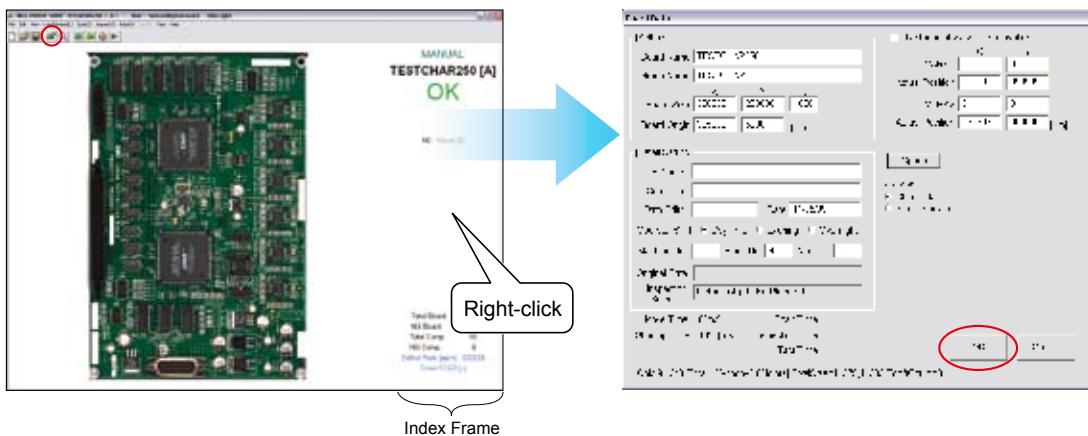


Figure 1-8 Board Data Edit

The table below describes the items in **Board Data Edit** window.

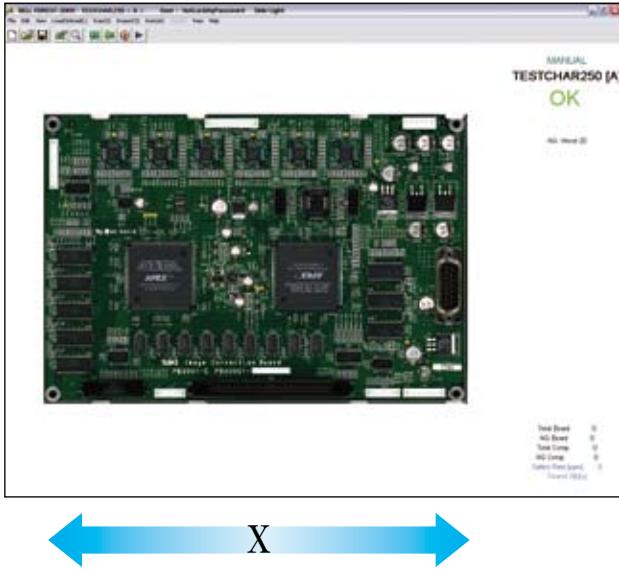
| | |
|--------------------------------|--|
| Board Name | The name of selected image. |
| Group Name | Group name. |
| Board size | <p>Set the target PCB size. t is PCB thickness. (*1)</p>  |
| Board Origin | Set the PCB origin. |
| Model Name | Not available. |
| Comment | Enter any comments if necessary. |
| Data Editor | Enter data creator. |
| Date | Created date(Month/Day/Year). |
| Operator Shift | Work shift. |
| Machine No. | Not available. |
| Block No. | Enter the number of sub-PCBs, if necessary. |
| Number | Not available. |
| Use Fiducial Mark Compensation | Set the fiducial marks to correct the warpage of PCB or distortion. |
| MARK1 | Set the position of the first fiducial mark in X and Y coordinates. |
| Actual Position | Set the actual position of the fiducial mark in X and Y coordinates. The gap between this value and the MARK1 value represents the amount of deviation between the inspection data and the scanned image. |
| MARK2 | Set the position of the second fiducial mark in X and Y coordinates. |
| Actual Position | Set the actual position of the fiducial mark in X and Y coordinates. The gap between this value and the MARK2 value represents the amount of deviation between the inspection data and the scanned image. |
| Option | Not available. |

Table 1-1 Explanation of the Respective Items of **Board Data Edit** Window

CAUTION

(*1) In case of BF-Comet10, BF-Comet18, and BF-Sirius, longitudinal direction is **X** and lateral direction is **Y**.

1.1.7 Display the Edit Component Data Window

If there are many false calls, the inspection data should be readjusted. Right-click the target component, open the **Edit Component Data** window and adjust the inspection data.

NOTE Select inspection data in order of making by pressing **←** or **→**.

The above operation is available in **Full View Screen** and **Enlarged View Screen**.

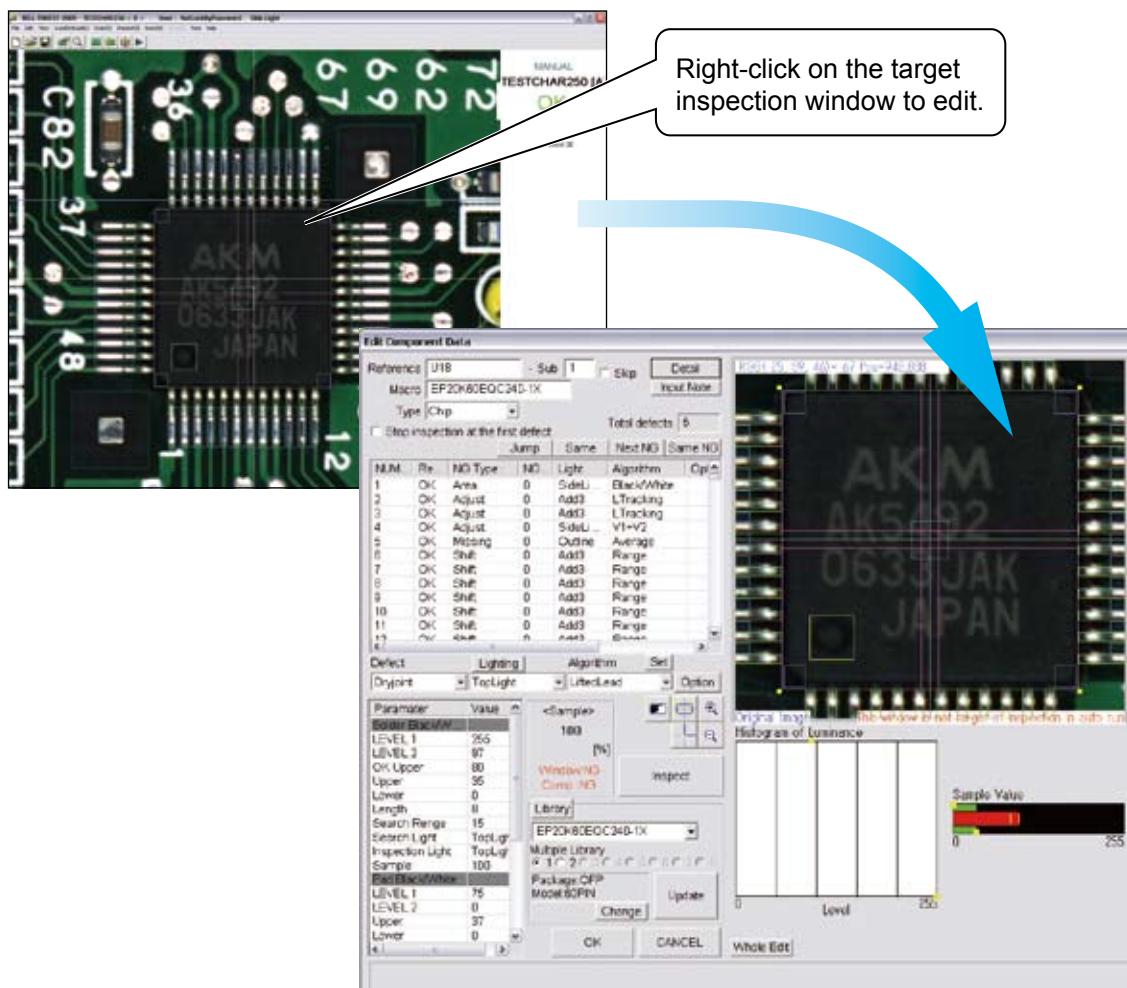


Figure 1-10 Edit Component Data

The following three ways are available to open **Edit Component Data** window.

Search the component and open Edit Component Data window

Press **Ctrl** + **Alt** + **F** concurrently and **Search Component** window shown in Figure 1-11 appears. Enter the component name and press **Edit**, **Edit Component Data** window for the component appears.

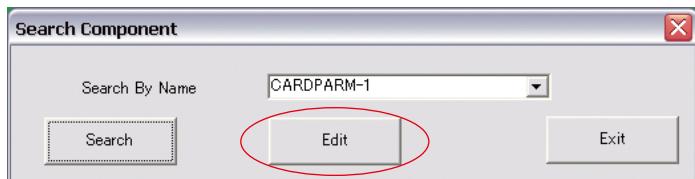


Figure 1-11 Search Component

In another way, select **Edit > Search** from the menu-bar and **Search Data** window shown in Figure 1-12 appears. Select the component and press **Edit**. **Edit Component Data** window for the component appears.

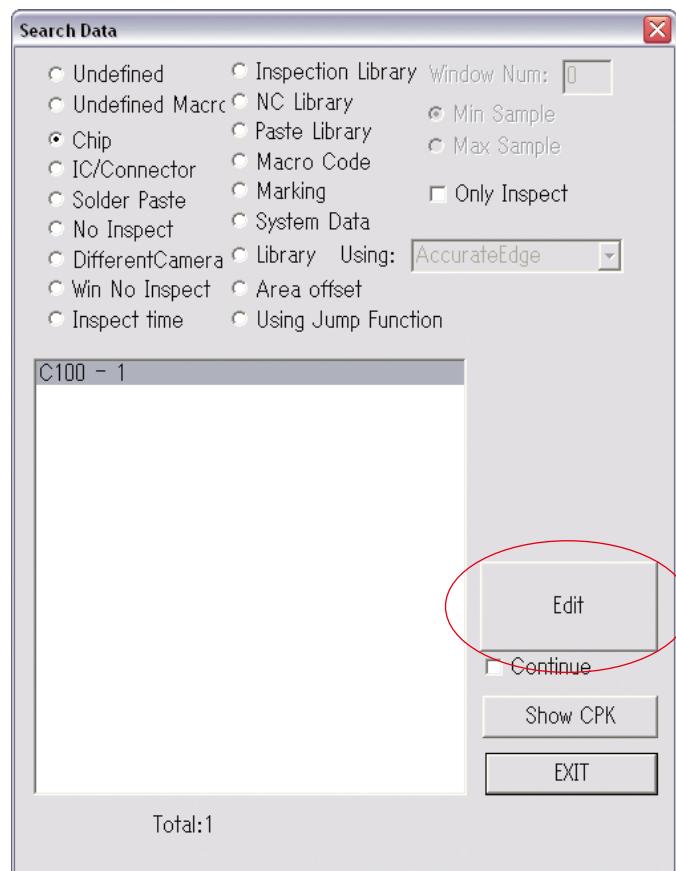


Figure 1-12 Search Data

Press **Enter** to open Edit Component Data window

Click arbitrary position on the image and press **Enter**. The NG component data that is in the closest to the clicked position is displayed.

NOTE This operation is available in **Full View Screen** and **Enlarged View Screen**.

Select Edit NG to open Edit Component Data window

Step1: Select **Edit > Edit NG** from the menu-bar and **Edit Components** window shown in Figure 1-13 appears.

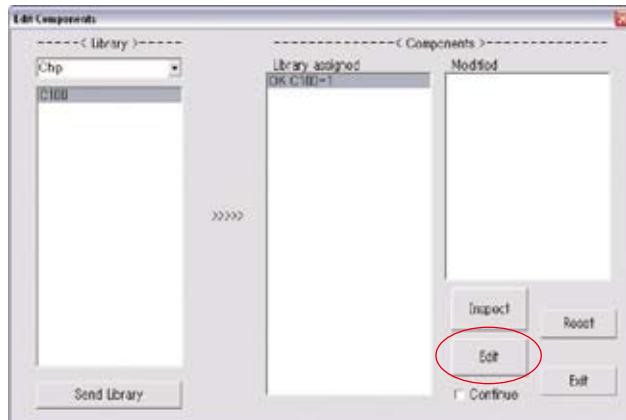


Figure 1-13 Edit Components

Step2: Select the type of the component from the library.

Step3: Select the library name of the component and select the target component from **Library assigned**.

Step4: Press **Edit** and **Edit Component Data** window shown in appears.

The display items of **Edit Components** window are described.

| | |
|--------------|---|
| Send Library | Send the specified library data to BF-Editor(optional system). |
| Inspect | Re-inspect all components that the selected library is used and display the inspection result on Edit Components window. |
| Reset | Discard the separate setting. The dialog shown in Figure 1-14 appears. |
| OK | Discard the separate setting. |
| Cancel | Return to the Edit window. |
| Edit | Open Edit Component Data window. |
| Continue | After close the Edit Component Data window, the next component is automatically selected. |
| Exit | Return to the original inspection window. |

Table 1-2 Explanation on Each Item of **Edit Components**

1.1.8 Setting the Range

Surround the arbitrary area by mouse dragging. Inspection data of several components in the area can be edit at once. This operation can be applied to both multiple and single components.

Group Edit window shown in Figure 1-15 appears.

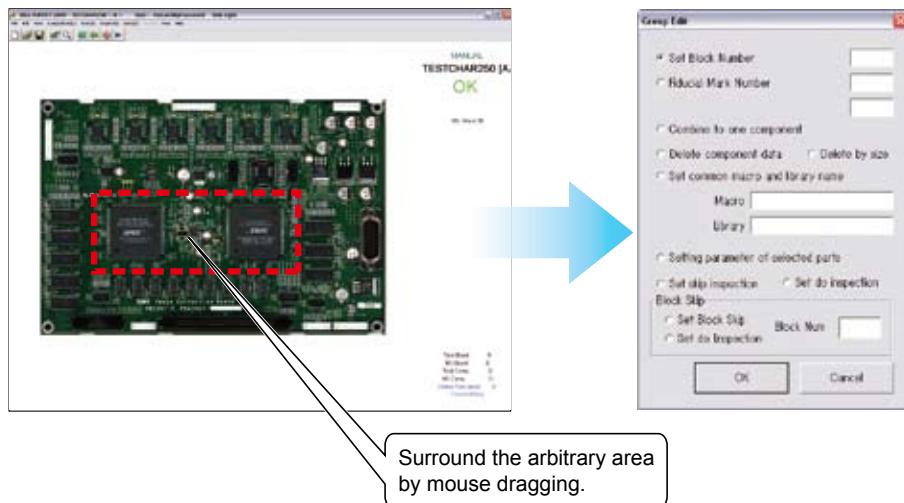


Figure 1-15 Group Edit

OK Apply the change and close the window.

Cancel Cancel the change and close the window.

NOTE The above operation is available in **Full View Screen** and **Enlarged View Screen**.

The items on the **Group Edit** window are described.

| | | |
|-------------------------------------|---|--|
| Set Block Number | Check the Set Block Number and enter arbitrary value to changes Sub number in the upper left side of the Edit Component Data Window(Refer to Figure 2-10). | |
| Fiducial Mark Number | Check the Fiducial Mark Number and register arbitrary fiducial mark number. All data in the specified area are corrected with the fiducial marks. | |
| Combine to one component | Combine all data in a specified area as one data. | |
| Delete component data | Delete all components data in the specified area. | |
| Delete by size | Indicate all inspection results of all components data in a specified area as NG. | |
| Set common macro and library name | Unify the macro names and the library names for all components data in a specified area. | |
| Setting parameter of selected parts | Set the parameters of the inspection window for all components data in a specified area collectively. | |
| Set skip inspection | Exclude all components in a specified area from the target of the inspection. | |
| Set do inspection | Designate all components in a specified area as the target of the inspection. | |
| Block Skip | Set Block Skip | Exclude a given sub-PCB from the target of the inspection. |
| | Set do inspection | Designate a given sub-PCB as inspection target. |
| | Block Num | Input the block number. |

Table 1-3 Explanation of the Respective Items for **Group Edit** Window

1.1.9 Moving Component Data

Drag the component data to the target position. **Move Component** window shown in Figure 1-16 appears. Select appropriate items. This function is used to set the CAD data on the actual position of the component or to operate ECD function.

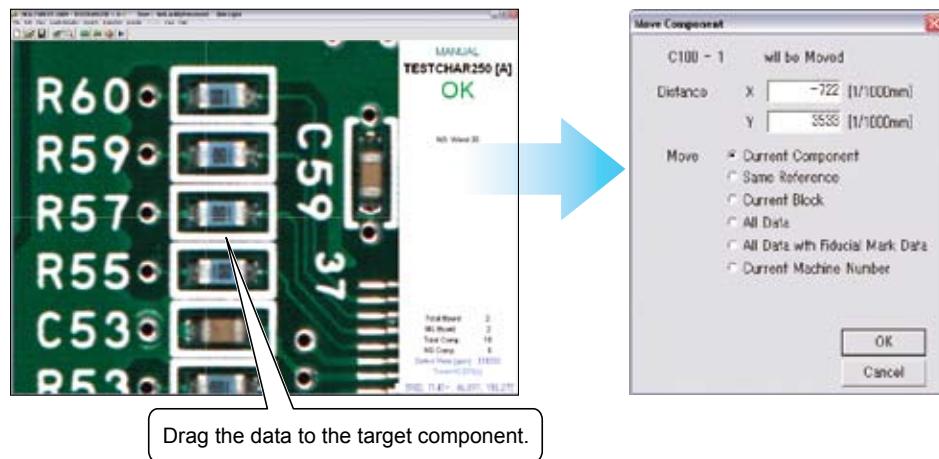


Figure 1-16 Move Component

OK Apply the change and close the window.

Cancel Cancel the change and close the window.

The items on the **Move Component** window are described.

| | |
|----------------------------------|---|
| Current Component | Move only the selected components data. |
| Same Reference | Move all the components with the same reference name. |
| Current Block | Move all components in the sub-PCB with the selected component. |
| All Data | Move all components data on the PCB together with the selected component. |
| All Data with Fiducial Mark Data | Move all components data with the fiducial marks data. |
| Current Machine Number | Move all components data that use the same mounter data as the selected data. |

Table 1-4 Explanation of the Respective Items for **Move Data** Window

2 System Setup

This chapter describes the detail on system setup.

Select **Edit > System Setup** from the menu-bar. **Select System Setup** dialog shown in Figure 2-1 appears. Each item of **Select System Setup** in Figure 2-1 are described as follows.

NOTE

Benchtop machine is different dialog from inline machine.

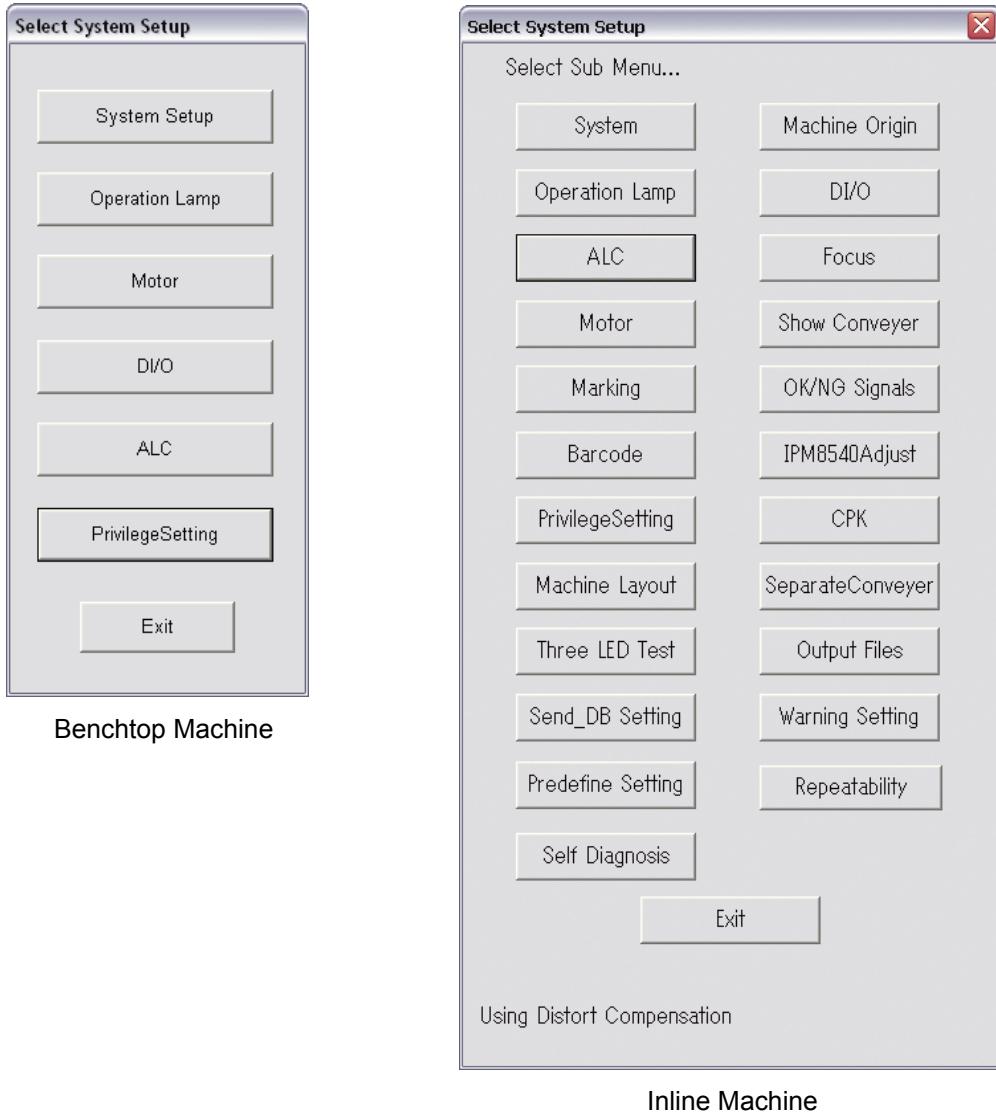


Figure 2-1 Select System Setup

2.1 System

The destination of the file to save, the name of NG type or the flow direction of PCB can be set in **System**. Press **System** in Figure 2-1 **Select System Setup**. **System** window shown in Figure 2-2 appears.

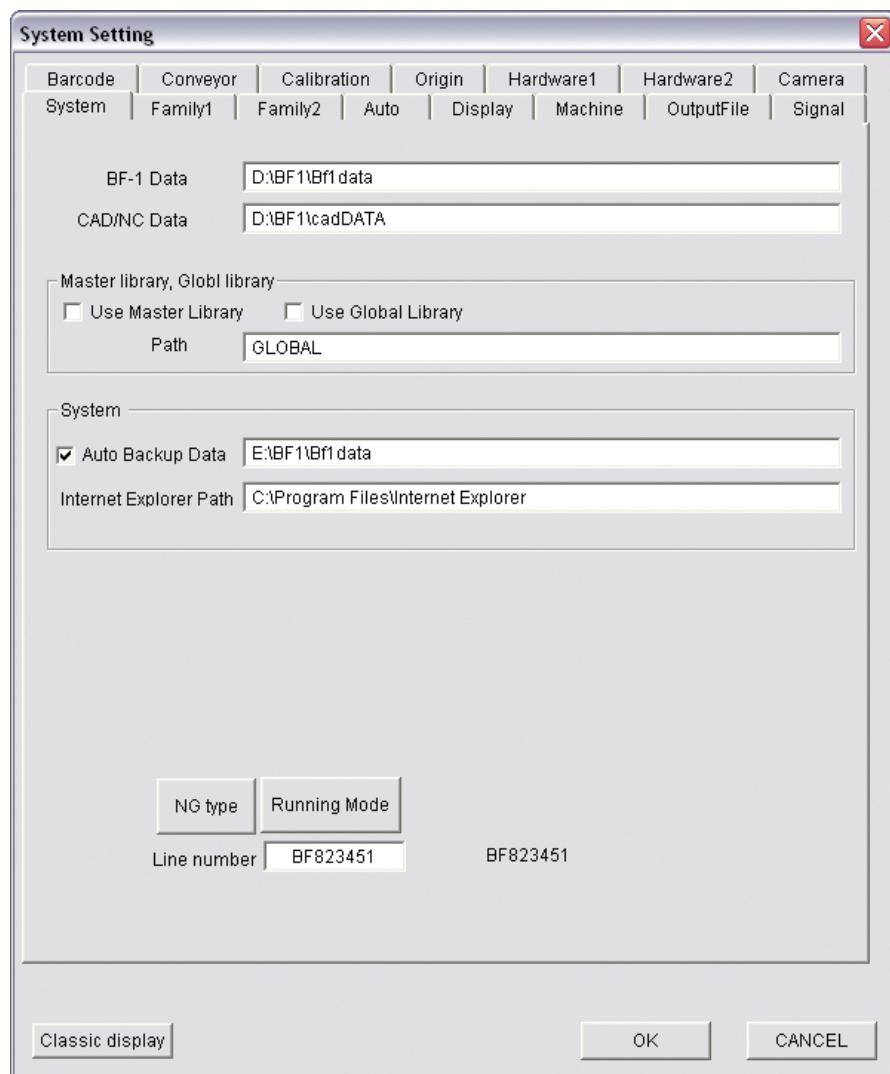


Figure 2-2 System

2.1.1 Contents of System

This table describes the contents of System.

| Tab | Item | Description |
|---------|---|--|
| System | BF-1 Data | Destination of the inspection data to save. Default Setting: D:\BF1\BF1DATA |
| | CAD/NC Data | Destination of the original CAD and NC data to save. Default Setting: D:\BF1\NCDATA |
| | Use Master Library | Check the box to use the master library. |
| | Use Global Library | Check the box to use the global library. |
| | Path | Destination of the master library to save. |
| | Auto Backup Data | Made the backup file automatically. Dialog of confirmaton is displayed before making backup. |
| | Internet Explorer | Link of total report. Default Setting: C:\Program Files\Internet Explorer |
| | NG Type | Set NG types. Defects name can be modified. |
| Family1 | Running Mode | Switch the mode(Normal Mode / Test Mode / Ignore Hardware). |
| | Connect BF-RP1 | Connect with BF-RP1(optional system). |
| | BF-RP1 | Specify the destination of the connected PC to save in BF-RP1. |
| | BF-RP1 Backup | Specify the master BF-RP1 PC in case of connecting with several BF-RP1. |
| | Export NG Files | Save inspection results in auto mode. |
| | NG Limit | Specifies the upper limit number of the NG component per PCB. |
| | Date and Time | Save the NG file name as inspection date and time. |
| | Inspect Number | Save the NG file name as inspection number. |
| | Barcode | Save the NG file name as barcode. |
| | Not Create OK File | Create files with NG inspection results only. |
| | Use Lot Number | Manage NG file by lot number. |
| | Create False Call Data | Create a false call data file. |
| | Repair A/B Side by One Barcode | Combine inspection results for both top and bottom side in case barcode is on one side. |
| | Enable OK Button After Click Component Images | OK button is enabled by clicking the image (Benchtop machine only). |
| | Save BadMark Error | Add badmark error to NLT file. |
| | Use Current Date to Lot Number | Create lot number folder with the current date. |
| | Lot Number Required | Lot number must be entered in this setting. |
| | Save Defect Images | Saves images of defect component. |
| | Save False Images | Saves the component image of false calls. |
| | Image Limit | Specifies the upper limit number of the NG image to save per inspection. |
| | jpeg | Saves the images by JPEG. |
| | Send Side Light Image to BF-RP1 | Transfer the images by SideLight. |
| | BF-RP1 Enlarge Images | Transfer the enlarged image to BF-RP1. |
| | NG File | Specify the transferring destination of NG file. |
| | NG File1 | Specify the transferring destination of NG file (Backup). |

| Tab | Item | Description |
|---------|--|---|
| Family1 | BF-Editor | Connect BF-Editor |
| | | Specify the saving inspection data destination of BF-Editor. |
| | | Specify the saving destination of data when using offline debug. |
| | | Validate offline debug consistently. |
| | | Not to send library to BF-Editor. |
| Family2 | BF-Monitor | Connect BF-Monitor |
| | | Specify the folder of RAM disk of BF-Monitor. |
| | | Specify the saving destination of BF1DATA in BF-Monitor. |
| | | Display enlarged image in BF-Monitor. |
| | | Cursor of mouse is automatically positioned on OK button when making judgements. |
| | | Send Enlarge Image to BF-Monitor. |
| | | Transfer NG images and criterial OK images for judgement. |
| | | Display NG images and criterial OK images for judgement. |
| | BF-View | Send Image-Match and OCR Reference |
| | | In case that use character recognition algorithm, display OK image when judged NG. Check same item of BF-Monitor. |
| | | Output log file for NetView |
| | | Connect with BF-View(optional system). |
| Auto | BF-View | Image saved for NetView Limit |
| | | Specify the maximum number of the image to save per inspection. |
| | | Only Output NG Images |
| | | Transfer NG images only. |
| | BF-WebTracer | Only Output False Call Images |
| | | Transfer the images of false calls only. |
| | | Connect BF-WebTracer |
| | | Connect with BF-WebTracer(optional system). |
| | | Host |
| | | Enter host of BF-WebTracer. |
| | Monitor Mode, Debug Mode | Max Save Image Num: |
| | | Specify the maximum number of the image to transfer per inspection. |
| | | Only Output NG Images |
| | | Transfer NG images only. |
| | | Only Output False Call Images |
| | | Transfer the images of false calls only. |
| | Warning | Output whole Board images |
| | | Transfer the whole PCB image. |
| | | Output OCR log |
| | | Transfer log information of OCR. |
| | | Output component Information |
| | | Transfer inspection data. |
| | Operator Call at Mark Error | Conduct operator call when mark error occurs in auto mode. |
| | | Conduct operator call if air pressure goes lower than the specified value. |
| | | Conduct operator call when NG is detected in auto mode. |
| | Check Board After Exchanging in Monitor Mode | Confirmation dialog is displayed after PCB is unloaded. |
| | | At NG detection, confirmation dialog appears with PCB inside the machine. |
| | | Invalidate the function to stop alarm when NG is detected. |
| | | OK button is enabled by clicking the image(Inline machine only). |
| | | Automatically run in monitor mode. |
| | | Displays registered characters of OCR and current result. |
| | | Specify the time period to display the next NG image. |

Basic Operation

| Tab | Item | Description |
|---------|---|--|
| Auto | Others | Screen Saver |
| | | Check Next Board |
| | | Unload when Mark Error |
| | | Save Detected Images |
| | | Auto Load Model |
| | | Continuous Drive in Pass Mode |
| | | Must input Model Name |
| | | WinXP Super Thread |
| | | Using Accelerating Method |
| Display | Display | Set Scale 1:1 in Debug Mode |
| | | New Editor (Beginner mode) |
| | | Legacy display (Non BF+) |
| | Programming | Display History Diagram |
| | | Make Dry-joint Window |
| | | Set Binary Image on Upper / Lower Level |
| | | Display Statistic History Diagram |
| | | Link Library Automatically |
| | System | Shutdown Windows |
| | | Check Servo |
| Signal | Send OK/NG Signal to Next Machine | Output OK/NG singal to downstream machine. |
| | Reset OK/NG Signal after Unloading PCB | Reset OK/NG signal right after unloading PCB. |
| | OK/NG Output for Next Machine | ON at NG |
| | | OK at OK |
| | OK/NG Input from Previous Machine | ON at NG |
| | | OK at OK |
| | For SMEMA Standard | Use to connect to upstream/downstream machines by SMEMA. |
| | FUJI Mounter | Not available. |
| | SMEMA 2007 | Check For SMEMA Standard and SMEMA 2007 to use SMEMA(SMEMA standard: IPC-SMEMA-9851). |
| | Reset Ready Signal after Loading (No Preconveyor, Not SMEMA) | Reset the Ready Out signal after PCB carry-in. Not available with SMEMA. |
| | Reset Ready-Out Signal, when Entrance Senser is Touched (QA/QC) | Not available. |
| | Output Busy-Out Signal before Ready-In Signal from Next Machine | Output Busy Out signal before Ready-in signal is input from downstream machine. |
| | Send Ready Signal when there is no PCB | Output Ready signal to upstream machine if there is no PCB inside of the machine. |
| | Set Ready Signal during Unload if inspection is OK | If the inspection result is OK, unload the PCB and output the ready signal. |
| | Connected with NG Buffer | Check the box to use NG buffer. |

Programming Manual

| Tab | Item | Description |
|---------|---|---|
| Signal | Set Ready Signal when Sensor Detected | Output Ready signal while PCB inlet sensor is activated. |
| | Send OK/NG, Surface A/B info by Comport | Output OK/NG signal from Comport. |
| Barcode | Use Barcode Reader | Check the box to use barcode-reader (either fixed or handy type). |
| | Reader is Set Out of BF | Check the box to use fixed barcode-reader. |
| | Use Handy Barcode for Hero Machine | Not available. |
| | Inspect Both Side by One Barcode | Not available. |
| | Two Dimension Barcode | Check the box to use 2D barcode-reader. |
| | Not Input Text Reader | Check the box to use barcode-reader without text input (e.g. TOKEN). |
| | Com2 (Com1 Unchecked) | Not available. |
| | Print Shft Data (SKP) | Not available. |
| | Multi Head Reader | Check the box to use barcode-reader of multi head. |
| | Select the Board by Barcode | Check the box to select data by barcode. |
| Option | Compare Barcode | Make comparison with registered barcode information. |
| | Input Barcode on BF-RP1 | Enter barcode information on BF-RP1. |
| | Don't Change Jump Value | Check the box not to change the jump setting automatically if inspection item is added or deleted to the data with jump function. |
| | Wait for Barcode Recognition | Keep on trying until barcode-reader reads barcode. |
| | Don't Popup Input Dialog while Read Barcode Error | Output NG file named current date if reading barcode is failed. |
| | Show Skip Message | Display (Some components are skipped to inspect) in the lower left side of the window, if any inspection window is set as skip. |
| | Barcode on Two Sides | Check the box to manage the number of two sides by one barcode. |

Table 2-1 **System** Parameter List 1

| Tab | Item | Description |
|-------------|-------------|---|
| Output File | | * |
| Machine | | * |
| Conveyor | | * |
| Calibration | | * |
| Origin | | * |
| Hardware1 | Conveyor | 2 Speed Conveyor |
| | Other Items | Use in the case of validate board delay sensor. |
| Hardware2 | | * |
| Camera | | * |

Table 2-2 **System** Parameter List 2**CAUTION**

Regarding the items with *, these are for Saki engineer only.

2.1.2 NG Type

Modify the NG type name to appropriate ones. The analysis of the inspection result will be done effectively based on the proper NG type name.

- Step1: Press **NG Type** in Figure 2-2 System. NG Type Setup window shown in Figure 2-3 appears.



Figure 2-3 NG Type Setup

- Step2: 21 NG types name(from 12 to 32) can be modified.

Enter arbitrary name in the each **Name** text-box.

- Step3: Press **OK** to update.

NOTE Press **Default** and **OK** to back to the default.

2.2 Operation Lamp

This section describes the settings of signal tower and buzzer.

The operation of signal tower lighting and buzzer can be modified in **Operation Lamp** according to the operating condition of the machine.

Press **Operation Lamp** in Figure 2-1 **Select System Setup**. **Operation Lamp and Buzzer Settings** window shown in Figure 2-4 appears.

Check the arbitrary boxes based on the operating condition of the machine.

NOTE Press **Default** and **OK** to back to the default.

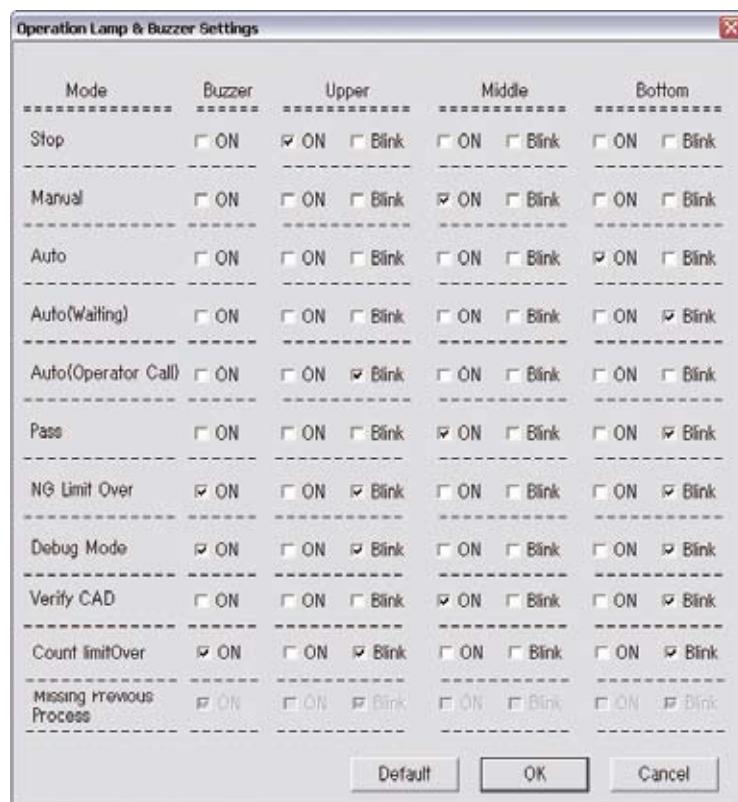


Figure 2-4 Operation Lamp and Buzzer Settings

| Mode | State | Description |
|--------------------------|---|---|
| Stop | Emergency Stop | Emergency stop switch is pressed or the front door is opened. |
| Manual | Manual Mode Running | Normal operation under Manual Mode. |
| Auto | Auto Mode Running | Normal operation under Auto Mode. |
| Auto (Waiting) | Waiting for the next PCB | Stand by status for PCB carry-in under normal operation. |
| Auto (Operator Call) | During Auto Mode Running Defect Occurrence | Stand by status for operator check on detected NG under normal operation. |
| Pass | Pass Mode Running | Pass Mode. |
| NG Limit Over | Continuous NG Occurrence | The number of NG PCB reach the specified value. |
| Debug Mode | Debug Mode Running | Debug Mode is running normally. |
| Verify CAD | | Not available. |
| Count Limit Over | Reached limit number of inspection | Completed the specified number of the PCB inspection. |
| Missing Previous Process | | Not available. |

Table 2-3 Operation Lamp and Buzzer Settings Parameter List

2.3 ALC

This section describes the setting of Automatic Luminance Control. All parameter is adjusted appropriately at the time of installation or before shipping.

CAUTION Normaly customers do not need modify the Automatic Luminance Control setting as wrong setting cause unexpected errors.

2.4 Motor

This section describes settings of Motors. All parameter is adjusted appropriately at the time of installation or before shipping.

CAUTION Normaly customers do not need modify the Automatic Luminance Control setting as wrong setting cause unexpected errors.

2.5 Marking

This section describes how to set the marking function.

Collective Setting and **Setting by Type of Marking** are available to set the marking function. If both are selected, priority is given to marking type setup.

CAUTION Enable the settings only marking unit.

2.5.1 Collective Setting

Press **Marking** in Figure 2-1 Select System Setup. **Mark Position Default Settings** window shown in Figure 2-5 appears.

A in Figure 2-5 specify the type of marking. **B** specify the position of marking. **C** specify the plot selection of XY marking and rotation angle of characters by PLOT NUMBER when plotting.

D specify the size of characters and contents of comments (in the case of selecting PLOT NUMBER).

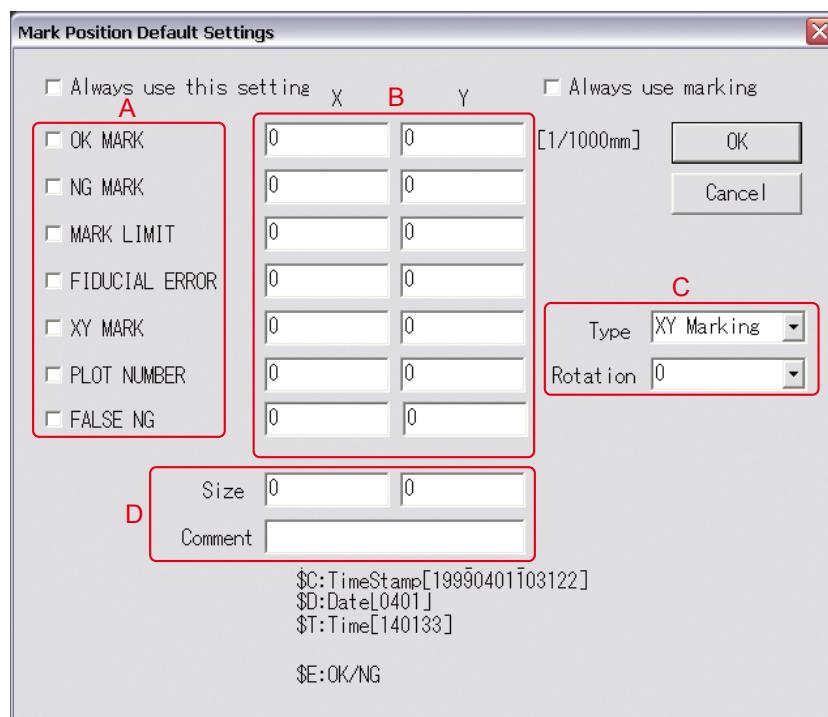


Figure 2-5 Mark Position Default Settings

2.5.2 Setting by Type of Marking

Here describes the way to setup marking respectively.

Step1: Open the inspection data which you wish to change marking setup.

Step2: Select **Edit > Search** from the menu-bar. **Search Data** window shown in Figure 2-6 appears.

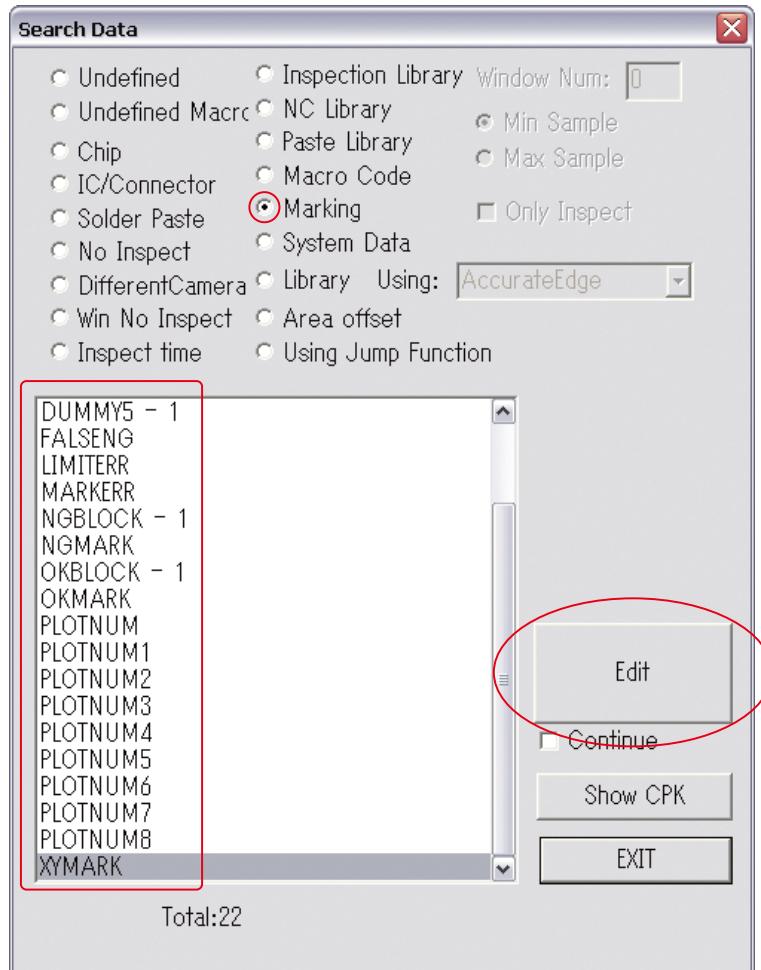


Figure 2-6 Search Data

XY Marking (Painting) Setup

Check the **Marking** in Figure 2-6 **Search Data**, select XYMARK and press **Edit**. **Painting Setup** window shown in Figure 2-7 appears. Refer to Table 2-4 **XY Painting Setup** and proceed the setup procedures. After all the settings are completed, press **OK**.

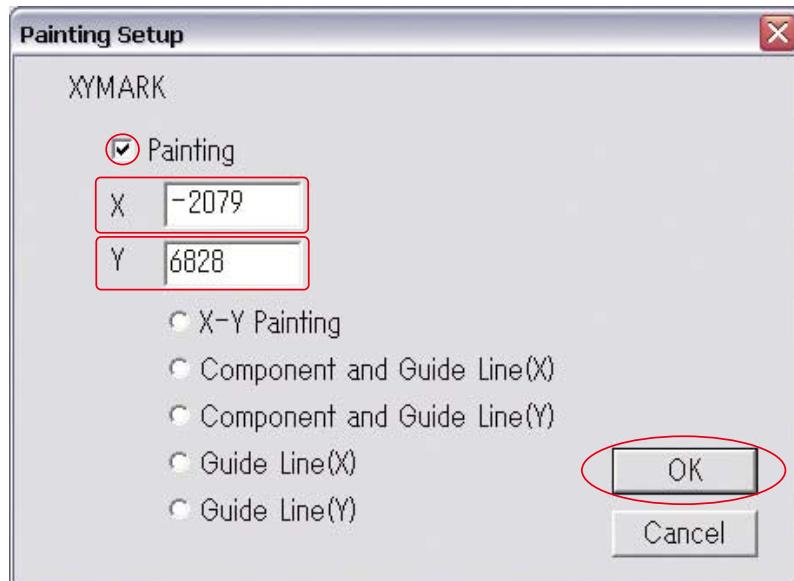


Figure 2-7 Painting Setup

| Item | Description |
|------------------------------|--|
| Painting | With check mark in, XY painting function works. |
| XY Coordinates Setup | The marking position for NG components can be specified. (X,Y = (325000, 5000) [μm]) is marking origin (X,Y = (0, 0) [μm]). If you wish to change the position of marking, enter coordinates. |
| X-Y Painting | Put marks on the specified coordinates point. |
| Component and Guide Line (X) | Put two marks, one on the NG components, and the other on the axis of X coordinates of the component. |
| Component and Guide Line (Y) | Put two marks, one on the NG component, and the other on the axis of Y coordinates of the component. |
| Guide Line (X) | Put a mark on the axis of X coordinates of the NG component. |
| Guide Line (Y) | Put a mark on the axis of Y coordinates of the NG component. |

Figure 2-8 XY Coordinates Setup

Table 2-4 Painting Setup

Plot Number Setup

Check the **Marking** in Figure 2-6 **Search Data**, select PLOTPNUM(Plot Number) and press **Edit**. **Plot Number Settings** window shown in Figure 2-9 appears. Refer to Table 2-5 **Plot Number Settings** and proceed the setup procedures. After all the settings are completed, press **OK**.

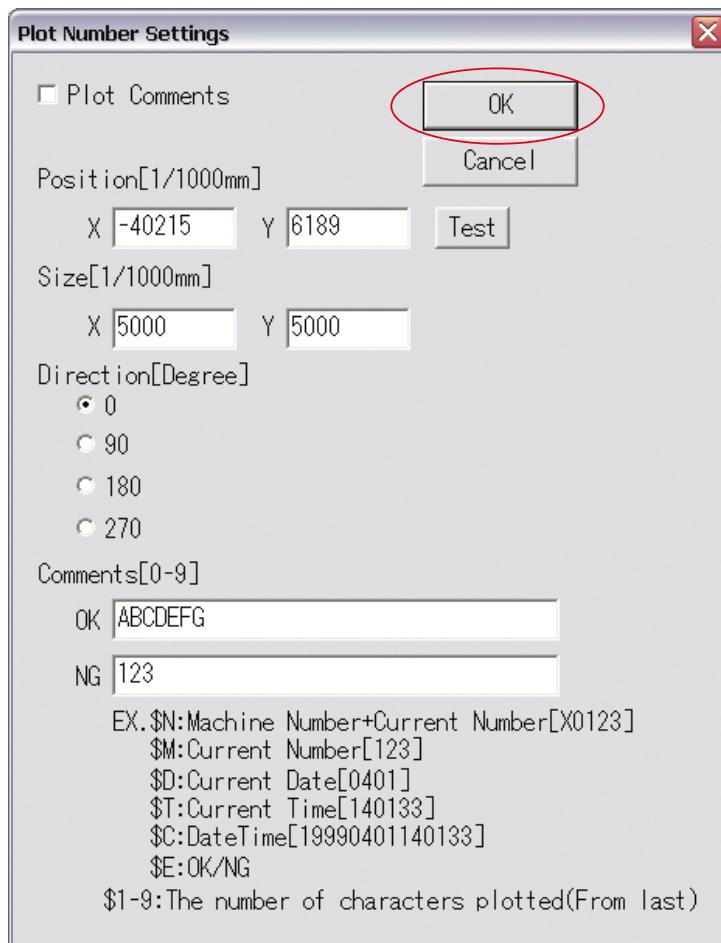


Figure 2-9 Plot Number Settings

| Item | Description |
|---------------------|--|
| Plot Comments | Check in the case of plotting comments. |
| Position [1/1000mm] | Specify the central position to start plotting. |
| Size [1/1000mm] | Specify the size of characters to plot. |
| Direction [Degree] | Specify the direction of characters. |
| Comments [0-9] | Enter comments. |
| Test | Test if plotting can be performed correctly on the board based on the specified setup. |

Table 2-5 Plot Number Settings

Other Setup Methods

Check the **Marking** and select one from the following items in the window of Figure 2-6 **Search Data**, FALSENG, LIMITERR, MARKERR, NGBLOCK-1, NGMARK, OKBLOCK, or OKMARK. Press **Edit**.

Painting Setup 2 window shown in Figure 2-10 appears.

Check the **Painting**, enter the coordinates of marking location and press **OK**.

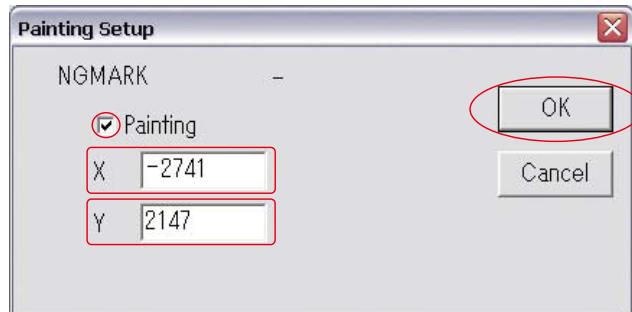


Figure 2-10 Painting Setup 2

2.6 Barcode

The reading data by barcode-reader can be checked in case of using the barcode-reader as optional.

Press **Barcode** in Figure 2-1 Select System Setup. **Barcode** window shown in Figure 2-11 appears.

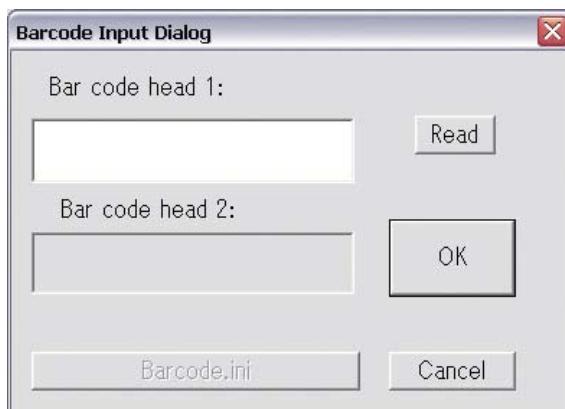


Figure 2-11 Barcode

Press **Read** in Figure 2-11 **Barcode** to check the reading barcode function.

Reading value is displayed in **Barcode head 1**.

2.7 Privilege Setting

The section describes how to register the user level. Unexpected change of system setup or inspection data can be avoided with this function.

Press **Privilege Setting** in Figure 2-1 Select System Setup. **Privilege Setting** window shown in Figure 2-12 appears.

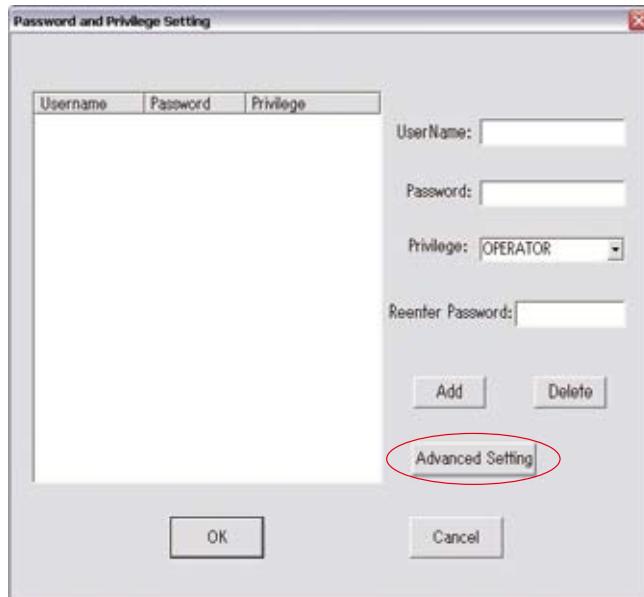


Figure 2-12 Privilege Setting

2.7.1 User Accessible Level

Accessible level of the user can be arranged into five levels.

Operable functions in each level can be changed in **Advanced Setting** window of Figure 2-13. Press

Advanced Setting in Figure 2-12 and **Advanced Setting** window shown in Figure 2-13 appears.

Select user accessible level in **Privilege**. Operable functions are displayed in **Selected Functions**.

Inoperable functions are displayed in **Optional Functions**.

Press <<< or >>> to move functions.

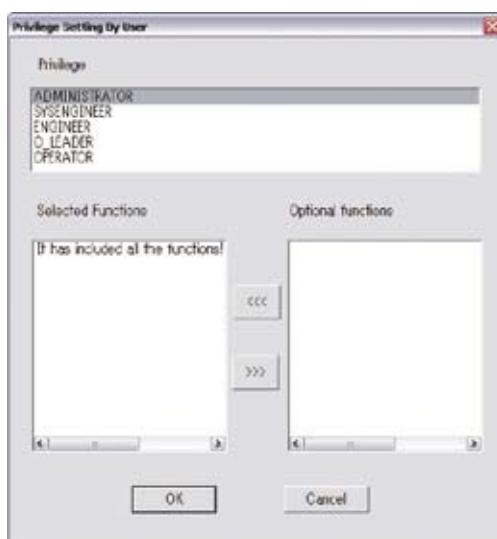


Figure 2-13 Advanced Setting

| No. | User Accessible Level | Description |
|-----|-----------------------|---|
| L1 | Administrator | All functions and windows are available. |
| L2 | System Engineer | Not allowed to change the privilege setting. |
| L3 | Engineer | Not allowed to change the privilege setting and system setup. |
| L4 | O_Leader | Not allowed to save inspection data. |
| L5 | Operator | Allowed to select inspection data and run Auto Mode only. |

Table 2-6 User accessible level and functions availability

| Function | Item which can be changed in accessible level in advanced setting | L1 | L2 | L3 | L4 | L5 |
|--|---|----|----|--------------|-------------|----|
| Edit Inspection Data | | ○ | ○ | ○ | ○ | × |
| Auto Inspection | | ○ | ○ | ○ | ○ | ○ |
| BF Termination | | | | Return to OS | OS Shutdown | |
| Menu-bar→File→Select Data | File->Select Data | ○ | ○ | ○ | ○ | ○ |
| Menu-bar→File→Save Data | File->Save Data | ○ | ○ | ○ | × | × |
| Menu-bar→File→Add Data | File->Add Data | ○ | ○ | × | × | × |
| Menu-bar→File→Append CAD Data | File->Select CAD Data | ○ | ○ | × | × | × |
| Menu-bar→File→Select Image | File->Select Image | ○ | ○ | ○ | × | × |
| Menu-bar→Edit→Search | Edit->Search | ○ | ○ | ○ | × | × |
| Menu-bar→Edit→Add | Edit->Add | ○ | ○ | ○ | × | × |
| Menu-bar→Edit→Input mode | Edit->Input Mode | ○ | ○ | ○ | × | × |
| Menu-bar→Edit→Delete | Edit->Delete | ○ | ○ | ○ | × | × |
| Menu-bar→Edit→Edit NG | Edit->Edit NG | ○ | ○ | ○ | × | × |
| Menu-bar→Edit→Block | Edit->Block | ○ | ○ | ○ | × | × |
| Menu-bar→Edit→Offset | Edit->Offset | ○ | ○ | ○ | × | × |
| Menu-bar→Edit→Reference List | Edit->Reference List | ○ | ○ | ○ | × | × |
| Menu-bar→Edit→SubMark | Edit->SubMark | ○ | ○ | ○ | × | × |
| Menu-bar→Edit→Edit Library | Edit->Edit Library | ○ | ○ | ○ | × | × |
| Menu-bar→Edit→Link Library | Edit->Link Library | ○ | ○ | ○ | × | × |
| Menu-bar→Edit→Unlink Library | Edit->Unlink Library | ○ | ○ | ○ | × | × |
| Menu-bar→Edit→System Setup | | ○ | ○ | × | × | × |
| Menu-bar→Edit→System Setup →privilege setting | | ○ | × | × | × | × |
| Menu-bar→View→Rename Component | View->Rename Component | ○ | ○ | ○ | × | × |
| Menu-bar→Auto→Lotnumber | Autorun->Lotnumber | ○ | × | × | × | × |
| Menu-bar→Auto→Marking | Autorun->Marking pen | ○ | × | × | × | × |
| Menu-bar→Pass | | ○ | ○ | ○ | ○ | × |
| Not used | BFRP1->Delete OK Data | ○ | × | × | × | × |
| Not used | BFRP1->Delete This Data | ○ | × | × | × | × |
| Not used | BFRP1->Repaired | ○ | × | × | × | × |
| Not used | BFRP1->All Repaired | ○ | × | × | × | × |
| Not used | BFRP1->Show Current Offset | ○ | × | × | × | × |
| Not used | BFRP1->Make Report | ○ | × | × | × | × |

Table 2-7 User Accessible Level and restricted function

CAUTION

Diagonal items can not be changed in accessible level.

When the password wish to change, please contact Saki Corporation.

2.7.2 Registration Method of New User

Here describes how to register new user name.
Only Administrator is authorized to use this function.

Step1: Select **Edit > System Setting > Privilege Setting** from the menu-bar.

CAUTION Register **Administrator** first as only Administrator can enter **System Setting > Privilege Setting** and change settings.

CAUTION If the password for Administrator is lost, please contact Saki Corporation.

Step2: Enter **User name**, **Password**, and **Re-enter Password**. Select user accessible level in **Privilege** and press **Add**. After all the settings are completed, press **OK**.

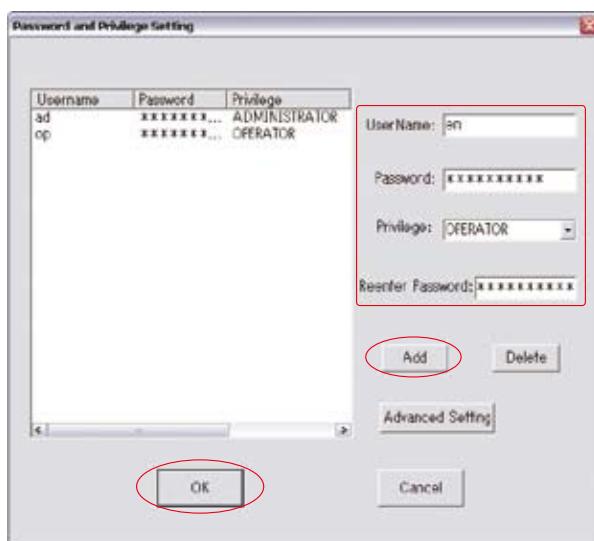


Figure 2-14 Privilege Setup Screen

Step3: Log in dialog appears right after system is activated. Enter user-name and password. Press **OK**. Operation starts depending on the specified user accessible level.



Figure 2-15 Log in

Step4: Select **File > Log in** to return to Figure 2-15 to change the user's accessible level.

2.8 Send_DB Setting

Disabled function.

2.9 Three LED Test

Check the lighting of LED's. This function controls the lighting-up of the LEDs.

Press **Three LED Test** in Figure 2-1 **Select System Setup. Light Test** window shown in Figure 2-16 appears.

Press **ALL ON** and check if all lights are turned on. Press **ALL OFF** and check if all lights are turned off. All lights are turned off automatically in 15 seconds.

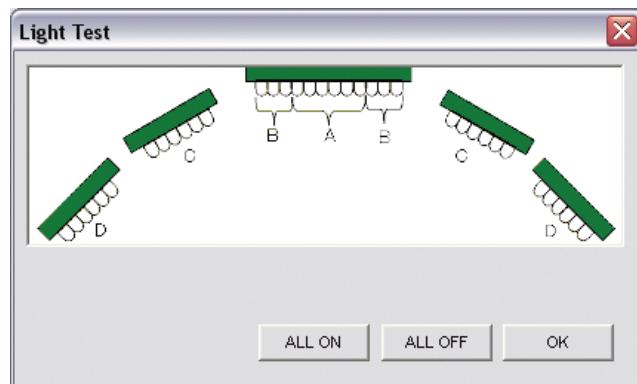


Figure 2-16 Light Test

2.10 Machine Layout

Disabled function.

2.11 Predefine Setting

This list displays the parameters, such as NG Type, Screen Selection, Judgement saved in Edit Component Data Window. Press **Predefine Setting** in Figure 2-1 **Select System Setup. Predefine Setting** window shown in Figure 2-17 appears.

| Order | Type | Kind | Lighting | Algorithm | Max | Min | Level1 | Level2 |
|-------|------|------|----------|-----------|-----|-----|--------|--------|
| 1 | 997 | 次品 | 飛射 | 2階化 | 0 | 100 | 128 | 0 |
| | | | | | | | | |

Figure 2-17 Predefine Setting

The follows explanation to save inspection data parameter.

Right-click the inspection data to open Figure 2-18 Edit Component Data Window.

Right-click the inspection window and select **Save Parameter** to save parameter of the inspection data in Figure 2-17 Predefine Setting.

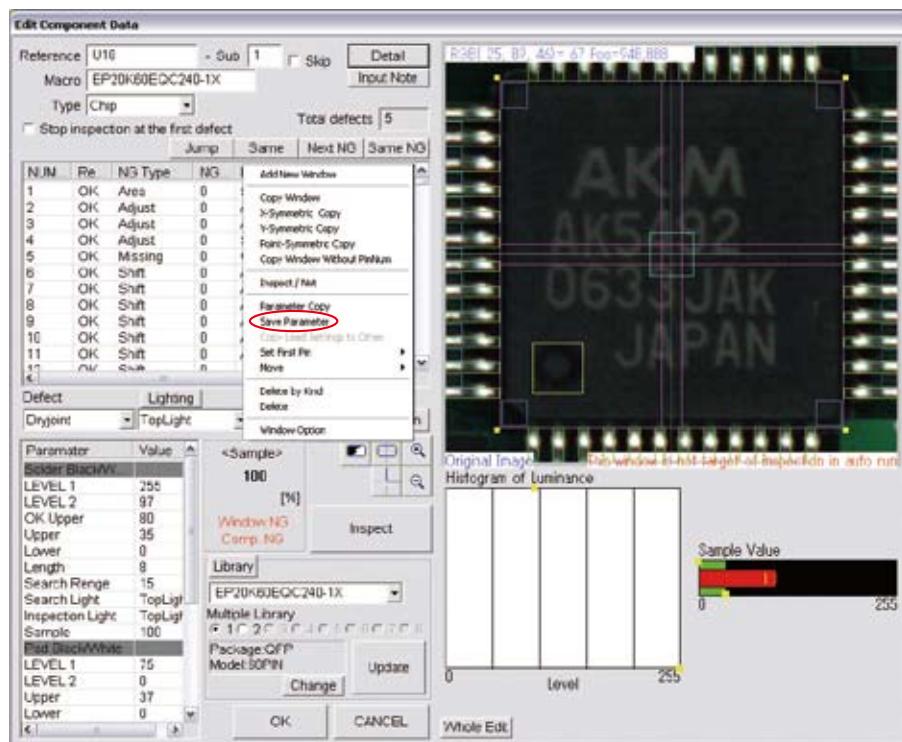


Figure 2-18 Edit Component Data Window

2.12 Self Diagnosis

Disabled function.

2.13 Machine Origin

Disabled function.

2.14 DI/O

Input or output signals can be checked in this window.

Press **DI/O** in Figure 2-1 Select System Setup. Check PLC Functions window shown in Figure 2-19 appears.

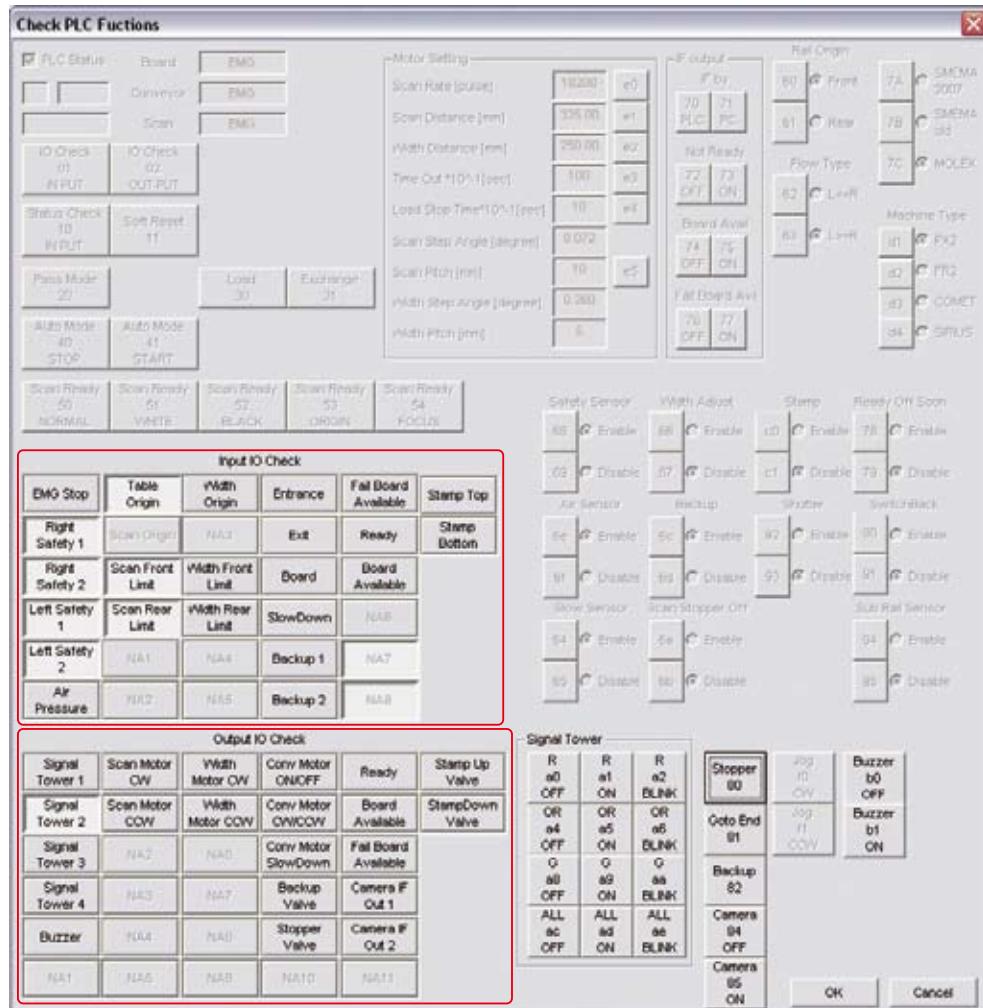


Figure 2-19 Check PLC Functions

A(Input IO Check) items in Figure 2-19 shows the state of input signals from external devices and sensors. When signal is input, corresponding item is on.

B(Output IO Check) items shows the operating status of signal tower or each motors. When unit is operating, corresponding item is on.

2.15 Focus

Disabled function.

2.16 Show Conveyer

Disabled function.

2.17 OK/NG Signals

This section describes the connection settings with upstream/downstream machines.

Press **OK/NG Signals** in Figure 2-1 **Select System Setup**. **OK/NG Signal Settings** window shown in Figure 2-20 appears.

Refer to **Signal** tab in Table 2-1.

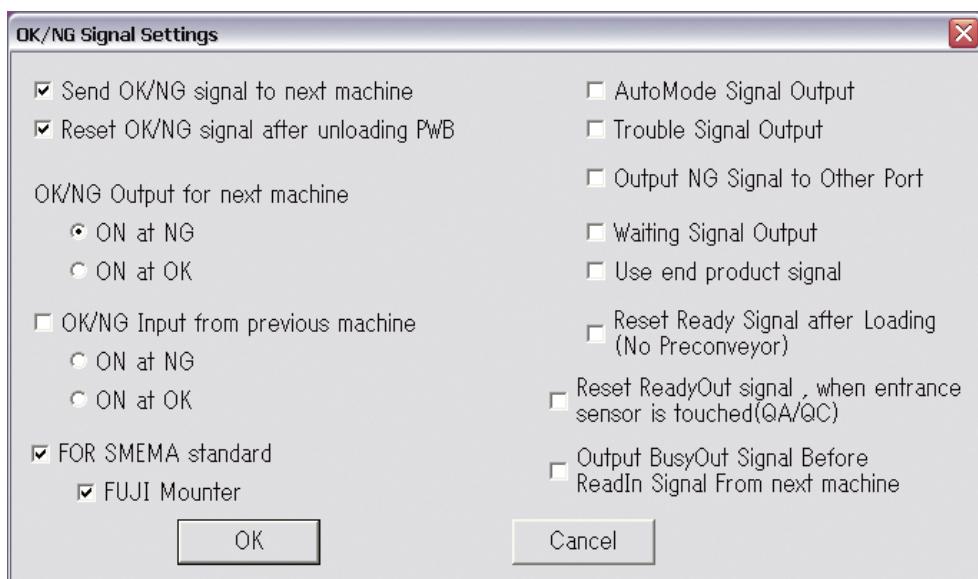


Figure 2-20 OK/NG Signal Settings

In case of receiving OK/NG signal from upstream machine, OK/NG signal is output from AOI based on the AOI inspection result as below.

| | | Inspection Result | |
|----------|-----------|-------------------|----------------|
| | | The Case of OK | The Case of NG |
| OK/NG In | No Signal | OK | NG |
| | OK | OK | NG |
| | NG | NG | NG |

Table 2-8 Relations between Signals from the Upstream Machine and Output Signal

2.18 IPM8540Adjust

Disabled function.

2.19 CPK

Disabled function.

2.20 Separate Conveyer

Disabled function.

2.21 Output Files

Disabled function.

2.22 Warning Setting

This is the function to issue the warning if the NG or false calls are detected more than the specified occurrence frequency. As the warning is issued based on the frequency, errors are detected and informed to operators although the operation is continued over the long term.

Press **Warning Setting** in Figure 2-1 **Select System Setup**. **Warning Setting** window shown in Figure 2-21 appears. Refer to Table 2-9 **Warning Kind Setting**.

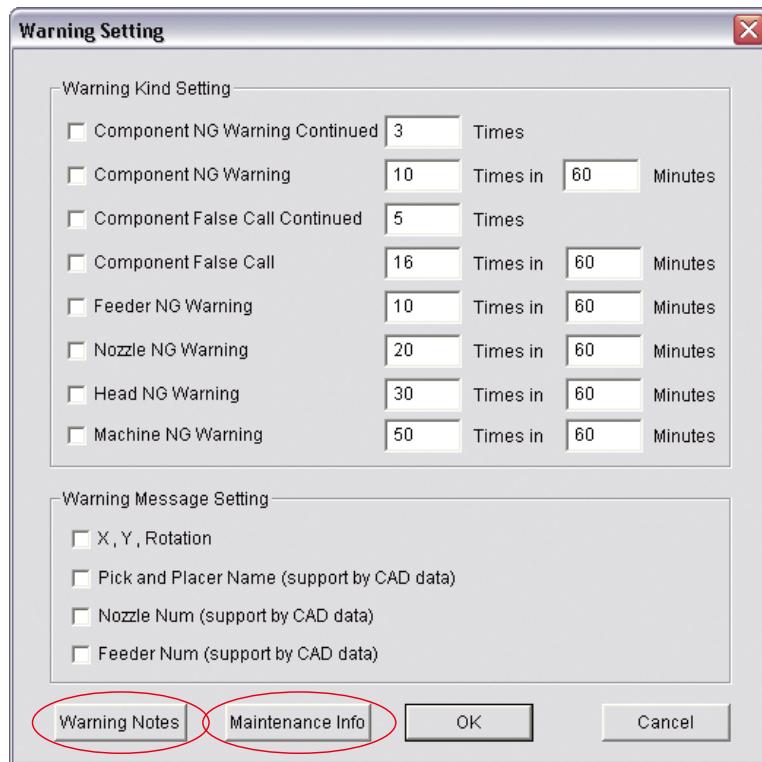


Figure 2-21 Warning Setting

| Items | Description |
|--|---|
| Component NG Warning Continued | If NG of the component in a reference are detected continuously and the number of the continuous NG detection reaches the specified times, the warning message appears. |
| Component NG Warning | If the number of detected NG of a component in a reference during the specified time reach the specified time, the warning message appears. |
| Component False Call Continued | If false call of a component in a reference are detected continuously and the number of the continuous false call detection reaches the specified times, the warning message appears. |
| Component False Call | If the number of false call of a component in a reference during the specified time reach the specified time, the warning message appears. |
| Feeder NG Warning | |
| Nozzle NG Warning | |
| Head NG Warning | |
| Machine NG Warning | |
| X, Y, Rotation | |
| Pick and Placer Name (support by CAD data) | |
| Nozzle Num (support by CAD data) | |
| Feeder Num (support by CAD data) | |

Table 2-9 Warning Kind Setting

Press **Warning Notes** in Figure 2-21 **Warning Setting** window. **Warning Notes** window shown in Figure 2-22 appears. Modify the warning message in this window.

In **Common Advice**, advice message as to defect kind can be arranged. Select the defect type from the **Advice Kinds** drop-down list and enter advice in the text-box. Press **Save**.

In **Equipment Info**, message for each component can be set. Press **Add** to add new items. Press **Delete** to delete items. Press **Save** to apply changes.

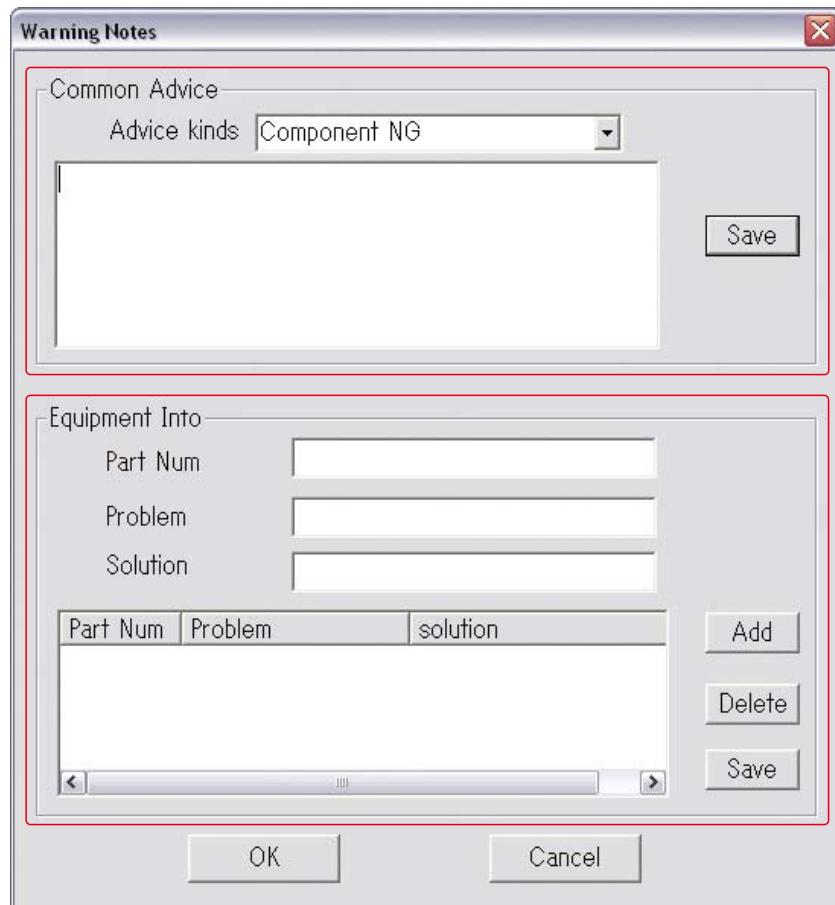


Figure 2-22 Warning Notes

Press **Maintenance Info** in Figure 2-21 **Warning Setting** window. **Maintenance Information** window shown in Figure 2-23 appears. In each text-box, information such as the timing of the maintenance can be recorded. Press **Add** to add new items. Press **Delete** to delete items. Press **Save** to apply changes.

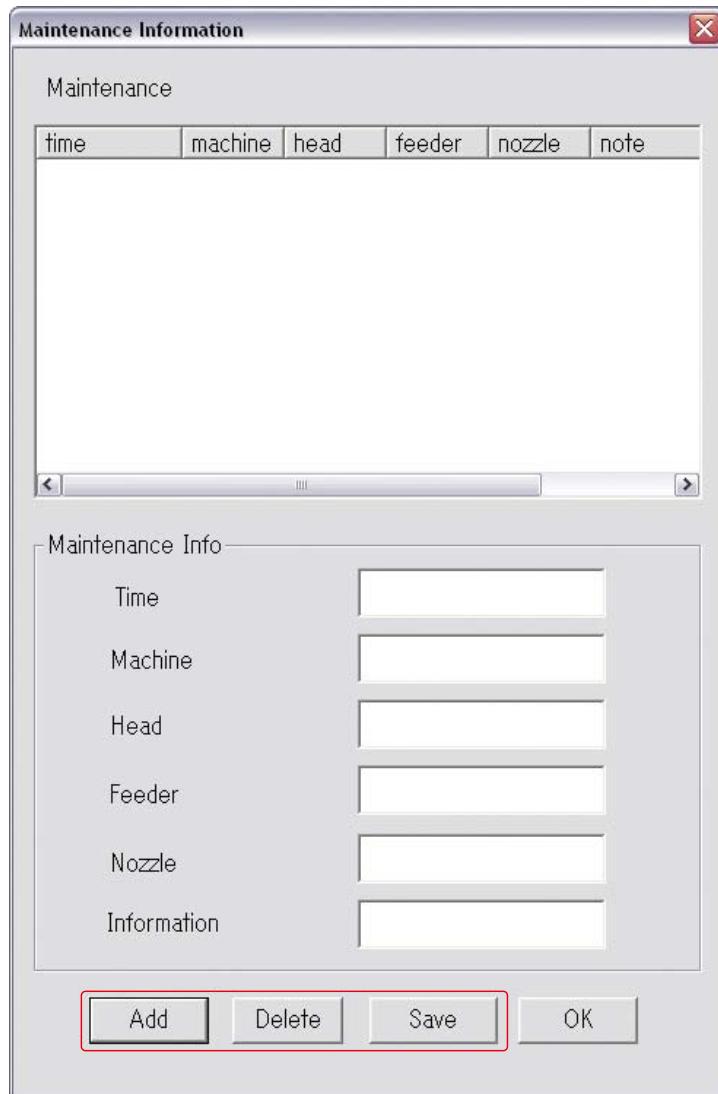


Figure 2-23 Maintenance Information

2.23 Repeatability

Disabled function.

Inspection Data

1 Make Inspection Data

Inspection data can be made by AOI machine and BF-Editor(optional system).

CAUTION Do not use two-byte character, space, tab, and symbolic character(\ < > : " / | ? * . , ; & % =). It would cause unexpected errors.

1.1 Make Inspection Data on AOI Machine

Step1: Press **New** button on the tool-bar or select **File > New** from the menu-bar.

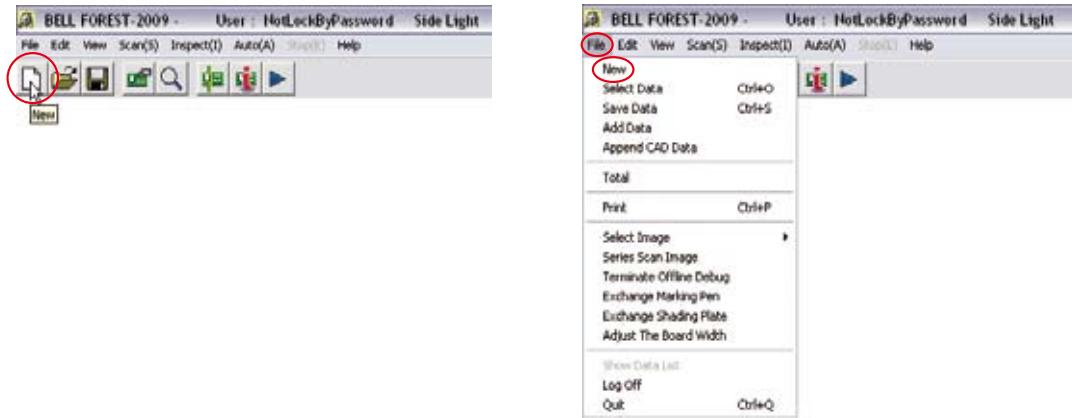


Figure 1-1 New

Step2: Check the **Make Inspection Data for Side A** and press **Next**.

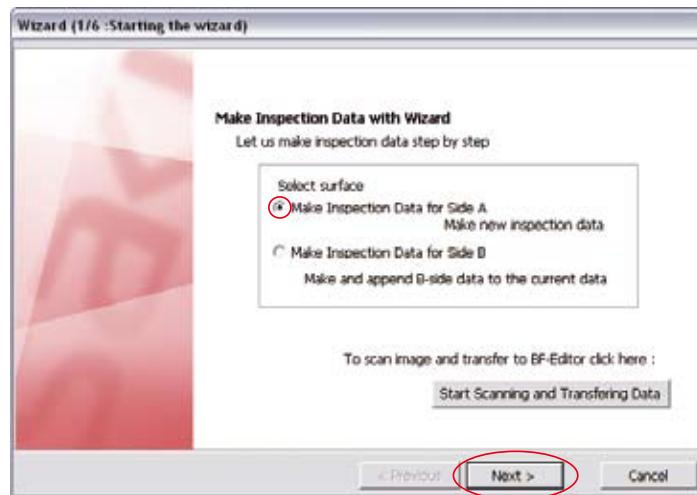


Figure 1-2 Wizard 1

Step3: Press **Browse** in **CAD Data** to specify the CAD data.

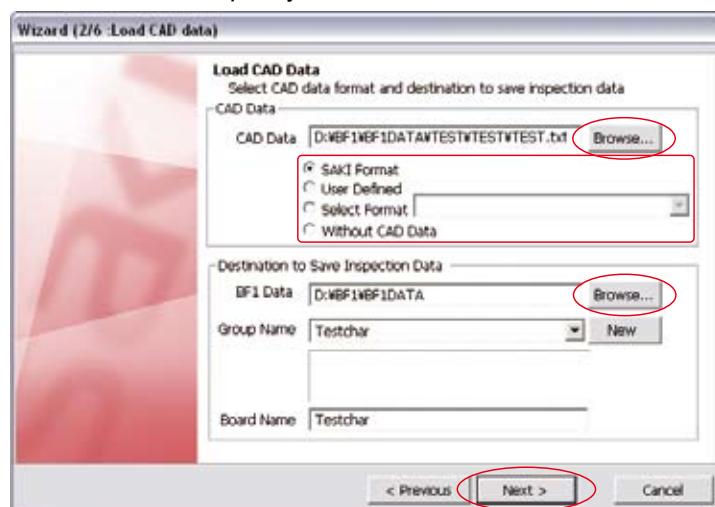


Figure 1-3 Wizard 2

Step4: Select the format of the CAD data.

| Item | Description |
|------------------|---|
| SAKI Format | Check the SAKI Format which CAD data is output with Saki format. |
| User Defined | Check the User Defined which CAD data is output with other format. |
| Select Format | Check the Select Format which mount data is used. |
| Without CAD Data | Check the Without CAD Data which there is no CAD data. |

Table 1-1 Select the Format

Step5: Press **Browse** in **BF1 Data** to specify destination to save the inspection data.

NOTE In default setting, the inspection data is saved in D:\BF\BF1DATA.

Step6: Select **Group Name** from the drop-down list. Press **New** to add new group. The window shown in Figure 1-4 appears. After all the settings are completed, press **OK**.

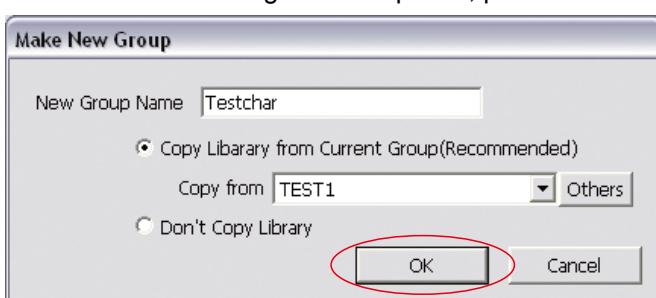


Figure 1-4 Make New Group

| Item | Description |
|---------------------------------|--|
| New Group Name | Enter new group name. |
| Copy Library from Current Group | Check the Copy Library from Current Group to use existing library data. Select library from the Copy from drop-down list. |
| Don't Copy Library | Check the Don't Copy Library not to use existing library data. |

Table 1-2 Make New Group

Step7: Enter **Board Name of Destination to Save Inspection Data** in Figure 1-3 and press **Next**. If **SAKI Format** or **Select Format** in step4 is checked, CAD data will be automatically extracted. If **User Defined** is checked, the format should be made newly. Refer to **1.3 Make User Define Format**. After format is made, CAD data will be automatically extracted.

NOTE

If **Without CAD Data** is checked, CAD data is not extracted. Make inspection data individually.

Step8: After CAD data is extracted, open the image. Press **Load Image** and specify the image file to open the reserved image. Procedures to scan the PCB depend on machine type differs between benchtop machine and inline machine.

In case of benchtop machine

Set the PCB in the machine and press **Scan Board Image**.

In case of inline machine

Adjust conveyor rail width and set the PCB on conveyor rail. Press **Load / Unload the Board**. Set the PCB in the machine and press **Scan Board Image**. To unload the PCB, press **Load / Unload the Board**.

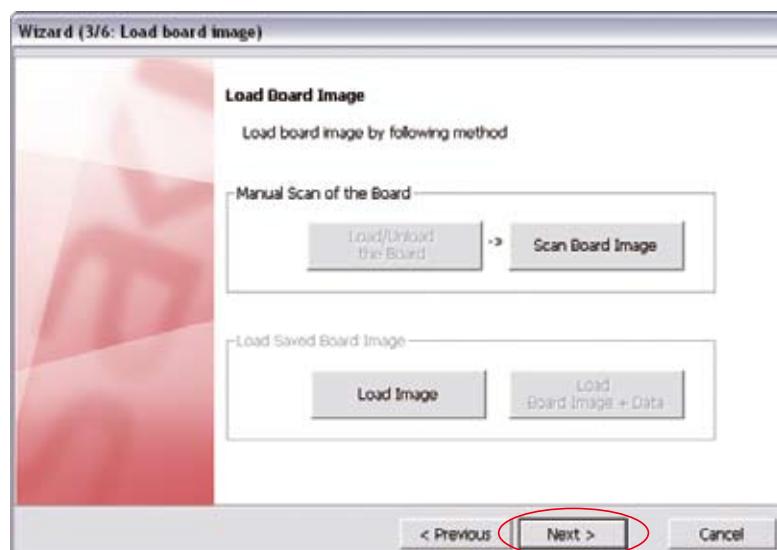


Figure 1-5 Wizard 3

Step9: Check the PCB is scanned properly and press **Next**.

Step10: Select two fiducial mark data from the list-box. The second selected fiducial mark data is displayed. Press **Switch of Mark Data Image** to display another fiducial mark data.

NOTE Magnification percentage of image can be changed by pressing **ENLARGE** or **REDUCE**.

NOTE Top 50 components data in all component data registered as fiducial mark, all component data including **Mark** or all outlying component data from the center of PCB are displayed in the list-box as possible fiducial mark data.

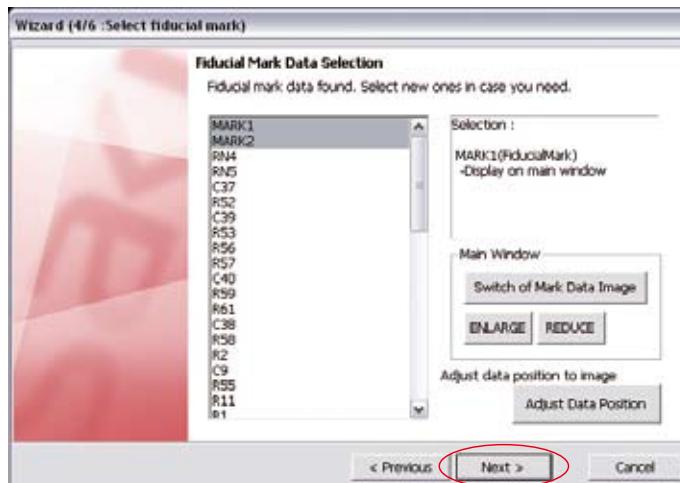


Figure 1-6 Wizard 4

Step11: Press **Adjust Data Position** in Figure 1-6, the window shown in Figure 1-7 appears. Press **Adjust Tool** to match the position of component data and the image. After all the adjustments are completed, press **OK**.

NOTE The position of component data can be adjusted by dragging mouse. In addition, magnification percentage can be changed by scrolling wheel of mouse.

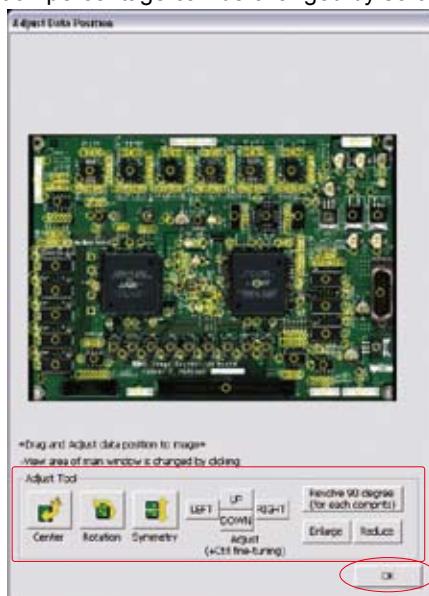


Figure 1-7 Adjust Data Position

Step12: After all the settings are completed, press **Next**.

Step13: Make fiducial mark data and press **MARK1**. The window shown in Figure 1-9 appears.

NOTE If more than one CAD data is used, press **Append** and refer to after Step3.

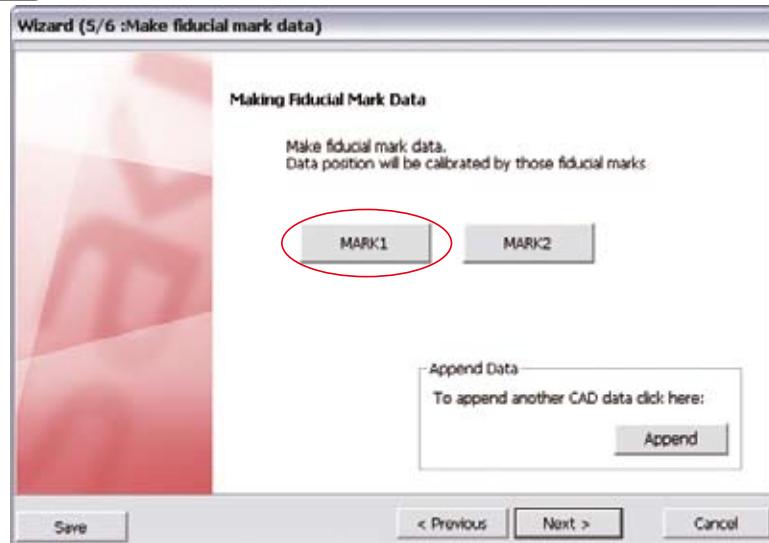


Figure 1-8 Wizard 5

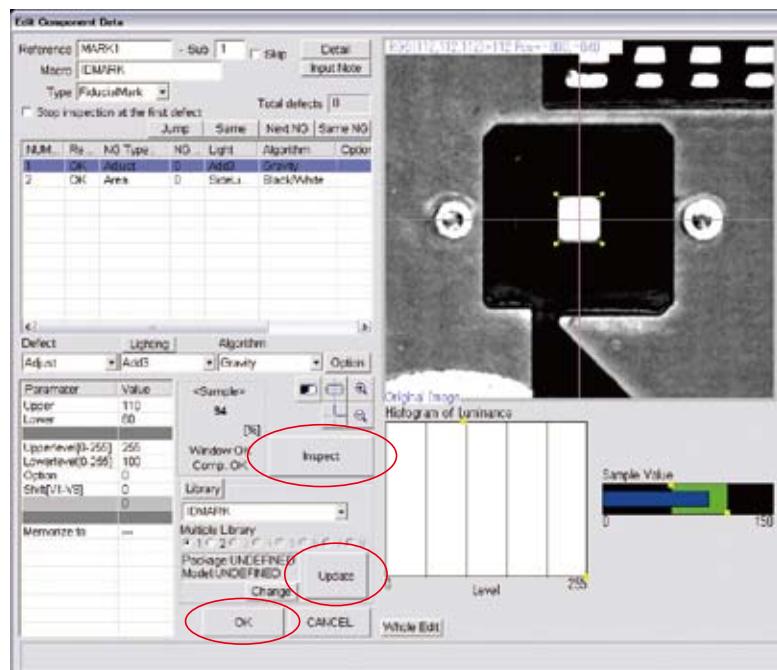


Figure 1-9 Fiducial Mark 1

Step14: Select **Fiducial Mark** from the **Type** drop-down list.

Step15: Right-click on the list and select **New**.

Step16: Select **Adjust** from the **Defect** drop-down list.

Step17: Select a lighting that fiducial mark is visually clear from the **Lighting** drop-down list.

Step18: Select a algorithm from the **Algorithm** drop-down list.

| Figure of Fiducial Mark | Description |
|-------------------------|----------------------------|
| Square | Select Gravity . |
| Circle | Select New_Circle . |

Table 1-3 Select Algorithm

Step19: Adjust **Adjust** inspection window size to surround the fiducial mark.

NOTE Change **Diameter** to adjust inspection window size if **New_Circle** is used.

Step20: Enter **Upperlevel** and **Lowerlevel**.

| Brightness Level | Description |
|------------------------------|--|
| Fiducial Mark > Surroundings | Enter 255 in Upperlevel field and 150 in Lowerlevel field. |
| Fiducial Mark < Surroundings | Enter 150 in Upperlevel field and 0 in Lowerlevel field. |

Table 1-4 Upperlevel and Lowerlevel setting

Step21: Right-click on **Adjust** and select **Copy**. The same parameter will be copied in **2 of NUM...**

Step22: Select **2 of Num...** and select **Area** from the **Defect** drop-down list.

Step23: Adjust **Area** inspection window can inspect the fiducial mark. This is the search range for the fiducial mark data. Ideal window size is about three times bigger than the fiducial mark size as a rough guide.

CAUTION The larger inspection window can inspect the fiducial mark if it is out of the target position. However it takes longer time to inspect it and some PCB pattern might be mis-judged as a fiducial mark.

Step24: Select **Adjust** and press **Inspect**. Pink line crossing center of the fiducial mark appears if the search is successful.

Step25: Press **Update**. The dialog shown in Figure 1-10 appears and press **OK**.

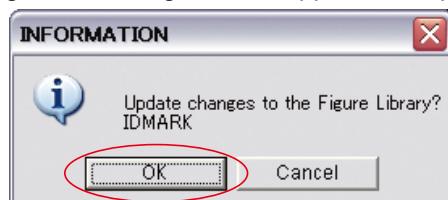


Figure 1-10 Fiducial Mark 2

Step26: The dialog shown in Figure 1-11 appears and press **OK**.

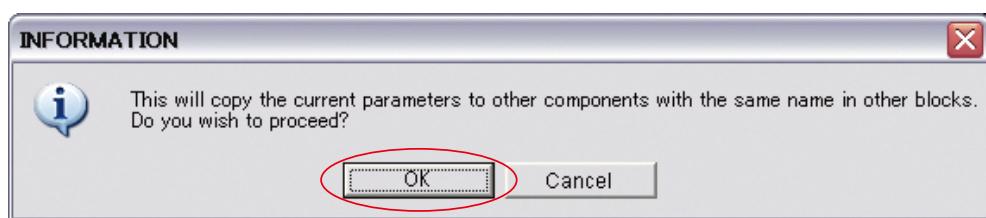


Figure 1-11 Fiducial Mark 3

Step27: Press **OK** in Figure 1-9 and the dialog shown in Figure 1-12 appears. If CAD data is used, press **Cancel**. If CAD data is not used, press **OK**.

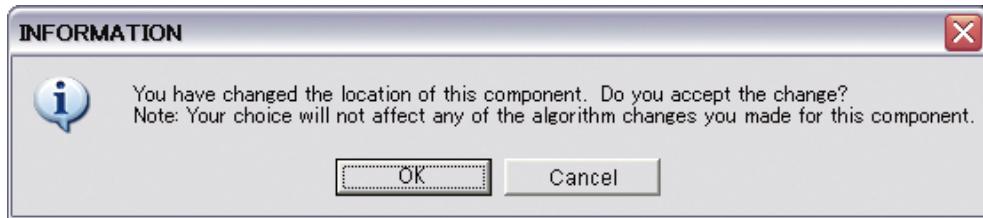


Figure 1-12 Fiducial Mark 4

Step28: The dialog shown in Figure 1-13 appears and press **OK**.

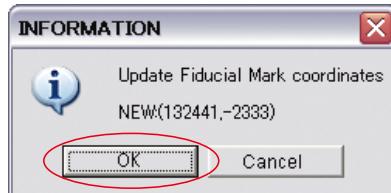


Figure 1-13 Fiducial Mark 5

Step29: The dialog shown in Figure 1-14 appears. If CAD data is used, press **OK**. If CAD data is not used, press **Cancel**.

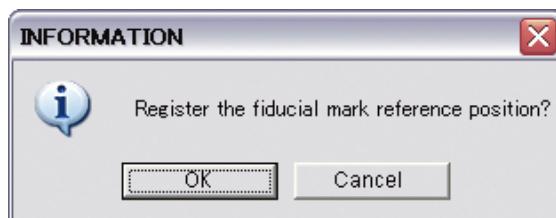


Figure 1-14 Fiducial Mark 6

Step30: Press **MARK2** and set as well as **MARK1**. After all the settings are completed, press **Next**.

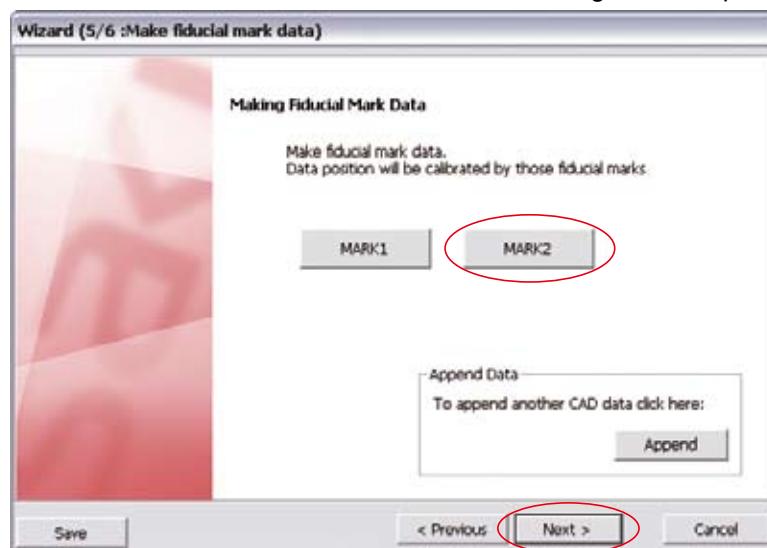


Figure 1-15 Wizard 5

Step31: Assign library to each component data. Library has information of inspection data. The time to make the inspection data can be reduced by sharing the common library among the same component type. The components assigned no libraries are displayed in the list-box. Select a component and press **Library Data Assignment**.

NOTE

If there is no library which corresponds to the component, the new library should be made. Refer to **1.4 Auto Deployment of inspection data** to make the inspection data easily.

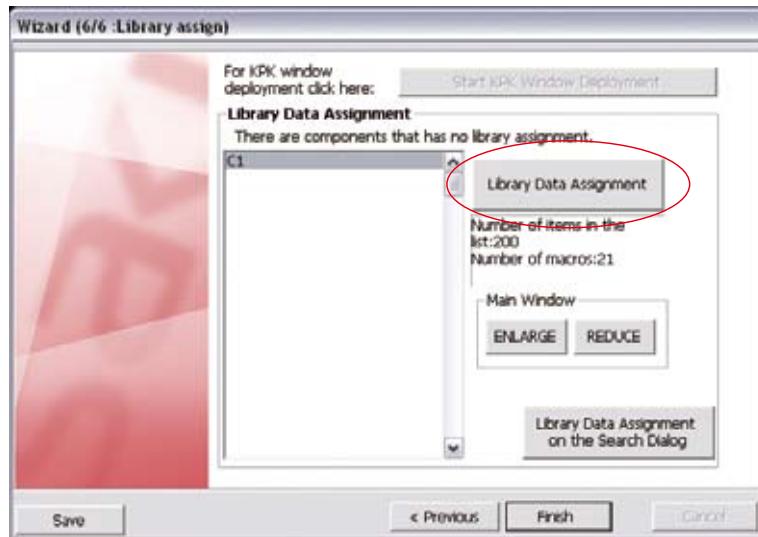


Figure 1-16 Wizard 6

| Item | Description |
|--|--|
| Start KPK Window Deployment | Press Start KPK Window Deployment to make KPK inspection data. Refer to 2 KPK . |
| ENLARGE / REDUCE | Press ENLARGE or REDUCE to change magnification percentage of image. |
| Library Data Assignment on the Search Dialog | Search window appears. Press Library Data Assignment on the Search Dialog and close wizard. The window shown in Figure 1-17 appears. In this case, assign library in search window. |

Table 1-5 Other Items

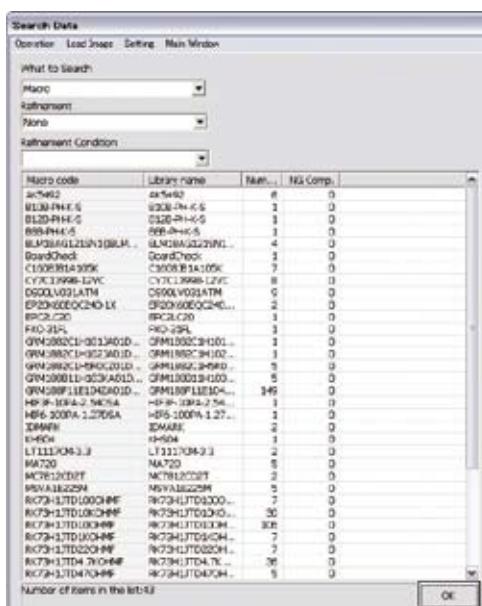


Figure 1-17 Search Data

Step32: The window shown in Figure 1-18 appears. Select an appropriate library for the component.

Double-click the library to edit the inspection data. In case of making a new library, select an existing library that can be a base of new library. After select the base library, press **New(Use this as a template)**. The base library is registered as template library. The window shown in Figure 1-19 appears. Enter the library name and press **OK**.

NOTE In case of making a new library, select a library which can be applied to a lot of similar components and set the library as a template.

NOTE Press **Import** in Figure 1-19. Component name and macro name are displayed.

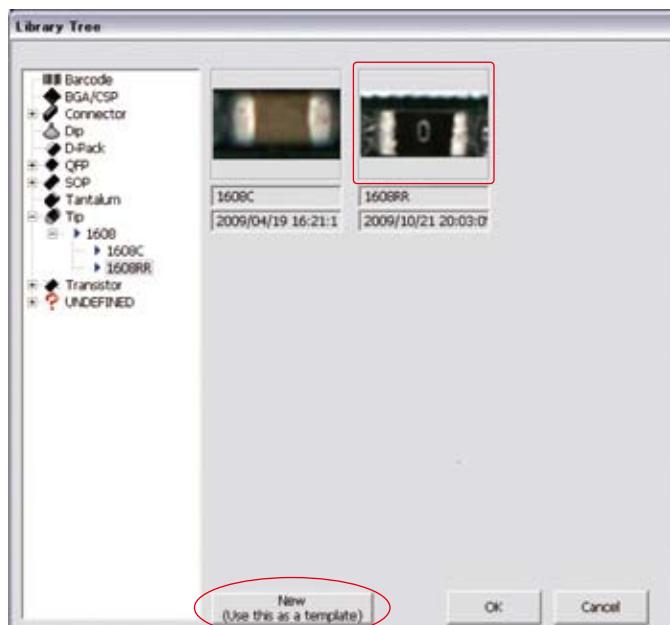


Figure 1-18 Assign Library

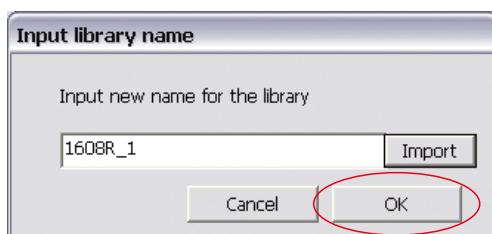


Figure 1-19 Input Library Name

Step33: Edit component data window of template library is appeared. Press **Whole Edit** in the lower side of the window and the window shown in Figure 1-21 appears. The following settings are available to zoom the component, expansion and contraction of one direction only, rotation of 90°, adjust the number of IC lead, clearance, and lead length. After all settings are completed, press **Update** and **OK**.



Figure 1-20 Edit Component Data Window

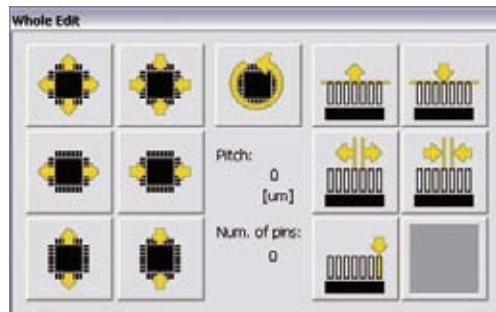


Figure 1-21 Whole Edit

Step34: After libraries are assigned to all components, press Finish in Figure 1-16. The window shown in Figure 1-22 appears and press **Save**. Check **Change destination to save inspection data** and specify the directory to save, if necessary.



Figure 1-22 Save Data

1.2 Make Inspection Data on BF-Editor

The scanned image can be transferred from AOI machine to the BF-Editor. The inspection data can be made with the transferred image in BF-Editor.

1.2.1 Transfer Data to BF-Editor

Step1: Press **New** button on the tool-bar or select **File > New** from the menu-bar on AOI machine.

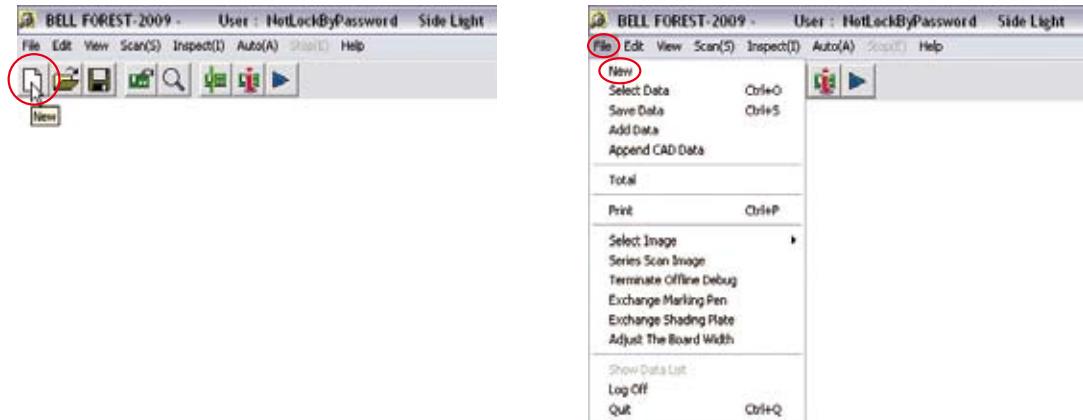


Figure 1-23 New

Step2: Press **Start Scanning and Transferring Data**.

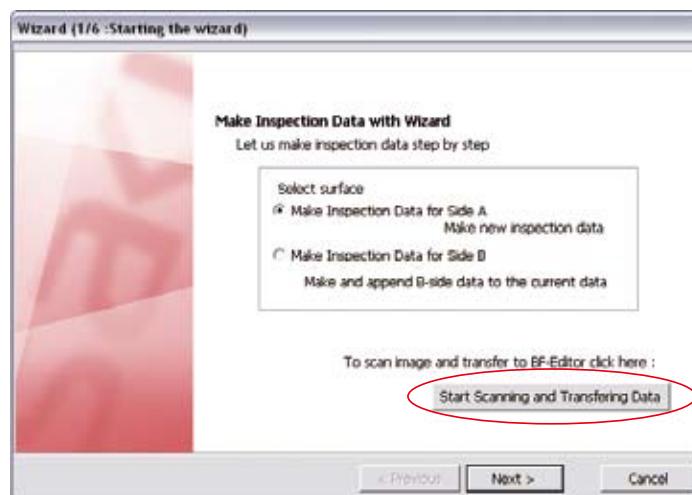


Figure 1-24 Wizard 1

Step3: Check the **BF-EDITOR Transfer Data to**. Enter **Board Name**, **Board Size**, and **Board Thickness**. Press **OK**.

NOTE The destination to save the transfer data was set during the installation of BF-Editor.

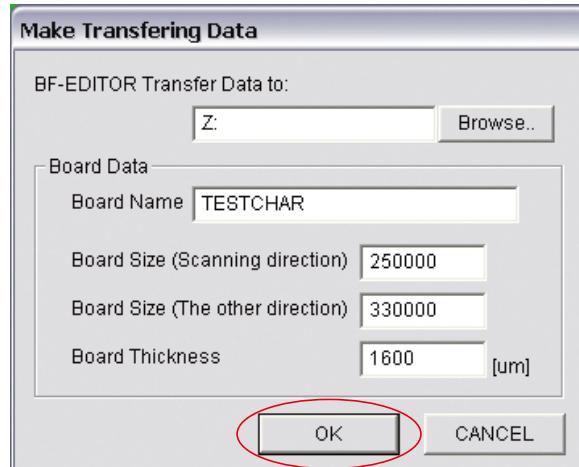


Figure 1-25 Make Transferring Data

Step4: Scan the PCB. Procedures differs between benchtop machine and inline machine.

In case of benchtop machine

Set the PCB in the machine and press **Scan the Board**. After scanning the PCB, the dialog shown in Figure 1-27 appears. Some comment can be added if necessary. Enter comments in the text-box and press **OK**. If you do not need to add comment, press **OK**.

In case of inline machine

Adjust conveyor rail width and set the PCB on conveyor rail. Press **Load / Unload the Board**. Set the PCB in the machine and press **Scan the Board**. To unload the PCB, press **Load / Unload the Board**.

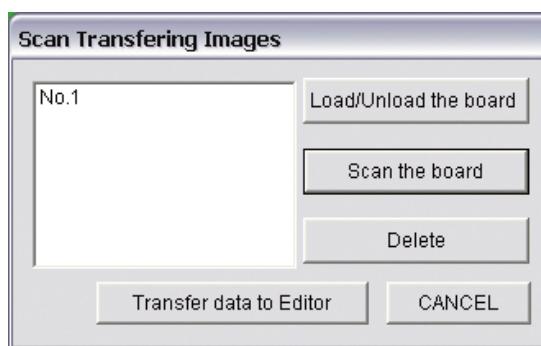


Figure 1-26 Scan Transferring Images



Figure 1-27 Input SERIES Image Comment

Step5: Images can be used for inspection data debugging if several images are saved.

NOTE The maximum number of images that can be saved is 10.

Step6: Press **Transfer data to Editor** to transfer image. Transferred data will be saved in **Transferring destination of BF-Editor data\TRANSDATA** folder.

CAUTION Check the BF-Editor is activated before pressing **Transfer data to Editor**.



Figure 1-28 Transfer Data to Editor

1.2.2 Make Inspection Data on BF-Editor

Step1: Press **New** button on the tool-bar or select **File > New** from the menu-bar on BF-Editor.

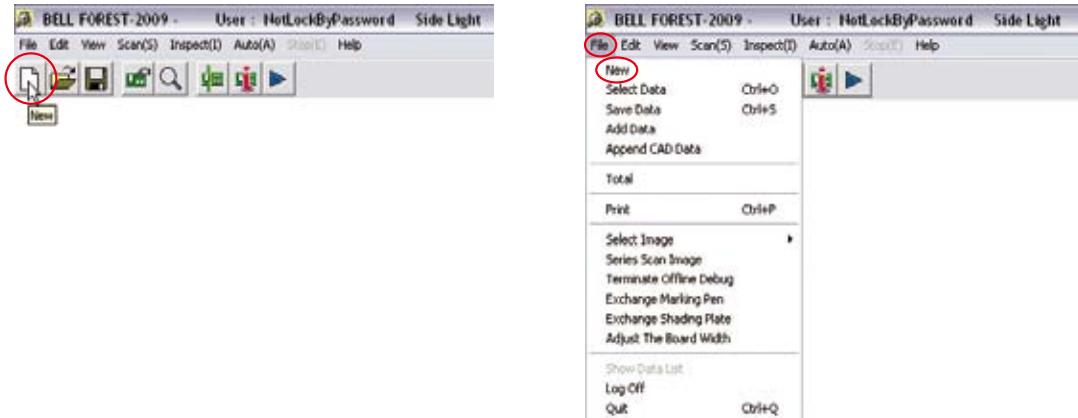


Figure 1-29 New

Step2: Check the **Make Inspection Data for Side A** and press **Next**.

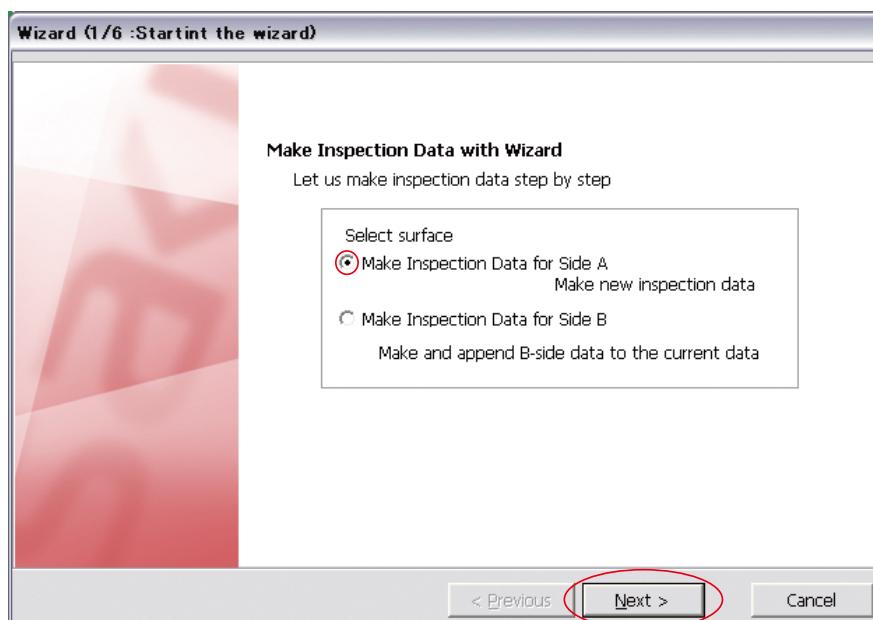


Figure 1-30 Wizard 1

Step3: Press **Load Board Image + Data** and select transferred data from AOI machine. Transferred data will be saved in **TRANSDATA** folder. Select the transferred data and press **OK**. Check if the image is appeared and press **Next**.

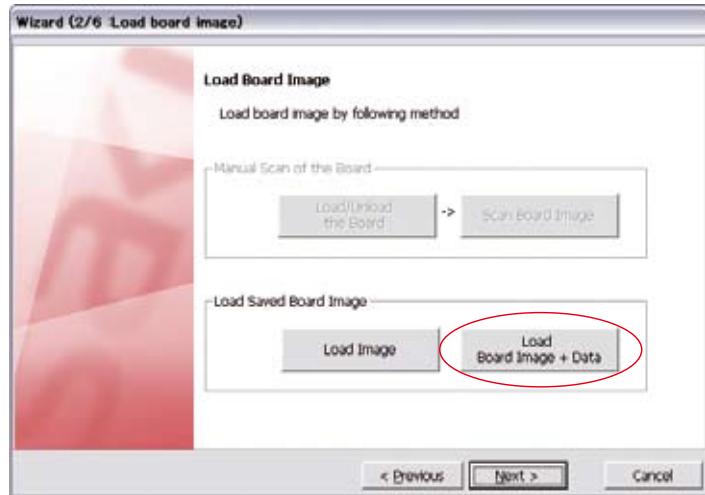


Figure 1-31 Wizard 2

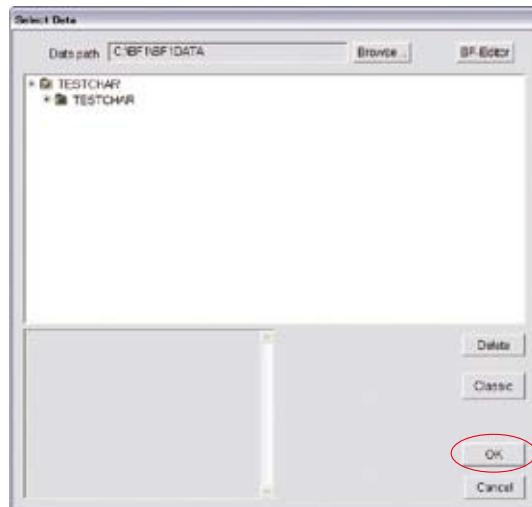


Figure 1-32 Select Data

Step4: Make inspection data with referring to after Step3 in **1.1 Make Inspection Data on AOI Machine**.

1.3 Make User Define Format

If User Defined is checked in 1.1 Make Inspection Data on AOI Machine Step4, the window shown in Figure 1-33 appears. A format can be made to extract the CAD data. In case of double-side PCB, both sides need each own user define format.

Step1: Press **New Format** to make a new format. If there is a similar format, press **Copy and Edit**.

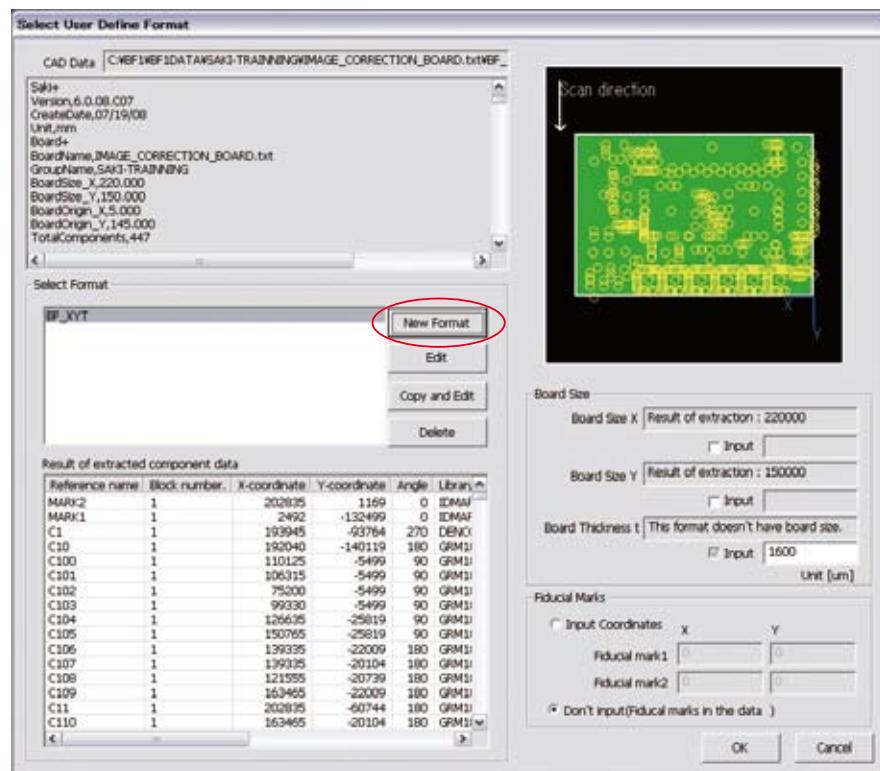


Figure 1-33 User Define Format

Step2: Enter format name in the text-box and press **Next**.

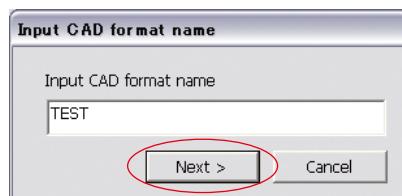


Figure 1-34 Enter Format Name

Step3: CAD data is displayed. Specify lines contains the component data such as name or coordinates of components.

CAUTION

Text-box is case-sensitive.

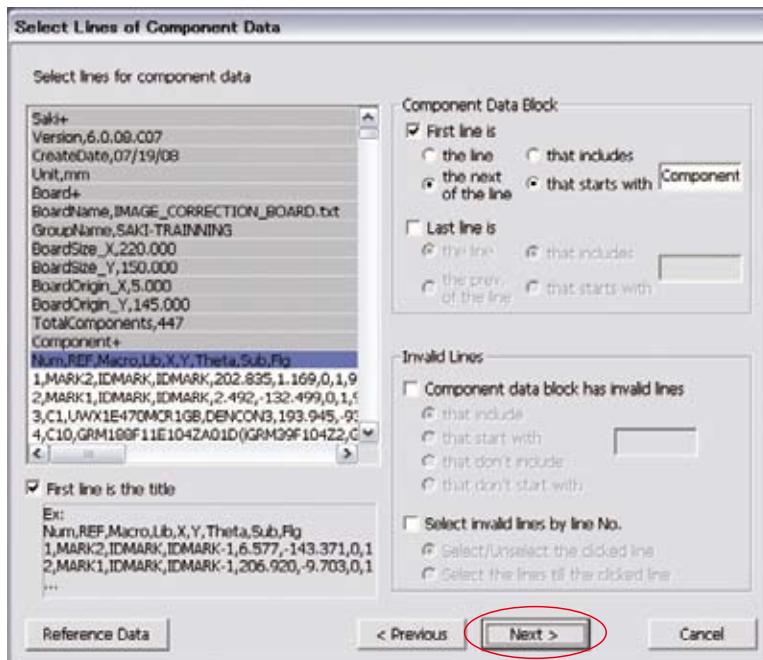


Figure 1-35 Select Lines of Component Data

| Parameter | Description |
|---|---|
| First line is the title | Check the First line is the title if the first line of component data defined each columns. |
| First line is | Check the First line is to specify the first line of component data. |
| Last line is | Check the Last line is to specify the last line of component data. |
| the line and that includes | Check the the line and that includes to specify the line which is including words entered in the text-box. |
| the next(prev.) of the line and that includes | Check the the next(prev.) of the line and that includes to specify the next(previous) line of the line which is including words entered in the text-box. |
| the line and that starts with | Check the the line and that starts with to specify the line that start with the entered words in the text-box. |
| the next(prev.) of the line and that starts with | Check the the next(prev.) of the line and that starts with to specify the next(previous) line of the line that start with the entered words in the text-box. |
| Component data block has invalid lines | Check the Component data block has invalid lines if component data have the line that does not include component information. The specified line becomes invalid line. |
| that include | Check the the line and that includes to specify the line which is including words entered in the text-box. |
| that start with | Check the the line and that starts with to specify the line that start with the entered words in the text-box. |
| that don't include | Check the that don't include to specify the line which is not including words entered in the text-box. |
| that don't start with | Check the that don't start with to specify the line that doesn't start with the entered words in the text-box. |
| Select invalid lines by line No. | Check the Select invalid lines by line No. to specify the line that is not component data. As the particular line is specified with this function, the user define format might be inapplicable to other CAD data. |
| Select/Unselect the clicked line | Check the Select/Unselect the clicked line to specify clicked line. |
| Select the lines till the clicked line | Check the Select the lines till the clicked line to specify from the top line to the clicked line. |
| Reference Data | CAD data is displayed in other window. |

Table 1-6 Description of Parameters

| | |
|----------|---|
| CAD Data | Board+ BoardSize_X,220.000 BoardSize_Y,150.000 Component+ (Component data line always starts from the following line of Component+) Num,REF,Macro,Lib,X,Y,Theta,Sub,Flg (The title line should be also considered as line of component data) 1,MARK2,MARK,MARK-1,6.577,-143.371,0,1,98 2,MARK1,MARK,MARK-1,206.920,-9.703,0,1,98 ... |
| Settings | Check the First line is . Enter Component+ in the text-box. Check the the next of the line and that includes . Check the First line is the title . |

Table 1-7 Example 1

| | |
|----------|--|
| CAD Data | BSIZE150000Y300000 ORX5000Y5000 C "R101"X101223Y050234T090 (Component data always starts by C) C "C202"X059526Y189256T270 ... C "IC5" X033564Y253654T000 END (The last line is not component data) |
| Settings | Check the First line is . Enter C in the text-box. Check the the line and that starts with . Check the Last line is . Enter C in the text-box. Check the the line and that starts with . |

Table 1-8 Example 2

| | |
|----------|---|
| CAD Data | ... 374,U35,DS90LV031ATM,SOP8PIN,152.467,-27.459,90,1,2 (The line of component data always include ",") 375,U35,DS90LV031ATM,SOP8PIN,152.467,-27.459,90,1,2 <PAGE4> (The line which is not component data exist, the line don't include ",") 376,U4,TL7705ACPS,SOP4PINS,36.094,-99.379,180,1,1 377,U5,TL7705ACPS,SOP4PINS,172.382,-101.121,0,1,2 ... |
| Settings | Check the Component data block has invalid lines . Enter the , in the text-box. Check the that don't include . |

Table 1-9 Example 3

Step4: Check all lines of component data are highlighted in white and other lines in gray. Press **Next**.

NOTE If the title line is specified, the title line is highlighted in blue.

Step5: The lines specified as component data in step4 are displayed. Specify the definition type to classify the data according to the type such as name or coordinates of components.

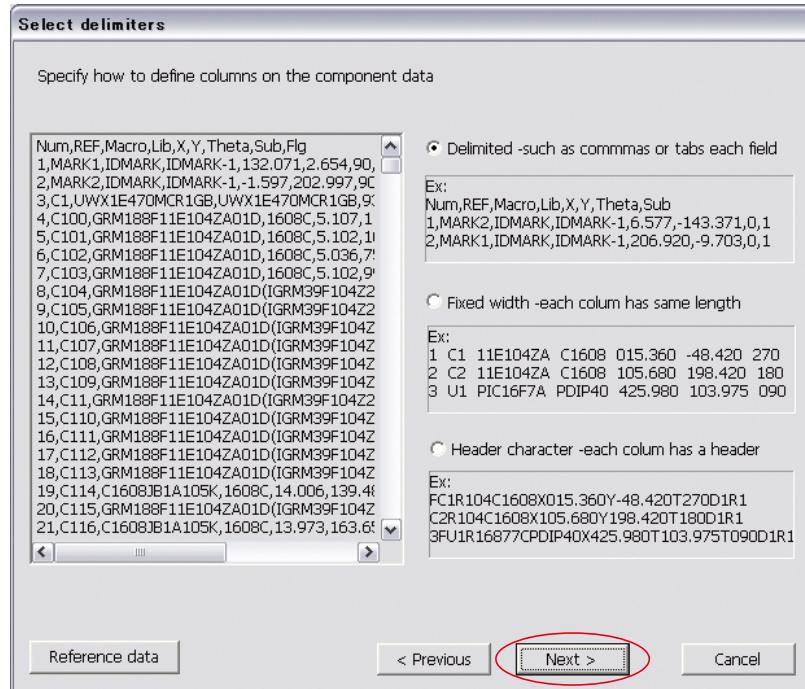


Figure 1-36 Select Delimiters

Delimited(such as commas or tabs each field)

Check the **Delimited** in Figure 1-36 and press **Next** if parameters is separated by comma, tab, or space. Check the item of **Separators** in Figure 1-37. Each parameter is automatically separated. Check the **Treat successive separators as one separator** if more than one space or tab are contained. After all the settings are completed, press **Next**.

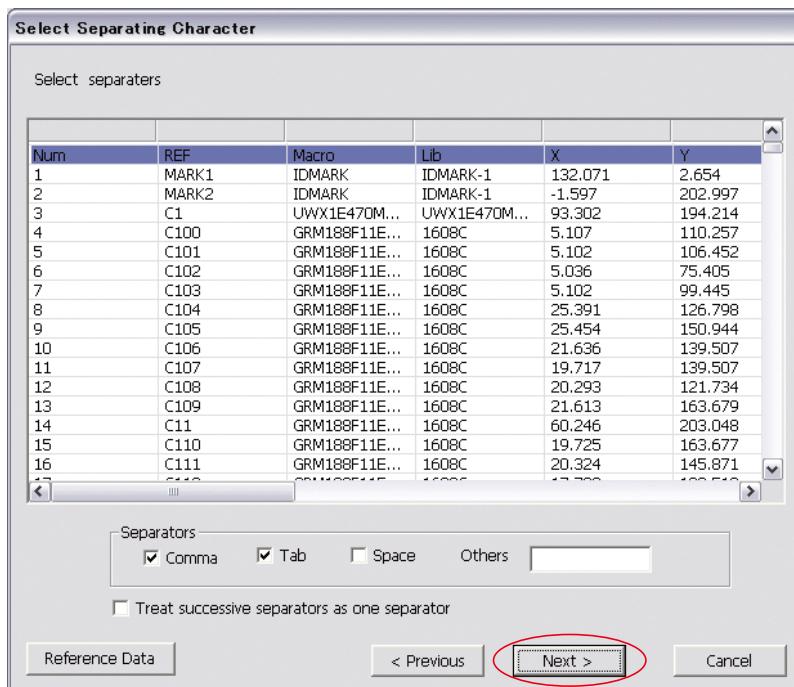


Figure 1-37 Delimited(such as commas of tabs each field)

Fixed width(each column has same length)

Check the **Fixed width** in Figure 1-36 and press **Next** if parameters is separated by fixed width. Adjust column widths by dragging the boundary of the header in Figure 1-38. After all the settings are completed, press **Next**.

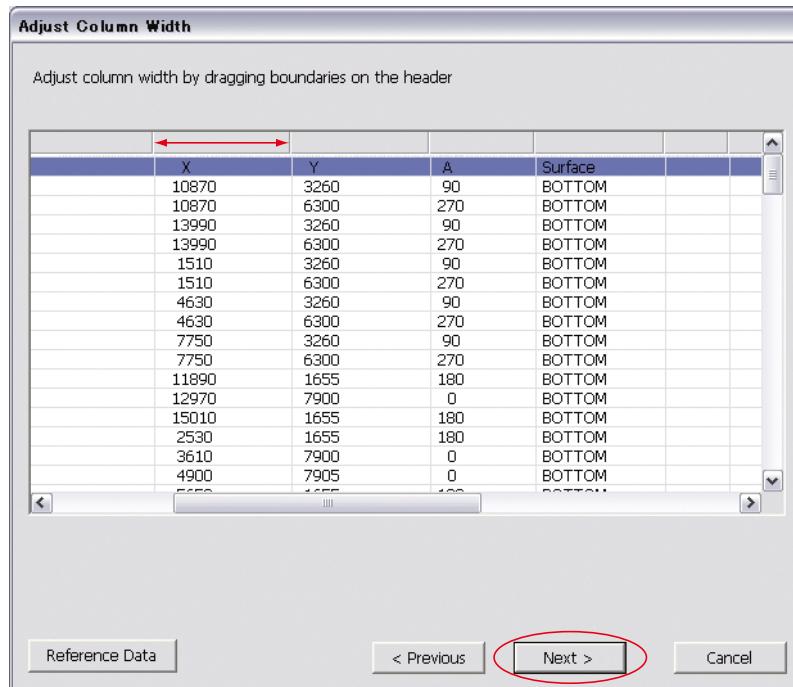


Figure 1-38 Fixed Width(each column has same length)

Header character(each column has a header)

Check the **Header character** in Figure 1-36 and press **Next** if parameters is separated by head character. Enter header character of parameter in the text-box of each columns in Figure 1-39. After all the settings are completed, press **Next**.

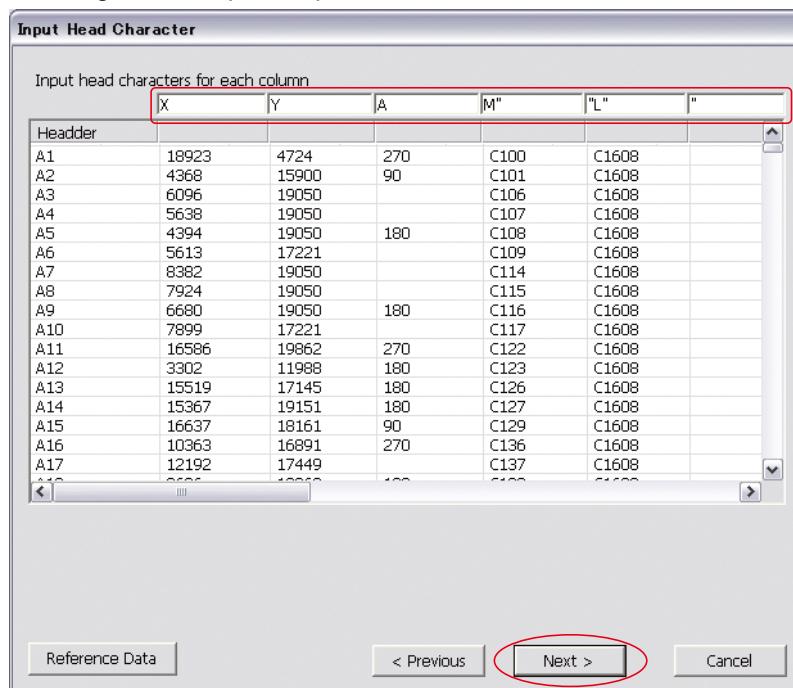


Figure 1-39 Header Character(each column has a header)

Inspection Data

Step6: Press each column header, parameter's item is displayed, as shown in Figure 1-40. Select parameters that matched with each column. After all the settings are completed, press **Next**.

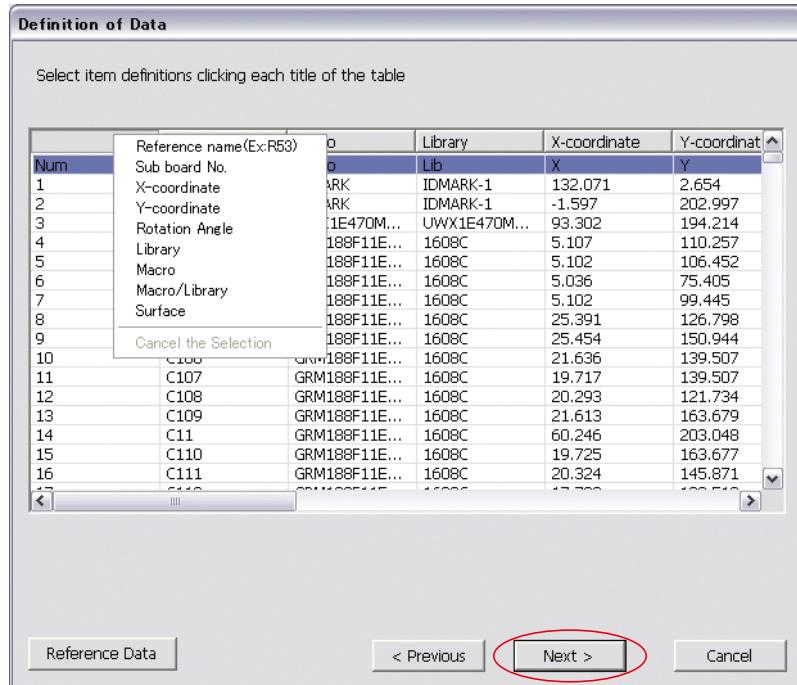


Figure 1-40 Definition of Data

Step7: Specify conversion conditions for coordinate and angle. Select items from the drop-down list. **Multiplier** is available if **Other** is selected from the drop-down list. The specified amount of offset will be added to all the component rotation if enter offset angle in **Offset angle** field. If **Surface** is specified in step6, enter appropriate parameter in **Assign surface** field. After all the settings are completed, press **Next**.

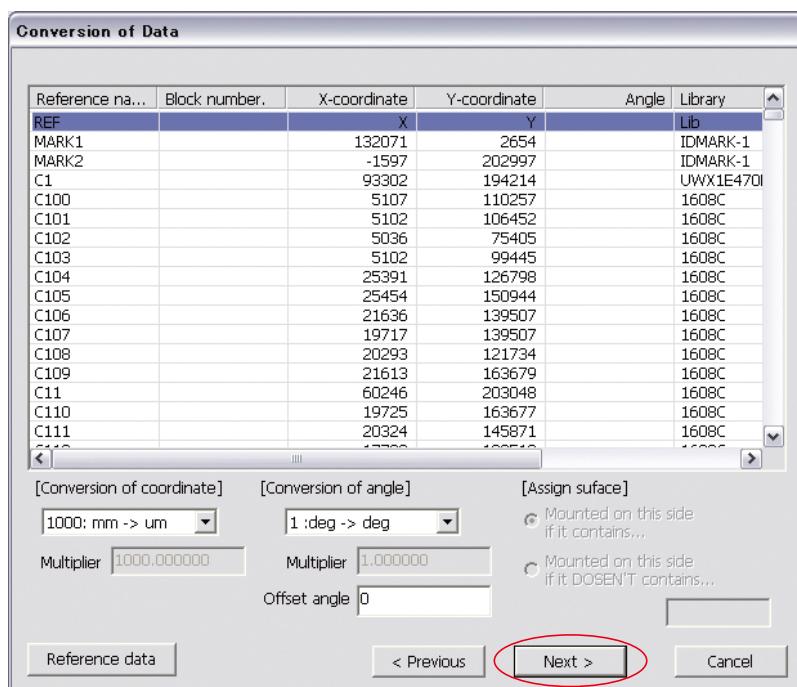


Figure 1-41 Data Conversion

Step8: The part this is not selected as component data in CAD data is displayed. Specify conditions to extract PCB size and PCB thickness from data. These data will be automatically extracted from the next time.

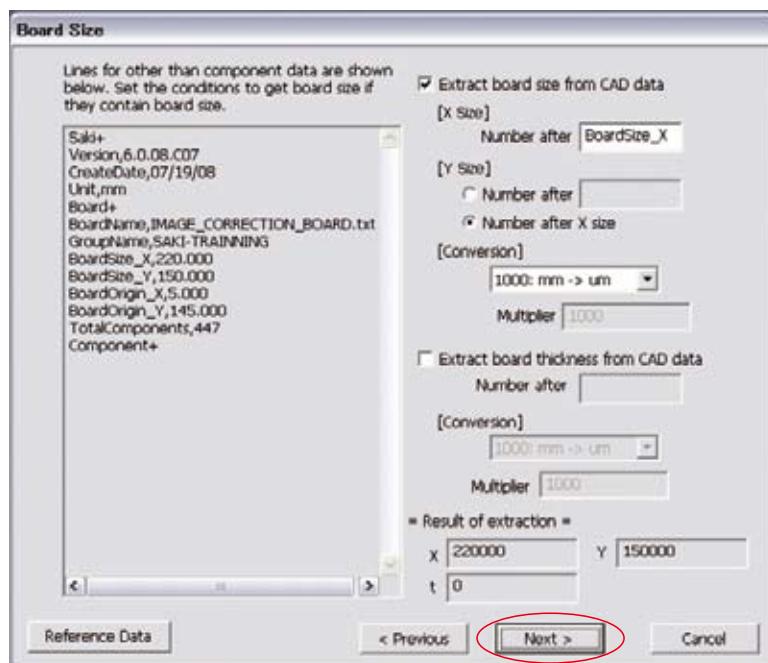


Figure 1-42 Extract PCB Size

| Parameter | Description |
|---------------------------------------|---|
| Extract board size from CAD data | Check the Extract board size from CAD data to extract length of X direction and Y direction of the PCB. |
| X Size | Enter the character preceding the number which shows the X direction length of the PCB. The extracted value is displayed in Result of extraction . |
| Y Size | Enter the character preceding the number which shows the Y direction length of the PCB. Check the Number after X size if length of X direction and Y direction are continuing. The extracted value is displayed in Result of extraction . |
| Conversion | Select conversion conditions from the drop-down list. Select Other from the drop-down list and enter multiplier in Multiplier field. |
| Extract board thickness from CAD data | Check the Extract board thickness from CAD data to extract PCB thickness. Enter the character preceding the number which shows the PCB thickness. |
| Conversion | Select conversion conditions from the drop-down list. Select Other from the drop-down list and enter multiplier in Multiplier field. |

Table 1-10 Description of Parameters

| | |
|----------|--|
| CAD Data | Board+ BoardSize_X,220.000 (Next value of BoardSize_X is always length of X direction of the PCB) BoardSize_Y,150.000 (Next value of BoardSize_Y is always length of Y direction of the PCB) |
| Settings | Enter BoardSize_X in X Size field. Enter BoardSize_Y in Y Size field (It can also substitute checking the Number after X size). Select mm→μm from the drop-down list of Conversion . |

Table 1-11 Example

Step9: Press **Next** to enter PCB size and PCB thickness manually. Enter necessary conditions to extract these data automatically. Check if necessary data is extracted correctly in **Result of extraction** and press **Next**.

Step10: Press three buttons to match CAD data origin and machine origin. Starting from the left, **Place all data position inside of the PCB**, **Rotate all data 90° in counterclockwise direction**, **Flip all data vertical**. After all the settings are completed, press **Next**.

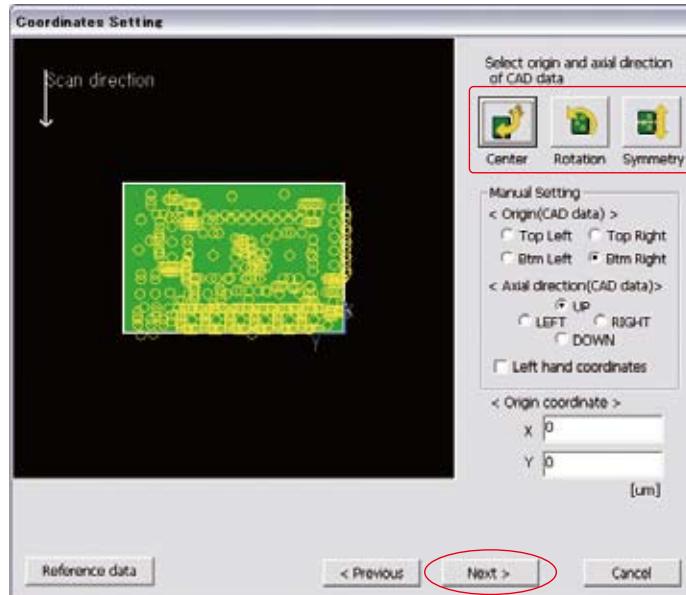


Figure 1-43 Coordinates Setting

Step11: Check if the component data is shown on the PCB image and **board size** is displayed. Enter the PCB size manually if the data is not automatically extracted. Check the **Input coordinates** if the fiducial mark data is not in the data and enter arbitrary coordinates. After all the settings are completed, press **OK**.

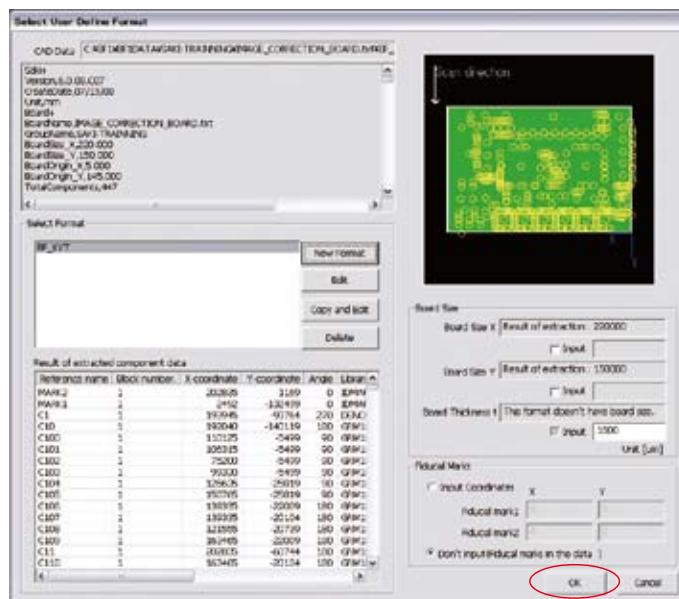


Figure 1-44 User Define Format

Step12: This is the end of making user define format. Refer to after Step8 in **1.1 Make Inspection data on AOI Machine**.

NOTE

Once user define format is registered, extracting CAD data is easy when the same format is used from the next time. Select the relevant format from **select format**, set **Board size** and **Fiducial marks**. Press **OK**.

1.4 Auto Deployment of Inspection Data

If component has not corresponding library, need to make inspection data individually.

To use auto deployment of inspection data, make inspection data easily.

Auto deployment procedure differs between chip component and IC component.

1.4 Auto Deployment of Chip Component

Step1: Right-click the center of CAD data and the window shown in Figure 1-45 appears.

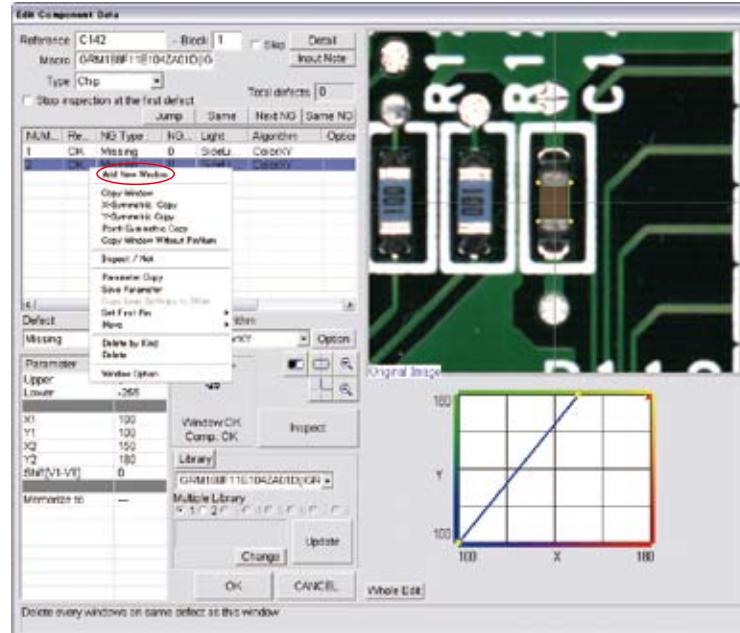


Figure 1-45 Auto Deployment of Chip Component 1

Step2: Select **Add New Window** from right-click to make a window and repeat it three times to make three inspection windows. Adjust the first inspection window size to surround electrode and body of component. Adjust the second inspection window size to surround body of component. Adjust the third inspection window size to surround pad, electrode, and body of component.

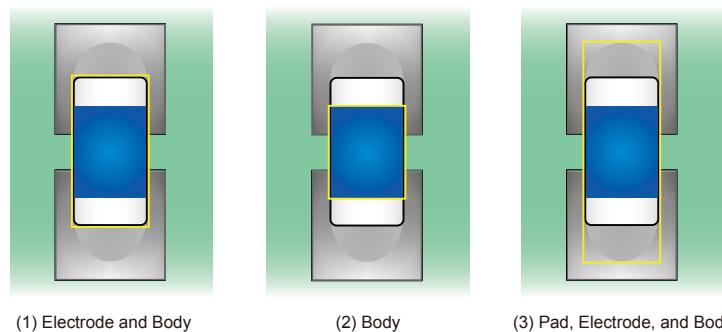


Figure 1-46 Auto Deployment of Chip Component 2

Step3: Select **Chip** from the **Type** drop-down list.

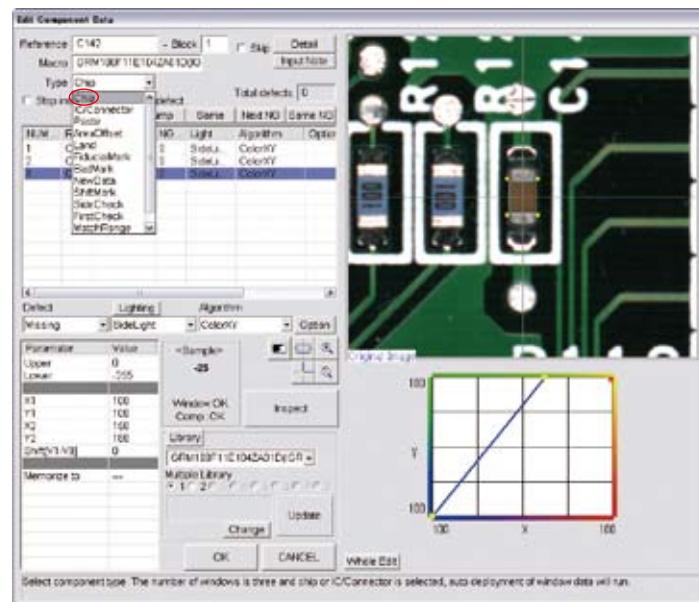


Figure 1-47 Auto Deployment of Chip Component 3

Step4: Check the **Search by NEW_ASC** and press **OK**.

NOTE Check the **Search by L/Wtracking** if the electrode of chip component is not visually clear .

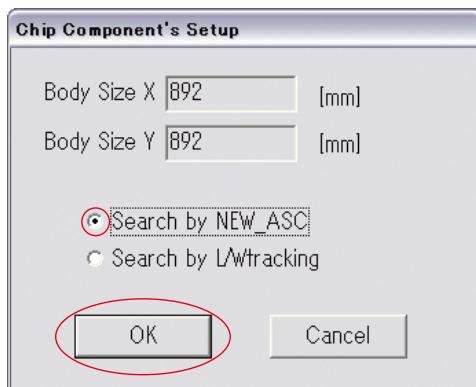


Figure 1-48 Auto Deployment of Chip Component 4

Step5: Inspection items are automatically made. For details of inspection data settings, refer to **3 Inspection Algorithm**.

1.4.2 Auto Deployment of IC Component

Step1: Right-click the center of CAD data and the window shown in Figure 1-49 appears.

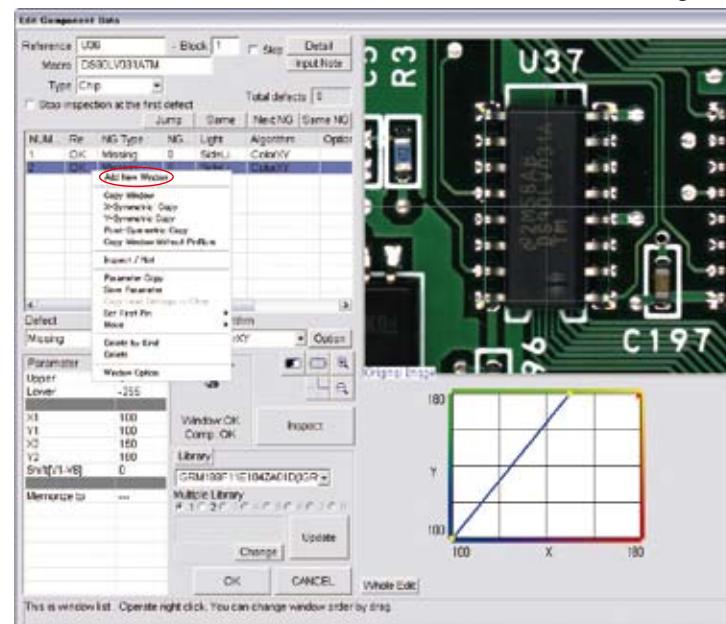
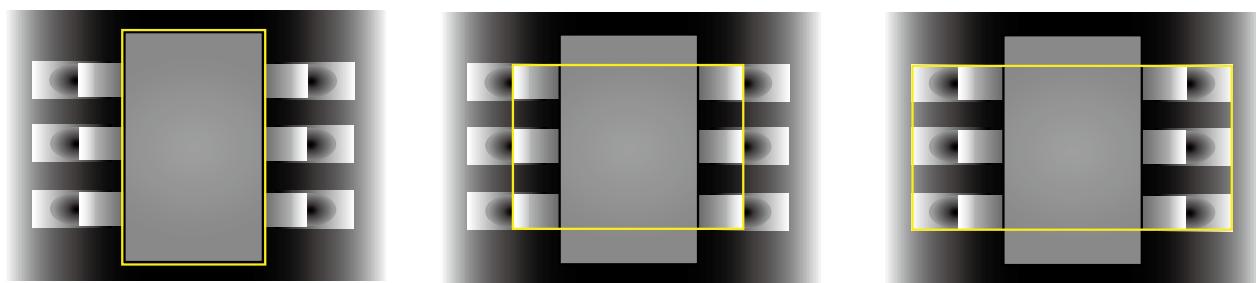


Figure 1-49 Auto Deployment of IC Component 1

Step2: Select **New** from right-click to make a window and repeat it three times to make three inspection windows. Adjust the first inspection window size to surround body of component. Adjust the second inspection window size to surround lead and body of component. Adjust the third inspection window size to surround pad, lead, and body of component.



(1) Body

(2) Lead and Body

(3) Pad, Lead, and Body

Figure 1-50 Auto Deployment of IC Component 2

Step3: Select **IC / Connector** from the **Type** drop-down list.

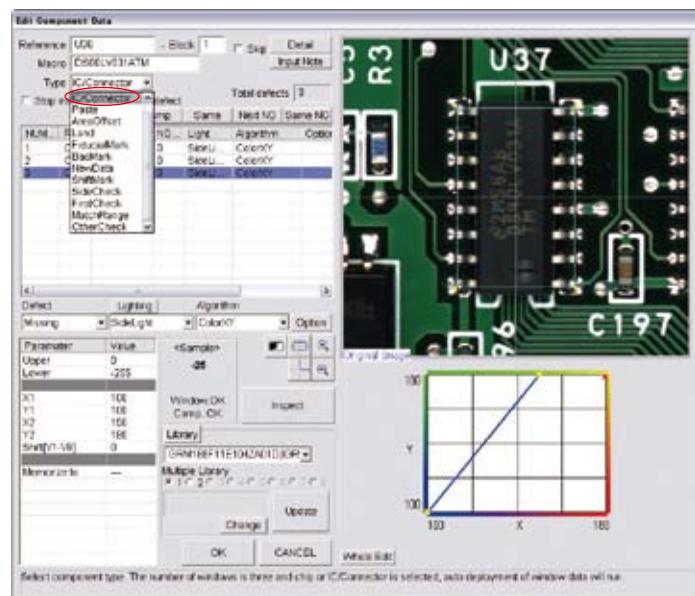


Figure 1-51 Auto Deployment of IC Component 3

Step4: Set **Package Type**, **Lead Pitch**, **Number of Leads X**, and **Number of Leads Y**. After all the settings are completed, press **OK**.

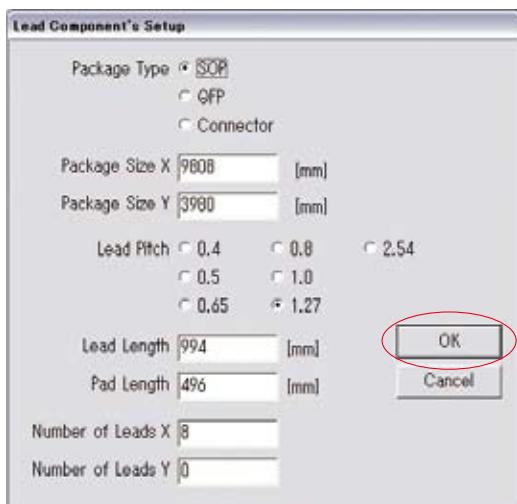


Figure 1-52 Auto Deployment of IC Component 4

| Parameter | Description |
|--------------------------------------|---|
| Package Type | Check the SOP , QFP , or Connector . |
| Package Size X, Package Size Y | Body size is displayed. |
| Lead Pitch | Set lead pitch. |
| Lead Length, Pad Length | Lead length and pad length are displayed. |
| Number of Leads X, Number of Leads Y | Enter number of leads. |

Table 1-12 Description of Parameters

Step5: Inspection items are automatically made. For details of inspection data settings, refer to **3 Inspection Algorithm**.

1.5 Search Inspection Data

Search function is useful to debug data.

Step1: Press **Search** button on the tool-bar or select **Edit > Search** from the menu-bar.

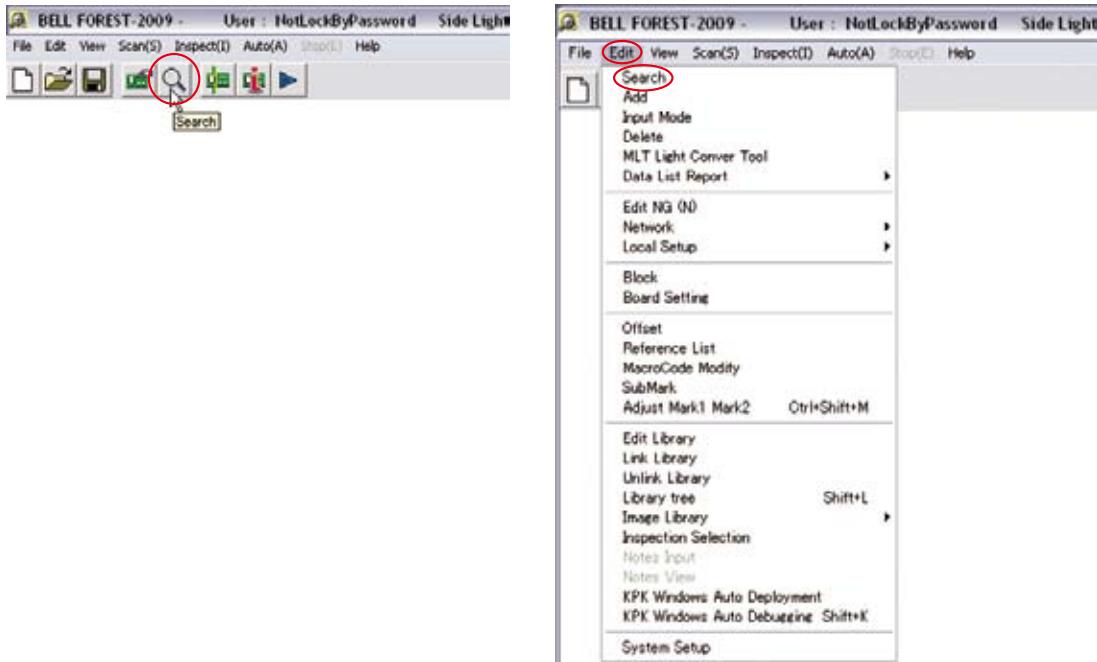


Figure 1-53 Search

Step2: Select **Operation > Inspect the Board** from the menu-bar to inspect.

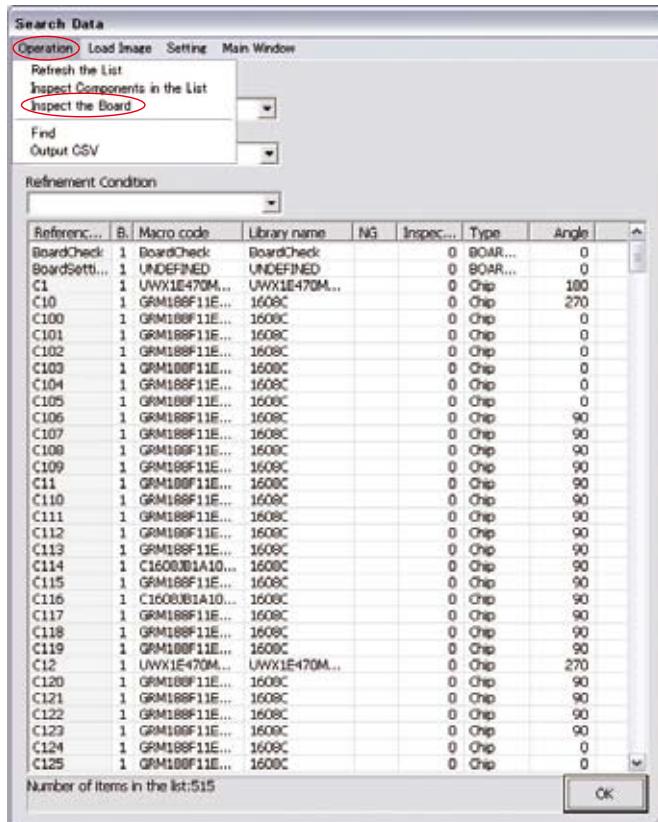


Figure 1-54 Inspect the Board

Step3: Select **library** from the **What to Search** drop-down list. Press **NG Comp.** of header to sort number of NG component in descending order.

NOTE The same operation can also be performed by selecting **Setting > Commonly-used settings > View Numbers of NG Components** from the menu-bar.

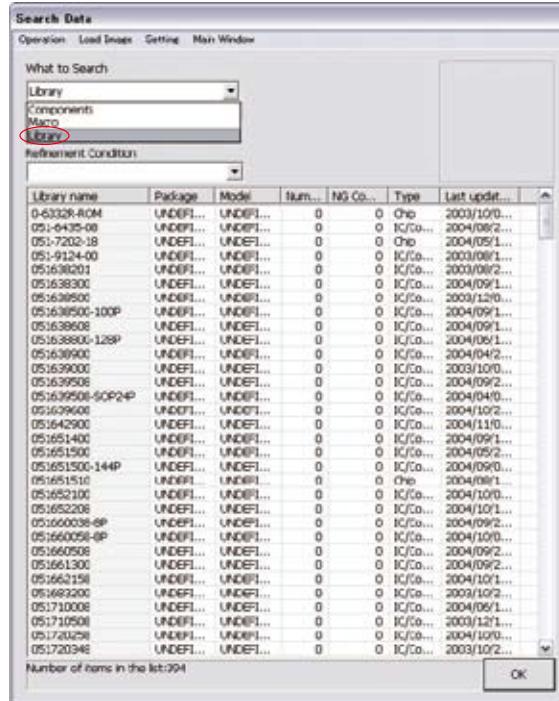


Figure 1-55 Library

Step4: Right-click the library to edit and select **Edit NG of This Library** or double-click the library. The window shown in Figure 1-56 appears. Double-click the library to edit and edit component window appears.

| Component list | | | | |
|----------------|----------------|--------------|------------|-----------------|
| Load Image | | | | |
| NG | Reference name | Block number | Macro code | Inspection time |
| NG | U6 | 1 | U6 | |
| NG | U6 | 1 | U6 | |

Double click-Popup Edit component data window.

Figure 1-56 Library Component List

Step5: Debug inspection data and press **Update** in edit component window to update inspection data.

1.6 Inspection Image

Combining three different LED lighting, TopLight(Coaxial Overhead illumination), SideLight, and LowLight, create the most appropriate image for the inspection.

| Lighting | Top | Side | Low | Description |
|----------------|-----|------|-----|--|
| TopLight | ○ | | | Image scanned with TopLight. TopLight is suitable for solder inspection to shed light from the overhead. |
| SideLight | | ○ | | Image scanned with SideLight. Nearly visual color repeatability lighting and a dark part becomes bright. SideLight is suitable for inspection using colors. |
| LowLight | | | ○ | Image scanned with LowLight. Silk characters or characters on a component becomes bright. LowLight is suitable for character inspection. |
| Density | ○ | | | Image that gamma-corrected TopLight brightness level. Density is suitable for denoising of TopLight. |
| Outline | ○ | | | Image that doubled TopLight brightness level. Outline is suitable for contour extraction of component. |
| MultiColorEx | ○ | | | Image that converted TopLight brightness into hue information. Bright part is converted to look like red and dark part is converted to look like blue. MultiColorEx is suitable for solder inspection. |
| Add | ○ | ○ | | Image that totaled brightness of TopLight and SideLight. |
| Add3 | ○ | ○ | | Image that totaled brightness of TopLight and SideLight, and in addition highlighted bright parts and dark parts. Add3 is suitable for inspection of fiducial mark or misalignment correction. |
| RED | | ○ | | Image that outputs constituent of Red at the 256 shades of gray from 0 to 255. |
| GREEN | | ○ | | Image that outputs constituent of Green at the 256 shades of gray from 0 to 255. |
| BLUE | | ○ | | Image that outputs constituent of Blue at the 256 shades of gray from 0 to 255. |
| HSV_Color | | ○ | | Image that converted SideLight brightness to HSV format. It is possible to highlight the specific color information. Each HSV parameter can be set optionally from Set . |
| Two Red-TOP | ○ | ○ | | Image that subtracted TopLight brightness from double Red constituent. Two Red-TOP is suitable for extract of laser-printed characters such as barcode. |
| TOP-SIDE | ○ | ○ | | Image that subtracted SideLight brightness from TopLight brightness. TOP-SIDE is suitable for extract(highlight) of plain surface. |
| SIDE-TOP | ○ | ○ | | Image that subtracted TopLight brightness from SideLight brightness. SIDE-TOP is suitable for extract(highlight) of inclined surface. |
| TOP-LOW | ○ | | ○ | Image that subtracted LowLight brightness from TopLight brightness. TOP-LOW is suitable for solder inspection to appear fillet part darkly. |
| LOW-TOP | ○ | | ○ | Image that subtracted TopLight brightness from LowLight brightness. Silk characters or plain surface becomes brightly. |
| SIDE-LOW | | ○ | ○ | Image that subtracted LowLight brightness from SideLight brightness. Silk characters or plain surface becomes brightly. |
| LOW-SIDE | | ○ | ○ | Image that subtracted SideLight brightness from LowLight brightness. LOW-SIDE is suitable for extract(highlight) of inclined surface. |
| Multi-Lighting | ○ | ○ | ○ | Image that can clearly display fillet shape by color. Outputting red in case of TopLight, green in case of SideLight, or blue in case of LowLight. |
| TOPSIDELOW | ○ | ○ | ○ | Brightness of TopLight, SideLight, and LowLight can be set freely. |
| UserDefine | ○ | ○ | ○ | Brightness of TopLight, SideLight, and LowLight can be set freely. UserDefine can set more flexible than TopSideLow. |
| SPECT | ○ | ○ | ○ | Image that converted brightness into hue information. SPECT is used in Algorithm IC_Solder2 . |
| OKNGColors | ○ | ○ | ○ | OKNGColors separates between OK color as white and NG color as black. It is possible to detect the difference of similar colors. OKNGColors can use in fare-paying software. |

Table 1-13 Description of Each Images

2 KPK

KPK (Key-colors Peak Keeping method) is a new inspection solution, which allows easier programming for missing inspection in terms of operation and speed. KPK is compatible with other functions of inspection software. By the combination use with existing inspection algorithm, missing inspection can be enhanced further. KPK data can be added to the existing inspection data. KPK can use in fare-paying software.

CAUTION

If inspection data is made by auto deployment and library assignment after making KPK data, KPK library will be overwritten.

2.1 Inspection Overview

2.1.1 OKNGColors Lighting

OKNGColors lighting separates between OK color as white and NG color as black by registering OK and NG colors in advance. If the color of the detected area is closer to the one registered as OK color, the area would become brighter. If the color of the detected area is closer to the one registered as NG color, the area would become darker. To set component colors as OK color and PCB colors as NG color, component color would become white and PCB color would become black.

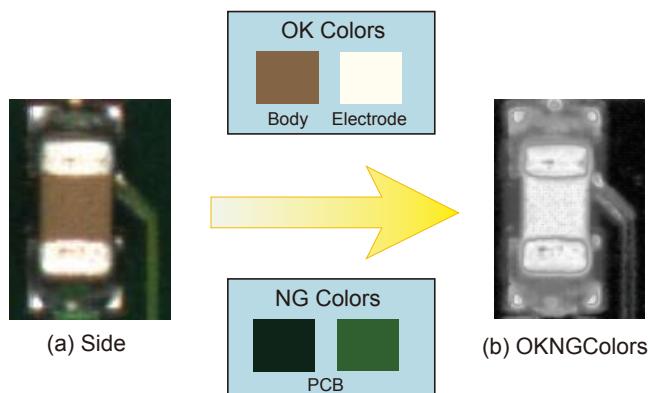


Figure 2-1 OKNGColors Lighting

2.1.2 Inspection Method

KPK uses Black/White algorithm, which calculates the percentage of the area where the pixel is brighter. If the percentage of the area where the pixel is brighter, the result will be missing.

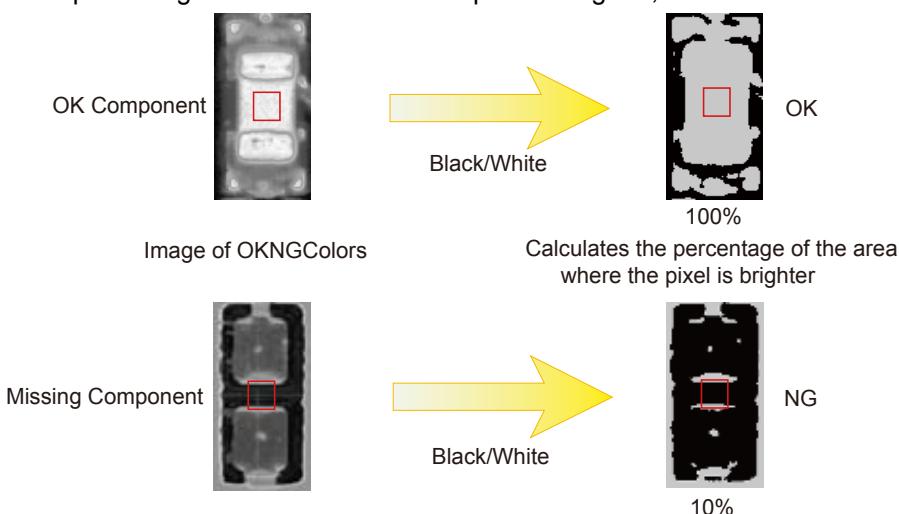


Figure 2-2 Inspection Method

2.2 Make KPK Data

Step1: Open KPK setting window.

Select **Edit > KPK Windows Auto Deployment** from the menu-bar to add KPK in existing inspection data.

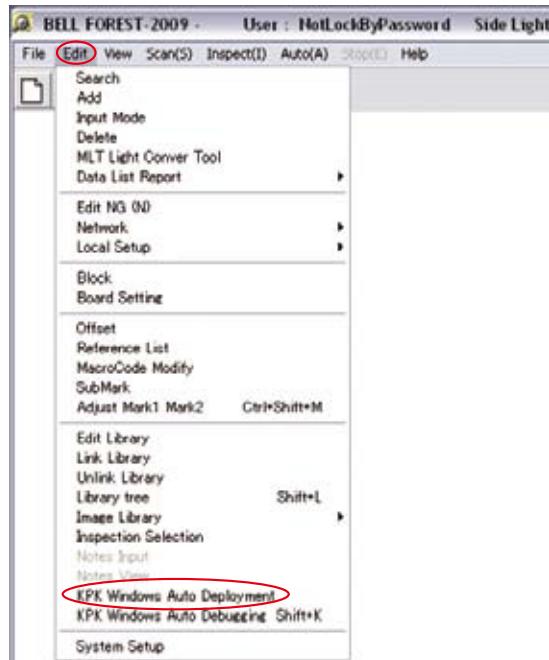


Figure 2-3 KPK Windows Auto Deployment

Refer to **1.1 Make Inspection Data on AOI Machine** to make new inspection data and press **Start KPK Window Deployment** in step31.

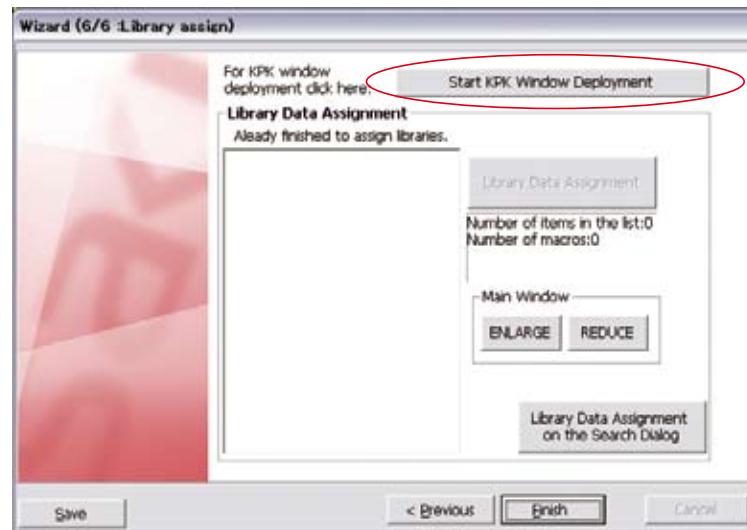


Figure 2-4 KPK Deployment

Inspection Data

Step2: The window shown in Figure 2-5 appears. Register the PCB color as NG color. Procedures depend on the presence or absence of bare PCB.

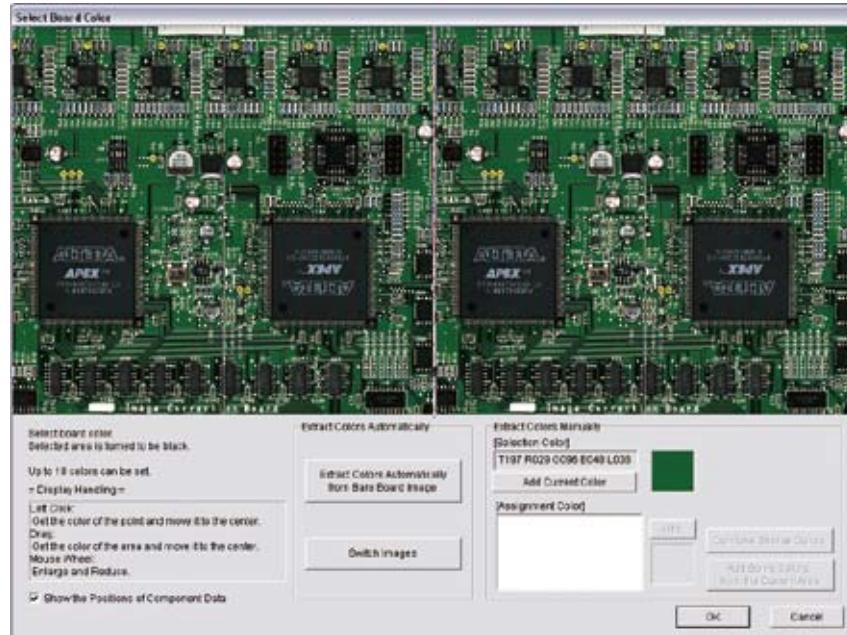


Figure 2-5 Specify PCB Color

2.2.1 With Bare PCB

Extract PCB color from bare PCB and register it as NG color.

NOTE

In the case of using KPK for post-reflow inspection, it is recommended to use a bare PCB after reflow-oven. That is able to reduce color variation caused by flux and to extract PCB color properly.

Step1: Press **Switch Images**.

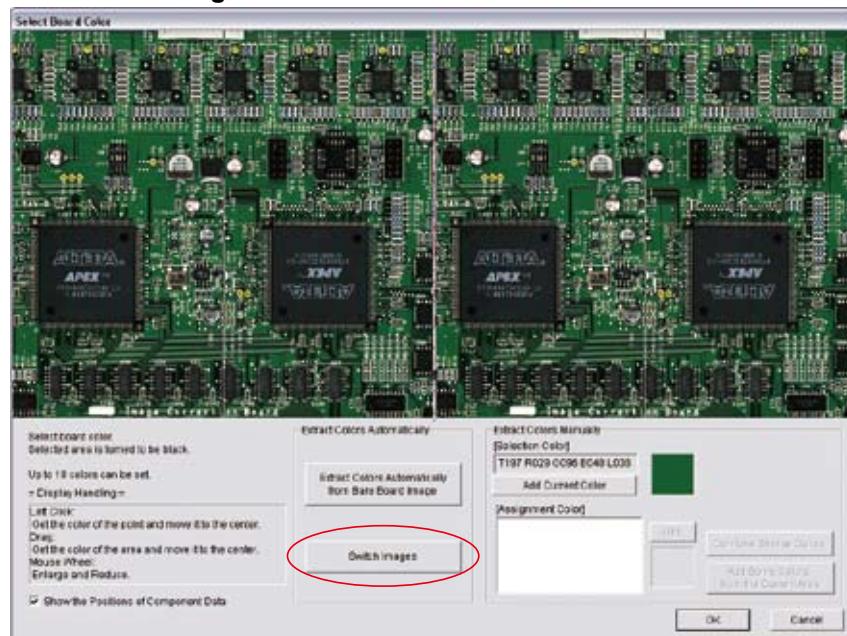


Figure 2-6 Switch Images 1

Programming Manual

Step2: If bare PCBs are already scanned and saved, select the file from the **SERIES Image** list-box, and press **Load SERIES Image**. If no series image is saved, procedures depend on machine type benchtop machine, inline machine, or BF-Editor.

In case of benchtop machine

Set the PCB in the machine and press **Scan Board Image**.

In case of inline machine

Adjust conveyor rail width and set the PCB on conveyor rail. Press **Load / Unload the Board**. Set the PCB in the machine and press **Scan Board Image**. To unload the PCB, press **Load / Unload the Board**.

In case of BF-Editor

Press **Load Image** and select **TOPLIGHT.BMP** saved in arbitrary folder.
(e.g. D:\BF1\BF1DATA\Inspection Group Name\PCB Name folder)

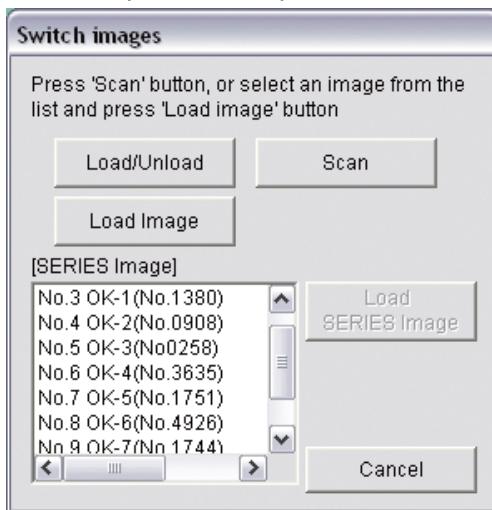


Figure 2-7 Switch Images 2

Step3: Press **Extract Colors Automatically from Bare Board Image** in Figure 2-6, the window shown in Figure 2-8 appears.

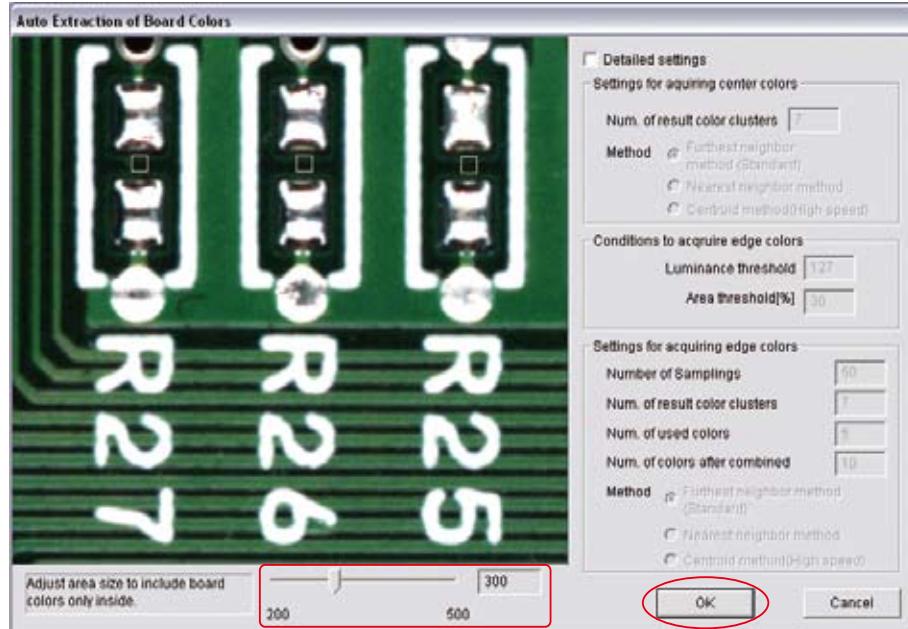


Figure 2-8 Auto Extraction of Bare PCB Image

Step4: Adjust the window size to extract component color by moving a slide-bar. The window size is area to extract PCB color. Press **OK** and start PCB color extraction.

NOTE The specified window size is common to all components data. Therefore make the window size in accordance with the minimum component size.

NOTE No need for **Detailed settings**.

Step5: Check the PCB color is displayed in black. The closer the PCB color is to the extracted PCB color, the darker it displays. Refer to **2.2.3 Auto Deployment of KPK**.

2.2.2 No Bare PCB

Register the PCB color under the component as NG color.

Step1: Click the parts to be registered as NG colors and press **Add Current Color**.

NG color is displayed in the **Assignment Color** list-box.

The area which color is similar to the registered color is displayed in black on the right image. Continue to register all NG colors in the list-box until the NG area is displayed in black.

NOTE

Maximum 10 colors can be registered.

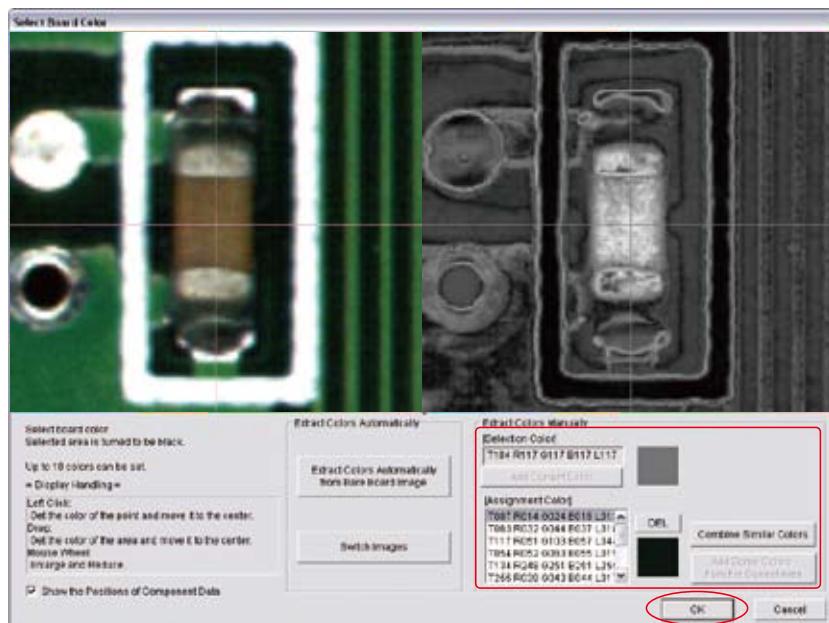


Figure 2-9 Extract Colors Manually

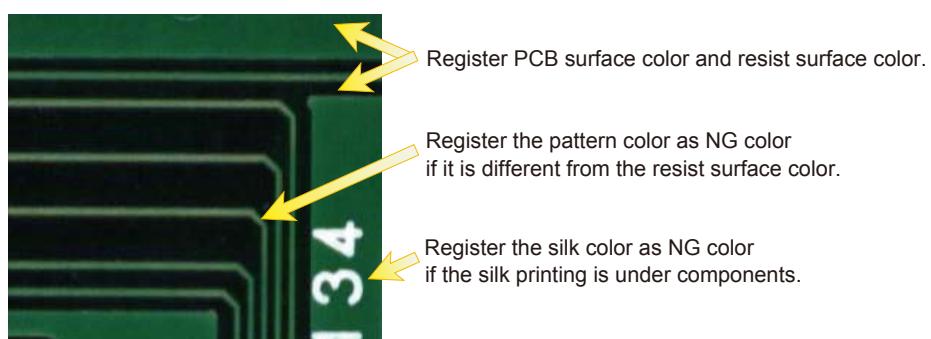


Figure 2-10 Register NG Colors

| Item | Description |
|---------------------------------------|--|
| DEL | Select the color in the list-box and press DEL to delete the color. |
| Combine Similar Colors | Press Combine Similar Colors and the window shown in Figure 2-11 appears. Press OK to combine the selected two similar colors to decrease the number of registered colors. |
| Add Some Colors from the Current Area | Select the area which color is to be registered as NG. Press Add Some Colors from the Current Area and the window shown in Figure 2-12 appears. Press OK and the window shown in Figure 2-13 appears. The extracted colors are displayed. To register the color as NG colors, check the Set as NG Color and press OK . |

Table 1-14 Description of Extract Colors Manually

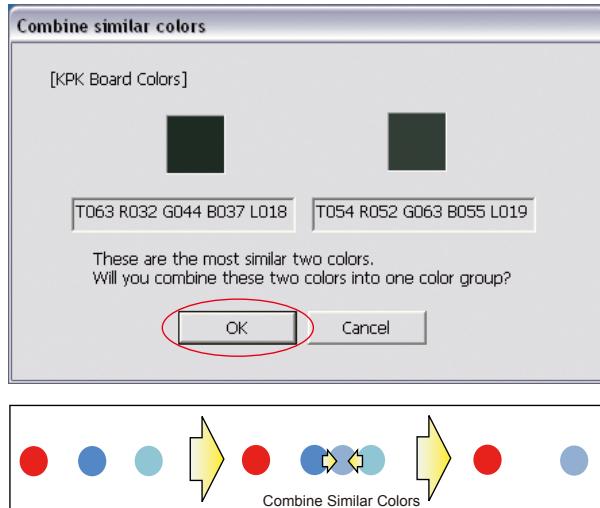


Figure 2-11 Combine Similar Colors

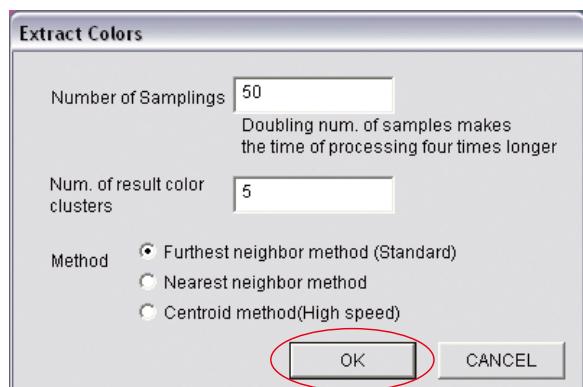


Figure 2-12 Add Some Colors from the Current Area 1

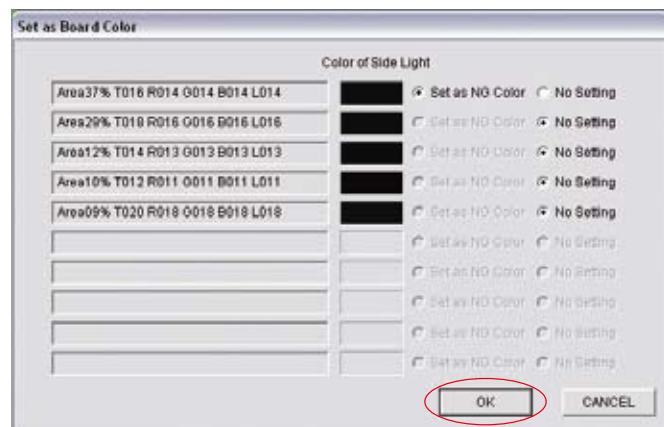


Figure 2-13 Add Some Colors from the Current Area 2

Step2: Check the PCB color is displayed in black. If the PCB color is closer to the extracted PCB color, the PCB color will be darker. Refer to **2.2.3 Auto Deployment of KPK**.

2.2.3 Auto Deployment of KPK

Step1: Register all NG colors and press **OK**. The window shown in Figure 2-15 appears.

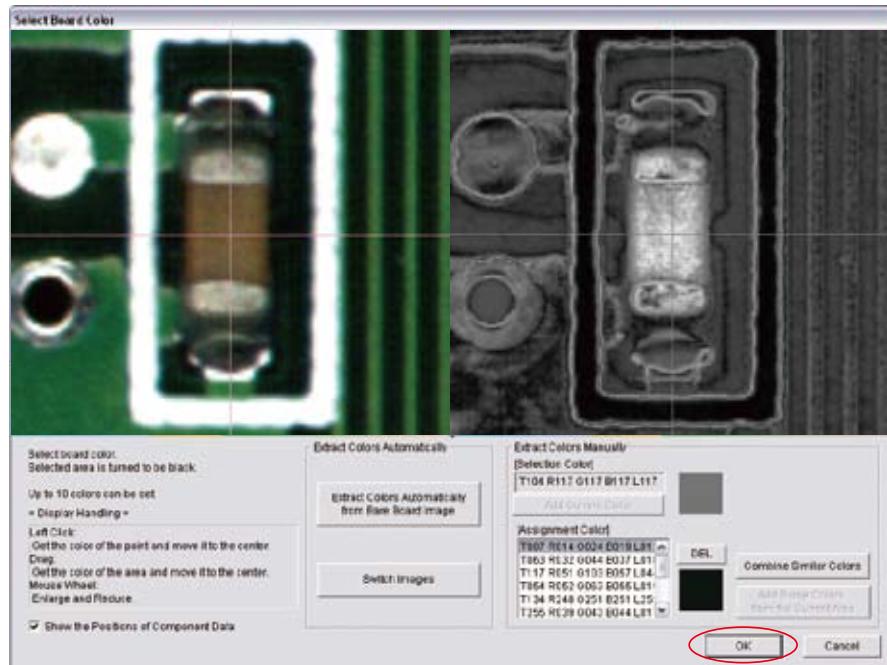


Figure 2-14 Specify PCB Color

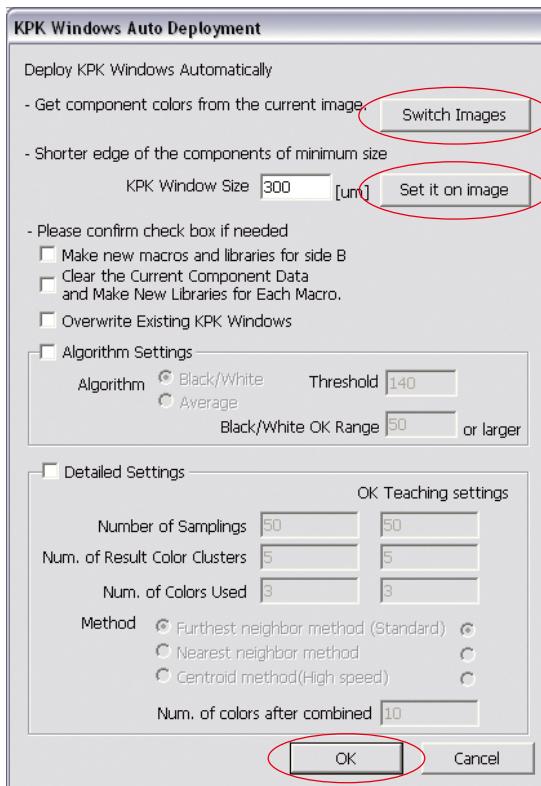


Figure 2-15 KPK Windows Auto Deployment

Step2: Press **Switch Images** and open OK PCB images.

Step3: Press **Set in on image** and the window shown in Figure 2-16 appears. Adjust the window size to extract component color by moving a slide-bar. After all the settings are completed, press **OK**.

NOTE The specified window size is common to all components data. Therefore, make the window size to surround the component color only. If the window size is not appropriate, PCB color or print color on the component might influence the inspection result.

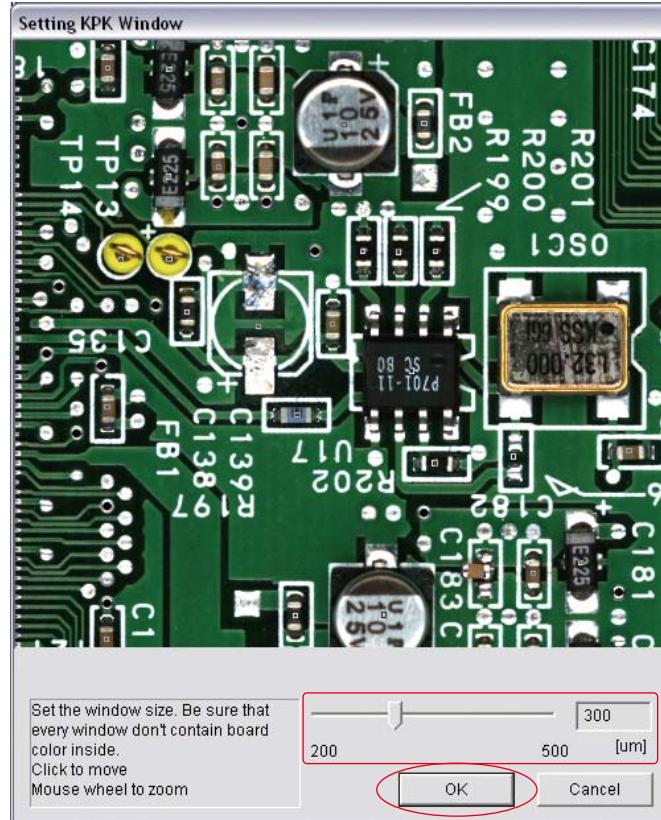


Figure 2-16 KPK Window Size Setting

Step4: If there is only KPK data or KPK data should be assigned newly to each component without deleting existing libraries, check **Clear the current component data and make new libraries for each macro**. Library name corresponds to macro name is assigned.

NOTE Macro classifies the component more finely than library. KPK judges missing component by component colors. It is necessary to extract colors not by library unit, but by macro unit. For the component with **1000C** of library and **123** of macro, a library named **KPK_123** is created and assigned. Therefore, the existing library **1000C** remains.

| Component | Library | Macro |
|-----------|---------|-------|
| | 1000C | 123 |
| | | 456 |
| | 1000R | 789 |

| Component | Library | Macro |
|-----------|---------|-------|
| | KPK_123 | 123 |
| | KPK_456 | 456 |
| | KPK_789 | 789 |

Table 2-1 Library and Macro(Left Side: Before Changing, Right Side: After Selecting **Clear the current**)

Step5: When KPK data is opened in B-side for the double-side PCB, the check-box of **Make new macros and libraries for side B** is displayed. Check the **Make new macros and libraries for side B** to have each macro and library data in each side. Macro and library name including side information are assigned to components.

NOTE

For the component with **1000C** of library and **123** of macro, a library named **B_KPK_123** is created and assigned. The existing library **1000C** remains.

| Component | Library | Macro |
|---|---------|-------|
|  | 1000C | 123 |
|  | | 456 |
|  | 1000R | 789 |

| Component | Library | Macro |
|---|-----------|-------|
|  | B_KPK_123 | B_123 |
|  | B_KPK_456 | B_456 |
|  | B_KPK_789 | B_789 |

Table 2-2 Library and Macro(Left Side: Before Changing, Right Side: After Selecting **Make new macros**)

Step6: After all the settings are completed, press **OK**. KPK data will be automatically extracted .

CAUTION

This process might take a few minutes.

Step7: Inspect the data after extracting KPK data. **KPK Debug** window shown in Figure 2-17 appears. Refer to **2.3.1 KPK Debug**.

NOTE

KPK inspection window is extracted in second window(Type: Missing, Lighting: OKNGColors, Algorithm: Black/White). When existing inspection data was extracted, KPK window will be added in second window by interruption. Inspection window shifts by one. Although jump settings such as OKJump / NGJump will be automatically updated in order properly by the inspection software.

2.3 Adjust KPK Data

2.3.1 KPK Debug

KPK Debug window shown in Figure 2-17 appears after KPK data is extracted. Adjust KPK inspection data. Double-click the component to open component window. Refer to **2.3.2 Edit Component Data Window**.

NOTE The same operation can be performed by selecting **Edit > KPK Windows Debugging** from the menu-bar or pressing **Shift** + **K**.

NOTE Select a component from the list-box and component image is displayed.

Magnification percentage can be changed by scrolling wheel of mouse.

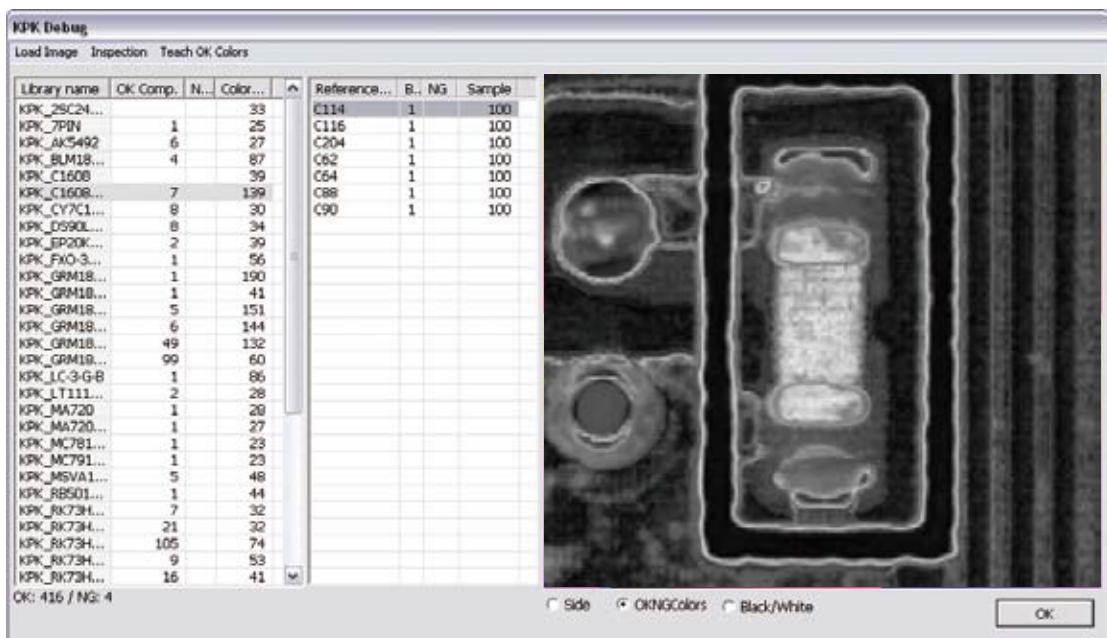


Figure 2-17 KPK Debug

| Item | Description |
|-----------------|---|
| Load Image | Open images or switch images. |
| Inspection | Inspect opened images. The inspection is automatically operated if the inspection data is changed. |
| Teach OK Colors | OK component might be mis-judged NG because of component color variation. Combine the color which is mis-judged as NG and the OK color to reduce the false call. Select All NG components or Selected Library to find the false call data . |

Table 2-3 Menu-bar

| Component Name | Component Color | Inspection Result before Adjustment (Registered  as OK color) | Inspection Result after Adjustment 1 (Combine  with OK color) | Inspection Result after Adjustment 2 (Combine  with OK color) |
|----------------|---|---|---|---|
| C1 |  | OK | OK | OK |
| C2 |  | NG (False Calls) | OK | OK |
| C3 |  | NG (False Calls) | NG (False Calls) | OK |
| C4 |  | NG (False Calls) | NG (False Calls) | OK |

Table 2-4 The Example of Teach OK Colors

| Item | Description |
|---------------------|--|
| Library Name | Library name. |
| OK Comp. / NG Comp. | Each numbers of the component OK/NG is displayed. If the inspection data is adjusted properly, the result will be OK with OK PCB and the result will be NG with bare PCB. |
| Color distance | Extract two the most similar colors. One is from OK color, another is from NG color. The distance of these two similar colors is displayed as a value. The smaller the value is, the less color difference is between components and PCBs. |
| Reference Name | Component name. |
| Block number | Block number. |
| NG | All NG components is marked as NG . |
| Sample | Sample values is the percentage of area which brightness level is over the specified value in the inspection window if the default algorithm Black/White is used. |

Table 2-5 Description of Header

| Item | Description |
|-------------|--|
| Side | SideLight image is displayed. |
| OKNGColors | OKNGColors image is displayed. |
| Black/White | Monochrome image by algorithm Black/White is displayed. |

Table 2-6 Select Lighting

2.3.2 Edit Component Data Window

Double-click the component in KPK Debug window and the window shown in Figure 2-18 appears. The second inspection window is KPK window.

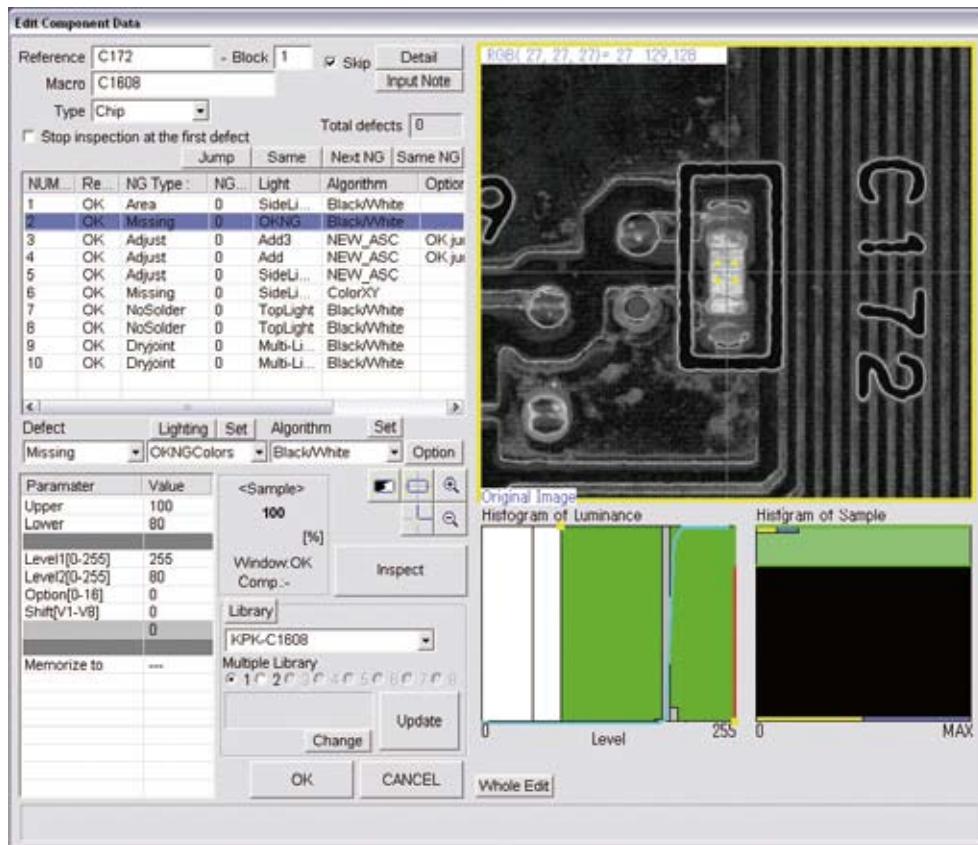


Figure 2-18 KPK Window

| Parameter | Description |
|------------------------------|---|
| Defect | Select Missing . |
| Lighting | Select OKNGColors . Press Set in the right side of Lighting to set details. |
| Algorithm | Select Black/White . |
| Upper, Lower | Set OK range. Enter 100 in Upper field and arbitrarily value in Lower field. |
| level1[0-255], level2[0-255] | Level1 is upper limit of brightness level. Level2 is lower limit of brightness level. Enter 255 in Level1 field. Press Set in the right side of Algorithm to adjust Level2 . |
| Option[0-16] | Enter 0 . |
| Shift[V1-V8] | Enter 0 . |
| Memorize to | - |

Table 2-7 Parameter of KPK

2.3.3 Detail Settings of OKNGColors Lighting

Press **Set** in the right side of **Lighting** in Figure 2-18. The window shown in Figure 2-19 appears.

Press **OK Colors**, **Unused**, or **NG Colors** to move colors to the list of **OK Colors**, **Unused Colors**, or **NG Colors**.

NOTE

Press **OK Colors**, **Unused**, or **NG Colors** by pressing **[Ctrl]** to copy colors.

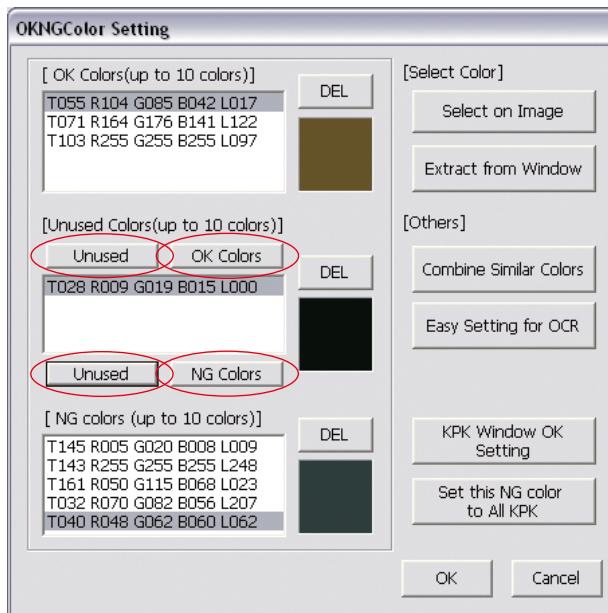


Figure 2-19 OKNGColors Lighting

| Parameter | Description |
|------------------------------|--|
| OK Colors | The top list is OK color list. Maximum 10 colors can be registered. |
| Unused Colors | The middle list is to save data for temporary purpose. Colors listed here can be referred from any other components or libraries. |
| NG Colors | The bottom list is NG color list. Maximum 10 colors can be registered. |
| DEL | Delete selected colors. |
| Select on Image | Extract selected colors manually. Component window appears(Refer to Figure 2-20). Left-click colors and press Select as OK color or Select as NG color . |
| Extract from Window | Extract colors from the window automatically. The window shown in Figure 2-21 appears and press OK (The window shown in Figure 2-22 appears). Check the Set as OK Color , Set as NG Color , or No Setting . Press OK . This setting is suitable for if PCB and component colors are very similar. |
| Combine similar Colors | Combine the closest colors between OK/NG colors to reduce the number of colors (Refer to Figure 2-23). Press OK to combine the selected colors. |
| Easy Setting for OCR | Register OK colors and NG colors automatically to recognize character on the component. |
| KPK Window OK Setting | Extract component colors from the window automatically and register as OK Color. The window shown in Figure 2-24 appears and press OK . This setting is suitable for if component color changed by change to lot. |
| Set this NG Color to All KPK | Extract selected NG color of the current window and reflect this NG color all KPK windows. This setting is suitable for if PCB color changed by change to lot. |

Table 2-8 Detail Settings of OKNGColors Lighting

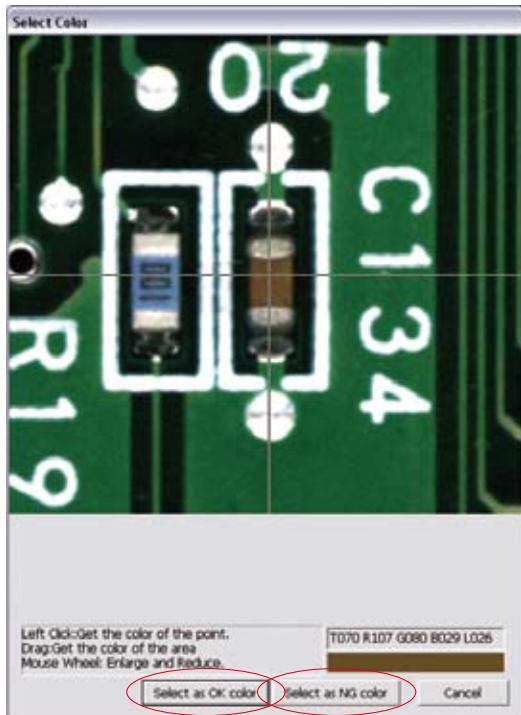


Figure 2-20 Select on Image

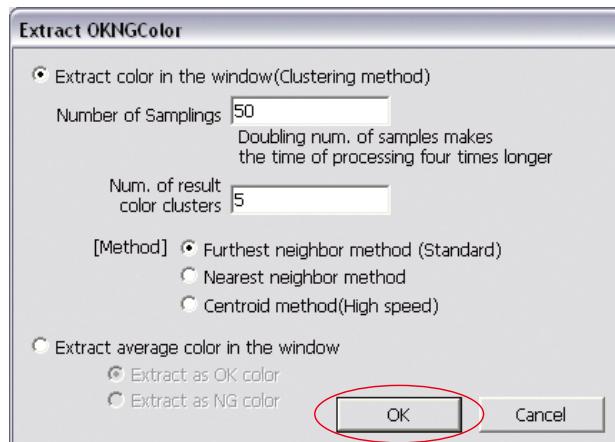


Figure 2-21 Extract from Window 1

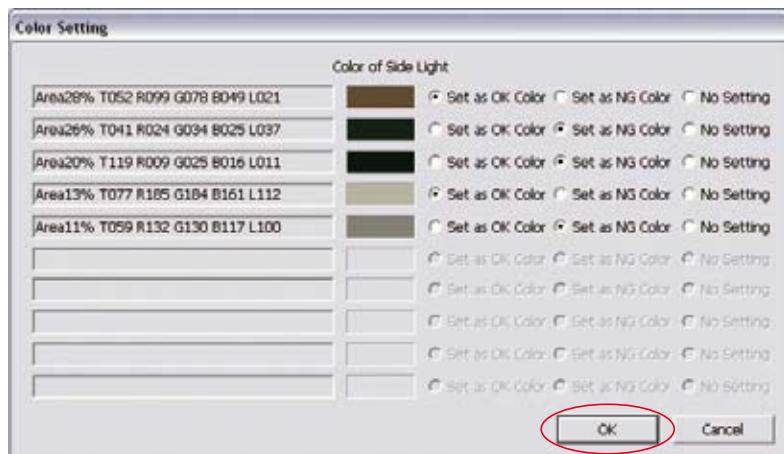


Figure 2-22 Extract from Window 2

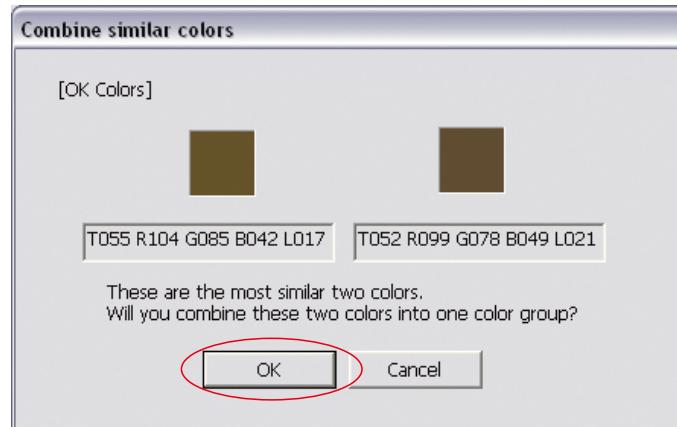


Figure 2-23 Combine Similar Colors

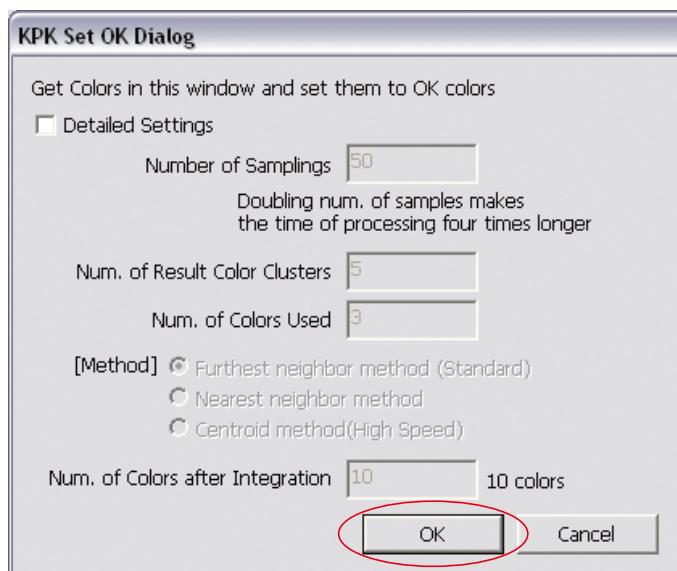


Figure 2-24 KPK Window OK Setting

3 ECD

ECD(Extra Component Detection) is a function to detect extra component which is fallen and attached to the area other than the component mounting area from any cause.

3.1 Inspection Overview

Sample several OK PCBs and make template images. Extra component is detected based on the difference of template images and inspection PCB images. ECD is enable to inspect entire PCB with one inspection window.

3.2 Inspection Procedure

Step1: Select **Edit > ECD OPTION** from the menu-bar.

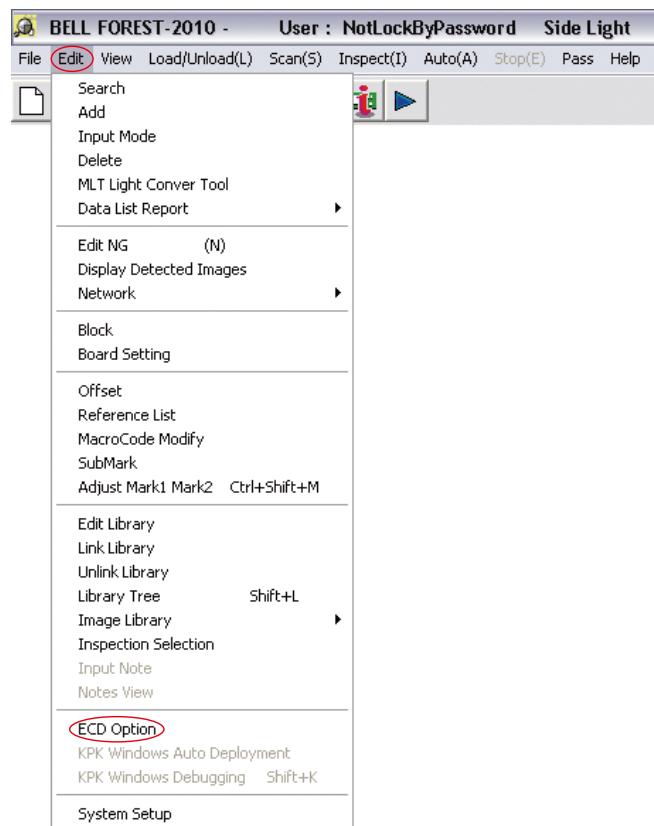


Figure 3-1 ECD Option

Step2: ECD setting window appears. Check the **Mark1**, **Mark2**, **Sampling**, and **Lighting** of **Default Parameters**. Press **OK**. No need to set for **Statistical Process** and **Template Matching Process**.

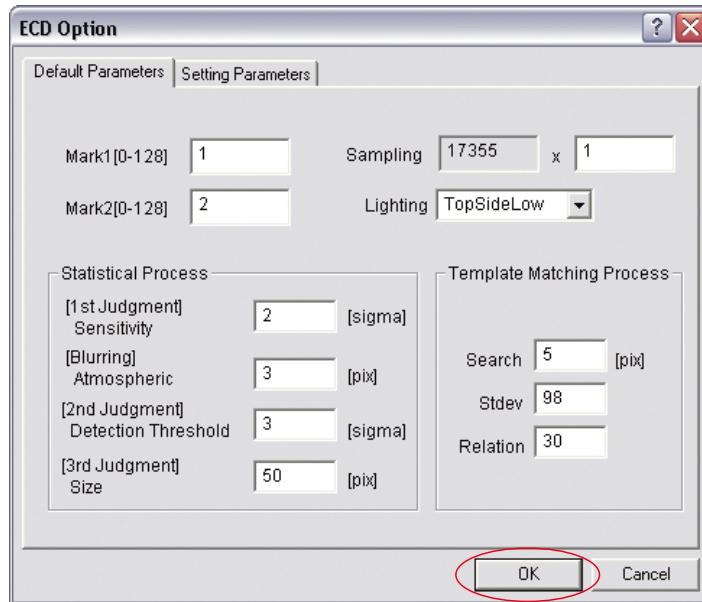


Figure 3-2 ECD Default Setting

| Item | Description |
|---------------|---|
| MARK1 [0-128] | Enter 1. |
| MARK2 [0-128] | Enter 2. |
| Sampling | Set the pixel interval to extract brightness. If setting value is 6, extract brightness at intervals of 6 pixels. If resolution is 10µm, enter 6 or greater. If resolution is 18µm, enter 8 or greater. Enter the bigger value to turn down the resolution accelerate the inspection speed. |
| Lighting | Select TopSideLow. |

Table 3-1 ECD Default Setting

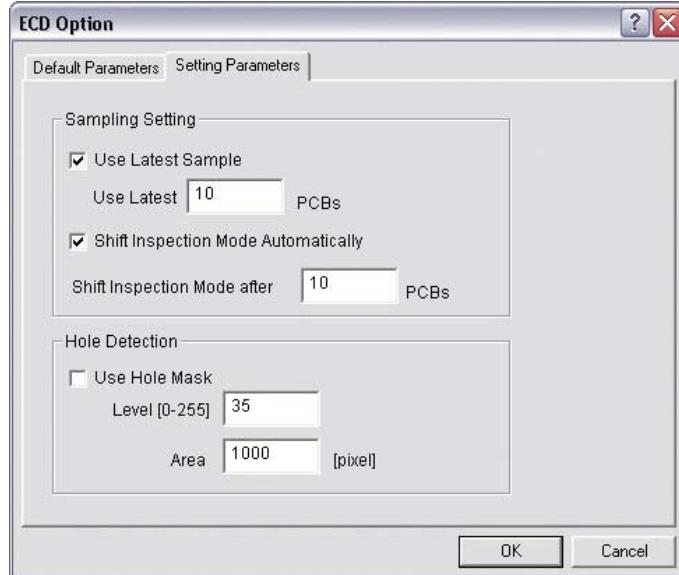


Figure 3-3 Parameter Setting

| Item | Description |
|-------------------------------------|---|
| Use Latest Sample | Latest scanned image is used as template image. Specify the number of PCBs in Use Latest . |
| Shift Inspection Mode Automatically | The mode will be switched to inspection mode automatically after sampling is completed. Default number of sampled PCB is 10. |
| Use Hole Mask | Exclude the through hole of PCB from inspection target. Specify brightness level of through hole in Level field. Specify area of through hole in Area field. Areas darker than Level and larger than Area will be judged as through hole and will not be inspected. |

Table 3-2 Parameter Setting

Step3: Set the OK PCB. Press **Scan** button on the tool-bar or select **Scan** from the menu-bar. The dialog shown in Figure 3-5 appears and press **OK**.



Figure 3-4 Scan

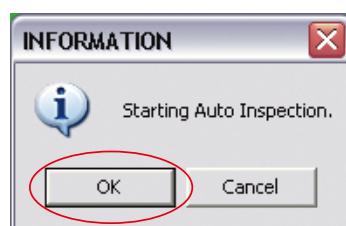


Figure 3-5 Check Auto Inspection Start

Step4: Left-click in the upper left side of the PCB. White cross line appears in the upper left side of the PCB.

Step5: Select **Edit > Add** from the menu-bar.

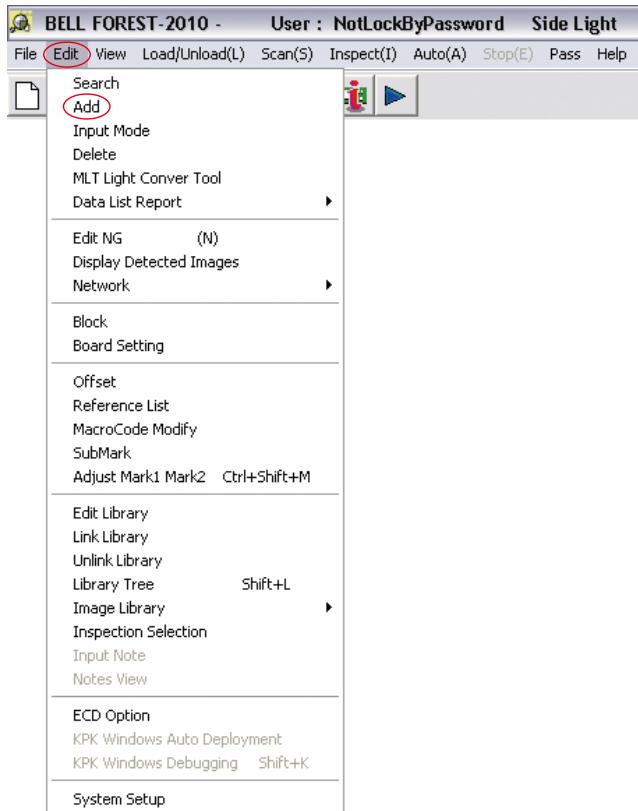


Figure 3-6 Add

Step6: Check the **ECD Area** and press **OK**.

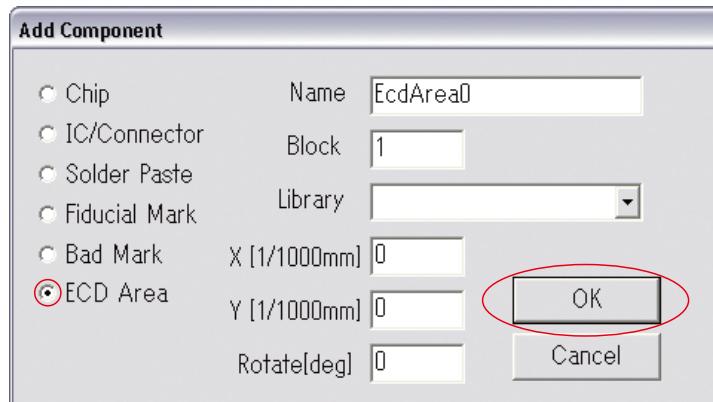


Figure 3-7 ECD Area

Step7: Detail setting window of ECD appears. Press **OK**.

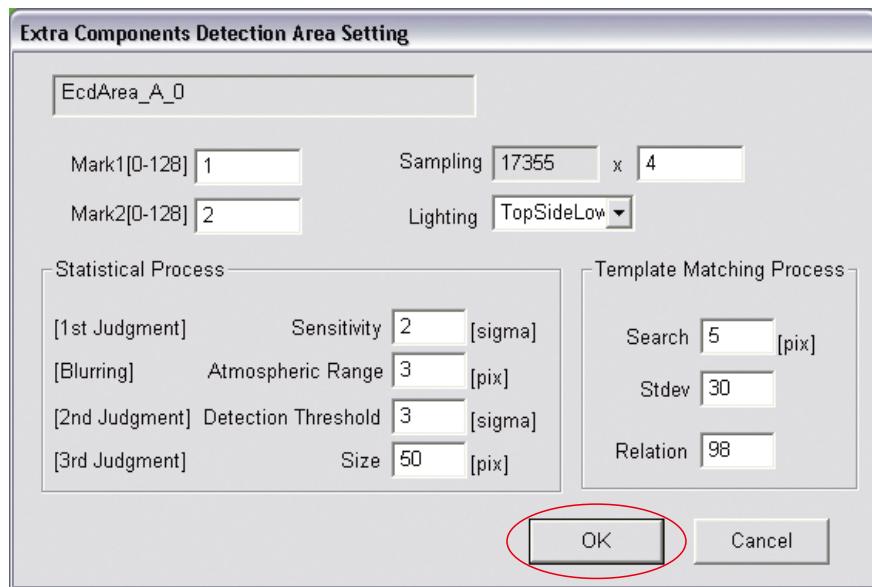


Figure 3-8 Detail Settings of ECD

Step8: Yellow and purple windows are displayed in the upper left side of the PCB. Drag the yellow window to the lower right side of the PCB.

NOTE

Purple window shows inspection area. Enlarge inspection area to include the entire PCB by dragging yellow window in the lower right side of the PCB.

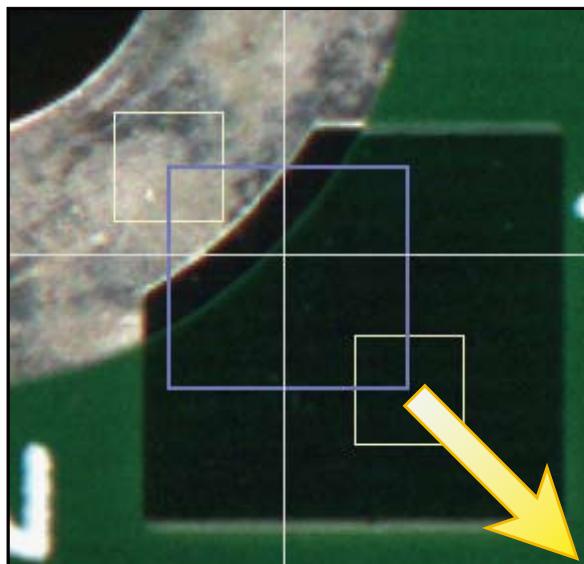


Figure 3-9 Enlarge Inspection Area

Step9: The window shown in Figure 3-10 appears. Check the **Current Component** and press **OK**.

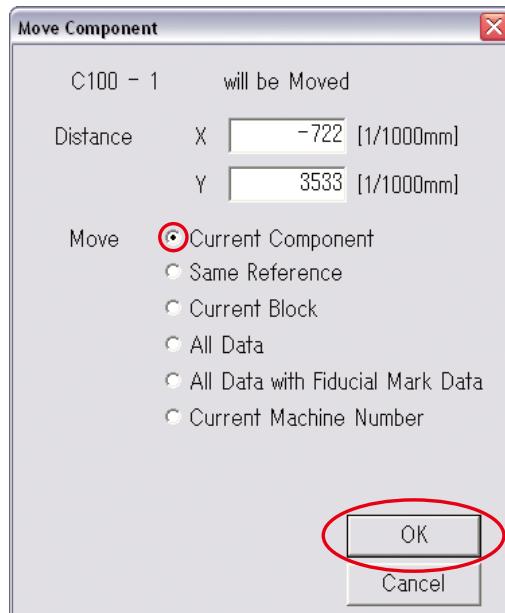


Figure 3-10 Move Component Data

Step10: Press **V** and the window shown in Figure 3-11 appears. Check the **Activate ECD Function** and press **Sampling**.



Figure 3-11 Sampling Mode

Step11: The dialog shown in Figure 3-12 appears and press **OK**.

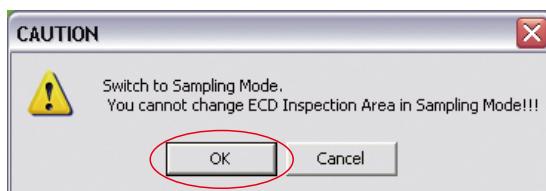


Figure 3-12 Switch to Sampling Mode

Step12: Select **Edit > System Setup > System > Machine** tab from the menu-bar and uncheck the **Hero Use Repair**. After all the settings are completed, press **OK**.

CAUTION In case of benchtop machine, check the **Hero Use Repair** after ECD inspection is completed.



Figure 3-13 Hero Use Repair

Step13: Press **Auto** button on the tool-bar or select **Auto** from the menu-bar.

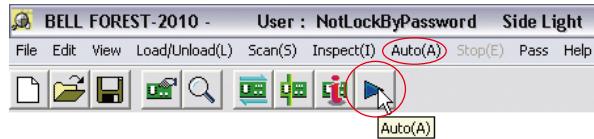


Figure 3-14 Auto

Step14: Check the **Conveyer**, **Inspect**, and **Monitor Mode**. Press **OK**.

CAUTION No **Conveyer** box in benchtop machine.

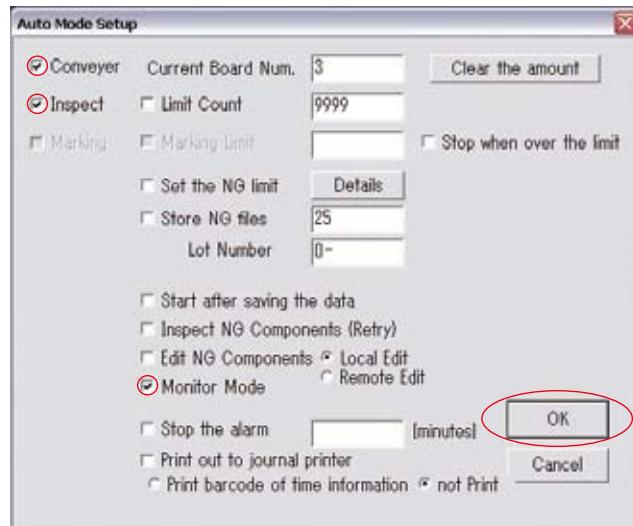


Figure 3-15 Auto Mode Setting

Step15: The dialog shown in Figure 3-16 appears and press **OK**.



Figure 3-16 Start Auto Inspection

Step16: Start sampling. Scan 10 OK PCBs. The window shown in Figure 3-17 appears and press **OK**.

The number of sampled PCB is displayed in Figure 3-18.

NOTE The number of sampled PCB can be set in **Shift Inspection Mode Automatically** of **Parameter Setting** shown in Figure 3-3.

NOTE To initialize sampling data, press **Setting** in Figure 3-18. The dialog shown in Figure 3-19 appears and press **OK**. The window shown in Figure 3-18 appears and press **Sampling**. Proceed from Step10.

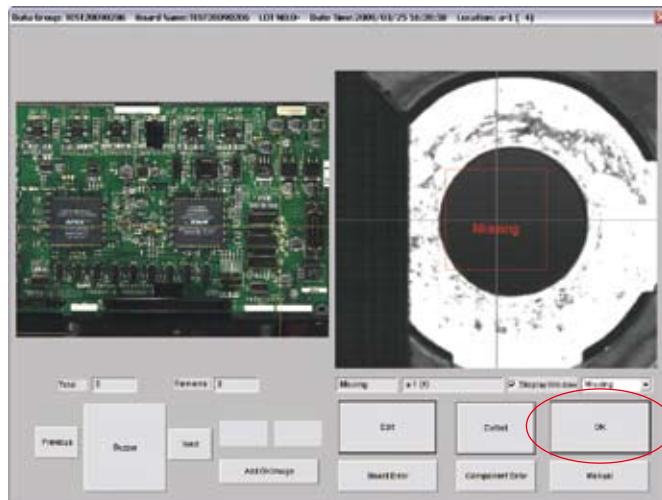


Figure 3-17 Monitor Mode

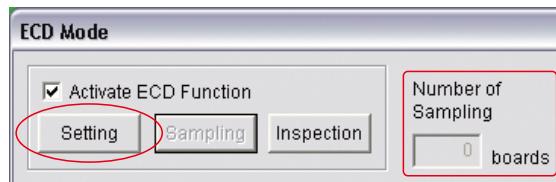


Figure 3-18 Setting Mode

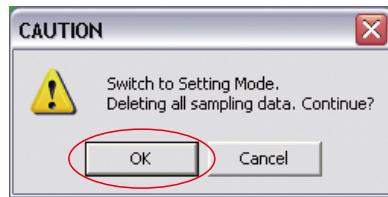


Figure 3-19 Switch to Setting Mode

Step17: After 10 OK PCB sampled, ECD mode will be automatically switched from **Sampling** to **Inspection**.

NOTE If **Shift Inspection Mode Automatically of Parameter Setting** shown in Figure 3-3 is unchecked, press **Inspection** after completing sampling of OK PCBs.



Figure 3-20 Inspection Mode

Step18: Scan sample NG PCB and check if extra components are detected properly. If extra components are detected, a red square frame is displayed in detection area. If any extra components are not detected or these are many false calls, press **Manual** to stop auto inspection. Refer to **3.3 ECD Debug**.

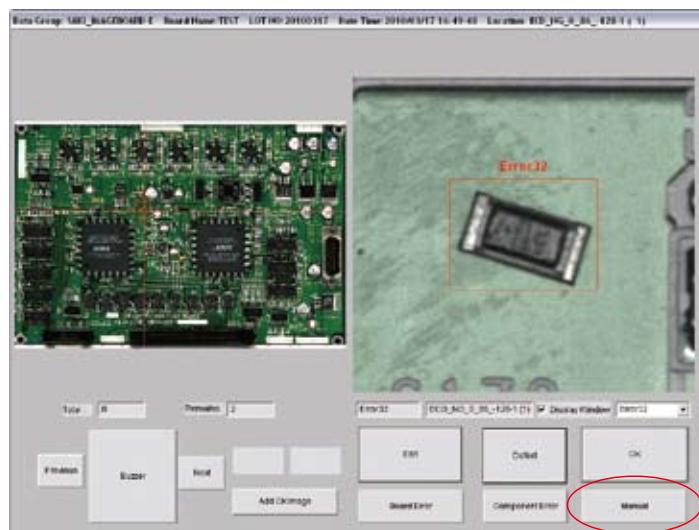


Figure 3-21 Inspection of NG PCB

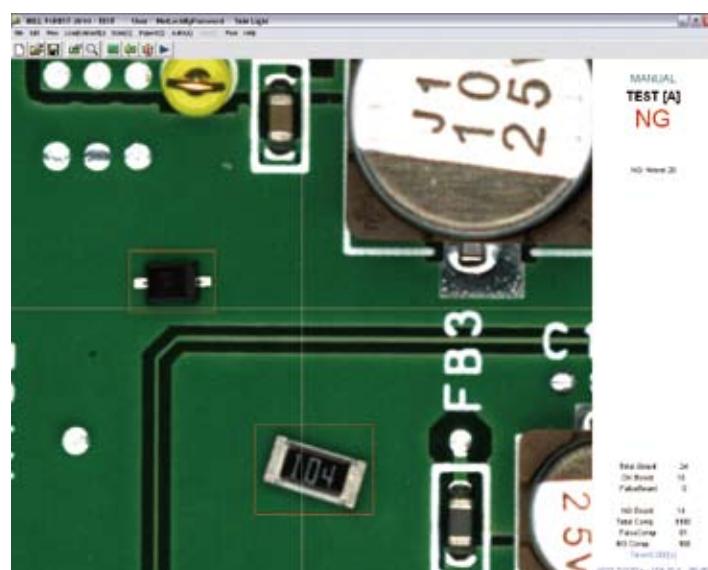


Figure 3-22 Detect Extra Component

3.3 ECD Debug

If any extra components are not detected or there are many false calls, adjust parameters.

Step1: Right-click the red square frame and the window shown in Figure 3-23 appears.

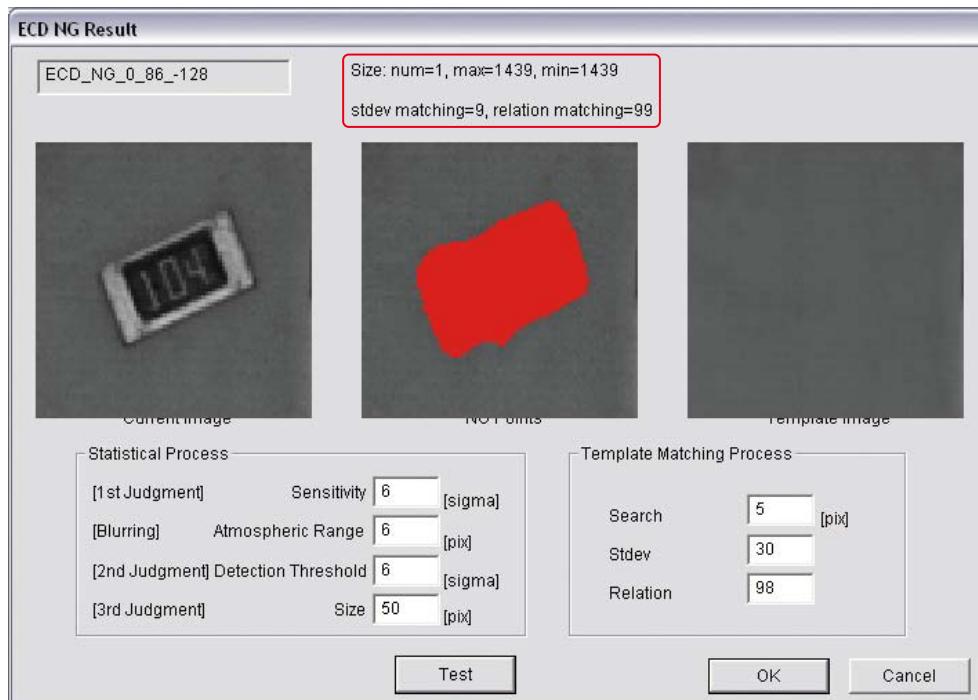


Figure 3-23 ECD Debug

| Item | Description |
|-------------------|--|
| num | The number of NG area is displayed. |
| max | The number of pixels of the largest NG area is displayed. If value of Size in Statistical Process is larger than value of max , judged as noise. The noise is not inspected. |
| min | The number of pixels that shows area of smallest NG area are displayed. |
| stdev matching | NG area is surrounded by circumscribed quadrangle. Calculate area of circumscribed quadrangle minus pixels of the NG area and the result will be divided by area of circumscribed quadrangle . If value of Stdev Matching in Template Matching Process is larger than value of stdev matching in the upper side of the window, the NG area is not detected as extra component. |
| relation matching | Calculate matching percentage of inspection PCB image and template image. If value of Relation Matching in Template Matching Process is larger than value of relation matching in the upper side of the window, the NG area is not detected as extra component. |

Table 3-3 ECD Debug 1

| Item | Description |
|----------------|--|
| Current Image | Detected extra component image is displayed. |
| NG Points | NG pixel is displayed in red. |
| Template Image | The latest sampled image is displayed as template image. |

Table 3-4 ECD Debug 2

| Item | Description |
|---------------------|--|
| Sensitivity | Scan several OK PCBs. Calculate average values and standard deviation value. If brightness level of inspection PCB differs from the average value greatly, the result will be NG. Specify OK range of variability in Sensitivity . Enter the bigger value to make the OK range wider. |
| Atmospheric Range | Brightness level of pixels that are judged NG in Sensitivity is averaged with brightness level of surrounding pixels. Enter the bigger value to average pixels in wider area. |
| Detection Threshold | After Atmospheric Range , detect pixels which brightness level differs from the average value. Enter the bigger value to make OK range wider. |
| Size | The size of the NG area which is detected in Detection Threshold is inspected in Size . If the NG area is smaller than the specified size, the NG area is eliminated from inspection target. |
| Search Range | The search area for matching inspection. Enter the bigger value to enlarge the search range. |
| Stdev Matching | Surround the NG area by circumscribed quadrangle. Calculate area of circumscribed quadrangle minus pixels of the NG area and divide the result by area of circumscribed quadrangle . If the stdev matching in the upper side of the window is smaller than the sentered value, the result will be NG. Default is 30[%]. |
| Relation Matching | Calculate matching percentage of inspection PCB image and template image. If relation matching in the upper side of the window is smaller than specified value, the result will be NG. Default is 98[%]. |

Table 3-5 ECD Debug 3

Step2: Refer to Table 3-6 and adjust values of **Sensitivity**, **Atmospheric Range**, **Detection Threshold**, and **Size**. Press **Test** to update parameters. After all the adjustments are completed, press **OK**.

NOTE

If any extra components are not detected or there are many false calls, adjust values of **Stdev Matching** or **Relation Matching**.

| Item | If extra component is not detected | If there are many false calls |
|---------------------|------------------------------------|-------------------------------|
| Detection Threshold | Down | Up |
| Atmospheric Range | Down | Up |
| Detection Threshold | Down | Up |
| Size | Down | Up |
| Stdev Matching | Up | Down |
| Relation Matching | Up | Down |

Table 3-6 Measure of Parameter Adjustment

Step3: Press **Inspect** button on the tool-bar or select **Inspect** from the menu-bar and if extra components on the NG PCB can be detected or not. If extra components are not detected, adjust parameters again.

Step4: Scan a target PCB.

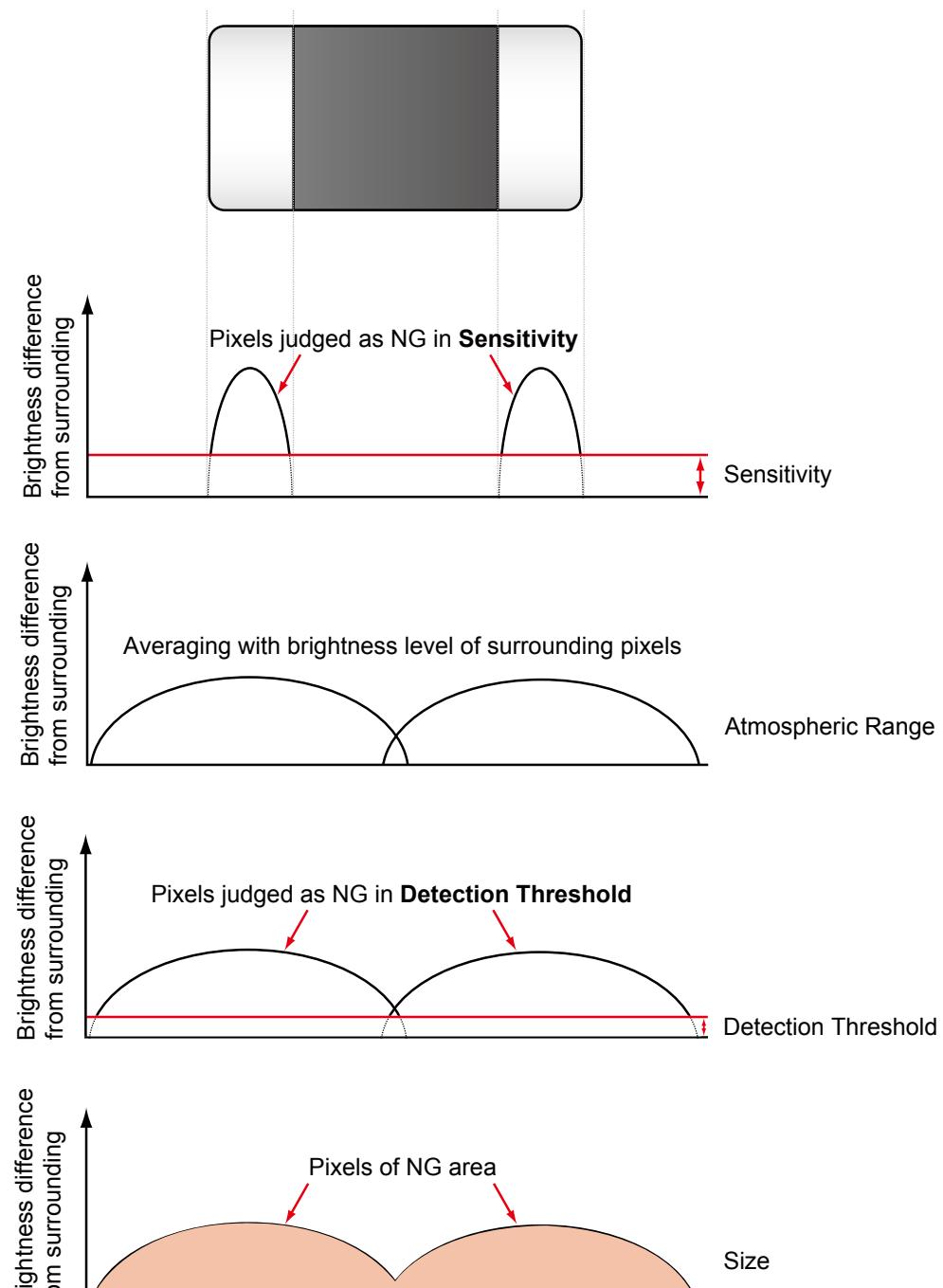


Figure 3-24 Detection of Extra Component

3.4 ECD Mask Function

ECD mask function can specify an area that is excluded from ECD inspection. The setting can be used to reduce false calls such as no-polarity chips as well as unique barcode given to each PCB.

Step1: Right-click the component to mask and the window shown in Figure 3-25 appears.



Figure 3-25 Edit Component Data Window

Step2: Selected inspection window size is range to apply mask. Select inspection window and press **Option**.

Step3: Check the **ECD Mask** and press **OK**.

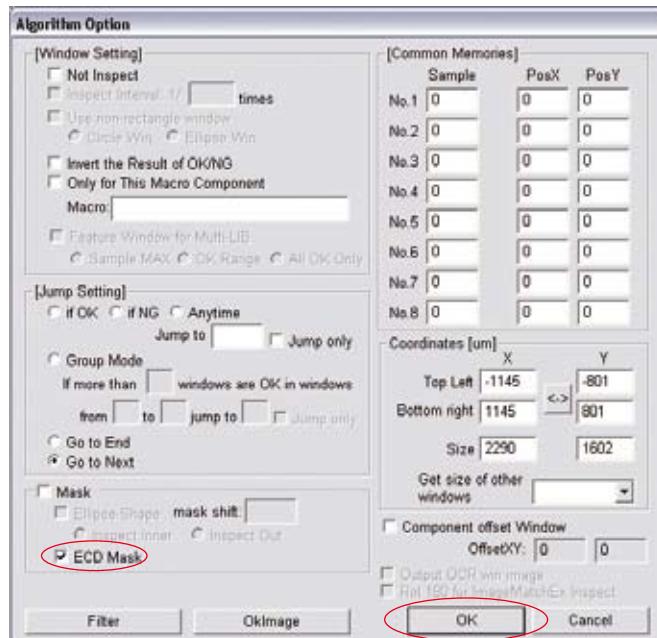


Figure 3-26 ECD Mask

Step4: Proceed to Step10 in **3.2 Inspection procedure**.

Inspection Algorithm

1 Inspection Algorithm

1.1 New_ASC

1.1.1 Inspection Overview

New_ASC is the algorithm to correct the misalignment of CAD data with the actual position of the components. Since the assembled components are easily shifted from the original position where CAD data assigns during the mounting process, this misalignment should be corrected to make the inspection data based on CAD data. New_ASC algorithm searches the chip electrode automatically based on its brightness level and corrects the misalignment(X axis, Y axis, θ axis).

New_ASC is also suitable to detect shift. LTracking / WTracking is more suitable for the chip components that its electrode is visually unclear or IC components. Refer to [1.2 LTracking / WTracking](#).

1.1.2 Parameter Setting

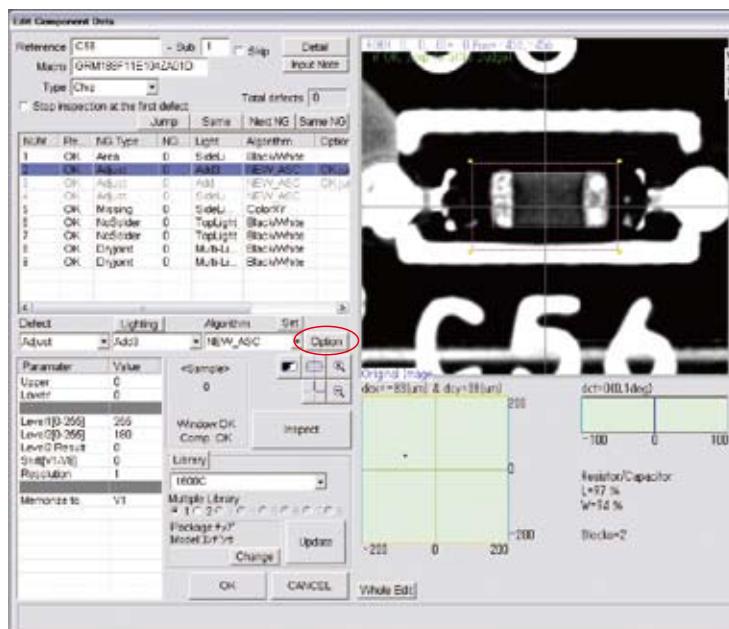


Figure 1-1 New_ASC

| Parameter | Description |
|---|---|
| Lighting | Select a lighting that electrode is visually clear. |
| Algorithm | Select New_ASC . |
| Upper, Lower | Set OK range. |
| Level1[0-255], Level2[0-255] | Level1 is upper limit of brightness level. Level2 is lower limit of brightness level. Enter 255 in Level1 field. Enter any suitable value in Level2 field. |
| Level2 Result | Enter 0 . |
| Shift[V1-V8] | Enter 0 . |
| Resolution | Enter 1 . |
| Memorize to | Enter V1 to register the amount of misalignment. Enter V1 in Shift field to reflect this amount of misalignment to other algorithms. |
| The graph in the lower right side of the window | Display the shift amount as graphs. |

Table 1-1 Parameter of New_ASC

1.1.3 Setting Procedure

Step1: Select a lighting that electrode is visually clear from the **Lighting** drop-down list.

CAUTION Select three different kinds of lightings for three adjust windows.

Step2: Adjust the size of **Adjust** window to surround the component body. The ideal window size is about 1.2 times larger than the component size.

Step3: Press **Option** in the right side of **Algorithm**. The window shown in Figure 1-2 appears.

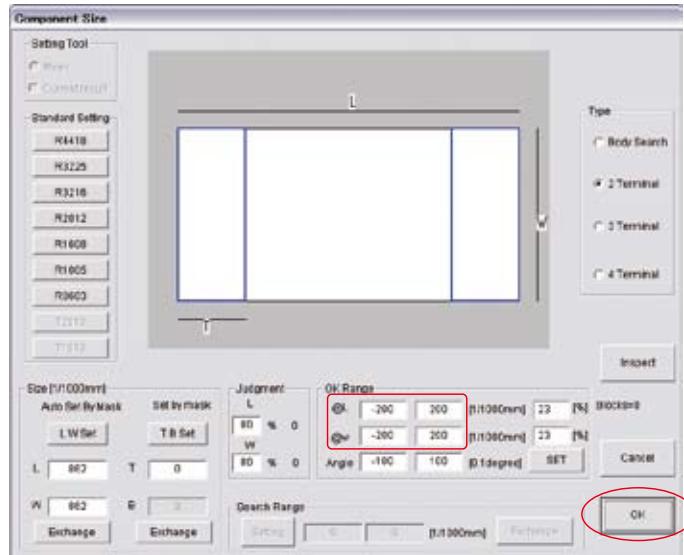


Figure 1-2 OK Range Setting

Step4: Adjust the **L** and **W** values in **OK range** and press **OK**. Check if the specified OK range is appropriate or not.

Step5: Press **Mask**.



Figure 1-3 Mask Setting

Step6: Mask window appears. Adjust the window size to surround the entire component body (including electrodes).

Step7: Press **Option** in the right side of **Algorithm**. The window shown in Figure 1-4 appears.

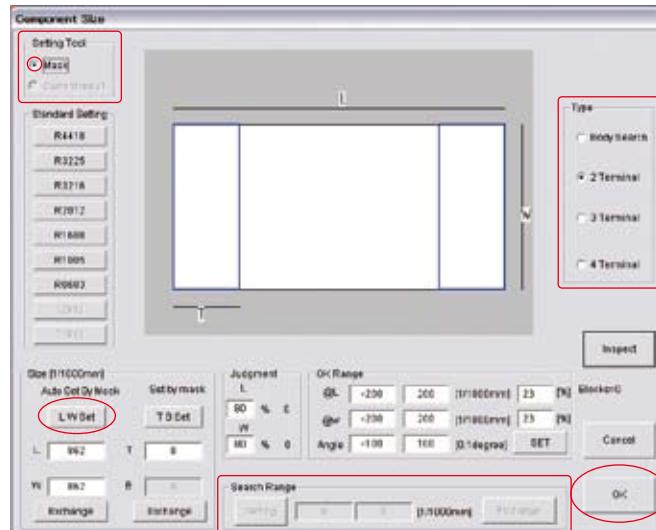


Figure 1-4 LW Setting

Step8: Select a component type from **Type**.

NOTE Search range setting is required if **4 Terminal** is selected.

Step9: Check the **Mask** in **Setting Tool**.

Step10: Press **LW Set** and **OK**.

Step11: Mask window appears. Adjust the window size to surround the one side of the electrode size.

Step12: Press **Option** in the right side of **Algorithm**. The window shown in Figure 1-5 appears.

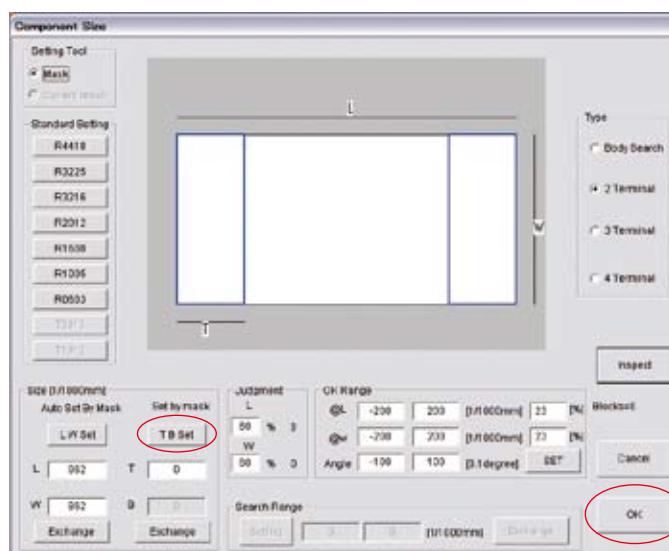


Figure 1-5 TB Setting

Step13: Press **TB Set** and **OK**.

Step14: Press **Mask** to remove mask.

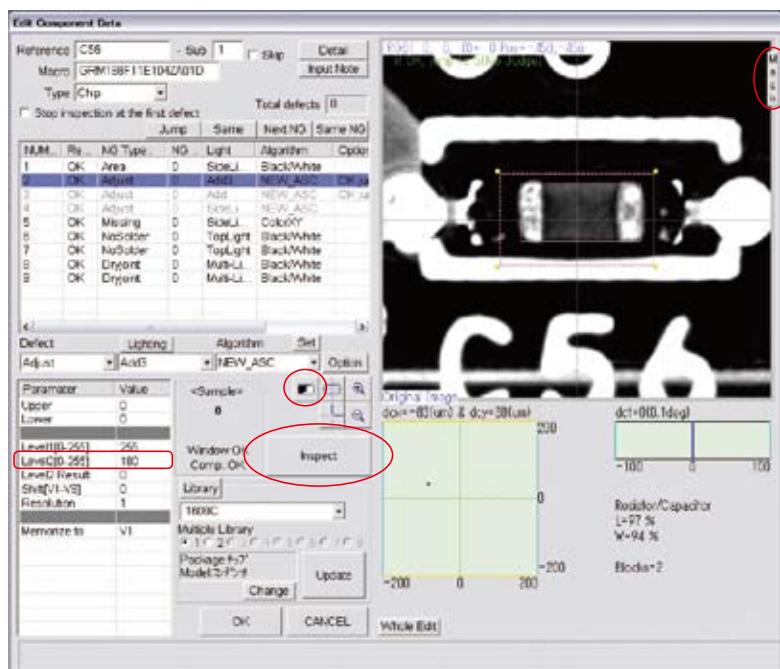


Figure 1-6 Remove Mask

Step15: Press the black-white button in the right side of **Sample** and check if searching electrode is successful.

NOTE Readjust the **Level2** value if the search is not successful.

Step16: Enter **V1** in **Memorize to** field.

CAUTION **V1** to **V8** are available in **Memorize to** field. Enter vector to use **New_ASC** as adjustment and register the inspection result in **Shift** field to reflect it to other algorithm. Do not use the same vector values in the several **Memorize to** field.

Step17: Press **Inspect**. Pink window surrounding the component's body appears if the search is successful.

1.2 LTracking / WTracking

1.2.1 Inspection Overview

LTracking / WTracking is the algorithm to correct the misalignment of CAD data with the actual position of the components. The actual component position is automatically searched based on the brightness difference between the PCB and the components and LTracking / WTracking corrects the misalignment(X axis, Y axis). LTracking should be used to correct longitudinal direction misalignment of the inspection window. WTracking should be used to correct lateral direction misalignment of the inspection window. LTracking / WTracking is more suitable for the chip components that its electrode is visually unclear or IC components.

1.2.2 Parameter Setting

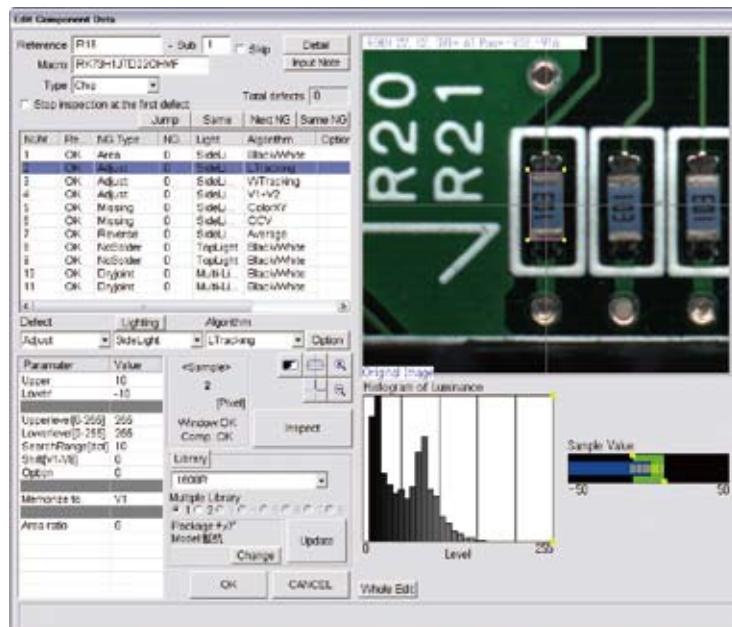


Figure 1-7 LTracking / WTracking

| Parameter | Description |
|--------------------------------------|--|
| Lighting | Select a lighting that edge is visually clear. |
| Algorithm | Select LTracking or WTracking (Refer to 1.2.4 The difference between LTracking and WTracking). |
| Upper, Lower | Enter the same value of Search Range to \pm field. |
| Upperlevel[0-255], Lowerlevel[0-255] | Enter 0 in Upperlevel and Lowerlevel field if the component brightness level is lower than the one of PCB. Enter 255 in Upperlevel and Lowerlevel field if the component brightness level is higher than the one of PCB. |
| SearchRange | Default is 10 . Enter the bigger value to enlarge the search range. However if the Search Range is too large, the calculation time might be long or PCB pattern might be mis-recognized as a component. |
| Shift[V1-V8] | Enter 0 . |
| Option | Enter 0 . |
| Memorize to | Enter V1 , V2 , and V3 to each three Adjust window. Register the amount of longitudinal misalignment as V1 , the amount of lateral misalignment as V2 . These two amounts are added to calculate V3 by using algorithm V1+V2 . Enter V3 in Shift field to reflect this amount of misalignment to other algorithms. |
| Area ratio | Enter 0 . |

Table 1-2 Parameter of LTracking / WTracking

1.2.3 Setting Procedure

- Step1: Select a lighting that edge is visually clear from the **Lighting** drop-down list.
- Step2: Check the **Upperlevel** and **Lowerlevel**. Enter **0** in **Upperlevel** and **Lowerlevel** field if the component brightness level is lower than the one of PCB. Enter **255** in **Upperlevel** and **Lowerlevel** field if the component brightness level is higher than the one of PCB.
- CAUTION** Select a lighting if the component edge is visually unclear with default setting.
- Step3: Enter **V1**, **V2**, and **V3** to each three **Adjust** window. Refer to **1.2.5 Algorithm V1+V2**.
- Step4: Press **Inspect**. Pink window surrounding the component's body appears if the search is successful.

NOTE

Value in Sample field shows the amount of misalignment. If the sample value is out of OK range, adjust the Area window position and re-check the sample value.

CAUTION

Adjust window can be scaled to any size by moving yellow square points in window corners. Do not move the window position with mouse dragging.

1.2.4 The difference between LTracking and WTracking

As the window shown in Figure 1-8(a), LTracking should be used to correct longitudinal direction misalignment of the inspection window. WTracking should be used to correct lateral direction misalignment of the inspection window. This is the same as the difference between ColorLTrack and ColorWTrack.

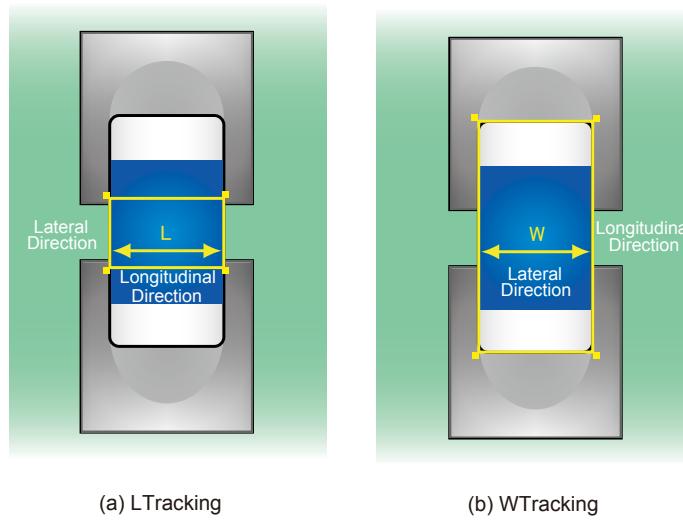


Figure 1-8 The difference between LTracking and WTracking

1.2.5 Algorithm V1+V2

Three **Adjust** windows are necessary to correct misalignment with **LTracking** and **WTracking**. The first window calculates the amount of longitudinal direction misalignment and the second window calculates the amount of lateral direction misalignment. Enter **V1** and **V2** to each window's **Memorized to** field. Enter **V3** to the last adjust window **Memorized to** field.

Enter **V3** in **Shift** field to reflect this amount of misalignment to other algorithms.

1.3 ColorLTrack / ColorWTrack

1.3.1 Inspection Overview

ColorLTrack / ColorWTrack is the algorithm to correct the misalignment of CAD data with the actual position of the components. The actual component position is automatically searched based on the color difference between Components and PCB. ColorLTrack / ColorWTrack corrects the misalignment (Xaxis, Yaxis). Extract the component color from two places in consideration of color variability(Extracted color should be differ from the PCB color) and register them as criterial color.

ColorLTrack should be used to correct longitudinal direction misalignment of the inspection window.

ColorWTrack should be used to correct lateral direction misalignment of the inspection window.

ColorLTrack / ColorWTrack is suitable if component color is clearly differ from PCB color.

1.3.2 Parameter Setting

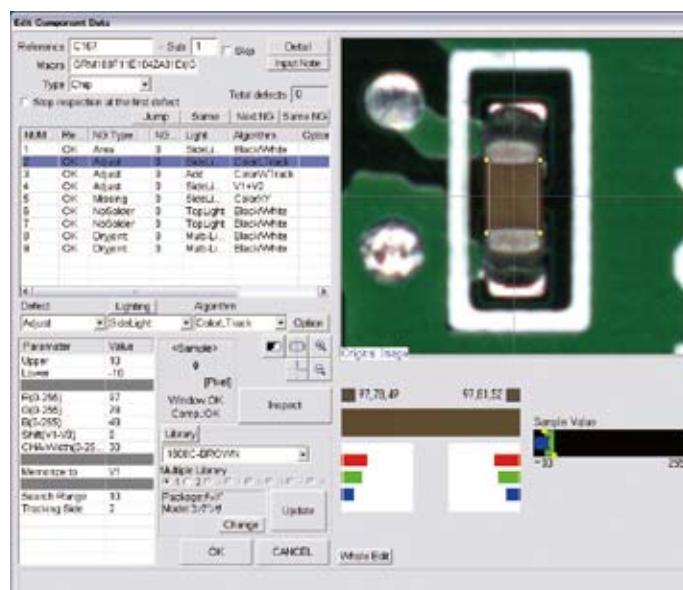


Figure 1-9 ColorLTrack / ColorWTrack

| Parameter | Description |
|---|---|
| Lighting | Select SideLight . |
| Algorithm | Select ColorLTrack or ColorWTrack (Refer to 1.2.4 The difference between LTracking and WTracking). |
| Upper, Lower | Set OK range. |
| R, G, B [0-255] | Value is automatically entered when component color is extracted. |
| CHA-Width | Default is 30 . Enter the bigger value to enlarge the color OK range. |
| Memorize to | Enter V1 to register the amount of misalignment. Enter V1 in Shift field to reflect this amount of misalignment to other algorithms. |
| Search Range | Default is 10 . Enter the bigger value to enlarge the search area. However if the Search Range is too large, the inspection time might be long or PCB pattern might be mis-recognized as a component. |
| Tracking Side | Default is 2 . If the value is 0 or 1 , misalignment is corrected one-way only. |
| The graph in the lower right side of the window | Component RGB values are displayed in the left side of the graph if specified color is left-clicked by pressing Ctrl . Component RGB values are displayed in the right side of the graph if specified color is left-clicked by pressing Alt . |

Table 1-3 Parameter of ColorLTrack / ColorWTrack

1.3.3 Setting Procedure

Step1: Select **SideLight** from the **Lighting** drop-down list.

Step2: **Adjust** window can be scaled to any size by adjusting the yellow square points to the corners of the colored part of the chip. The window position should be adjusted in **Area** window.

CAUTION

Do not move the **Adjust** window position with mouse dragging.

Step3: Extract colors from two places.

Component RGB values are displayed in the left side of the graph if specified color is left-clicked by pressing **Ctrl**. Component RGB values are displayed in the right side of the graph if specified color is left-clicked by pressing **Alt**.

NOTE

Extract colors two places to put flexibility into OK range. One should be extracted from dark color and another should be extracted from light color.

Step4: Enter **V1** in **Memorize to** field.

Step5: Press **Inspect**. Pink window surrounding the component's body appears if the search is successful.

NOTE

Value in **Sample** field shows the amount of misalignment. If the sample value is out of OK range, adjust the **Area** window position and re-check the sample value.

1.4 ChipMissing3

1.4.1 Inspection Overview

ChipMissing3 is the algorithm to inspect solder at either end of the chip component with Toplight and Sidelight used.

The brightness level of solder is lower when solder fillet is formed. The brightness level of solder is higher when solder fillet is not formed or component is missing(Refer to Figure 1-11).

ChipMissing3 is suitable for chip missing inspection or solder inspection.

1.4.2 Parameter Setting

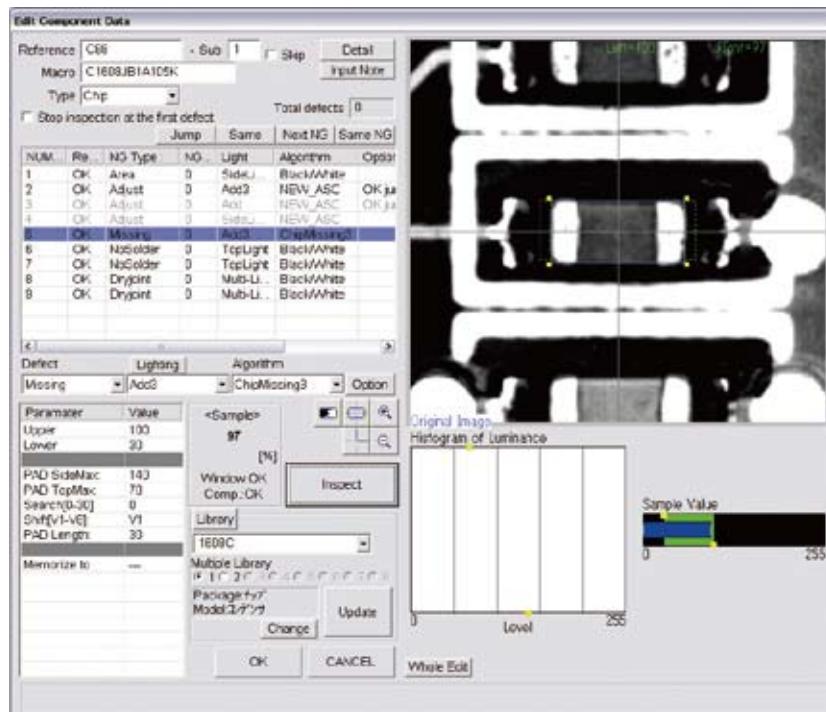


Figure 1-10 ChipMissing3

| Parameter | Description |
|--------------|---|
| Lighting | Select SideLight . |
| Algorithm | Select ChipMissing3 . |
| Upper, Lower | Set OK range. |
| PAD Side Max | Upper limit of brightness level in OK range(SideLight). |
| PAD Top Max | Upper limit of brightness level in OK range(TopLight). |
| Search[0-30] | Enter 0 . |
| Shift[V1-V8] | Enter appropriate vector according to the vector used in Memorize to in Adjust window. |
| PAD Length | Default is 30 . Enter the bigger value to enlarge the inspection area. |
| Memorize to | - |

Table 1-4 Parameter of ChipMissing3

1.4.3 Setting Procedure

- Step1: Select **SideLight** from the **Lighting** drop-down list.
- Step2: Enter appropriate vector in **Shift** according to the vector used in **Memorize to** in Adjust window.
- Step3: Check if the sample value is in OK range. If it is out of OK range, change values in **PAD Side Max** field or **PAD Top Max** field.
- NOTE** If the inspection area is too small, change values in **PAD Length** to larger.
- Step4: Press **Inspect**. Check if the inspection is completed properly.

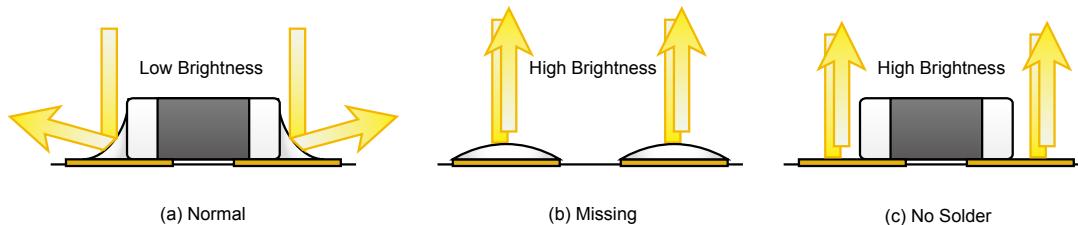


Figure 1-11 Missing / Solder inspection by ChipMissing3

1.4.4 Calculation of Sample Value

Set the OK brightness range of SideLight and TopLight by adjusting **PAD Side Max** / **PAD Top Max** values. The percentages of the area that the result is OK in solder inspection window at either end of the chip component with TopLight and SideLight, are calculated. The lower value is shown as sample value.

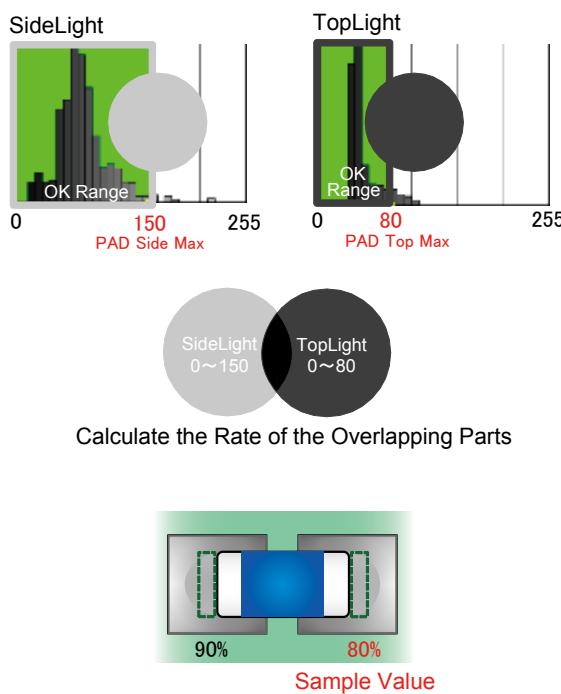


Figure 1-12 Calculation of Sample Value

1.5 Length

1.5.1 Inspection Overview

Length is the algorithm to inspect component's length.

Surround the component and around it by a window. Component's length is calculated based on the changes of brightness level in the window.

If the inspected component's length is in OK range, the result will be OK.

Length is suitable for missing inspection of chip components.

1.5.2 Parameter Setting

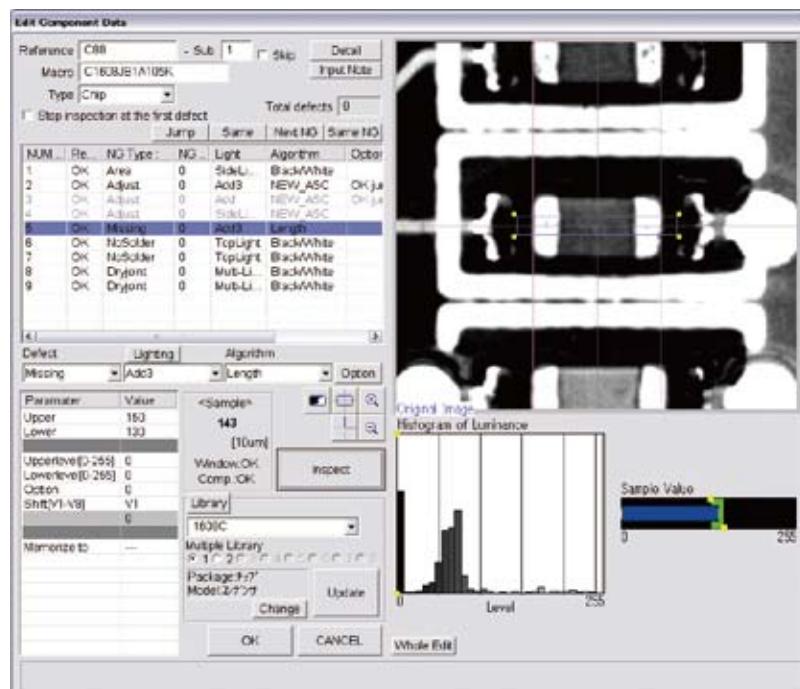


Figure 1-13 Length

| Parameter | Description |
|--------------------------------------|--|
| Lighting | Select a lighting that the component is visually clear. |
| Algorithm | Select Length . |
| Upper, Lower | Set OK range. |
| Upperlevel[0-255], Lowerlevel[0-255] | Enter 0 in Upperlevel and Lowerlevel field if the component brightness level is lower than the brightness level of PCB. Enter 255 in Upperlevel and Lowerlevel field if the component brightness level is higher than the brightness level of PCB. |
| Option | Enter 0 . |
| Shift[V1-V8] | Enter appropriate vector according to the vector used in Memorize to in Adjust window. |
| Memorize to | - |

Table 1-5 Parameter of Length

1.5.3 Setting Procedure

- Step1: Select a lighting that the target component is visually clear from the **Lighting** drop-down list.
- Step2: Adjust the inspection window to be longer than the length of component in longitudinal direction. In lateral direction, adjust the inspection window to be shorter than the one of the component.

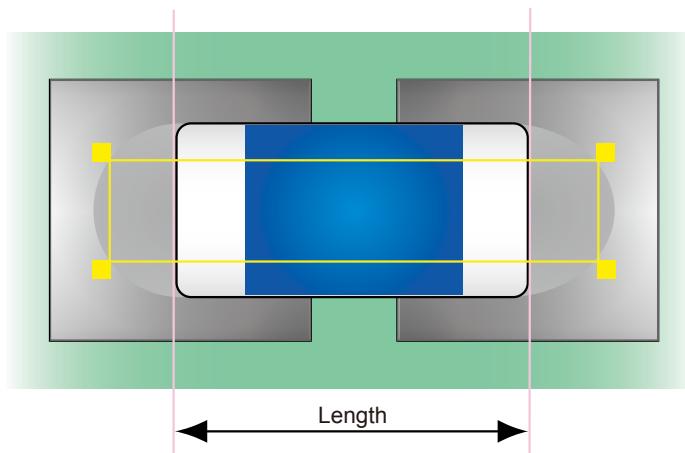


Figure 1-14 Inspection window of Length

- Step3: Check the value of **Upperlevel** and **Lowerlevel**. Enter **0** in **Upperlevel** and **Lowerlevel** field if the component brightness level is lower than the one of PCB. Enter **255** in **Upperlevel** and **Lowerlevel** field if the component brightness level is higher than the one of PCB.
- Step4: Set OK range. Sample value shows the length of component by 10µm.
- Step5: Enter appropriate vector in **Shift** field according to the vector used in **Memorize to** in Adjust window.
- Step6: Press **Inspect**. Check if the inspection is completed properly.

1.6 ColorXY

1.6.1 Inspection Overview

ColorXY is the algorithm to inspect the color of the component.

ColorXY calculates average color of the inspection window and display red x marking at the graph in the lower right side of the window.

The average color of the area which is to be OK and the average color of the area which is NG are displayed in the graph. Compare these two average colors and set the borderline between them.

ColorXY is suitable for missing, misalignment, and polarity inspection of the chip component by using color.

1.6.2 Parameter Setting

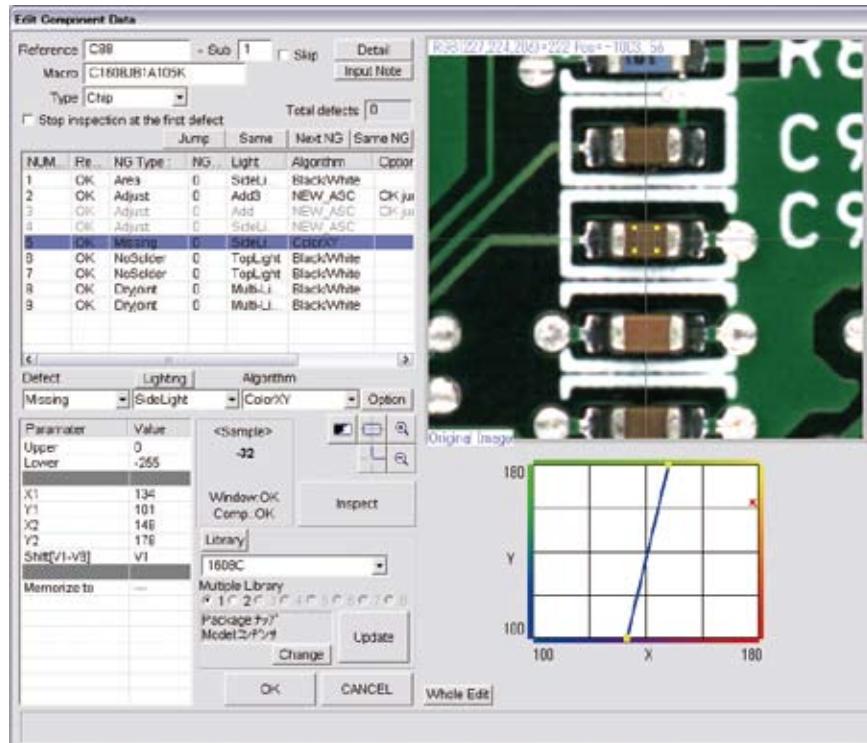


Figure 1-15 ColorXY

| Parameter | Description |
|---|--|
| Lighting | Select SideLight . |
| Algorithm | Select ColorXY . |
| Upper, Lower | If the average color of the area which is to be OK is in the left side of the blue borderline, enter 255 in Upper field and 0 in Lower field. If the average color of the area which is to be OK color is in the right side of the blue borderline, enter 0 in Upper field and 255 in Lower field. |
| X1, Y1, X2, Y2 | This field is automatically filled when the blue borderline is moved. |
| Shift[V1-V8] | Enter appropriate vector according to the vector used in Memorize to in Adjust window. |
| Memorize to | - |
| The graph in the lower right side of the window | Average color in the window is displayed as red x marking. Green x marking is the average color of other components which are sharing the same library. The borderline can be moved by adjusting the yellow square points at the either end of the blue borderline. |

Table 1-6 Parameter of ColorXY

1.6.3 Setting Procedure

- Step1: Select **SideLight** from the **Lighting** drop-down list.
- Step2: Check the average color of the area which is to be OK. Adjust the window size smaller and check the x marking distribution in the graph in the lower right side of the window. x marking position is changed according to the window position.
- Step3: Check the average color of the area which is to be NG. Adjust the window size smaller and check the x marking distribution in the graph in the lower right side of the window. x marking position is changed according to the window position.
- Step4: Set an inspection window on the component.
- Step5: Set the borderline between the position of the x marking if the window is in OK area and the position of the x marking if the window is in NG area.
- Step6: If the average color of the area which is to be OK is in the left side of the blue borderline, enter **255** in **Upper** field and **0** in **Lower** field. If the average color of the area which is to be OK color is in the right side of the blue borderline, enter **0** in **Upper** field and **255** in **Lower** field.
- Step7: Enter appropriate vector in **Shift** field according to the vector used in **Memorize to** in **Adjust** window.
- Step8: Press **Inspect**. Check if the inspection is completed properly.

NOTE

Sample value is the distance of x marking to blue borderline.

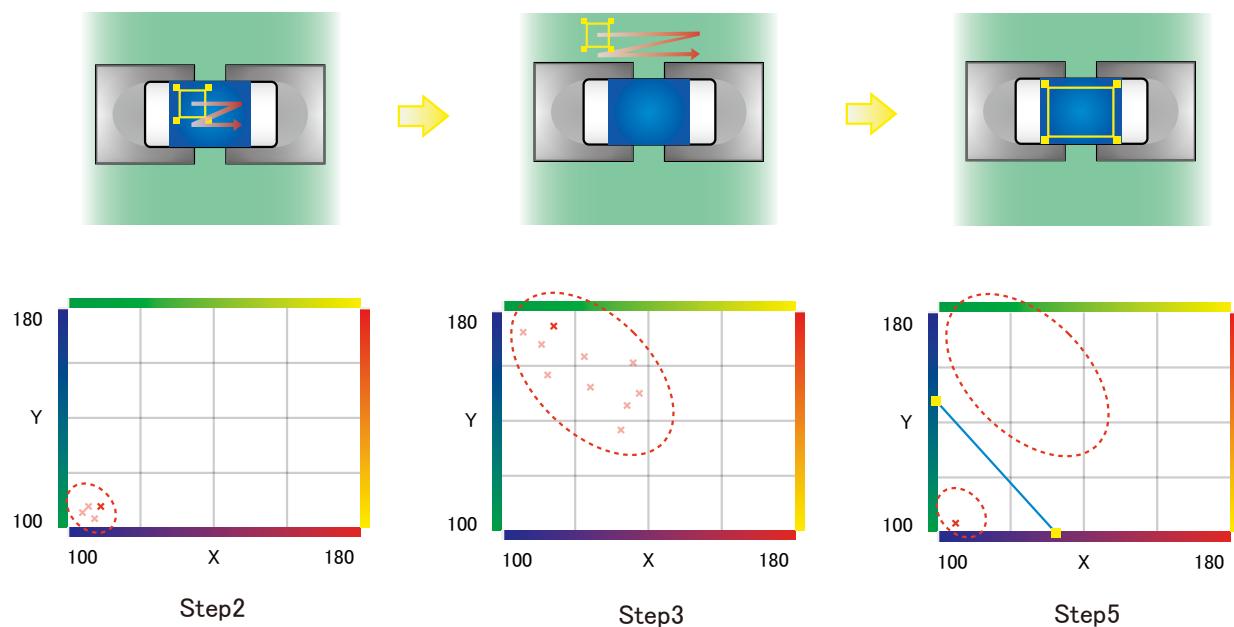


Figure 1-16 Setting Procedure of ColorXY

1.7 AreaColor

1.7.1 Inspection Overview

AreaColor is the algorithm to inspect the percentage of specified color in the inspection window. Extract the component color from two places in consideration of color variability.

Specify any color as OK color. If the percentage of the specified color exceeds a certain value, the result will be OK. Specify any color as NG color. If the percentage of the specified color falls below a certain value, the result will be NG.

AreaColor is suitable for missing inspection of chip components.

1.7.2 Parameter Setting

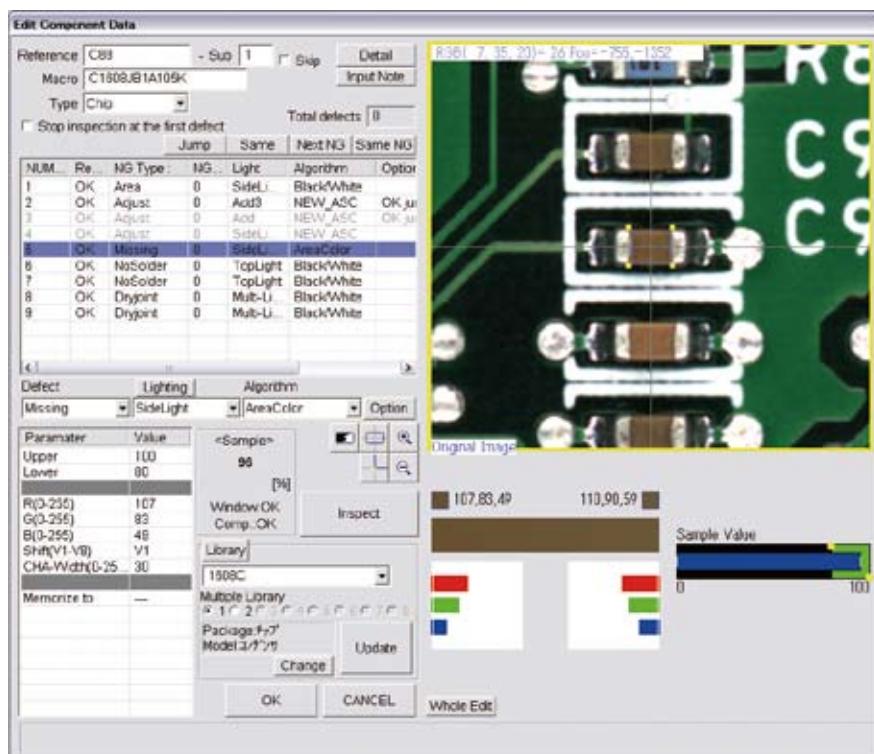


Figure 1-17 AreaColor

| Parameter | Description |
|---|---|
| Lighting | Select SideLight . |
| Algorithm | Select AreaColor . |
| Upper, Lower | If the specified color is registered as OK color, enter 100 in Upper field and arbitrarily value in Lower field. If the specified color is registered as NG color, enter arbitrarily value in Upper field and 0 in Lower field. |
| R, G, B [0-255] | Value is automatically entered when component color is extracted. |
| Shift[V1-V8] | Enter appropriate vector according to the vector used in Memorize to in Adjust window. |
| CHA-Width | Default is 30 . Enter the bigger value to enlarge the color OK range. |
| Memorize to | - |
| The graph in the lower right side of the window | Component RGB values are displayed in the left side of the graph if specified color is left-clicked by pressing Ctrl . Component RGB values are displayed in the right side of the graph if specified color is left-clicked by pressing Alt . |

Table 1-7 Parameter of AreaColor

1.7.3 Setting Procedure

Step1: Select **SideLight** from the **Lighting** drop-down list.

Step2: Extract colors from two places.

Component RGB values are displayed in the left side of the graph if specified color is left-clicked by pressing **Ctrl**. Component RGB values are displayed in the right side of the graph if specified color is left-clicked by pressing **Alt**.

NOTE

Extract colors two places to put flexibility into OK range. One should be extracted from dark color and another should be extracted from light color.

Step3: If the specified color is registered as OK color, enter **100** in **Upper** field and arbitrarily value in **Lower** field. If the specified color is registered as NG color, enter arbitrarily value in **Upper** field and **0** in **Lower** field.

Step4: Enter appropriate vector in **Shift** field according to the vector used in **Memorize to** in Adjust window.

Step5: Press **Inspect**. Check if the inspection is completed properly.

1.8 Average

1.8.1 Inspection Overview

Average is the algorithm to average the brightness level of the inspection window.

If the average of brightness level is in OK range, the result will be OK.

Average is suitable for reverse inspection of chip components or polarity inspection of IC components.

1.8.2 Parameter Setting

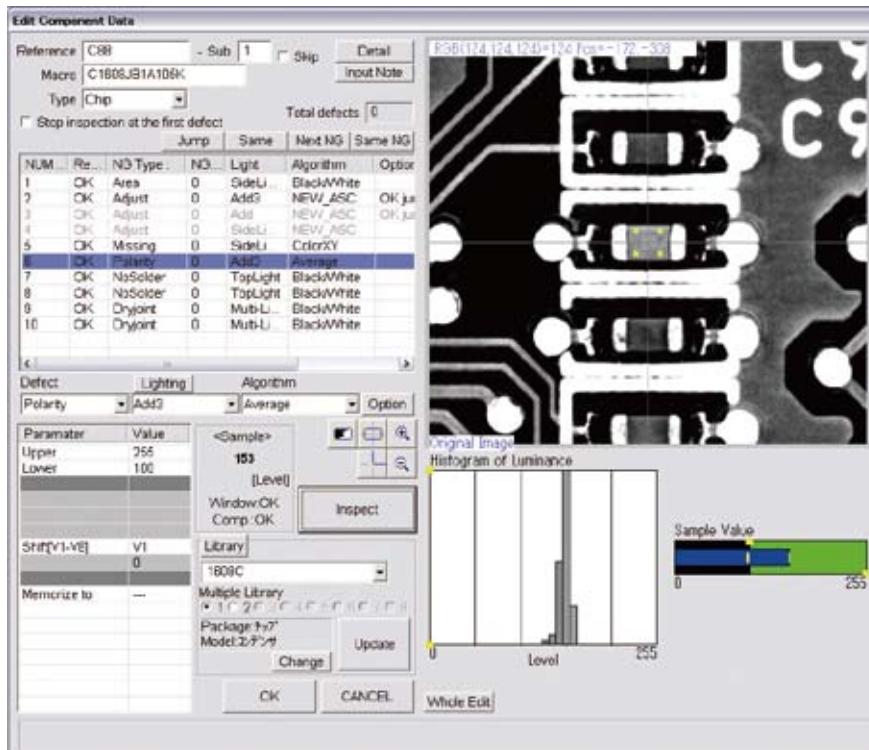


Figure 1-18 Average

| Parameter | Description |
|--------------|---|
| Lighting | Select a lighting that the brightness level difference between the surface and the back side is visually clear. |
| Algorithm | Select Average . |
| Upper, Lower | Calculate a value intermediate between OK sample value and NG sample value. If OK sample value is smaller than NG sample value, enter the intermediate value in Upper field and 0 in Lower field. If NG sample value is smaller than OK sample value, enter 255 in Upper field and the intermediate value in Lower field. |
| Shift[V1-V8] | Enter appropriate vector according to the vector used in Memorize to in Adjust window. |
| Memorize to | - |

Table 1-8 Parameter of Average

1.8.3 Setting Procedure

Step1: Select a lighting that the brightness level difference between the surface and the back surface from the **Lighting** drop-down list.

Step2: Check the OK brightness level. Move the inspection window onto the surface of the component and check the sample value.

NOTE

Sample value is the brightness level average of the inspection window.

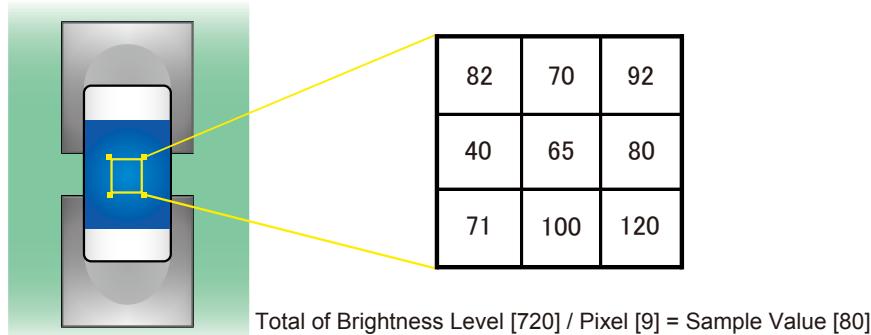


Figure 1-19 Calculation of Sample Value

Step3: Check the NG brightness level. Move the inspection window onto any position which brightness level is the nearly same as the brightness level of the back side of the component and check the sample value.

Step4: Calculate a value intermediate between OK sample value and NG sample value.

CAUTION

Change the lighting if there is no difference between OK sample value and NG sample value with default lighting.

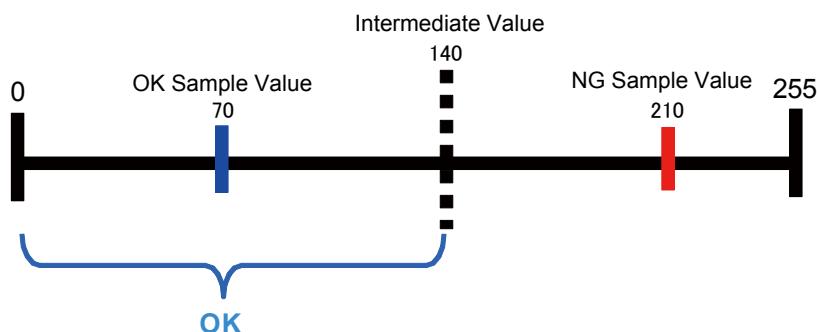


Figure 1-20 Calculation of Intermediate Value

Step5: If OK sample value is smaller than NG sample value, enter **intermediate value** in **Upper** field and the **0** in **Lower** field. If NG sample value is smaller than OK sample value, enter the **255** in **Upper** field and **intermediate value** in **Lower** field.

Step6: Enter appropriate vector in **Shift** field according to the vector used in **Memorize to** in Adjust window.

Step7: Press **Inspect**. Check if the inspection is completed properly.

1.9 Black/White

1.9.1 Inspection Overview

Black/White is the algorithm to inspect the percentage of the specified brightness level of the inspection window.

If the percentage of the specified level exceeds a certain value, the result will be OK.

Black/White is suitable for solder inspection of chip components.

1.9.2 Parameter Setting



Figure 1-21 Black/White

| Parameter | Description |
|---|---|
| Lighting | Select TopLight to inspect solder paste. |
| Algorithm | Select Black/White . |
| Upper, Lower | Set OK range. The maximum value is 100 in Upper field and minimum value is 0 in Lower field. |
| Level1[0-255], Level2[0-255] | Calculate a value intermediate between OK sample value and NG sample value. If OK sample value is smaller than NG sample value, enter the intermediate value in Level1 field and 0 in Level2 field. If NG sample value is smaller than OK sample value, enter 255 in Level1 field and the intermediate value in Level2 field. |
| Option | Enter 0 . |
| Shift[V1-V8] | Enter appropriate vector according to the vector used in Memorize to in Adjust window. |
| Memorize to | - |
| The graph in the lower right side of the window | The Histogram of Luminance bar graph shows the number of pixels of every bright levels. Green area is the specified area by Level1 and Level2 . Sample value shows upper limit and lower limit. |

Table 1-9 Parameter of Black/White

1.9.3 Setting Procedure

Step1: Select **TopLight** from the **Lighting** drop-down list.

Step2: Adjust the **Black/White** window position to surround the solder fillet.

Step3: Enter value in **Upper** field and **Lower** field.

NOTE

100 is for **Upper** field and 60 is for **Lower** field as a rough guide.

Step4: Check if the sample value is in OK range. If it is out of OK range, adjust values in **Level1** and **Level2**.

CAUTION

Inspection windows are created at either end of the chip component after auto deployment of chip component.

NOTE

The percentage of the specified brightness level in the inspection window is displayed as a sample value.

NOTE

Press the black-white button on the right side of **Sample**(Refer to the red circle in Figure 1-22). The OK area will be colored in gray.

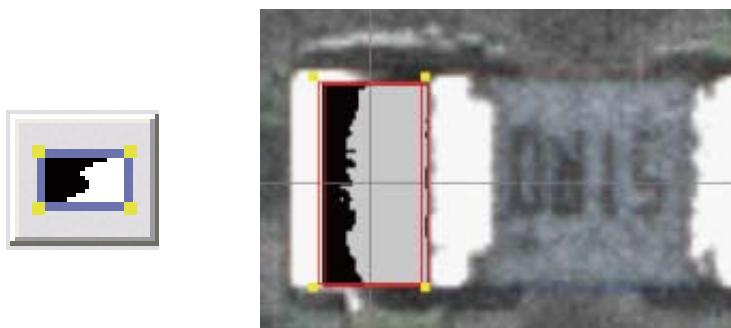


Figure 1-22 OK Range

Step5: Enter appropriate vector in **Shift** field according to the vector used in **Memorize to** in Adjust window.

Step6: Press **Inspect**. Check if the inspection is completed properly.

1.9.4 Algorithm BrightLevel

BrightLevel algorithm is available for components which brightness level are quite-variable. Black/White algorithm calculates the percentage of the specified brightness level in the inspection window. BrightLevel algorithm inspects the brightness level which accounts for the specified percentage.



Figure 1-23 BrightLevel

| Parameter | Description |
|--------------------|--|
| Lighting | Select an appropriate lighting depend on with which algorithm the bright level is used. (e.g. Select Toplight if the threshold of BrightLevel is used with Black/White for solder inspection.) |
| Algorithm | Select BrightLevel . |
| Upper, Lower | Enter 255 in Upper field and 0 in Lower field. |
| Bright[%], Dark[%] | Enter arbitrarily value in Bright field and 0 in Dark field to specify the percentage of brighter area in the inspection window. Enter 0 in Bright field and arbitrarily value in Dark field to specify the percentage of darker area in the inspection window. (e.g. The percentage of brighter area is 70% and the percentage is darker area is 30% if digitize the area of inspection window, enter 70 in Bright field, 0 in Dark field or enter 0 in Bright field, 30 in Dark field.) |
| Option | Enter 0 . |
| Shift[V1-V8] | Enter appropriate vector according to the vector used in Memorize to in Adjust window. Enter 0 in Shift field if the threshold of Bright level is used for misalignment correction. |
| Memorize to | Register the threshold of BrightLevel in Memorize to as M1 . Enter M1 in appropriate parameter field if other algorithms use the threshold of BrightLevel. |

Table 1-10 Parameter of BrightLevel

1.9.5 BrightLevel Setting Procedure

Step1: Select a inspection window which BrightLevel algorithm needs to be applied. Select **Copy** from right-click and change the **algorithm** to **BrightLevel**.

Step2: Enter arbitrarily value in **Bright** field and **0** in **Dark** field to specify the percentage of brighter area in the inspection window. Enter **0** in **Bright** field and arbitrarily value in **Dark** field to specify the percentage of darker area in the inspection window.

NOTE Display the brightness level which accounts for the specified percentage as sample value.

NOTE Select **Black/White** as **Algorithm** and press the black-white button in the right side of **Sample**. Brightness level in OK range will be colored in gray.

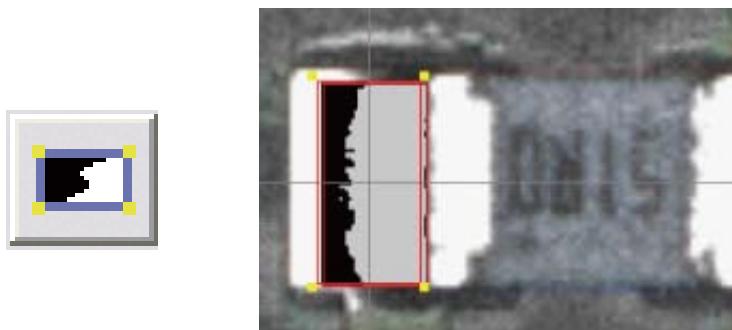


Figure 1-24 OK Range

Step3: Enter appropriate vector in **Shift** field according to the vector used in **Memorize to** in Adjust window.

CAUTION Do not enter any words in **Shift** field if the threshold of BrightLevel is used for misalignment correction.

Step4: Enter **M1** in **Memorize to** field.

CAUTION Register the inspection result of BrightLevel in **Memorize to** field. Any value from **M1** to **M8** is available. Enter it in the appropriate field to reflect the result to other algorithm.

Step5: Enter **M1** into the appropriate field.

NOTE In case the inspection result of brightLevel is used for the solder paste inspection of Chip component, enter **M1** in **Level1** or **Level2** field depending on the brightness level.

Step6: Press **Inspect**. Check if the inspection is completed properly.

1.9.6 Algorithm LandJudgement

LandJudgement is the algorithm to digitize the specified area with two selected lighting. Specify the brightness levels with each lighting and calculate the overlapping area where the each specified brightness levels surround in the window. The percentage of the overlapped area in the window is displayed as Sample. LandJudgement is suitable for the solder paste inspection of chip component.



Figure 1-25 LandJudgement

| Parameter | Description |
|--|---|
| Lighting | The selected lighting in this field does not influence to the inspection result. Select two kinds of lighting to use LandJudgment. Press Set in the right side of Algorithm . Select two lighting in this window. Default setting is TopLight and SideLight . |
| Algorithm | Select LandJudgement . |
| Upper, Lower | Set OK range. The maximum value is 100 in Upper field and minimum value is 0 in Lower field. |
| [Lighting1] Min, [Lighting2] Min, [Lighting2] Max, [Lighting1] Max | Specify brightness level in each lighting. The percentage of the area where the specified brightness levels in each two lighting overlap in the window is displayed as Sample. |
| Shift[V1-V8] | Enter appropriate vector according to the vector used in Memorize to in Adjust window. |
| Memorize to | - |

Table 1-11 Parameter of LandJudgement

1.9.7 LandJudgement Setting Procedure

Step1: Select two kinds of lighting to use LandJudgment. Press **Set** in the right side of **Algorithm** and select two lighting in this window. Default setting is **TopLight** and **SideLight**.

Step2: Specify brightness level in each lighting.

NOTE Calculate the area where the specified brightness levels in each two lighting overlap in the window. The percentage of the overlapped area in the window is displayed as Sample.

Step3: Set OK range. Enter value in **Upper** and **Lower** field.

Step4: Enter appropriate vector in **Shift** field according to the vector used in **Memorize to** in Adjust window.

Step5: Press **Inspect**. Check if the inspection is completed properly.

1.10 Peak

1.10.1 Inspection Overview

Peak is the algorithm to inspect based on peak value within the inspection window. If the peak of brightness level is in OK range, the result will be OK. This algorithm is not affected by noise, brightness level within the inspection window is stable. Peak is suitable for missing inspection of IC components.

1.10.2 Parameter Setting

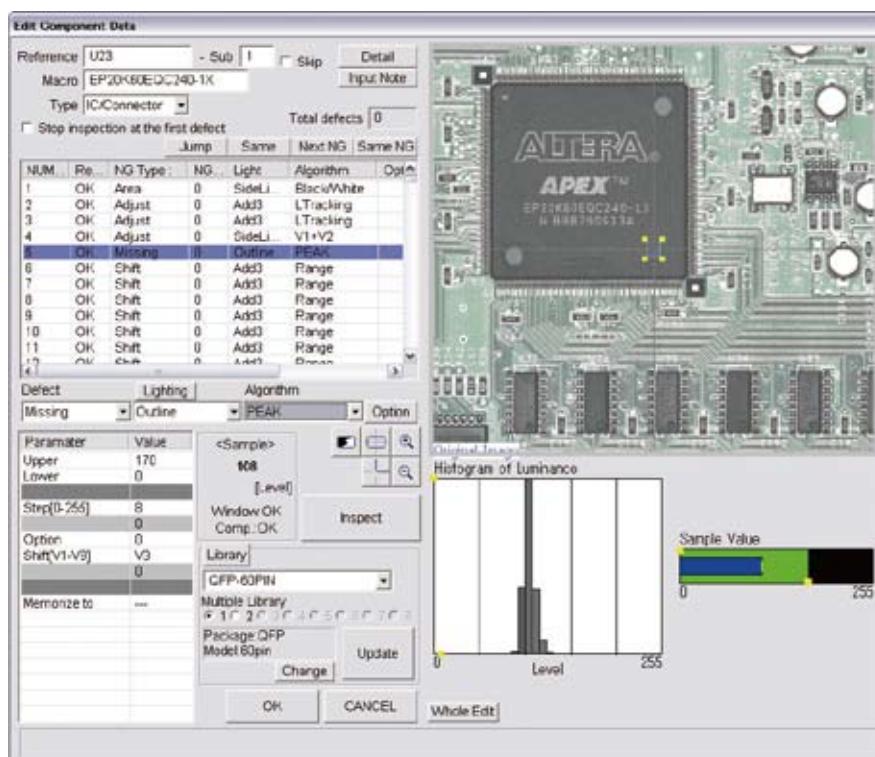


Figure 1-26 Peak

| Parameter | Description |
|---|---|
| Lighting | Select a lighting that the brightness level difference between the component and the PCB is visually clear. |
| Algorithm | Select Peak . |
| Upper, Lower | Calculate a value intermediate between OK sample and NG sample value. If OK sample value is smaller than NG sample value, enter intermediate value in Upper field and the 0 in Lower field. If NG sample value is smaller than OK sample value, enter the 255 in Upper field and intermediate value in Lower field. |
| Step[0-255] | Default is 8 . The bar graph shows the number of pixels that is divided brightness level by 8 in the graph in the lower right side of the window. |
| Option | Enter 0 . |
| Shift[V1-V8] | Enter appropriate vector according to the vector used in Memorize to in Adjust window. |
| Memorize to | - |
| The graph in the lower right side of the window | The Histogram of Luminance bar graph shows the number of pixels of every bright levels. Sample value is the largest brightness which is distributed within the inspection window. |

Table 1-12 Parameter of Peak

1.10.3 Setting Procedure

- Step1: Select a lighting that the brightness level difference between the component and the PCB from the **Lighting** drop-down list.
- Step2: Check the OK brightness level. Move the inspection window onto the surface of the component and check the sample value.

NOTE

Sample value is the peak value within the inspection window.

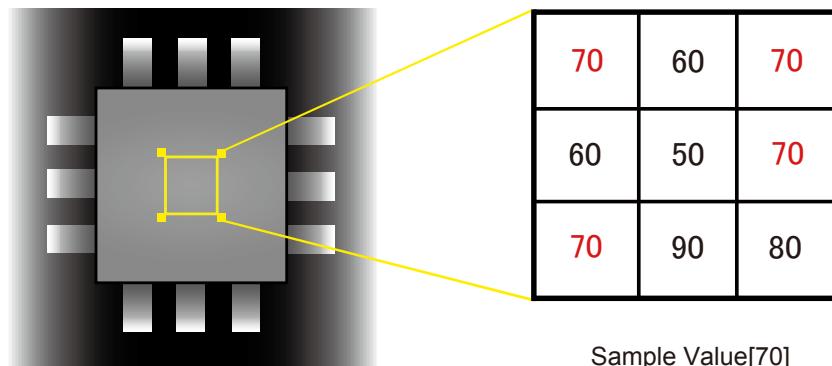


Figure 1-27 Calculation of Sample Value

- Step3: Check the NG brightness level. Move the inspection window to the PCB and check the sample value.
- Step4: Calculate a value intermediate between OK sample value and NG sample value.

CAUTION

Change the lighting if there is no difference between OK sample value and NG sample value with default lighting.

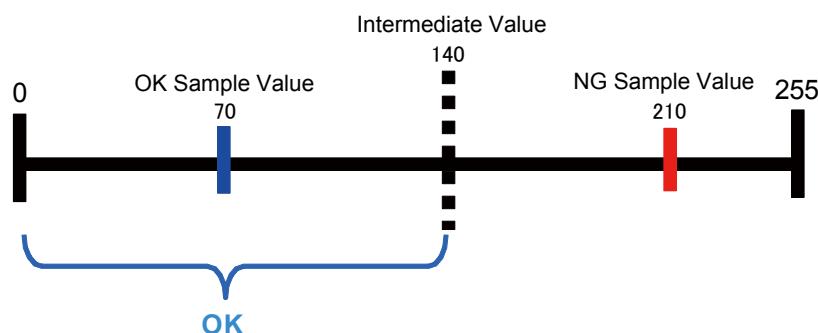


Figure 1-28 Calculation of Intermediate Value

- Step5: If OK sample value is smaller than NG sample value, enter **intermediate value** in **Upper** field and the **0** in **Lower** field. If NG sample value is smaller than OK sample value, enter the **255** in **Upper** field and **intermediate value** in **Lower** field.
- Step6: Enter appropriate vector in **Shift** field according to the vector used in **Memorize to** in Adjust window.
- Step7: Press **Inspect**. Check if the inspection is completed properly.

1.11 Range

1.11.1 Inspection Overview

Range is the algorithm to subtract the difference between the maximum brightness level and minimum brightness level within the inspection window. If the range of the brightness level is in OK range, the result will be OK. Range is suitable for shift or polarity inspection of IC components.

1.11.2 Parameter Setting

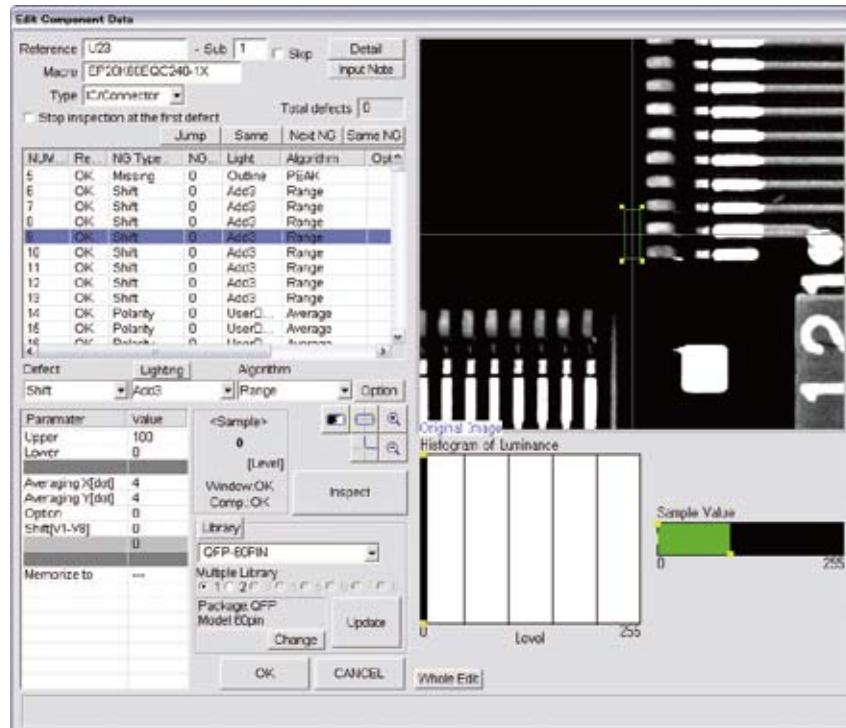


Figure 1-29 Range

| Parameter | Description |
|---|---|
| Lighting | For shift inspection, select a lighting that the brightness level difference between OK and NG is visually clear. For polarity inspection, select a lighting that a polarity is visually clear. |
| Algorithm | Select Range . |
| Upper, Lower | Calculate a value intermediate between OK sample value and NG sample value. If OK sample value is smaller than NG sample value, enter the intermediate value in Upper field and 0 in Lower field. If NG sample value is smaller than OK sample value, enter 255 in Upper field and the intermediate value in Lower field. |
| Averaging X [dot], Averaging Y [dot] | Default is 4 . Enlarge the value to reduce the effective of dusty or noise. |
| Option | Enter 0 . |
| Shift[V1-V8] | Enter appropriate vector according to the vector used in Memorize to in Adjust window. |
| Memorize to | - |
| The graph in the lower right side of the window | The Histogram of Luminance bar graph shows the number of pixels every brightness levels. |

Table 1-13 Parameter of Range

1.11.3 Setting Procedure of Shift Inspection

Step1: Select a lighting that the brightness level difference between OK and NG clear from the **Lighting** drop-down list.

Step2: Check the OK brightness level.

NOTE Sample value is the brightness level range of the inspection window.

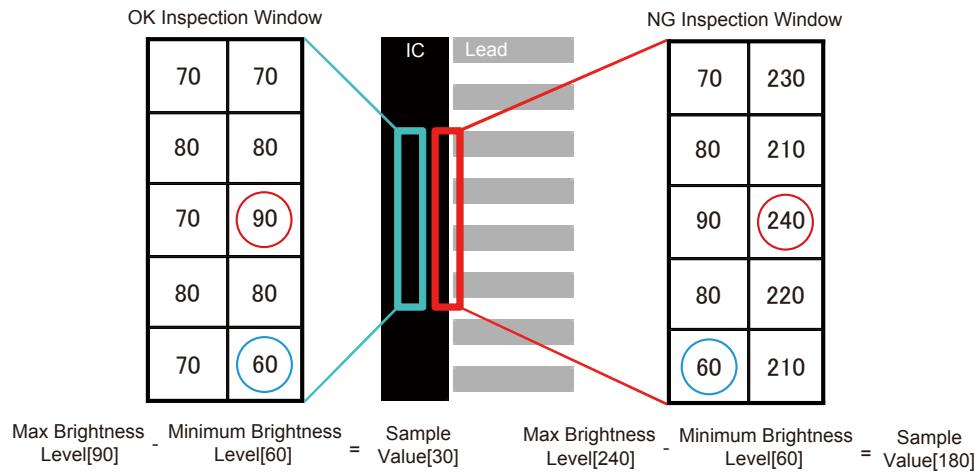


Figure 1-30 Calculation of Sample Value

Step3: Check the NG brightness level. Set the value in between the OK sample value and the NG sample value as OK range.

Step4: Calculate a value intermediate between OK sample value and NG sample value.

CAUTION Change the lighting if there is no difference between OK sample value and NG sample value with default lighting.

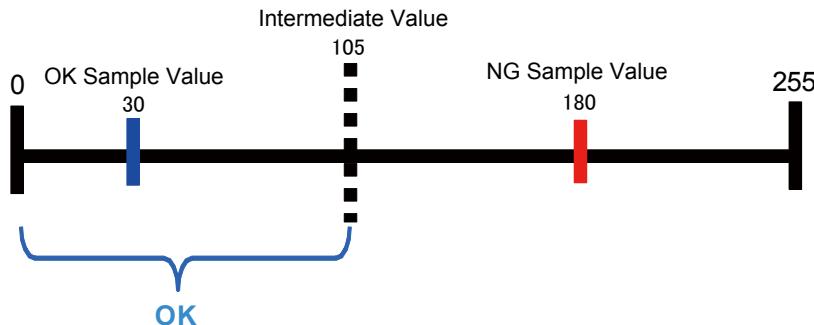


Figure 1-31 Calculation of Intermediate Value

Step5: If OK sample value is smaller than NG sample value, enter the **intermediate value** in **Upper** field and **0** in **Lower** field. If NG sample value is smaller than OK sample value, enter the **255** in **Upper** field and the **intermediate value** in **Lower** field.

Step6: Enter appropriate vector in Shift field according to the vector used in **Memorize to** in Adjust window.

Step7: Press **Inspect**. Check if the inspection is completed properly.

1.11.4 Setting Procedure of Polarity Inspection

Step1: Select a lighting that a polarity is visually clear from the **Lighting** drop-down list.

Step2: Adjust the **Range** inspection window position as surrounding the polarity.

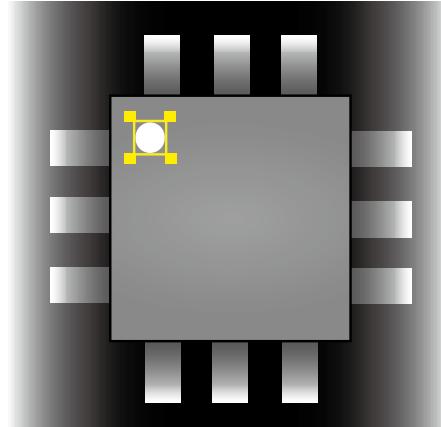


Figure 1-32 The Inspection Window for Polarity Inspection

Step3: Check if the sample value is in OK range. If it is out of OK range, adjust value in **Lower** field.

NOTE Sample value is the subtracted value between maximum and minimum brightness level inside the inspection window.

Step4: Enter appropriate vector in **Shift** field according to the vector used in **Memorize to** in Adjust window.

Step5: Press **Inspect**. Check if the inspection is completed properly.

1.11.5 Use of Average

Polarity inspection by using Average provides higher accuracy. In case of SOP, set the inspection window on point symmetric of the polarity by using point-symmetric copy and subtract the brightness level of both inspection windows to reduce the effective of dusty or noise. In case of QFP, set the inspection window on four corner of component by using X-symmetric copy, Y-symmetric copy and point-symmetric copy and subtract the brightness level of each inspection window.

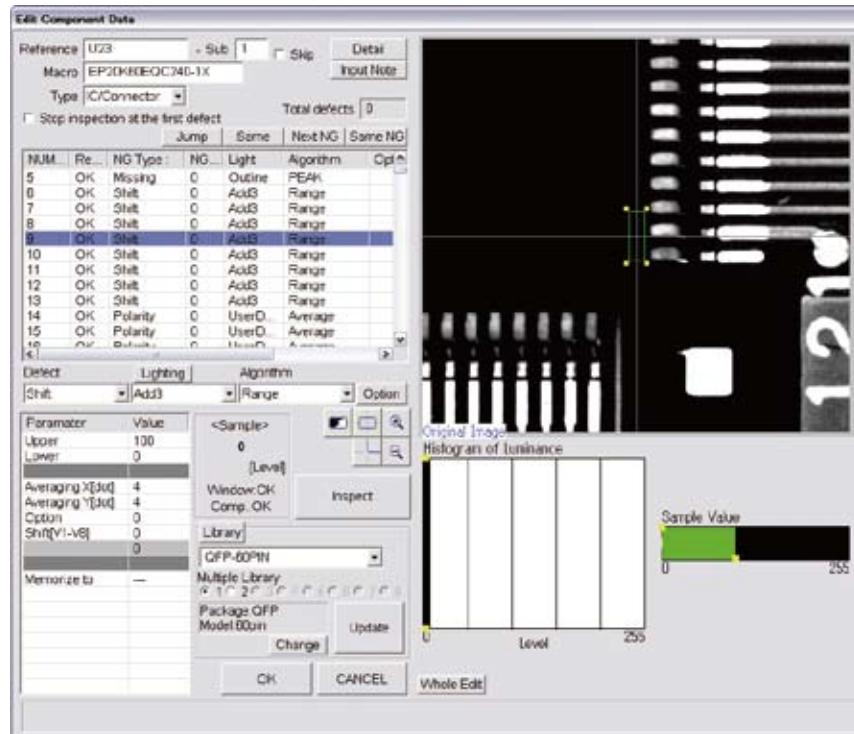


Figure 1-33 Average(Polarity)

| Parameter | Description |
|--------------------------------|--|
| Lighting | Select a lighting that the brightness level difference between the polarity and the surface is visually clear. |
| Algorithm | This inspection use Average and Mem1-Mem2 . |
| Upper, Lower | Enter 255 in Upper field and 0 in Lower field of Average . If brightness level of polarity is higher than brightness level of component body, enter 255 in Upper field and 1 in Lower field of Mem1-Mem2 . If brightness level of polarity is lower than brightness level of component body, enter -1 in Upper field and -255 in Lower field. |
| Shift[V1-V8] | This parameter is displayed only Average . Enter appropriate vector according to the vector used in Memorize to in Adjust window. |
| Memory1[M1-M8], Memory2[M1-M8] | This parameter is displayed only Mem1-Mem2 . If SOP is inspected, enter M1 in Memory1 field and M2 in Memory2 field. If QFP is inspected, make three Mem1-Mem2 inspection window. Enter M1 in Memory1 field in the three inspection window. Enter M2 in Memory2 in the first inspection window, M3 in Memory2 in the second inspection window, and M4 in Memory2 in the third inspection window. |
| Memorize to | If SOP is inspected, enter M1 or M2 in two Average inspection window to register the brightness level. Mem1-Mem2 calculates M1 minus M2 . If QFP is inspected, enter M1, M2, M3, or M4 in four Average inspection window to register the brightness level. Mem1-Mem2 calculates M1 minus M2, M1 minus M3, and M1 minus M4 . |

Table 1-14 Parameter of Average

1.11.6 Setting Procedure of Average(SOP)

- Step1: Select a lighting that a polarity is visually clear from the **Lighting** drop-down list.
- Step2: Change the algorithm of **Polarity** to **Average**.
- Step3: If polarity figure is circle, change the inspection window figure to circle. Press **Option** in the right side of **Algorithm**. Check **Use non-rectangle window** and **Circle Window** and press **OK**.
- Step4: Adjust inspection window size of **Polarity** with polarity mark.
- CAUTION** Change the lighting if there is no difference between polarity and component body with default lighting.
- Step5: Enter **255** in **Upper** field, **0** in **Lower** field, and **M1** in **Memorize to** field.
- Step6: Enter appropriate vector in **Shift** field according to the vector used in **Memorize to** in Adjust window.
- Step7: Right-click on **Average** in the inspection item list and select **Point-Symmetric Copy**.
- Step8: Enter **M2** in **Memorize to** field which made on Step7.
- Step9: Right-click on Average which made on Step7 in the inspection item list and select **Copy Window**.
- Step10: Change the algorithm which made on Step9 to **Mem1-Mem2**.
- Step11: If brightness level of polarity is higher than brightness level of component body, enter **255** in **Upper** field and **1** in **Lower** field. If brightness level of polarity is lower than brightness level of component body, enter **-1** in **Upper** field and **-255** in **Lower** field.
- Step12: Enter **M1** in **Memory1** field and **M2** in **Memory2** field.
- Step13: Press **Inspect**. Check if the inspection is completed properly.

1.11.7 Setting Procedure of Average(QFP)

- Step1: Refer to step1 to 6 of **1.11.6 Setting Procedure of Average(SOP)**.
- Step2: Right-click on **Average** in the inspection item list and select **Point-Symmetric Copy** to copy the inspection window onto polarity.
- Step3: Select two **Average** inspection window by pressing **Shift** and select **Y-Symmetric Copy** from right-click.
- Step4: Change the **Memorize to** of **Average** inspection window. Enter **M2**, **M3**, or **M4** in **Memorize to** field which made on Step2 and Step3.
- Step5: Right-click on **Average** which made on Step3 in the inspection item list and select **Copy Window**.
- Step6: Change the algorithm which made on Step5 to **Mem1-Mem2**.
- Step7: Right-click on **Average** which made on Step5 in the inspection item list and select **Copy Window**. Repeat the same step twice.
- Step8: Change the **Memory2** of **Mem1-Mem2** inspection window. Enter **M2**, **M3**, or **M4** in **Memory2** filed which made on step7.
- Step9: Change the **Upper** field and **Lower** field of **Mem1-Mem2**. If brightness level of polarity is higher than brightness level of component body, enter **255** in **Upper** field and **1** in **Lower** field. If brightness level of polarity is lower than brightness level of component body, enter **-1** in **Upper** field and **-255** in **Lower** field.
- Step10: Press **Inspect**. Check if the inspection is completed properly.

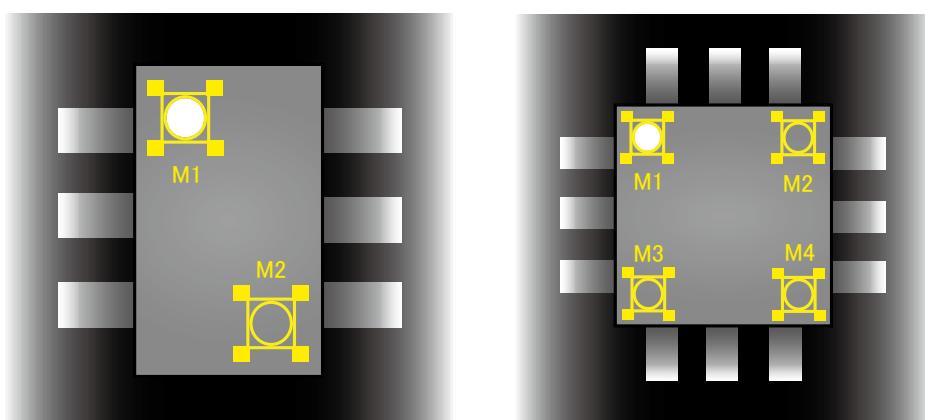


Figure 1-34 The Inspection Window for Polarity Inspection

1.12 LiftedLead

1.12.1 Inspection Overview

LiftedLead is the algorithm to calculate brightness level of solder in the lead end of IC components and in the pad end. In ideal solder joints form, the TopLight displays lower brightness level in pad lead area and higher brightness level is pad end area. LiftedLead is suitable for solder inspection of IC components. According the solder shape, brightness level in pad lead area will be higher.

In this case, if the brightness level is higher in pad end area, the result will be OK.

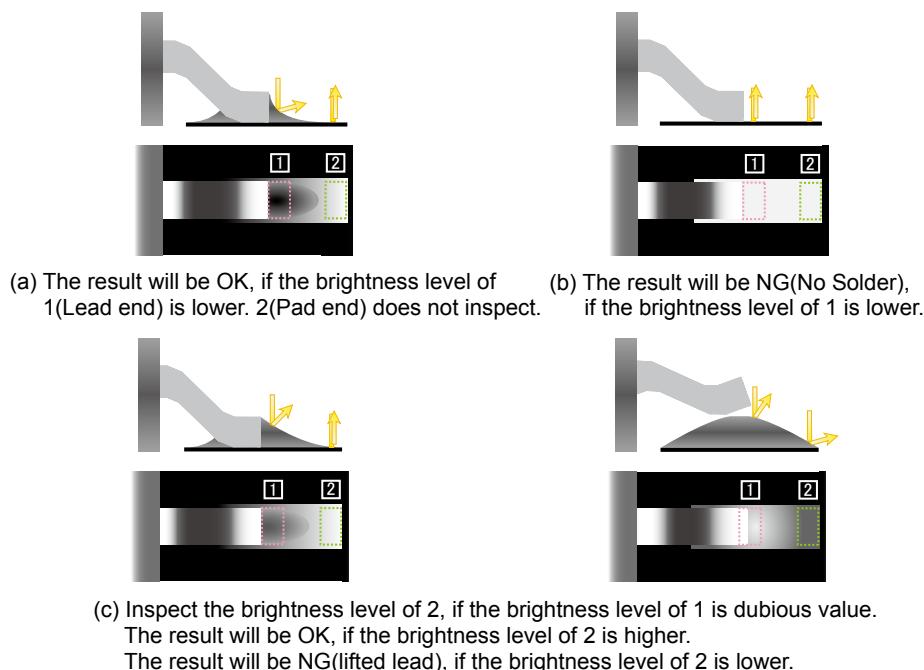


Figure 1-35 Inspection of LiftedLead

1.12.2 Parameter Setting

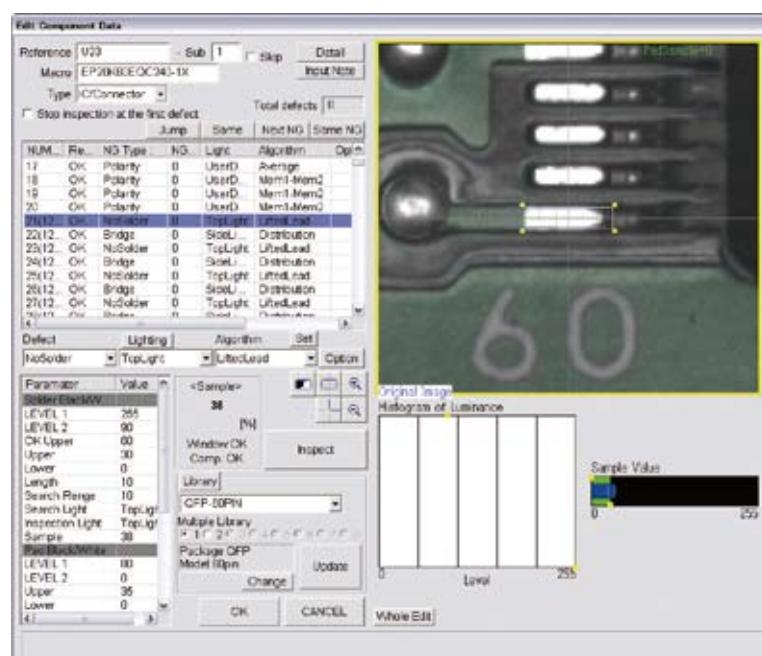


Figure 1-36 LiftedLead

| Parameter | Description |
|---------------|---|
| Lighting | Select TopLight . |
| Algorithm | Select LiftedLead . |
| Length, Width | Size of inspection window. The enter value is automatically changed after the inspection window is resized. |
| Shift[V1-V8] | Enter appropriate vector according to the vector used in Memorize to in Adjust window. |
| Memorize to | - |

Table 1-15 Parameter 1 of LiftedLead

| Parameter | Description |
|-----------------------------------|--|
| LEVEL1, LEVEL2 | Set the brightness level of no fillet shape. Enter 255 in LEVEL1 field. LEVEL2 is lower brightness level defined as NG(Default is 90). Enter the bigger value in LEVEL2 field if the OK sample value is higher and the result is NG. |
| OK Upper, Upper, Lower | The result is the percentage of specified brightness level as NG inside inspection window. The result will be NG, if sample value is higher than OK Upper . The result will be OK, if sample value is in the range between Upper and Lower . If sample value is in the range between OK Upper and Upper , pad end inspection will be done. Refer to Table 1-17 Parameter 3 of LiftedLead(Pad Black/White) to see detail settings of solder inspection at pad end area. Default of OK Upper is 60 , Upper is 10 . Enter 0 in Lower field. |
| Length | Width of the inspection area for solder inspection(surrounded by pink dotted line). |
| Search Range | Enlarge the value, automatically detecting the inspection area where the solder in the lead end(automatically picking between two pink lines) will extended. |
| Search Light, Inspection Light | Both Search Light and Inspection Light are fixed to TopLight . |
| Sample | The percentage of specified brightness level as NG inside window in pad lead area. |

Table 1-16 Parameter 2 of LiftedLead (Solder Black/White)

| Parameter | Description |
|-----------------------------------|--|
| LEVEL1, LEVEL2 | If it is difficult to inspect solder condition only in pad lead area, the pad end inspection will be done. In ideal solder joints form, the pad lead area is darker and pad end area is brighter(Refer to the left side of (c) Figure 1-35 Inspection of LiftedLead). Set the brightness level of LiftedLead. Enter smaller value in LEVEL1 field, if the OK sample value is lower and result is NG. LEVEL1 is the upper brightness level specified as NG. The default is 100 . Enter 0 in LEVEL2 field. |
| Upper, Lower | Tolerance of the sample value. The result will be OK, If sample value is in the range between Upper and Lower . Default of Upper is 10 . Enter 0 in Lower field. |
| Length | Width of the inspection area for lead end inspection(surrounded by green dotted line). |
| Search Range | Enlarge the value, automatically detecting the inspection area where the solder in the pad end(automatically picking between two green lines) will extended. |
| Search Light, Inspection Light | Search Light is fixed to SideLight . Inspection Light is fixed to TopLight . |
| Sample | The percentage of specified level as NG inside window in pad end area. In case the inspection is done in pad lead area, inspection at the pad end area is skipped and -1 will be displayed. |

Table 1-17 Parameter 3 of LiftedLead (Pad Black/White)

1.12.3 Setting Procedure

- Step1: Select **TopLight** from the **Lighting** drop-down list.
- Step2: Set search range for solder joint area. After changing **Search Range** value in **Solder Black/White**, press **Inspect**. Check if the pink dotted window is located on solder joint area.
- Step3: Set the inspection area of solder in the lead end. After changing **Length** value in **Solder Black/White**, press **Inspect**. Adjust the size of the pink dotted window.
- Step4: Check if the OK **Sample** value in **Solder Black/White** is in the between **Upper** and **Lower**. Enter bigger value in **LEVEL2** if OK sample value is out of **Upper** and **Lower** range.
- NOTE** The percentage of specified brightness level as NG is displayed.
- Step5: Set search area for pad end area. After changing **Search Range** value in **Pad Black/White**, press **Inspect**. Check if the green dotted window is located on pad end area.
- Step6: Set the inspection area of solder in the pad end. After changing **Length** value in **Pad Black/White**, press **Inspect**. Adjust the size of the green dotted window.
- Step7: Check if the OK **Sample** value in **Pad Black/White** is in the between **Upper** and **Lower**. Enter smaller value in **LEVEL1** if OK sample value is out of **Upper** and **Lower** range.
- Step8: Enter appropriate vector in **Shift** field according to the vector used in **Memorize to** in Adjust window.
- Step9: Right-click the **LliftedLead** inspection item list and select **Parameter Copy** to copy the parameter to other leads.
- Step10: Press **Jump** in the upper left side of the window and adjust inspection window size of the corner leads in each.
- Step11: Press **Inspect**. Check if the inspection is completed properly.

1.12.4 LiftedLead Setting Window

Press **Set** in the right side of **Algorithm**. The window shown in Figure 1-38 appears. The parameter can be set in this window. Press **Apply** to apply parameter. After all the settings are completed, press **OK**.

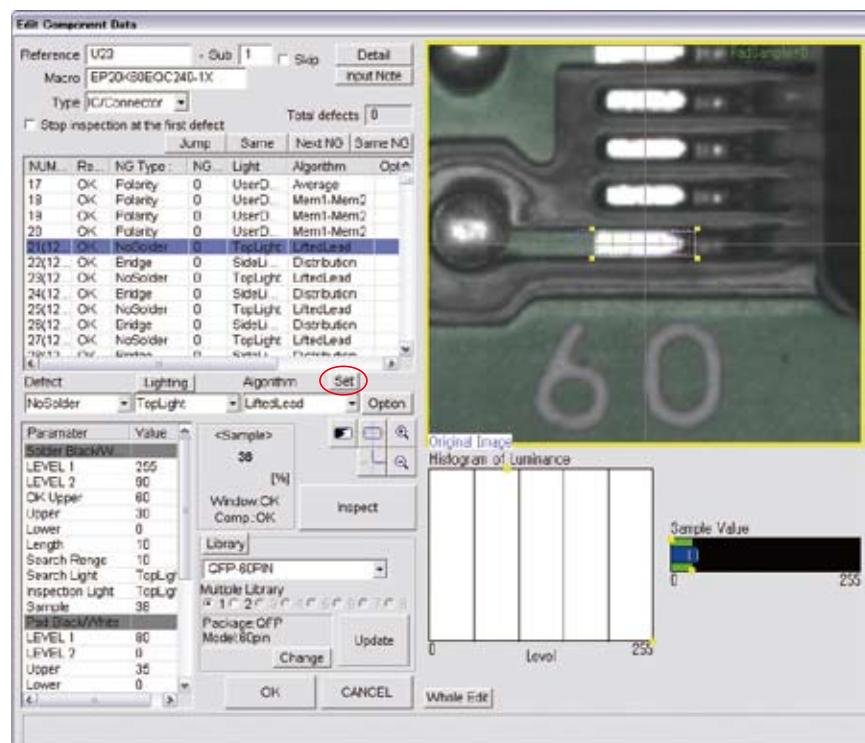


Figure 1-37 LiftedLead setting



Figure 1-38 Detail settings of LiftedLead

1.13 ASLeadLength

1.13.1 Inspection Overview

ASLeadLength is the algorithm to inspect leads length of IC components by measuring length from lead base area to lead end area.

Scanning with TopLight, brightness level of lead base area and lead end area are bright.

If lifted lead occurs, lead length is longer compare to normal condition.

If sample value is within OK range, the result will be OK.

ASLeadLength is suitable for lifted lead of IC components.

1.13.2 Parameter Setting

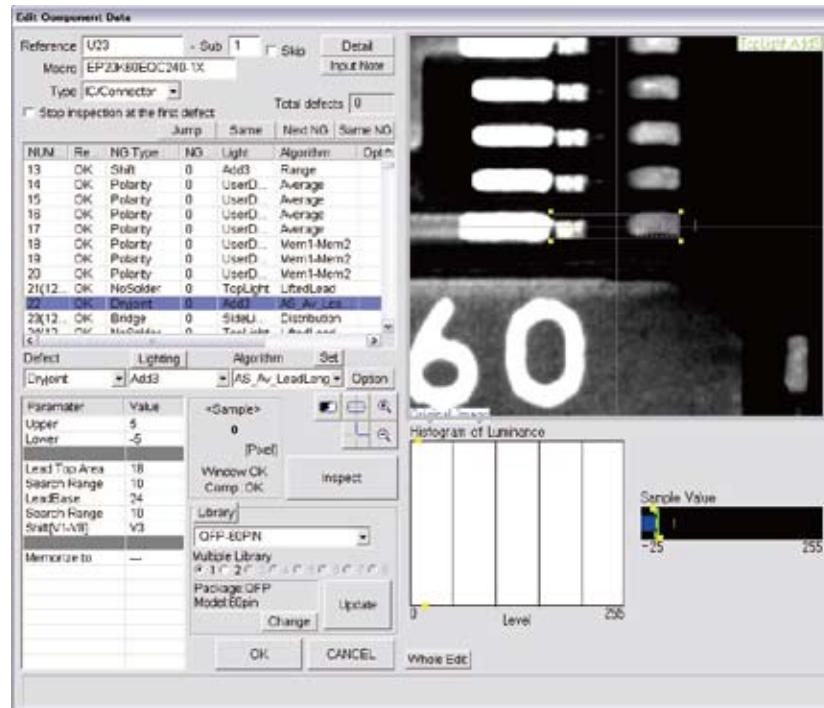


Figure 1-39 ASLeadLength

| Parameter | Description |
|---------------|--|
| Lighting | Select arbitrarily lighting. |
| Algorithm | Select ASLeadLength . |
| Upper, Lower | Check sample value of OK lead. Enter the value(sample value plus 20) in Upper field and the value(sample value minus 20) in Lower field. |
| Lead Top Area | The inspection window size of lead end area (=yellow dotted line). |
| Search Range | Default is 10 . Enter the bigger value to extend the search range of the lead end area. |
| LeadBase | The inspection window size of lead base area (=pink dotted line). |
| Search Range | Default is 10 . Enter the bigger value to extend the search range of the lead base area. |
| Shift[V1-V8] | Enter appropriate vector according to the vector used in Memorize to in Adjust window. |
| Memorize to | - |

Table 1-18 Parameter of ASLeadLength

1.13.3 Setting Procedure

Step1: Set search range for the lead end area. After changing parameter of **Search Range** below **Lead Top Area**, press **Inspect**. Check if the lead end area is surrounded by yellow dotted line automatically or not.

Step2: Set inspection window size for lead end area. After changing parameter of **Lead Top Area**, press **Inspect**. Adjust the size of the yellow dotted window.

Step3: Set search range for the lead base area. After changing parameter of **Search Range** below **LeadBase**, press **Inspect**. Check if lead base area is surrounded by pink dotted line automatically or not.

Step4: Set inspection window size for lead base area. After changing parameter of **LeadBase**, press **Inspect**. Adjust the size of the pink dotted window.

Step5: Check **Sample Value** of OK lead. Enter the value(**Sample Value** plus 20) in **Upper** field and the value(**Sample Value** minus 20) in **Lower** field.

NOTE

Sample value is distance of lead end area to lead base area.

Step6: Enter appropriate vector in **Shift** field according to the vector used in **Memorize to** in Adjust window.

Step7: Right-click on **ASLeadLength** in the inspection item list and select **Parameter Copy** to copy parameter to the other leads.

Step8: Press **Jump** in the upper left side of the window and adjust inspection window size of the corner leads in each.

Step9: Press **Inspect**. Check if the inspection is completed properly.

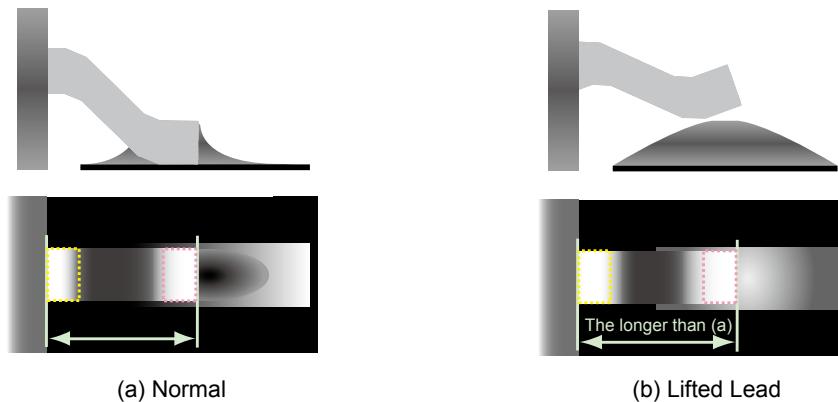


Figure 1-40 Lifted Lead Inspection by ASLeadLength

1.14 AS_Av_LeadLength

1.14.1 Inspection Overview

AS_Av_LeadLength is the algorithm to inspect leads length of IC components by measuring length from lead base area to lead end area.

Scanning with TopLight, brightness level of Lead base area and lead end area are bright.

If lifted lead occurs, lead length is longer compare to normal condition.

Sample value of ASLeadLength is lead length but sample value of AS_Av_LeadLength is average of lead length on the same line. If sample value is within OK range, the result will be OK.

AS_Av_LeadLength is suitable for lifted lead of IC components.

CAUTION It is also not valid in combination with IC_Solder2.

1.14.2 Parameter Setting

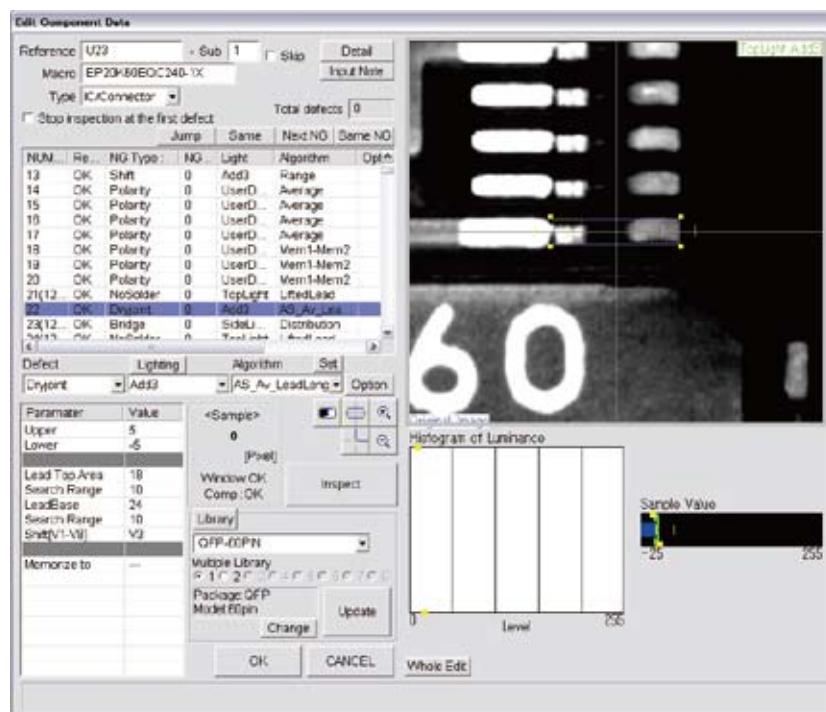


Figure 1-41 AS_Av_LeadLength

| Parameter | Description |
|---------------|---|
| Lighting | Select arbitrarily lighting |
| Algorithm | Select AS_Av_LeadLength . |
| Upper, Lower | Enter 5 in Upper field and -5 in Lower field. |
| Lead Top Area | The inspection window size of lead base area(=yellow dotted line). |
| Search Range | Default is 10 . Enter bigger value to extend search range of the lead end area. |
| LeadBase | The inspection window size of lead base area(=pink dotted line). |
| Search Range | Default is 10 . Enter bigger value to extend search range of the lead base area. |
| Shift[V1-V2] | Enter appropriate vector according to the vector used in Memorize to in Adjust window. |
| Memorize to | - |

Table 1-19 Parameter of AS_Av_LeadLength

1.14.3 Setting Procedure

- Step1: Set search range for the lead end area. After changing parameter of **Search Range** below **Lead Top Area**, press **Inspect**. Check if lead end area is surrounded by yellow dotted line automatically or not.
- Step2: Set inspection window size for lead end area. After changing parameter of **Lead Top Area**, press **Inspect**. Adjust the size of the yellow dotted window.
- Step3: Set search range for the lead base area. After changing parameter of **Search Range** below **LeadBase**, press **Inspect**. Check if lead base area is surrounded by pink dotted line automatically or not.
- Step4: Set inspection window size for lead base area. After changing parameter of **LeadBase**, press **Inspect**. Adjust the size of the pink dotted window.
- Step5: Enter **5** in **Upper** field and **-5** in **Lower** field.

NOTE

Sample value is distance of lead end area to lead base area.

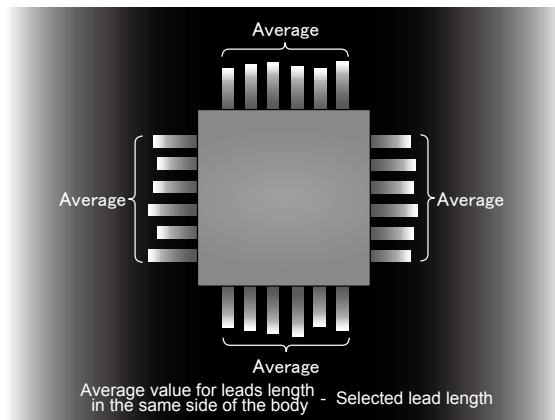


Figure 1-42 Lifted lead inspection by AS_Av_LeadLength

- Step6: Enter appropriate vector in **Shift** field according to the vector used in **Memorize to** in **Adjust** window.
- Step7: Right-click on **AS_Av_LeadLength** in the inspection item list and select **Parameter Copy** to copy parameter to the other leads.
- Step8: Press **Jump** in the upper left side of the window and adjust inspection window size of the corner leads in each.
- Step9: Press **Inspect**. Check if the inspection is completed properly.

1.15 Distribution

1.15.1 Inspection Overview

Distribution is the algorithm to detect bridge of IC components.

Set the inspection window between leads. If bridge occurs between leads, the solder which is brighter than PCB acrosses lateral direction of the inspection window.

The inspection window will be separated to several windows in longitudinal direction. The differences between maximum minus minimum brightness level in each separated windows are calculated.

The sample value is the minimum value calculated among separated window.

1.15.2 Parameter Setting

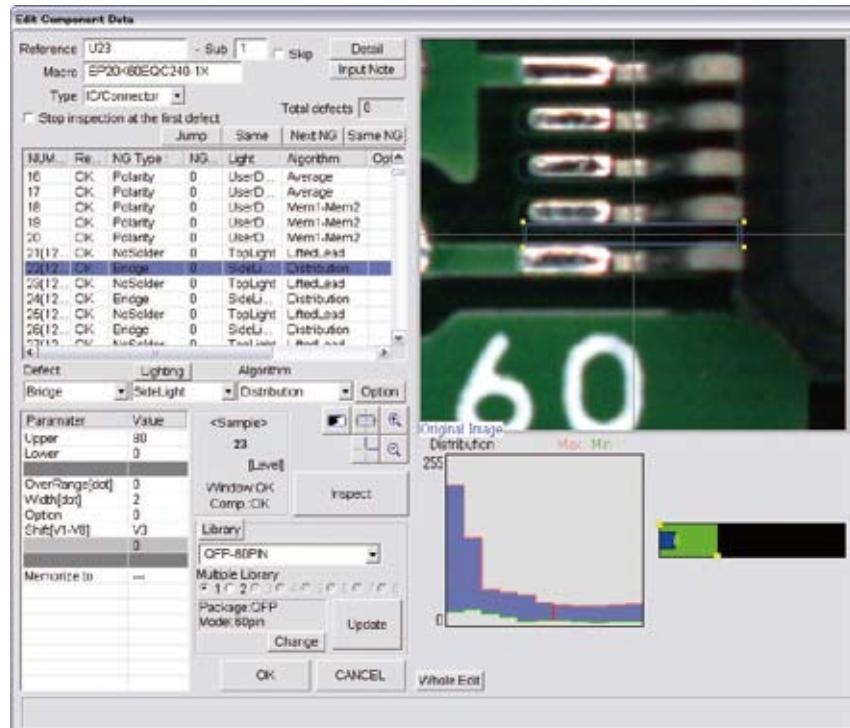


Figure 1-43 Distribution

| Parameter | Description |
|----------------|--|
| Lighting | Select SideLight . Change the lighting to LowLight , if flux is detected as bridge with SideLight. |
| Algorithm | Select Distribution . |
| Upper, Lower | Set OK range. |
| OverRange[dot] | Enter 0 . |
| Width[dot] | Default is 2 . Set the bigger value to reduce noise. |
| Option | Enter 0 . |
| Shift[V1-V8] | Enter appropriate vector according to the vector used in Memorize to in Adjust window. |
| Memorize to | - |

Table 1-20 Parameter of Distribution

1.15.3 Setting Procedure

Step1: Select **SideLight** from the **Lighting** drop-down list.

NOTE Change the lighting to **LowLight**, if flux is detected as bridge with SideLight.

Step2: Surround inspection window from lead base to pad end. Adjust lateral direction of the inspection window with lead pitch.

Step3: Enter value in **Upper** field and **Lower** field.

NOTE **80** is for **Upper** and **0** is for **Lower** as a reference value.

Step4: Enter appropriate vector in **Shift** field according to the vector used in **Memorize to** in Adjust window.

Step5: Right-click on **Distribution** in the inspection item list and select **Parameter Copy** to copy parameter to the other leads.

Step6: Lead pitch is adjusted automatically by pressing **Jump** in the upper left side of the window.

Step7: Press **Inspect**. Check if the inspection is completed properly.

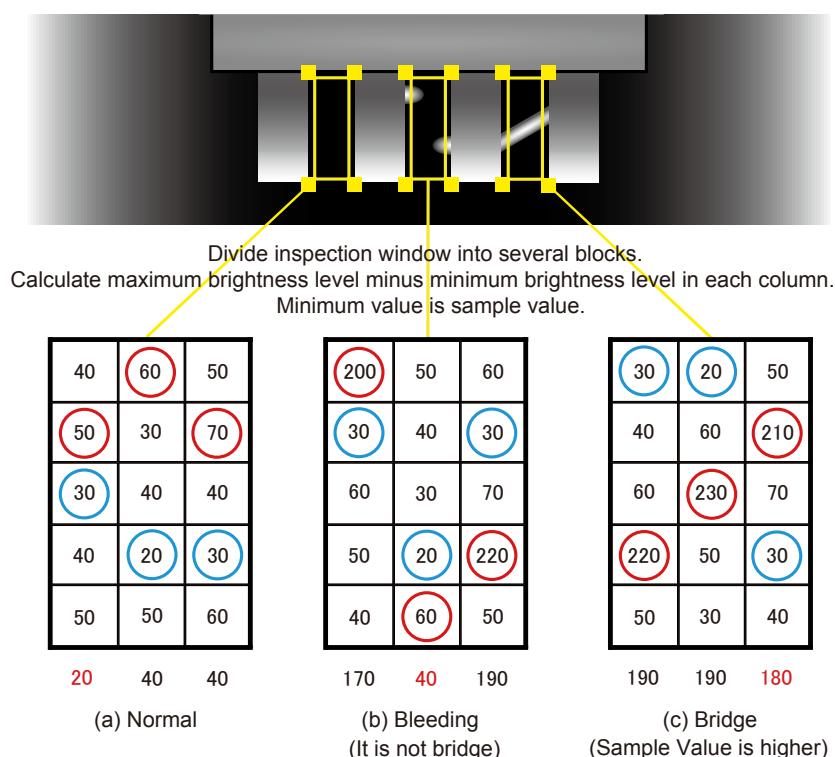


Figure 1-44 Bridge Inspection by Distribution

1.16 IC_Solder2

1.16.1 Inspection Overview

IC_Solder2 is the algorithm to inspect lead's length and shift, solder condition and lifted lead in one inspection window with high accuracy.

It automatically locates “inspection points” (lead end, lead base, pad end) on an IC component. Inspection flow is as following, lead length, lead shift, solder, copper, and lifted lead.

CAUTION If lead length or lead shift inspection is NG, all the following inspections, solder, copper and lifted lead inspections are skipped.

CAUTION IC_Solder2 is not available for two lighting system machine. It is also not valid in combination with AS_Av_LeadLength.

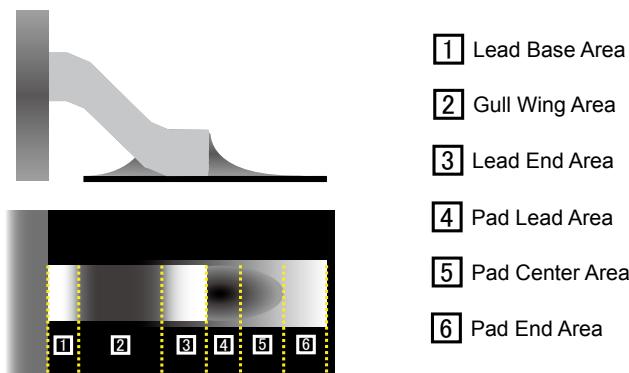


Figure 1-45 Inspection of IC_Solder2

1.16.2 Parameter Setting

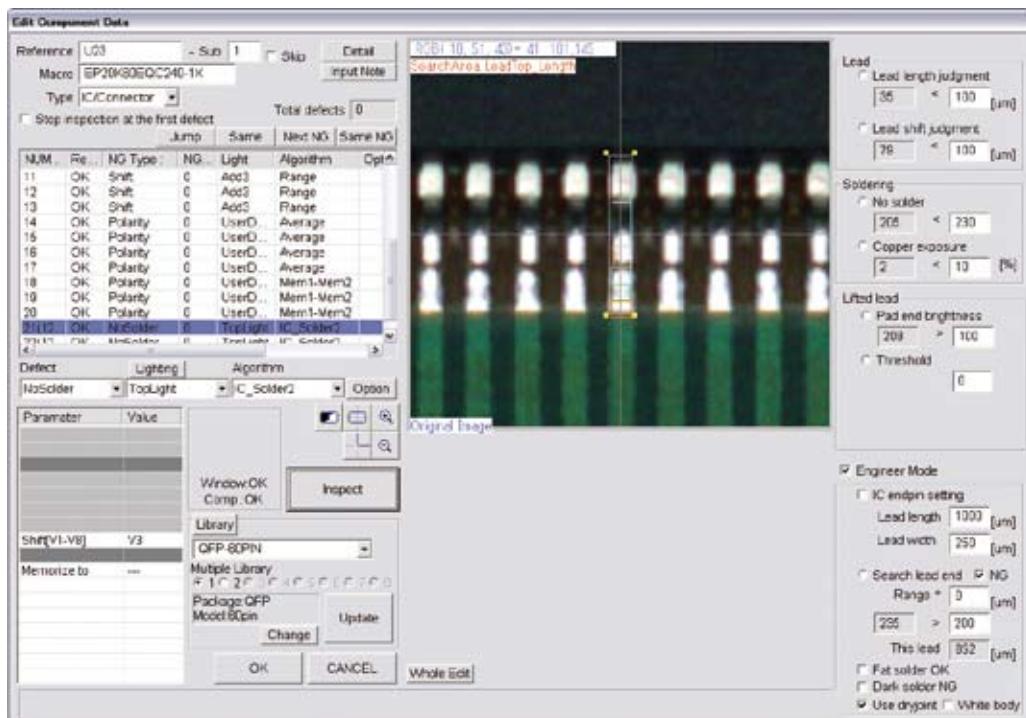


Figure 1-46 IC_Solder2

| Parameter | Description |
|--------------|---|
| Lighting | Select SPECT . |
| Algorithm | Select IC_Solder2 . |
| Shift[V1-V8] | Enter appropriate vector according to the vector used in Memorize to in Adjust window. |
| Memorize to | - |

Table 1-21 Parameter1 of IC_Solder2

| Parameter | Description |
|-----------------------|---|
| Lead length judgement | Set inspection parameters for lead length inspection. Refer to 1.16.3 Setting Procedure Step5 for details. |
| Lead shift judgement | Set inspection parameters for lead shift inspection. Refer to 1.16.3 Setting Procedure Step6 for details. |

Table 1-22 Parameter3 of IC_Solder2 (Lead Inspection)

| Parameter | Description |
|-----------------|--|
| No solder | Set inspection parameters for solder inspection. Refer to 1.16.3 Setting Procedure Step7 for details. |
| Copper exposure | Set inspection parameters for copper inspection. Refer to 1.16.3 Setting Procedure Step8 for details. |

Table 1-23 Parameter3 of IC_Solder2 (Solder Inspection)

| Parameter | Description |
|--------------------|--|
| Pad end brightness | Set inspection parameters for lifted lead inspection. Refer to 1.16.3 Setting Procedure Step9 for details. |
| Threshold | Set inspection parameters for lifted lead inspection. Refer to 1.16.3 Setting Procedure Step10 for details. |

Table 1-24 Parameter4 of IC_Solder2 (Lifted Lead Inspection)

| Parameter | Description |
|----------------|--|
| Engineer Mode | Engineer Mode enable to set detailed setting for parameters. The check mark to set parameter with bar chart. |
| Lead length | Enter measured value in lead length. |
| Lead width | Enter measured value in lead width. |
| Range | Search range for edge between solder and lead end. |
| This lead | Display measured lead length. |
| Fat solder OK | Judge heavy solder amount as OK. |
| Dark solder NG | Judge small solder amount as NG. |
| Use dryjoint | Detect dryjoint. |
| White body | It is useful to search component body which is brighter than lead base. |

Table 1-25 Parameter5 of IC_Solder2 (Detail Setting)

NOTE Check a radio button and corresponding histogram shows in the lower right side of the display.

NOTE When press **Inspect**, colored mark showed in the left side of the radio button If it's NG. Red refers NG and white refers skip inspection.

1.16.3 Setting Procedure

Step1: Adjust the size of the inspection window to surround the lead base to pad end. Window width should be same as pad width.

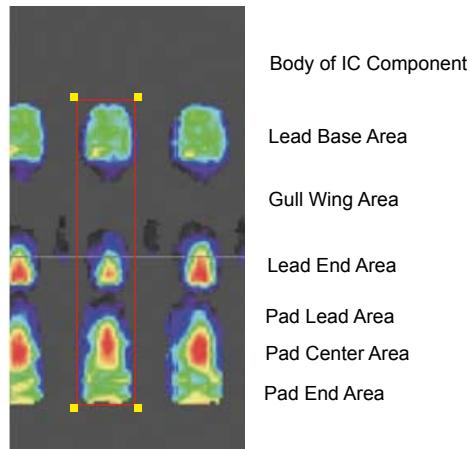


Figure 1-47 Inspection window of IC_Solder2

Step2: Lead length and width will be displayed in the upper right corner of the window if left-click a lead base and drag the pointer to opposite corner of the lead end. Enter window size shown in the upper right side of the display in **Lead length** and **Lead width**.

CAUTION Measure lead size at next lead of inspection window otherwise the inspection window is misaligned.

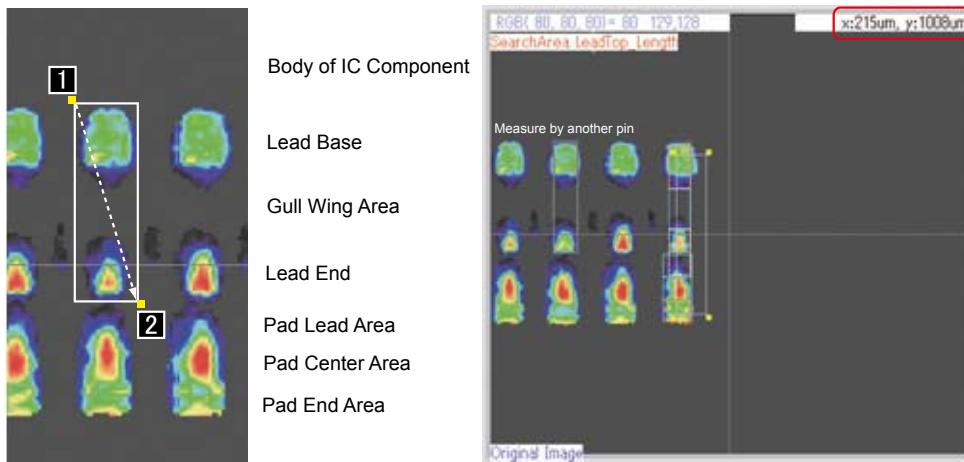


Figure 1-48 Enter Lead length and Lead width

Step3: It automatically locates the edge of lead end area and pad lead area by searching the edge of lead end and solder. Check if the pink dotted area includes both edge of the lead end area and solder. If the search range is too small or too large, change **Range** value to adjust search area size.

NOTE

NG should be always checked.

NOTE

The center of the search area is at the lead end. Adjust search area size by changing **Range** value.

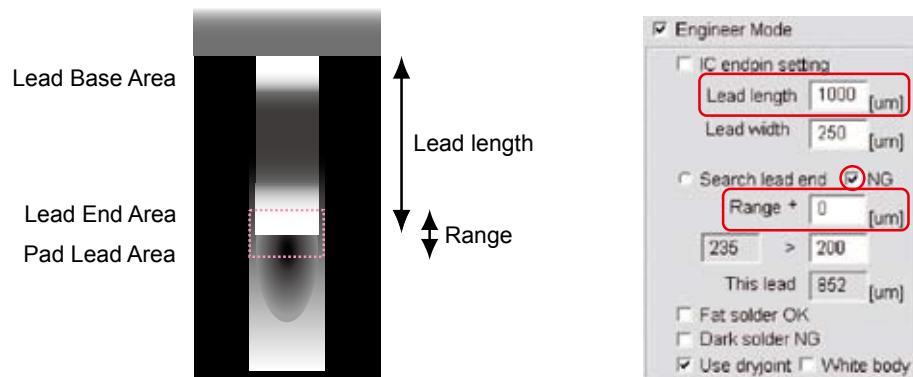


Figure 1-49 Adjust Search Range

Step4: Enter brightness different level between lead end and pad lead area in the lower right side of **Range**. In search area, the algorithm calculates maximum brightness level minus minimum brightness level as sample value(Sample value is shown in the lower left side of **Range**). If the sample value is larger than OK range, lead end will be located. Default is **200**. Depends on solder condition, adjust parameter.

NOTE

In case lead end is covered with heavy solder, fillet area has brighter brightness level and the difference between lead end and pad lead is smaller. In this case, enter search range lower than **200**.

Step5: This is the parameter setting for lead length inspection. It calculates the average value of leads length in the same side of the component. Then the different amount between average length and actual lead length is shown as sample value(Gray text-box in the lower left side of **Lead length judgement**). If the sample value is lower than OK range, the result will be OK. The inspection logic is same as **1.14 AS_Av_LeadLength**.

Default is **100[μm]**. If necessary, change the value depends on inspection accuracy.

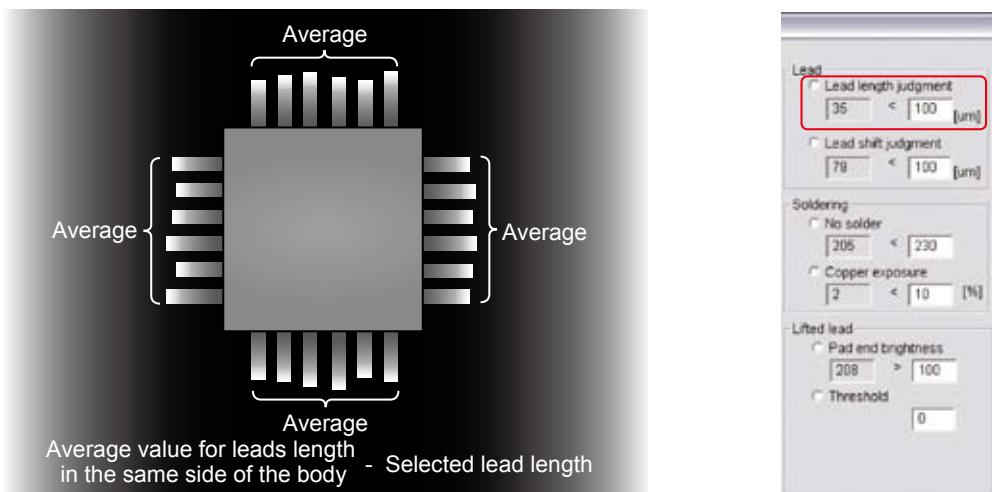


Figure 1-50 Lead length

Step6: This is the parameter setting of lead shift inspection. The shift amount from lead end area and pad end area is shown as sample value(Gray text-box in the lower left side of **Lead shift judgement**). If the sample value is lower than OK range, the result will be OK. Default is **100[μm]**. If necessary, change the value depends on inspection accuracy.

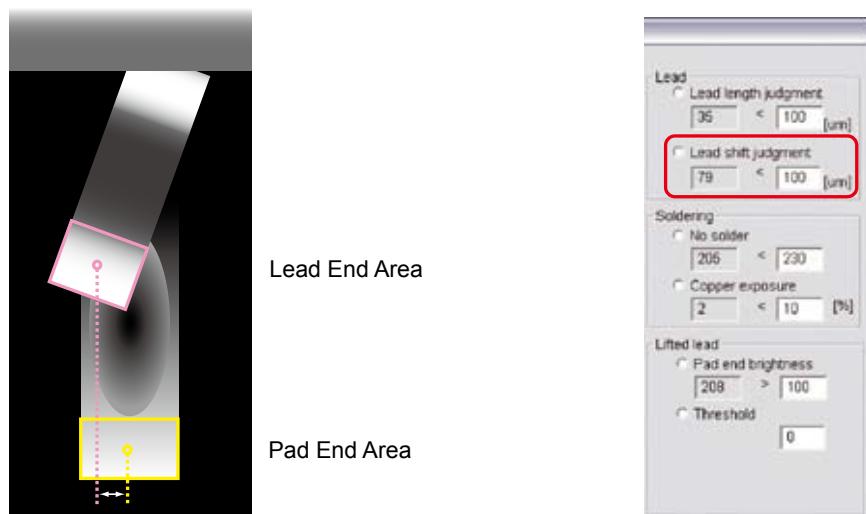


Figure 1-51 Lead shift

Step7: This is the parameter setting for solder inspection. It calculates average brightness level in pad lead area and pad center area as sample value. If the sample value is lower than OK range, the result will be OK. Default is **230**. If necessary, change the value depends on inspection accuracy.

NOTE

The average brightness level is lower in case of no solder or insufficient solder.

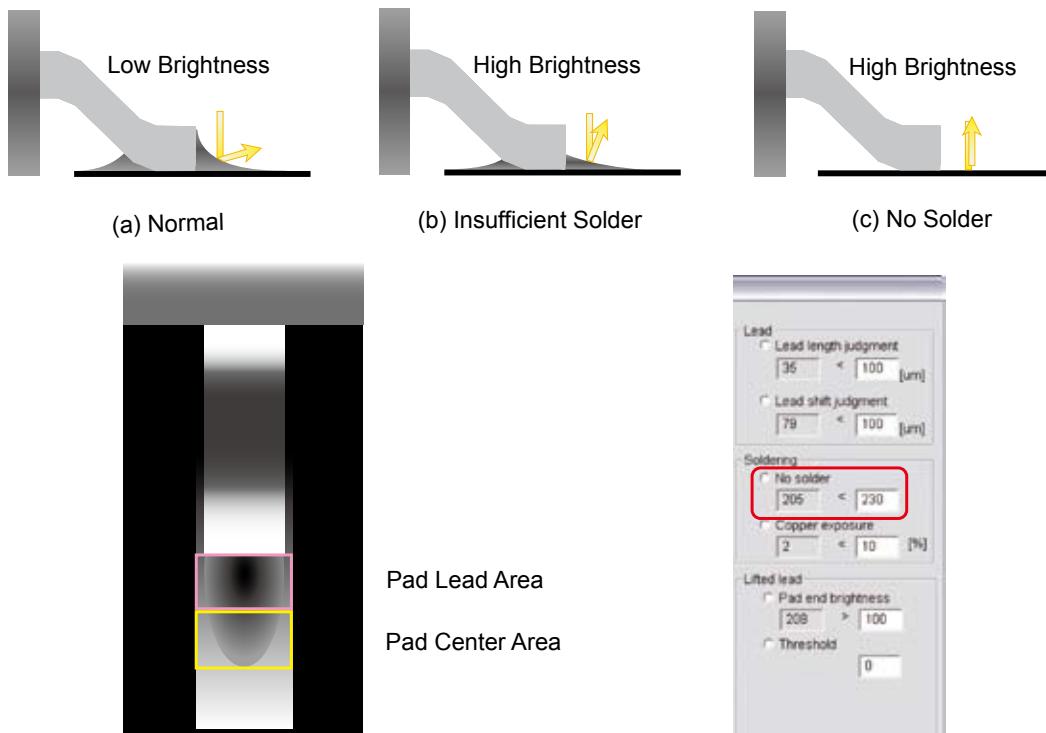


Figure 1-52 Solder Inspection

Step8: This is the parameter for copper exposure inspection. It is useful to detect copper area due to insufficient solder. It calculate the percentage of copper color defined as more than 80% of hue and color saturation and more than 60% of brightness in pad lead, pad center, and pad end area. If the sample value is lower than OK range, the result will be OK. The default is **10%**. If necessary, change the value depends on the solder condition.

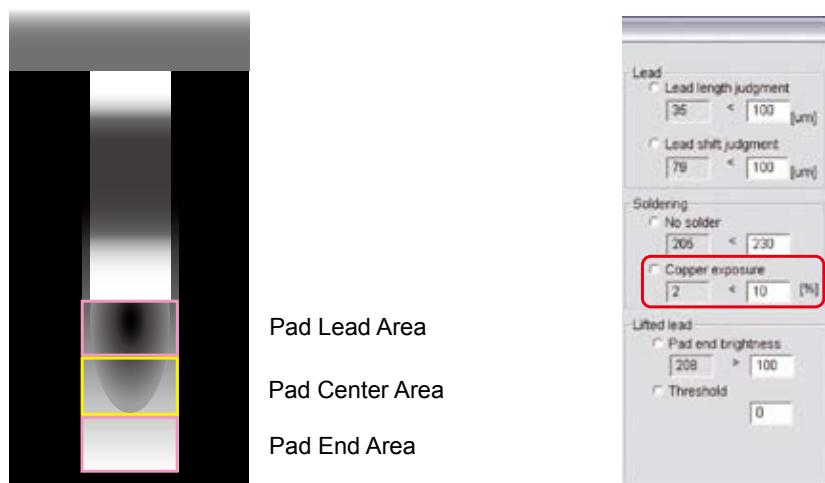


Figure 1-53 Copper Inspection

Step9: This is the parameter of lifted lead inspection. Lifted lead inspection has two steps. First inspection calculates average brightness level in pad end area. If the sample value is higher than OK range, the result will be OK. Default is **100**. If necessary, change the value depend on inspection accuracy. If the first inspection is NG, the second inspection shown in step10 will be done.

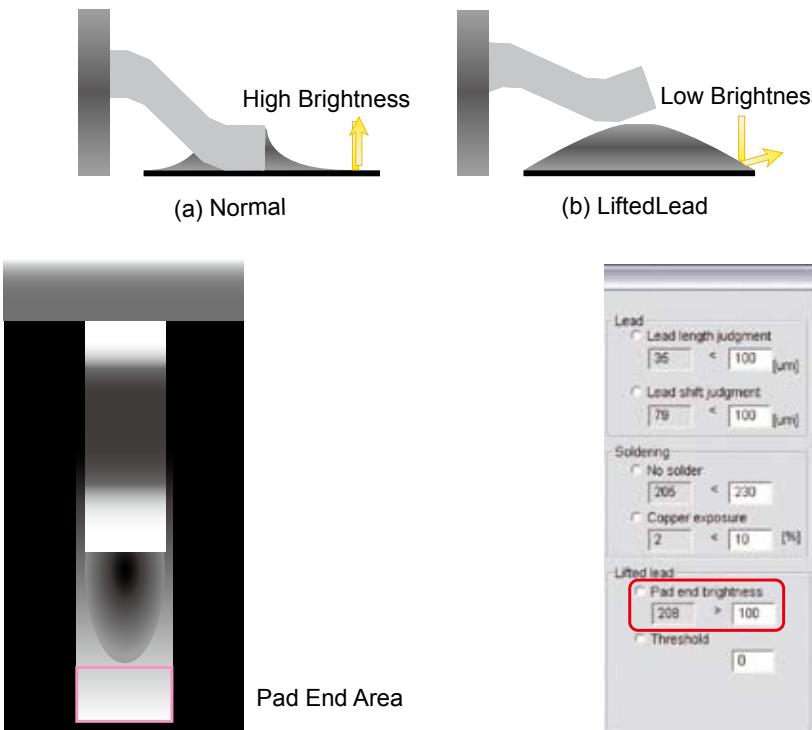
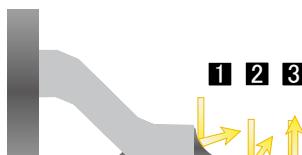


Figure 1-54 Lifted Lead Inspection 1

Step10: If the first inspection shown in Step9 is NG, the second inspection will be done. The comparison brightness level in pad lead, pad center, and pad end area will be shown as sample value. If solder is in good condition, the brightness level is darker in pad lead area and brighter in pad end area. This inspection is separated into two steps. The comparison of brightness level, **the brightness level in pad end area minus pad center area** and **the brightness level in pad end area minus pad lead area**, is shown as sample value in first inspection. If the sample value is larger than **Threshold**, the result will be OK(Default is 0). If either **the brightness level in pad end area minus pad center area** and **the brightness level in pad center area minus pad lead area** is NG, the second inspection, **the brightness level in pad center area minus pad lead area**, will be done. If the sample value is larger than **Threshold**, the result will be NG. If necessary, change the value depends on the solder condition.

- 
- (1) Calculate following equation. If the result will be NG, proceed to (2).

$$\text{Pad End Area(3)} - \text{Pad Center Area(2)} > \text{Setting Value} (\text{Default is } 0)$$

$$\text{Pad End Area(3)} - \text{Pad Lead Area(1)} > \text{Setting Value} (\text{Default is } 0)$$
 - (2) Calculate following equation. If the result will be NG, judged as lifted lead.

$$\text{Pad Center Area(2)} - \text{Pad Lead Area(1)} > \text{Setting Value} (\text{Default is } 0)$$

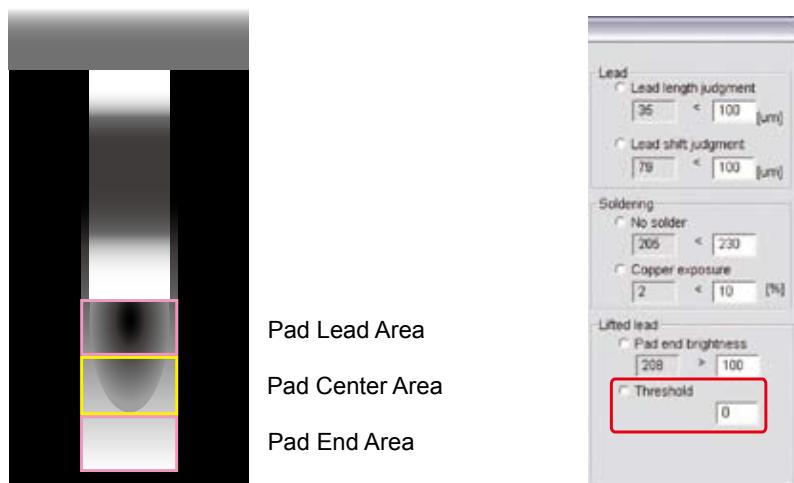


Figure 1-55 Lifted Lead Inspection 2

Step11: If solder volume is extremely high, the brightness level in pad area is darker. In case to judge high-volume-solder as OK, check **Fat solder OK**. If **Fat solder OK** is checked, the lifted lead inspection is skipped. Also after copper exposure inspection, If the average brightness level of pad lead, pad center and pad end area is lower than 100, the result will be OK.

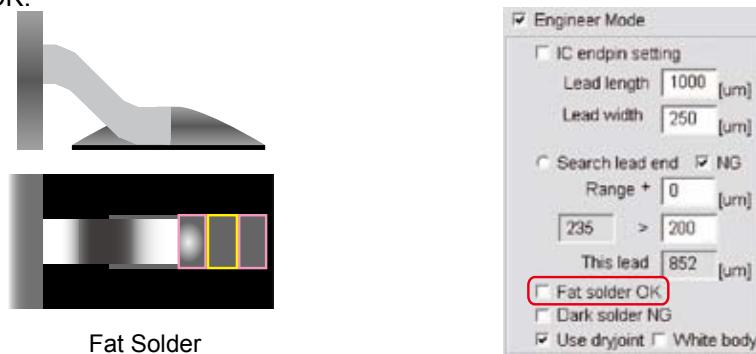


Figure 1-56 Fat solder OK

Step12: If solder volume is extremely low, the solder brightness level in pad end area is darker than pad center area. Check **Dark solder NG** if necessary. The inspection is done as following steps, lead shift, lead bend, no solder, copper exposure, and lifted lead. If **Dark solder NG** is checked, lifted lead inspection will be changed. After copper exposure inspection, the average brightness level in pad lead, pad center, and pad end area is calculated. If the sample value is lower than 100, the result will be NG. In this case, the lifted lead inspection will be skipped.

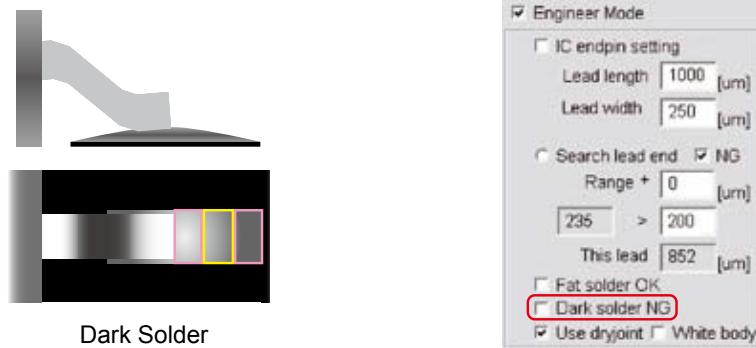


Figure 1-57 Dark Solder NG

Step13: In case of dry joint, the brightness level in pad center area is brighter than pad lead and pad end area. Check **Use dryjoint** if necessary. If **Use dryjoint** is checked and either of brightness level in **the brightness level in pad end area minus pad center area** or **the brightness level in pad end area minus pad lead area** is failed, the result will be NG. In this case, the third inspection, **the brightness level in pad center area minus pad lead area**, is skipped.

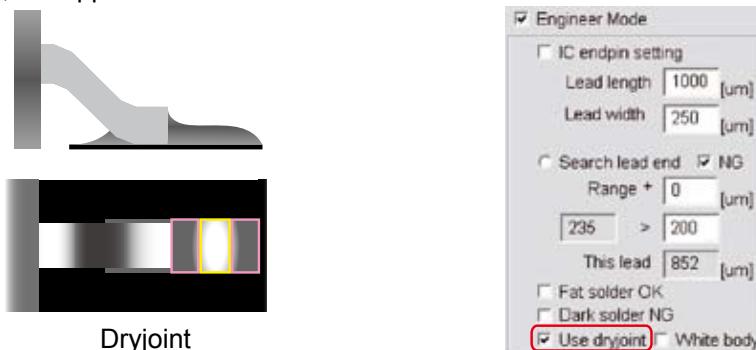


Figure 1-58 Use dryjoint

Step14: Check **White body** in case the body is brighter than leads.

Step15: If you change number of leads, press **Detail** shown in Figure 1-59. The window shown in Figure 1-60 appears.

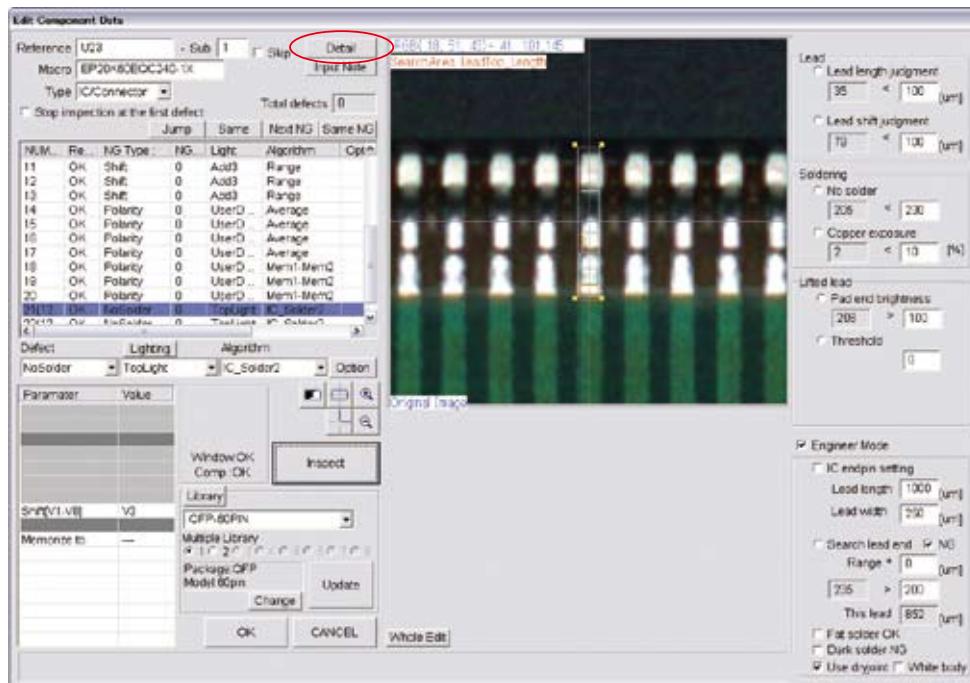


Figure 1-59 Detail

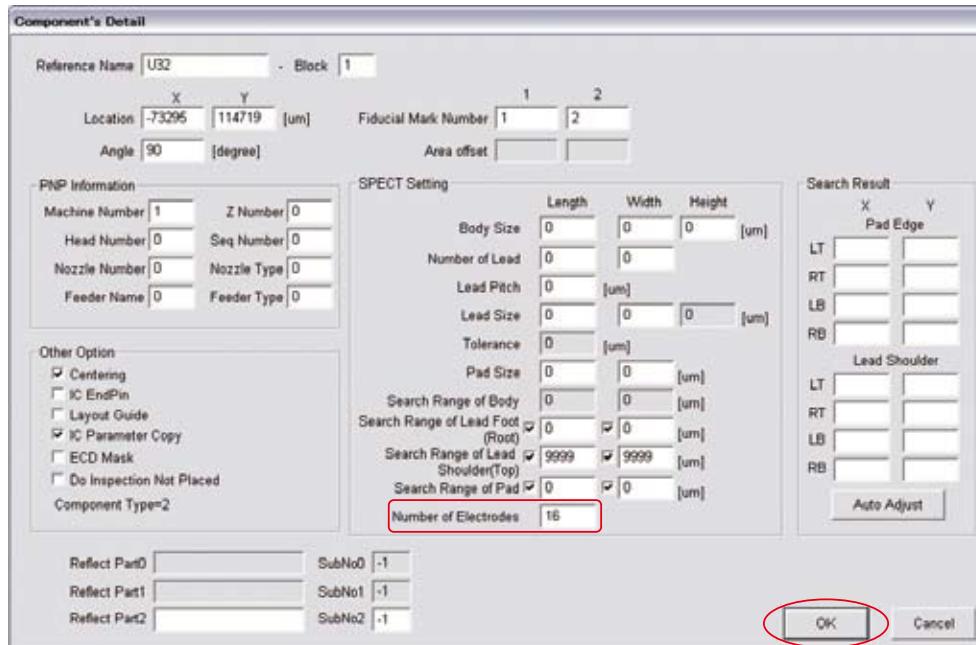


Figure 1-60 Number of Electrodes

Step16: Enter number of leads in **Number of Electrodes** and press **OK**.

Step17: Enter appropriate vector in **Shift** field according to the vector used in **Memorize to** in Adjust window.

Step18: Press **Inspect**. Check if the inspection is completed properly.

1.17 New_OCR

1.17.1 Inspection Overview

New_OCR is the algorithm to recognize character.

Register target the character before inspection. The sample value is number of characters matched with the target characters.

New_OCR can recognize alphanumeric characters.

New_OCR is suitable for missing and miss-mounting of any components inspection.

1.17.2 Parameter Setting

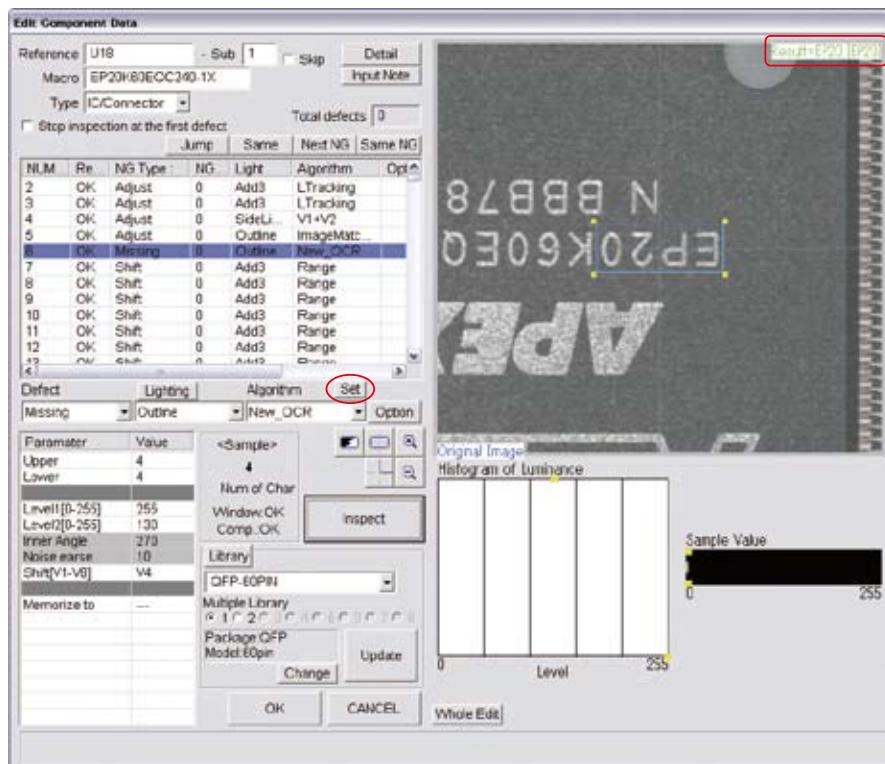


Figure 1-61 New_OCR

| Parameter | Description |
|---|--|
| Lighting | Select a lighting that characters are visually clear. |
| Algorithm | Select New_OCR . |
| Upper, Lower | After setting parameters in another window, the recognized number of characters is reflected in the Upper value and Lower value. If the number of target characters recognized characters are the same, the result will be OK. |
| level1[0-255], level2[0-255], Inner Angle, Noise erase | No needs to setting. The entered parameter values in Figure 1-62 window will be applied. |
| Shift[V1-V8] | Enter appropriate vector according to the vector used in Memorize to in Adjust window. Enter V4 to reflect the amount of misalignment calculated by ImageMatchEx . |
| Memorize to | - |

Table 1-26 Parameter of New_OCR

1.17.3 Setting Procedure

Step1: Select a lighting that the characters are visually clear from the **Lighting** drop-down list.

Step2: Adjust the size of the inspection window to surround the target characters.

Step3: Press **Set** in the right side of **Algorithm**. The window shown in Figure 1-62 appears.



Figure 1-62 Setting window of New_OCR

Step4: Adjust the character angle by **Rotation Degree** if the character is not upright.

Step5: Adjust the luminosity and the noise to recognize a character clearly. Adjust the **Bright setting** of **Level1** and **Level2** then press **Apply**, recognition **Result** will be displayed in the right side of **OK Value**. Adjust the parameter to recognize characters correctly. If the recognized characters are noisy, reduce the noise with slide-bar in the right side of **Clear Noise**.

Step6: If the similar characters such as “1” and “I” or “0” and “O” is miss recognized, enter similar characters to two text boxes in the right side of **Similar character** and press **Add** to register. Either of characters are recognized the result will be OK. Press **Delete** if remove similar characters.

Step7: If the character is recognized correctly, press **<-**, the recognition result is copy **Result** to **Reference**. Press **OK**.

Step8: Enter appropriate vector in **Shift** field according to the vector used in **Memorize to** in Adjust window.

NOTE Enter **V4** if you use positional correction information on ImageMatchEx. For details, refer to **1.20 ImageMatchEx** for details.

Step9: Press **Inspect** and check if the recognized character is display correctly in the upper right side of the window of Figure 1-61.

1.18 ImageMatchEx

1.18.1 Inspection Overview

ImageMatchEx is the algorithm to inspect for pattern matching inspection.

ImageMatchEx compares registered image and actual image inside the inspection window and calculate matching rate.

ImageMatchEx can be recognized not only alphanumeric character but also symbol.

ImageMatchEx is suitable for missing or miss-mounting of any components inspection.

NOTE ImageMatchEx can be used for Adjust. This algorithm correct the amount of misalignment of CAD data with the actual position on the components.

1.18.2 Parameter Setting

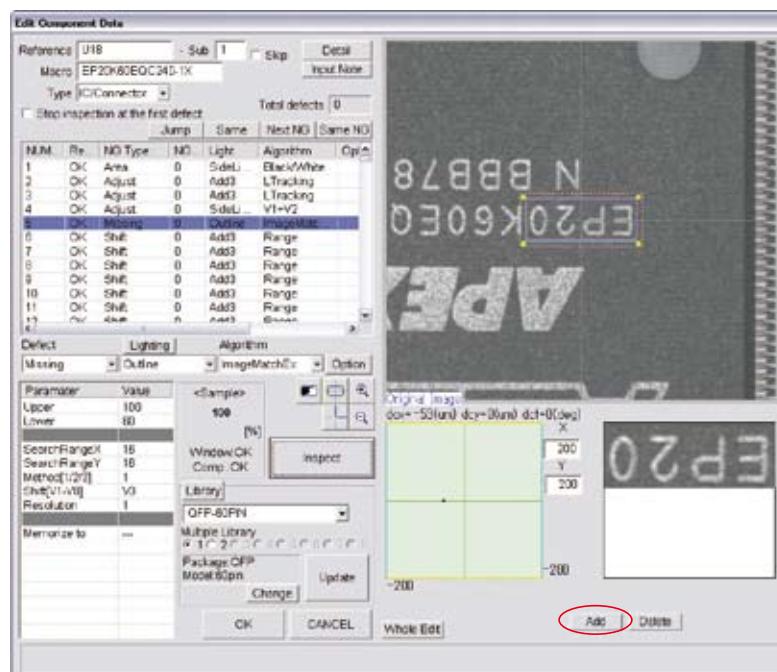


Figure 1-63 ImageMatchEx

| Parameter | Description |
|---|--|
| Lighting | Select a lighting that characters are visually clear. |
| Algorithm | Select ImageMatchEx . |
| Upper, Lower | Set OK range. |
| SearchRangeX, SearchRangeY | Set search range(=yellow dotted line). Enter the bigger value to enlarge the search range. If the search range is not appropriate, the calculation time might be long. |
| Method [1/2/3] | Enter 1. |
| Shift[V1-V8] | Enter appropriate vector according to the vector used in Memorize to in Adjust window. If ImageMatchEx use for Adjust, enter 0. |
| Resolution | Enter 1. |
| Memorize to | Enter V4 in Memorize to to reflect this amount of misalignment to other algorithm. |
| The X and Y in the lower right side of the window | Enter 99999. If ImageMatchEx use for Adjust, enter OK range in X,Y field. |

Table 1-27 Parameter of ImageMatchEx

1.18.3 Setting Procedure

- Step1: Select a lighting that the characters are visually clear from the **Lighting** drop-down list.
- Step2: Adjust the size of the inspection window to surround the target characters.
- Step3: Press **Add** in the lower side of the window. The window shown in Figure 1-64 appears and press **Cancel**. The image surrounded by inspection window appears.

NOTE

Press **Delete** and **Inspect**, then the reference image is deleted.

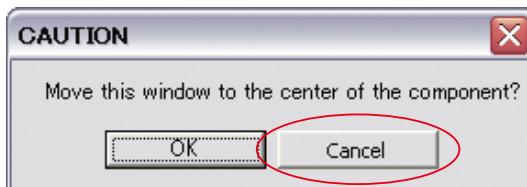


Figure 1-64 Dialog of ImageMatchEx

- Step4: Adjust the value of **SearchRangeX** and **SearchRangeY** to define the search range.
- Step5: Enter value in **Upper** field and **Lower** field.

NOTE

As a guide, **100** for **Upper**, **60** for **Lower**.

- Step6: Enter **99999** in **X** field and **Y** field in the lower right side of the window.

NOTE

To use ImageMatchEx for position alignment, enter the tolerance of misalignment value to X field and Y field.

- Step7: Enter appropriate vector in **Shift** field according to the vector used in **Memorize to** in Adjust window.
- Step8: Enter **V4** in **Memorize to** to reflect this amount of misalignment to other algorithm.
- Step9: Press **Inspect**. Check if the inspection is completed properly.

1.19 OCV

1.19.1 Inspection Overview

OCV is the algorithm to inspect for pattern matching inspection.

Register characters of component as font.

Scanned image is inspected by pattern matching with registered image as font.

OCV is suitable for missing and miss-mounting of any components inspection.

1.19.2 Parameter Setting

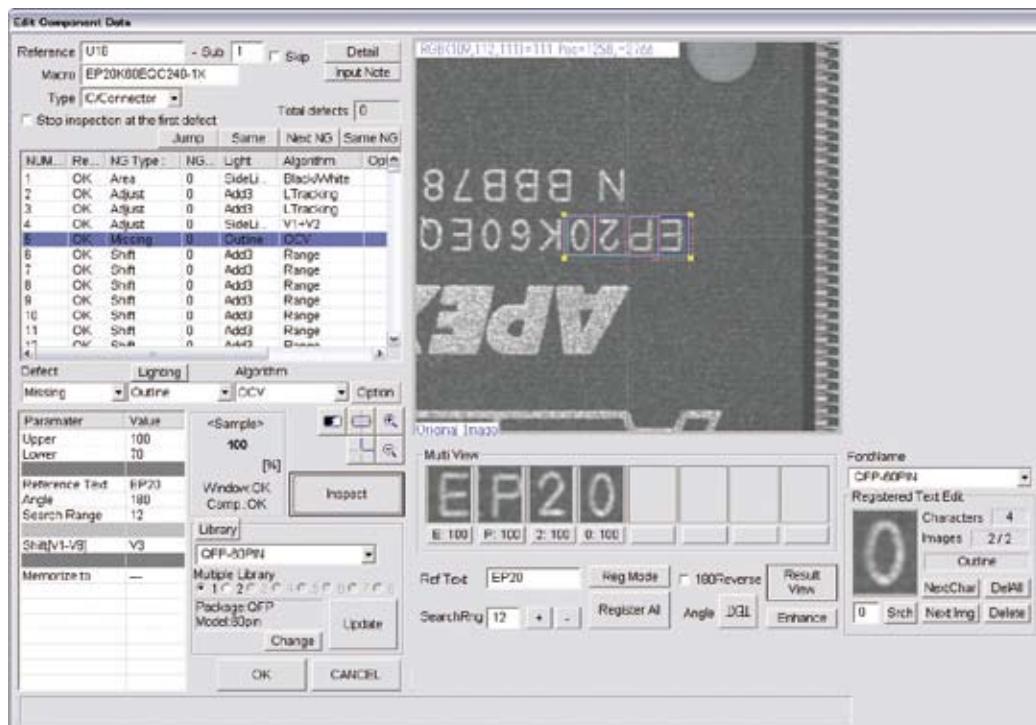


Figure 1-65 OCV

| Parameter | Description |
|----------------|---|
| Lighting | Select a lighting that characters are visually clear. |
| Algorithm | Select OCV . |
| Upper, Lower | Set OK range. |
| Reference Text | No need for setting. Ref Text shown in Table 1-29 is displayed. |
| Angle | No need for setting. Angle shown in Table 1-29 is displayed. |
| Search Range | No need for setting. SearchRng shown in Table 1-29 is displayed. |
| Shift[V1-V8] | Enter appropriate vector according to the vector used in Memorize to in Adjust window. |
| Memorize to | - |

Table 1-28 Parameter of OCV

| Item | Description |
|--------------|--|
| Multi View | Display recognized characters. Match percentage for each character is displayed below each character. Sample value refers the lowest match percentage of inspected characters. |
| Ref Text | Enter characters to read. |
| SearchRng | Search Range for characters. Display the search range as the yellow dotted line. Enter the search range or press + and - to adjust the search range. |
| Reg Mode | Register characters one by one. |
| Register All | Register all characters. |
| 180 Reverse | Check the 180 Reverse for components with no polarity. |
| Angle | Adjust direction of text by pressing TEXT . |
| Result View | Display is changed Result View (=scanned image) -> Font View (=registered image) -> Source View (=search image) by pressing Result View . |
| Enhance | Display a contrast enhanced image by Black/White. |

Table 1-29 Each Item of OCV Window

NOTE

Adjust the inspection window direction by pressing **TEXT** to become the same direction as the target.

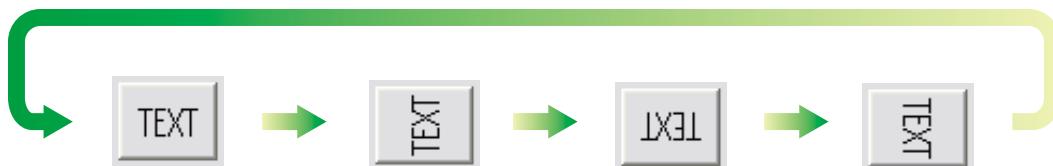


Figure 1-66 Angle

1.19.3 Setting Procedure

Step1: Select a lighting that characters are visually clear from the **Lighting** drop-down list.

Step2: Adjust direction of text by pressing **TEXT**.

Step3: Enter correct value of text in **Ref Text**.

CAUTION Do not use two-byte character, space, tab, and symbolic character(< > : " / | ? * . , ; & % =).

Step4: Adjust direction of text by pressing **TEXT**.

Step5: Check the **180 Reverse** for components with no polarity.

Step6: Enter appropriate vector in **Shift** field according to the vector used in **Memorize to** in **Adjust** window.

Step7: Press **Inspect**.

Step8: Press **Register All**.

Step9: Press **Inspect**. Check if the inspection is completed properly.

NOTE If the library is assigned to two component type, press **Option** in the right side of **Algorithm**. The window shown in Figure 1-67, check the **Only for This Macro Component** and press **OK**.

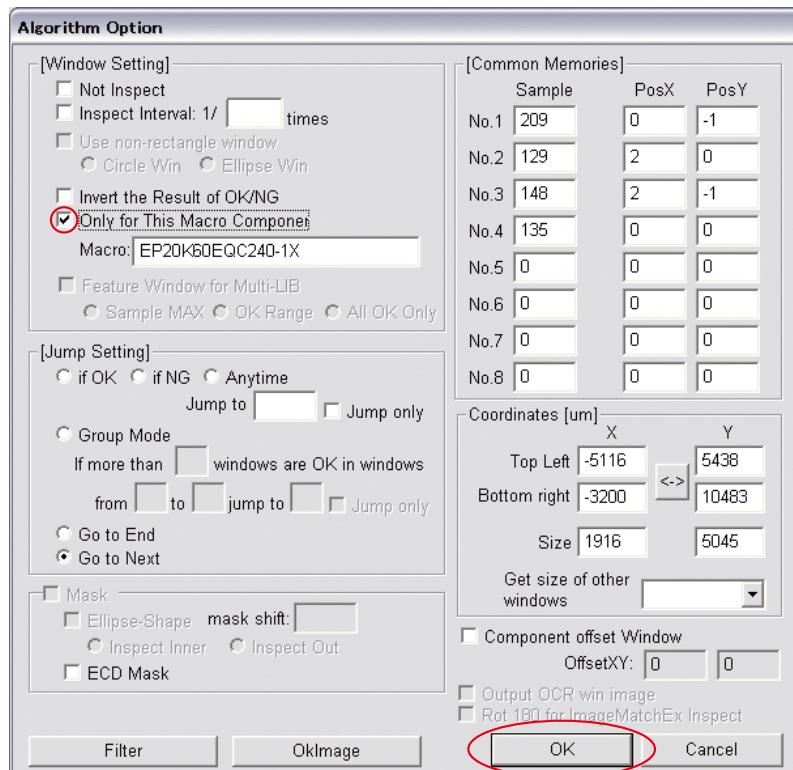


Figure 1-67 OCV

1.19.4 Registered Text Edit

Registered images can check in **Registered Text Edit**.

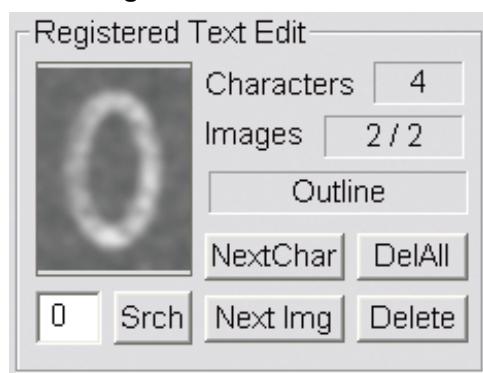


Figure 1-68 Registered Text Edit

| Item | Description |
|-------------------------|---|
| Characters | Display number of registered characters(Excluding same characters). |
| Images | Number of registered images for each character. |
| Below image of Text-box | Display a lighting name of current image. |
| Next Char | Display next character in the library. |
| Next Img | Display next registered character for that character. |
| DelAll | Delete all images. |
| Delete | Delete current image. |
| Srch | Enter the character in field and press Srch to search for a character. |

Table 1-30 Each Item of Registered Text Edit

1.20 Barcode

1.20.1 Inspection Overview

Barcode is the algorithm to recognize 1D barcode. Register the target barcode. The result will be OK if digit number of recognized barcode is in tolerance.

Barcode is suitable for PCBs traceability.

NOTE Refer to **2.2 Barcode Pro** for 2D barcode inspection.

1.20.2 Parameter Setting

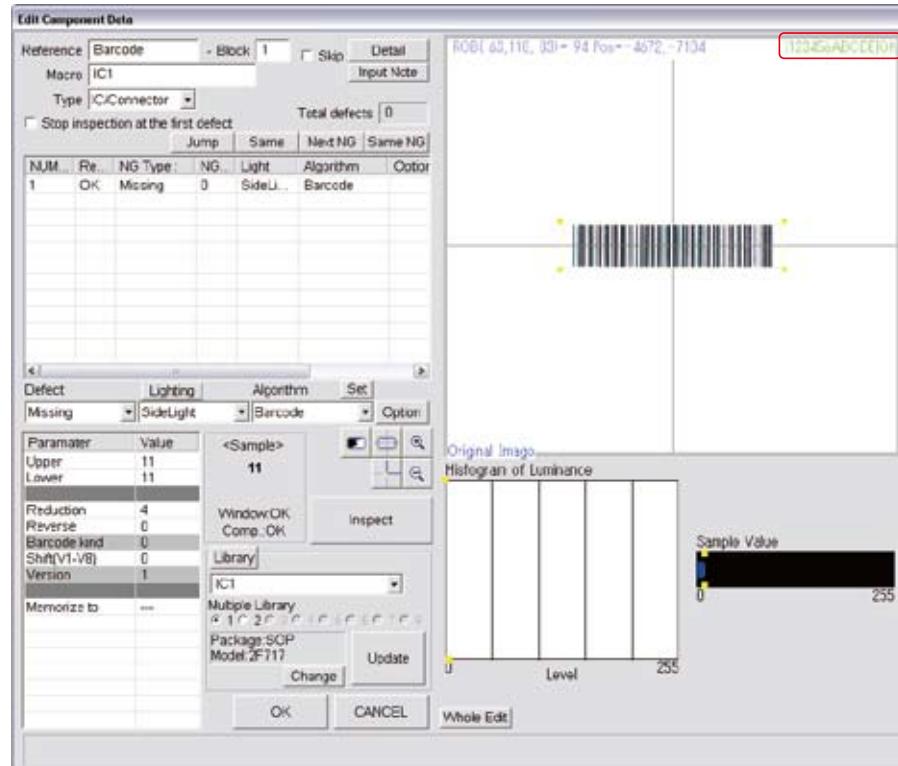


Figure 1-69 Barcode

| Parameter | Description |
|--------------|--|
| Lighting | Select a lighting that barcode is visually clear. |
| Algorithm | Select Barcode . |
| Upper, Lower | Enter the barcode digit number in Upper field and Lower field. The sample value is the digit number of recognized barcode. If the target digit and recognized digit number is the same, the result will be OK. |
| Reduction | Enter 4 . |
| Reverse | Enter 0 if the brightness level of the barcode is lower than surrounding brightness. Enter 1 if it is higher. |
| Barcode kind | - |
| Shift[V1-V8] | Enter appropriate vector according to the vector used in Memorize to in Adjust window. |
| Version | - |
| Memorize to | - |

Table 1-31 Parameter of Barcode

1.20.3 Setting Procedure

- Step1: Select a lighting that barcode is visually clear from the **Lighting** drop-down list.
- Step2: Adjust the size of the inspection window to surround the barcode. Leave space at the either end of barcode(make space three times wider than widest blank space in the barcode).

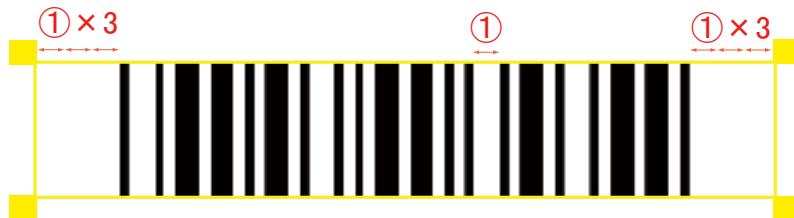


Figure 1-70 Inspection window of Barcode

- Step3: Press **Set** in the right side of **Algorithm**. The window shown in Figure 1-71 appears. Select the barcode kind and press **OK**.

NOTE

Check **BT_Autodetect for one dimension code**, the barcode will be recognized automatically. However inspection time will be longer.

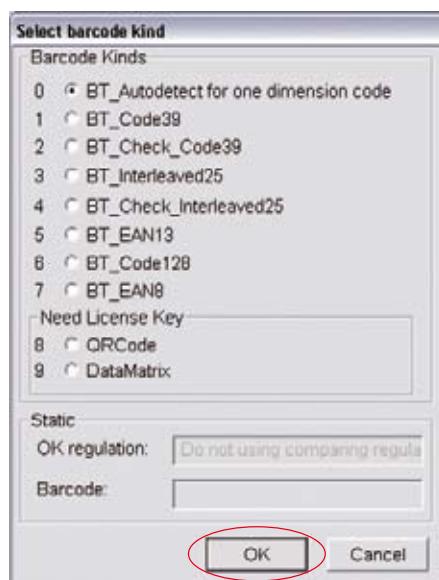


Figure 1-71 Barcode kind

- Step4: Press **Inspect** and check if the alphanumeric character of the barcode is correctly displayed in the upper right side of the window shown in Figure 1-69.

2 Optional Function

2.1 OCR_Pro

2.1.1 Inspection Overview

OCR_Pro is the algorithm to recognize characters.

Any kinds of font can be recognized.

OCR_Pro is suitable for the missing or miss-mounting component inspection.

2.1.2 Parameter Setting

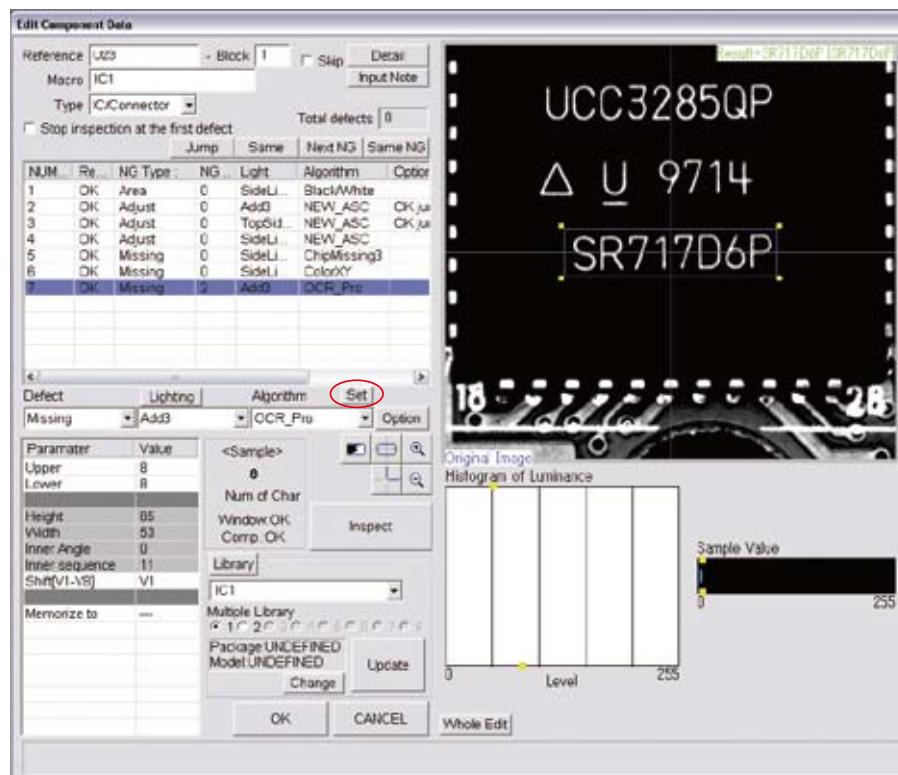


Figure 2-1 OCR_Pro

| Parameter | Description |
|--|---|
| Lighting | Select a lighting that characters are visually clear. |
| Algorithm | Select OCR_Pro . |
| Upper, Lower | Enter the number of characters to Upper field and Lower field. The sample value shows the number of recognized characters. The registered character and the recognized character are corresponding, the result will be OK. |
| Height, Width, Inner Angle, Inner Sequence | No need for setting. Value will be applied to the window displayed by pressing Set . |
| Shift[V1-V8] | Enter appropriate vector according to the vector used in Memorize to in Adjust window. |
| Memorize to | - |

Table 2-1 Parameter of OCR_Pro

2.1.3 Setting Procedure

- Step1: Select a lighting that characters are visually clear.
- Step2: Adjust the size of the inspection window to surround the target characters.
- Step3: Press **Set** in the right side of **Algorithm**. The window shown in Figure 2-2 appears.



Figure 2-2 OCR_Pro1

- Step4: Adjust the character angle by Angle setting if the character is not upright.
- Step5: Press **Define Font**. The window in Figure 2-3 is appeared. Switch the lighting to **Black / White** by pressing -->.



Figure 2-3 OCR_Pro2

Step6: Adjust the brightness level by pressing + and - in the lower side of --> until the characters are visually clear.

Step7: Enter the arbitrary font name to the text-box at the right of **Add Font**, and press **Add Font**. The font name is displayed in the drop-down list in the right side of **Register**.

NOTE

Enter the font name within 8 characters.



Figure 2-4 OCR_Pro3

Step8: Left-click in the upper left part of the first character.

Adjust the window size by dragging the mouse to the lower right side of the first character.



Figure 2-5 OCR_Pro4

Step9: Press **Cut out**, the selected image is displayed under the **Current Image**. Enter the first character to the text-box in the right side of **Char:**.

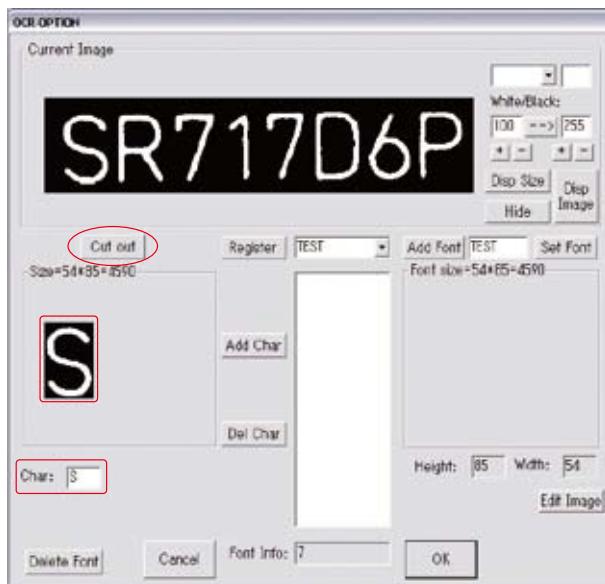


Figure 2-6 OCR_Pro5

Step10: Press **Add Char** to register the character and the image as a font added in Step7.

NOTE To delete characters, select character from the list-box and press **Del Char**.

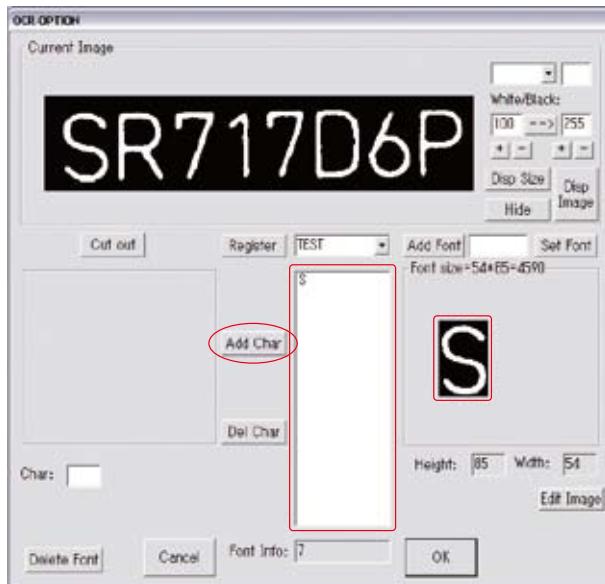


Figure 2-7 OCR_Pro6

Step11: Press **Disp Size**, the window will be displayed again, and it to surround the second character. Register the second character as follows Step9 and Step10. After the second character, repeat the same procedure to register all characters.

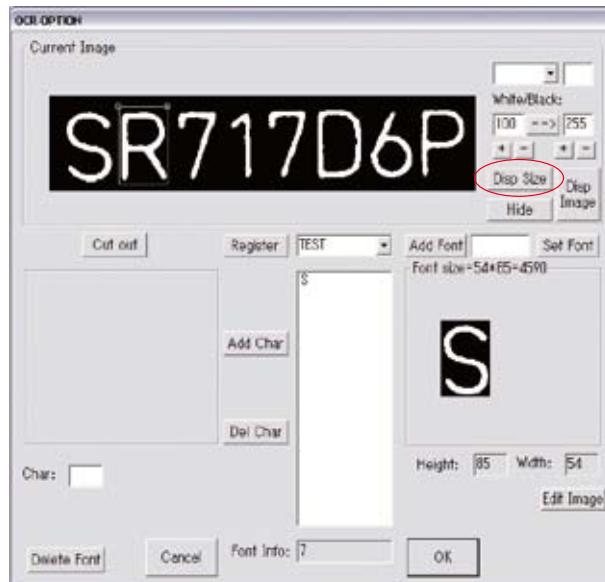


Figure 2-8 OCR_Pro7

Step12: All characters are registered and press **OK**. The dialog shown in Figure 2-10 appears and press **Yes**.

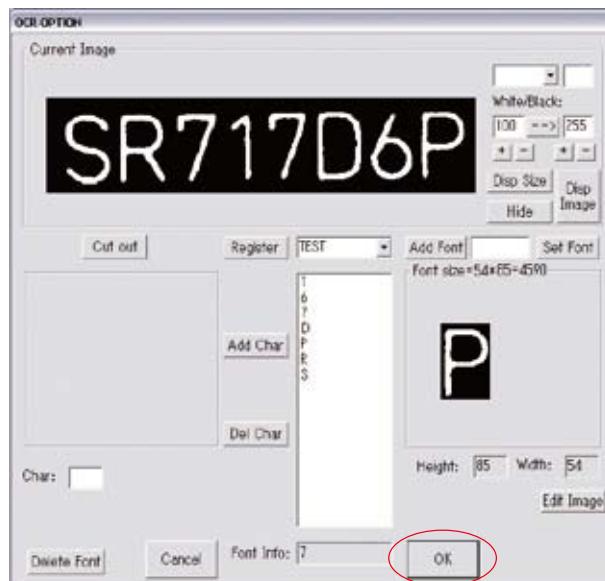


Figure 2-9 OCR_Pro8

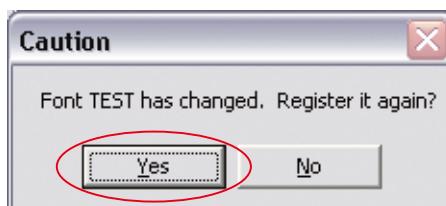


Figure 2-10 OCR_Pro9

Step13: Select **Font** from the **Define Font** drop-down list.

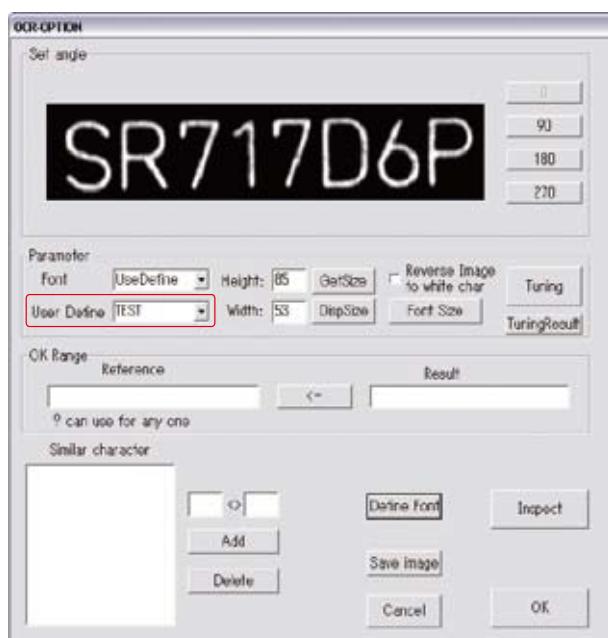


Figure 2-11 OCR_Pro10

Step14: Enter all target characters in the **Reference** text-box.

NOTE If "?" is registered, any character is judged OK.

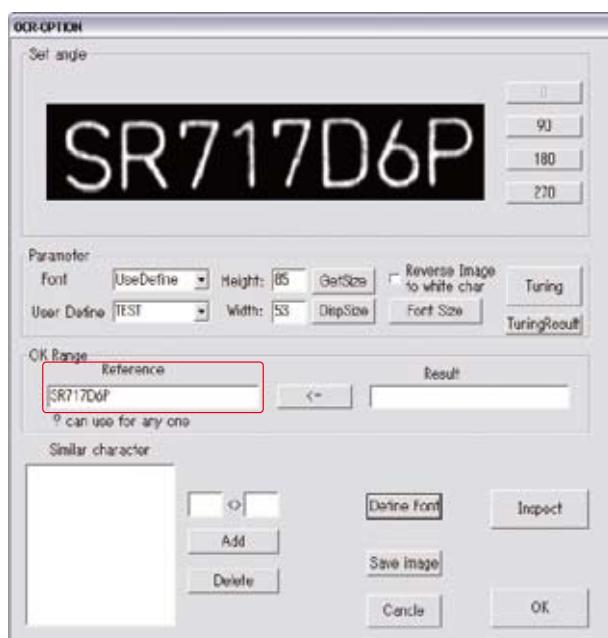


Figure 2-12 OCR_Pro11

Step15: Adjust the window size to surround a character and press **GetSize**. Height and Width are automatically calculated.

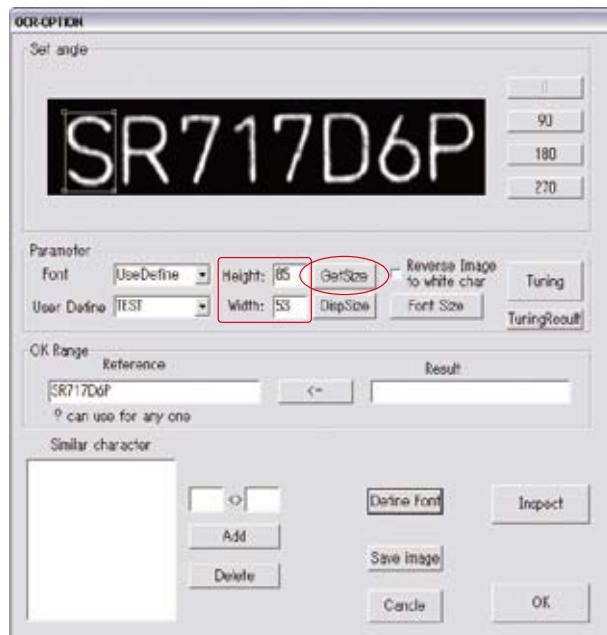


Figure 2-13 OCR_Pro12

Step16: Press **Tuning**. The recognized characters are displayed in the **Result** text-box.

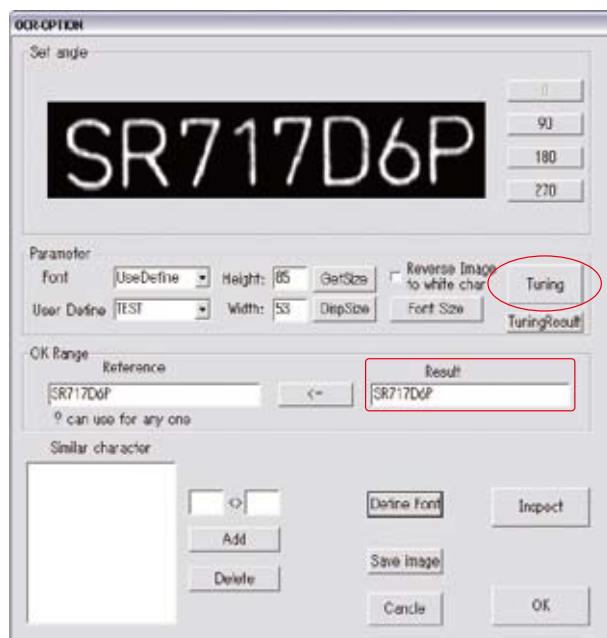


Figure 2-14 OCR_Pro13

Step17: If similar characters are mis-recognized such as “1” and “I” or “0” and “O”, enter the similar characters into two text boxes in the right side of **Similar character**. Once the characters are registered, the result will be OK, regardless of recognized character. To delete the registered item, select the item and press **Delete**.

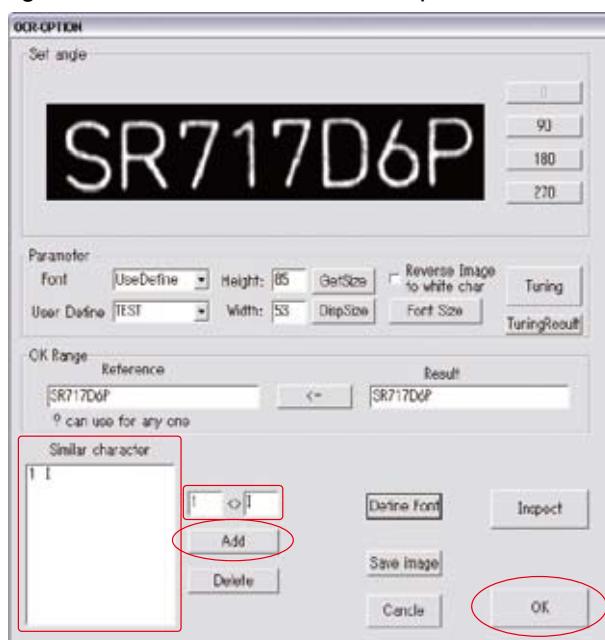


Figure 2-15 OCR_Pro14

Step18: If all target characters are correctly displayed in **Result** field. Press **OK**.

Step19: The window shown in Figure 2-16 appears. Enter the number of characters to **Upper** field and **Lower** field.

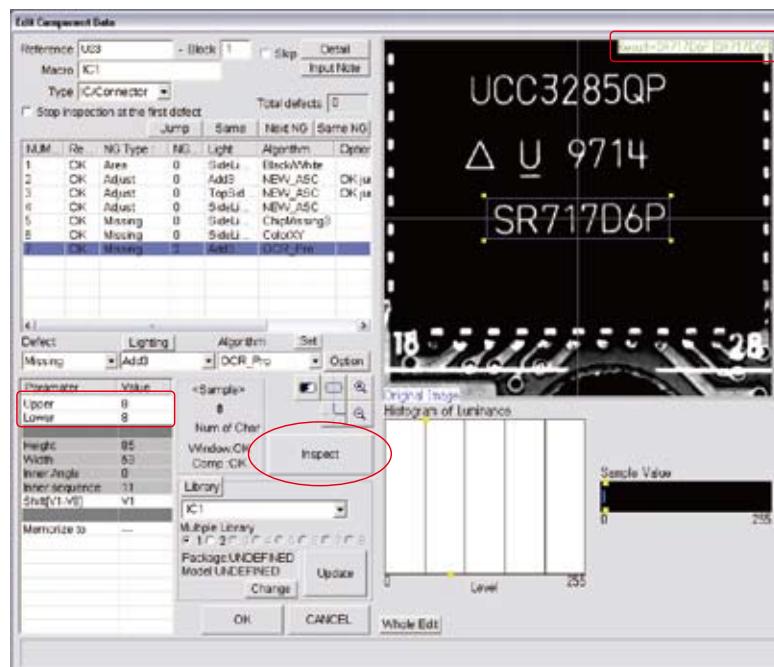


Figure 2-16 OCR_Pro15

Step20: Press **Inspect**. Check all target characters are correctly displayed in the upper right side of the window in Figure 2-16.

2.2 Barcode_Pro

2.2.1 Inspection Overview

Barcode_Pro is the algorithm to recognize 1D barcode and 2D barcode.

If the target digit and recognized digit number is the same, the result will be OK.

Barcode_Pro is suitable for PCBs traceability.

2.2.2 Parameter Setting

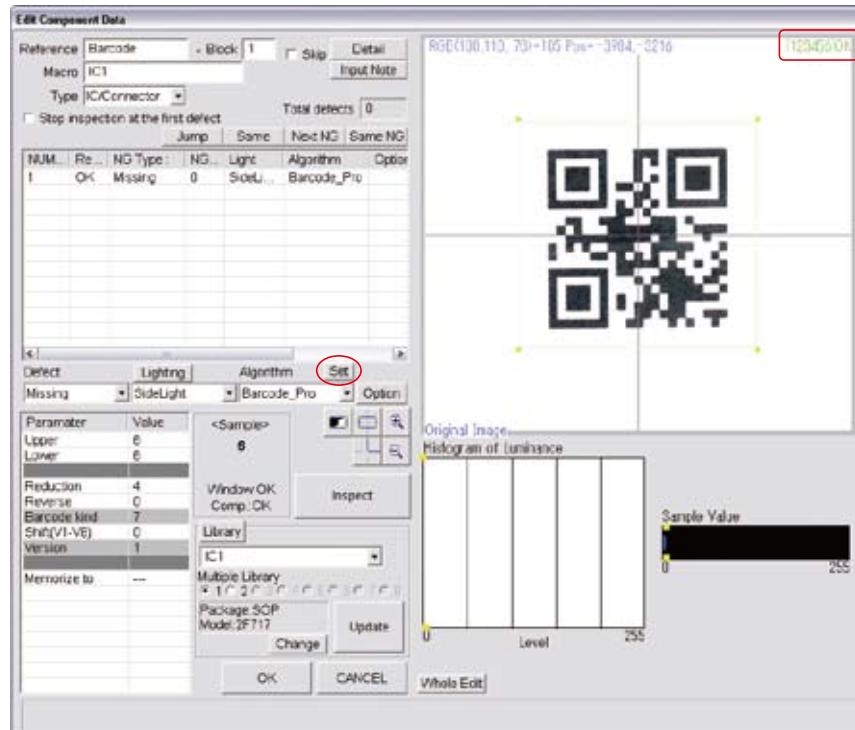


Figure 2-17 Barcode_Pro

| Parameter | Description |
|--------------|---|
| Lighting | Select a lighting that barcode is visually clear. |
| Algorithm | Select Barcode_Pro . |
| Upper, Lower | Enter the digit number of barcode to Upper field and Lower field. The sample value is the digit number of the recognized barcode. If the target digit and recognized digit number is the same, the result will be OK. |
| Reduction | Enter 4 this field. |
| Reverse | Enter 0 if the brightness level of the barcode is lower than surrounding brightness. Enter 1 if it is higher. |
| Barcode kind | - |
| Shift[V1-V8] | Enter appropriate vector according to the vector used in Memorize to in Adjust window. |
| Version | - |
| Memorize to | - |

Table 2-2 Parameter of Barcode_Pro

2.2.3 Setting Procedure

Step1: Select a lighting that barcode is visually clear from the **Lighting** drop-down list.

Step2: Set the inspection window three pixels wider than actual barcode.

NOTE

Refer to **1.20.3 Setting Procedure** step2 for 1D barcode inspection.

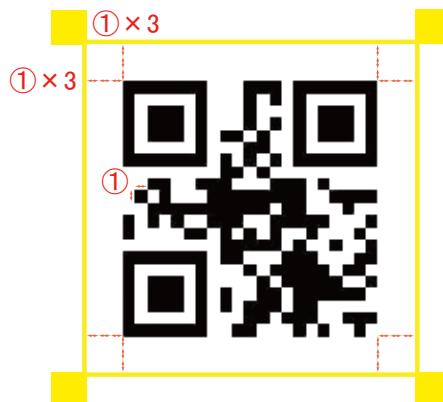


Figure 2-18 Inspection window of Barcode_Pro

Step3: Press **Set** and the window shown in Figure 2-19 appears.

Check the barcode kind and press **OK**.

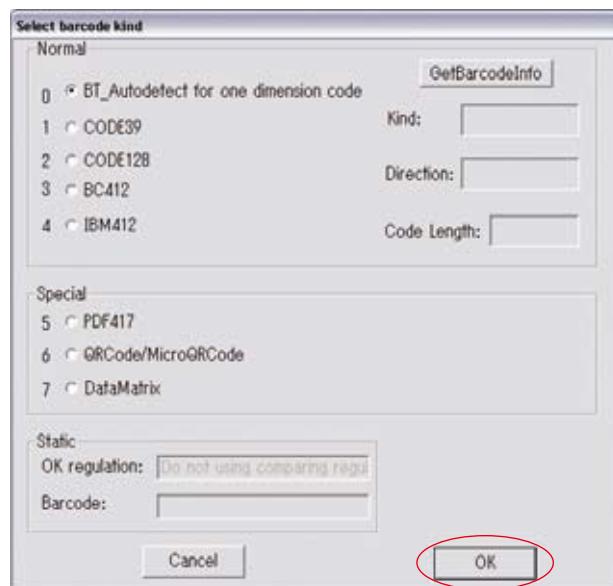


Figure 2-19 Barcode kind

Step4: Press **Inspect** and check if the alphanumeric character of the barcode is correctly displayed in the upper right of the window shown in Figure 2-17.

Customer Support Contacts

| | | |
|--------------|---|--------------------|
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